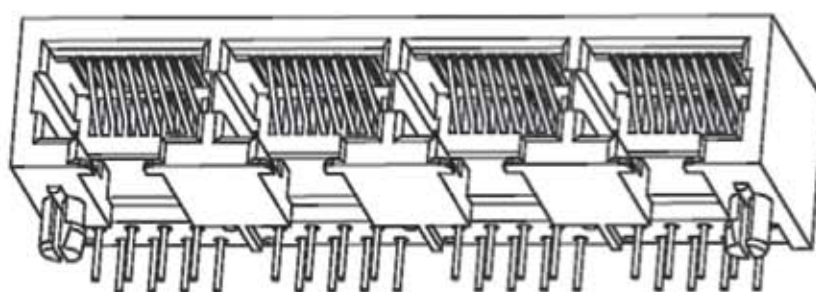
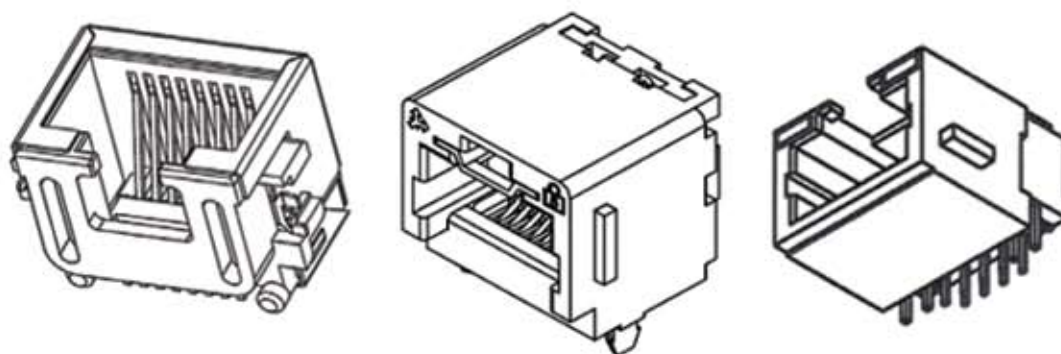


ELITALLA

MODULAR PCB JACKS

SIDE ENTRY SINGLE LEVEL MODULAR PCB JACKS

LOCK TYPE SIDE ENTRY MODULAR PCB JACKS



CAT. LAN-N-1-A
section A : shielded

DESCRIPTION	PAGE
SIDE ENTRY SINGLE LEVEL MODULAR PCB MOUNT JACKS	
FULLY & HALF SHIELDED SIDE ENTRY MODULAR PCB JACK DIP TYPE-----	SECTION - A-----N0001~N0210
FULLY & HALF SHIELDED SIDE ENTRY MODULAR PCB JACK SMT TYPE-----	SECTION - A-----N0701~N0735
UNSHIELDED SIDE ENTRY MODULAR PCB JACK DIP TYPE-----	SECTION - B-----N2001~N2220
UNSHIELDED SIDE ENTRY MODULAR PCB JACK SMT TYPE-----	SECTION - B-----N2501~N2541
LOCK TYPE SIDE ENTRY MODULAR PCB JACKS	
FULLY SHIELDED LOCK TYPE SIDE ENTRY MODULAR PCB JACK-----	N2901
UNSHIELDED LOCK TYPE SIDE ENTRY MODULAR PCB JACK-----	N2951~N2952
LOCK KEY FOR LOCK TYPE MODULAR PCB JACK-----	N2991~N2992

ORDERING INFORMATION:

P/N MJxx - xxxxxxxxxxxxxxxx
1 2 3 4 5 6 7 8

- | | |
|--|---|
| <p>1. JACK TYPE:
 "MJ" MODULAR PCB JACK
 "LT" MAGNETIC JACK</p> <p>2. JACK CODE:
 01, 02, 03 ... till 99
 1A, 1B, 1C ... till 9Z
 A1, A2, A3 ... till Z9
 AA, AB, AC ... till ZZ</p> <p>3. NO. OF POSITIONSS & CONTACTS:
 "42" 4P2C "44" 4P4C
 "62" 6P2C "64" 6P4C
 "66" 6P6C "82" 8P2C
 "84" 8P4C "86" 8P6C
 "88" 8P8C "00" 10P10C
 "08" 10P8C "T8" 12P8C</p> | <p>4. CONTACT FINISH:
 "A" 6 MICROINCH GOLD PLATED
 "B" 15 MICROINCH GOLD PLATED
 "C" 30 MICROINCH GOLD PLATED
 "D" 50 MICROINCH GOLD PLATED
 "E" GOLD FLASH PLATED</p> <p>5. COLOR OF HOUSING:
 "A" GRAY
 "B" BLACK
 "R" RED
 "W" WHITE</p> <p>6. MAGNETIC SCHEMATICS</p> <p>7. COLORS OF LED</p> <p>8. NO. OF PORTS:
 02, 04, 05, 06, 08 ... 16</p> |
|--|---|

- TECHNICAL ALTERNATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE.
- ALL ARTICLES ARE RoHS & REACH/SVHC COMPLIANT.

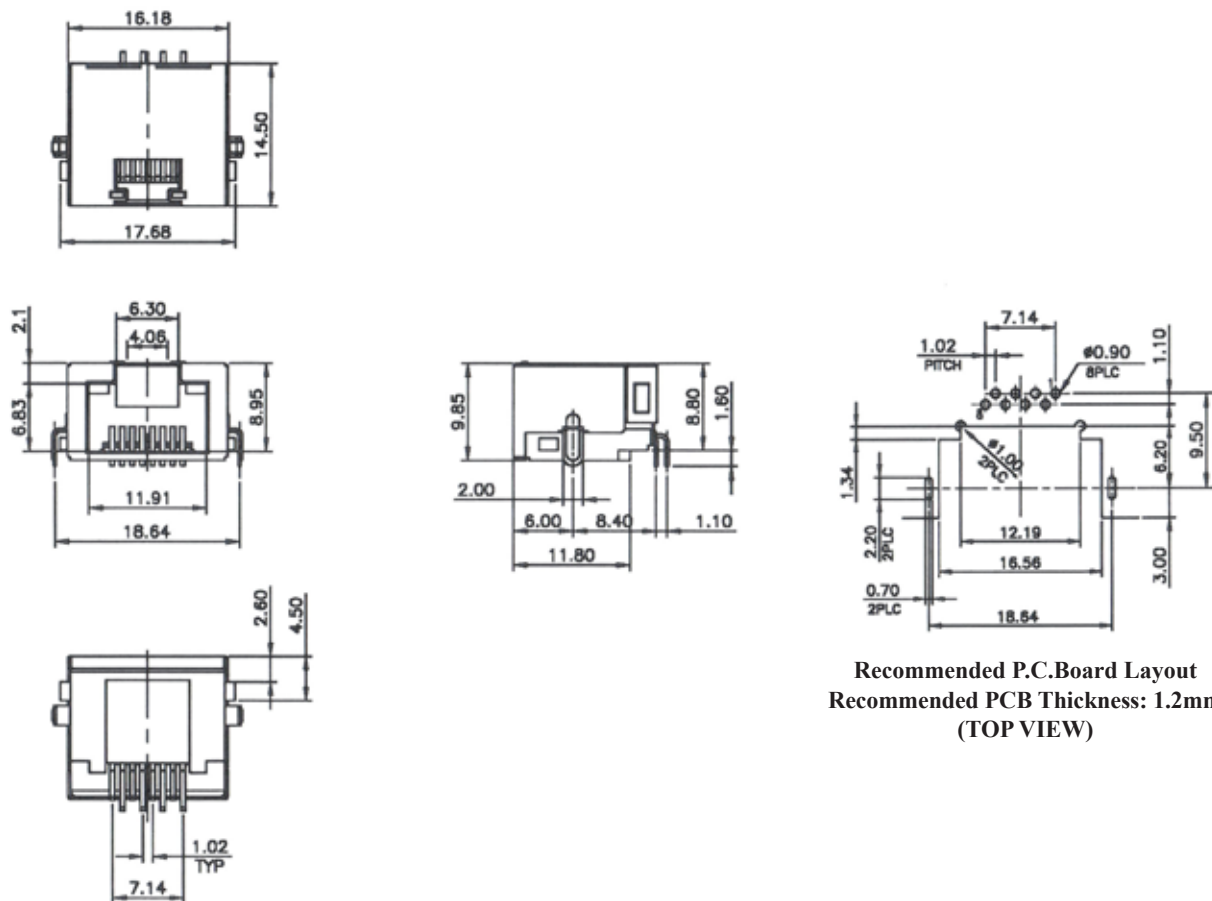
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=9.85MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
 Recommended PCB Thickness: 1.2mm
 (TOP VIEW)

ORDERING INFORMATION:

P/N M J ZA - 88 x B
 1 2 3 4

- MODULAR JACK TYPE:
"ZA" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=10.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

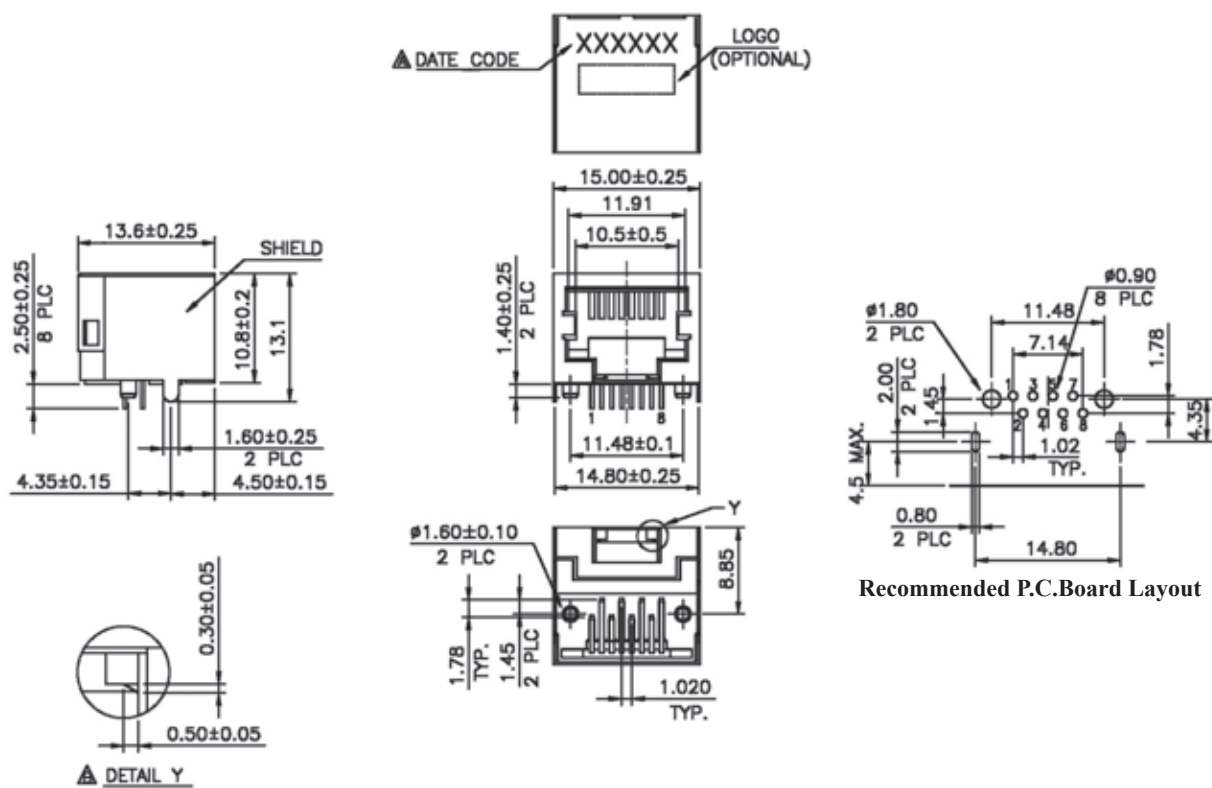
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J NG - 88 x B
1 2 3 4

1. MODULAR JACK TYPE:
"NG" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

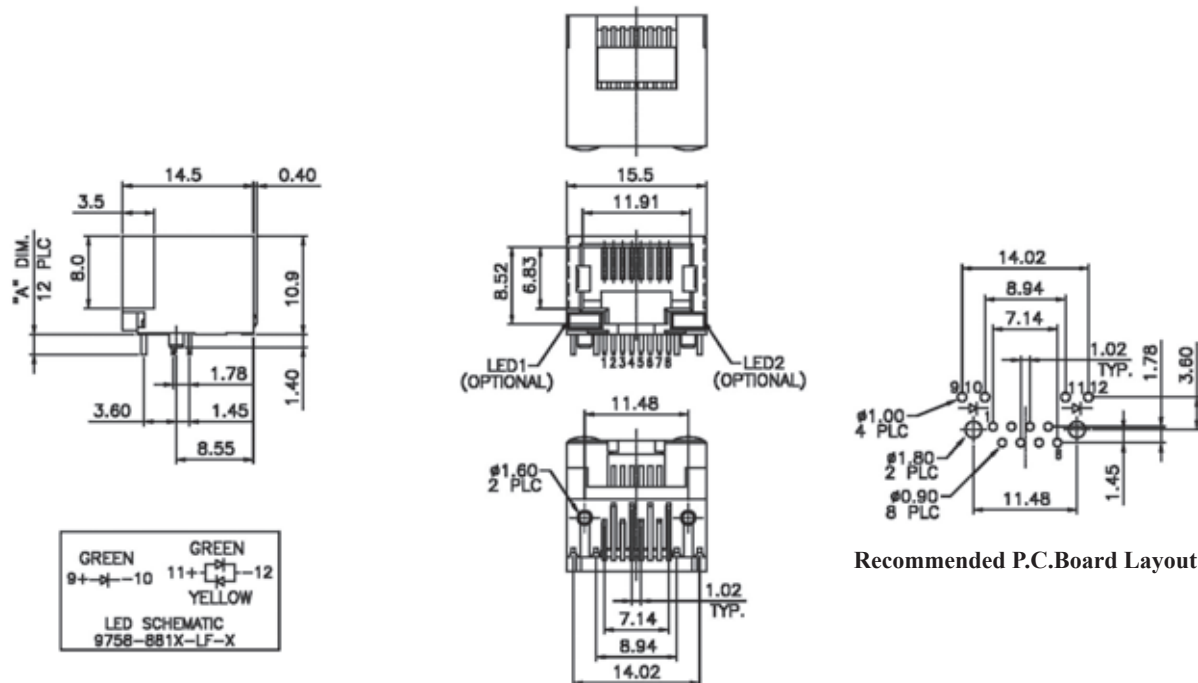
SIDE ENTRY MODULAR PCB JACK 8P WITH LED PROFILE=10.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K P - 8 8 X B X X
 1 2 3 4 5

- MODULAR JACK TYPE:
"KP" VERY LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

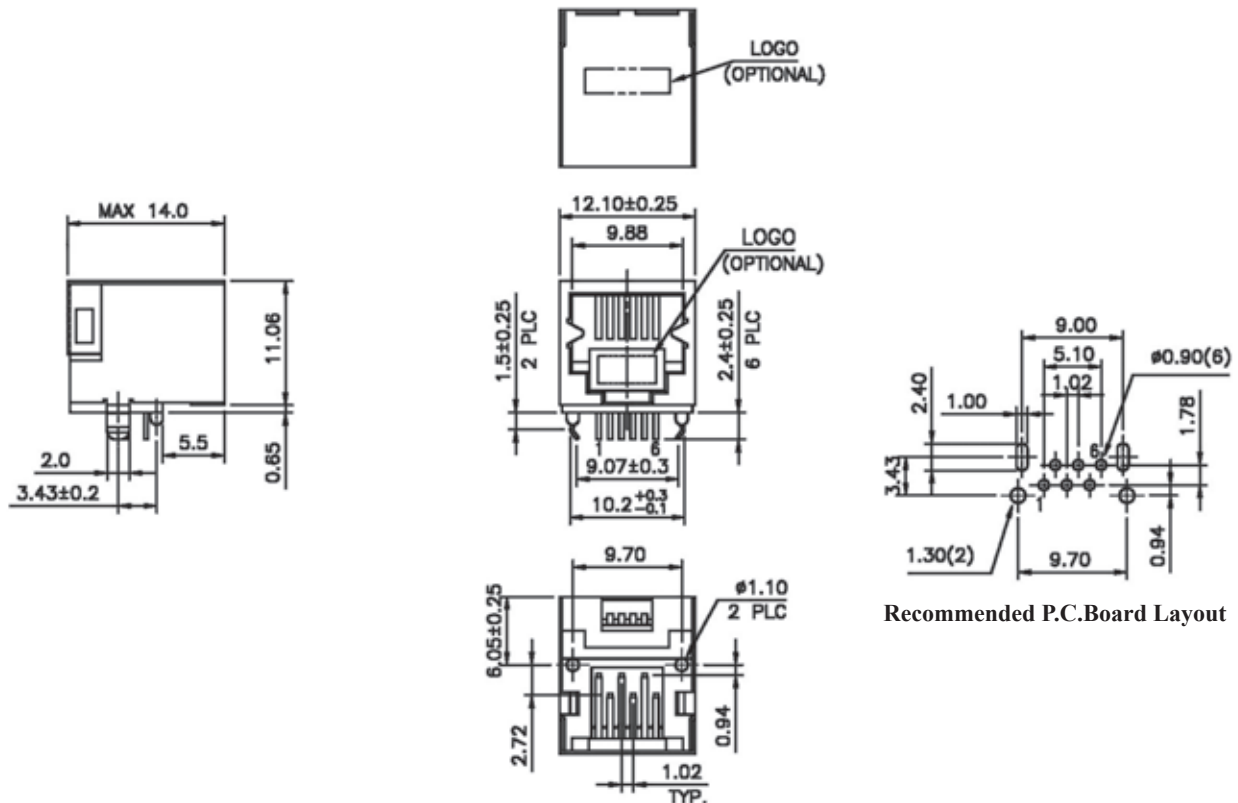
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{K}{I}$ U - $\frac{x}{2}$ $\frac{x}{3}$ $\frac{x}{4}$ B

1. MODULAR JACK TYPE:
"KU" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

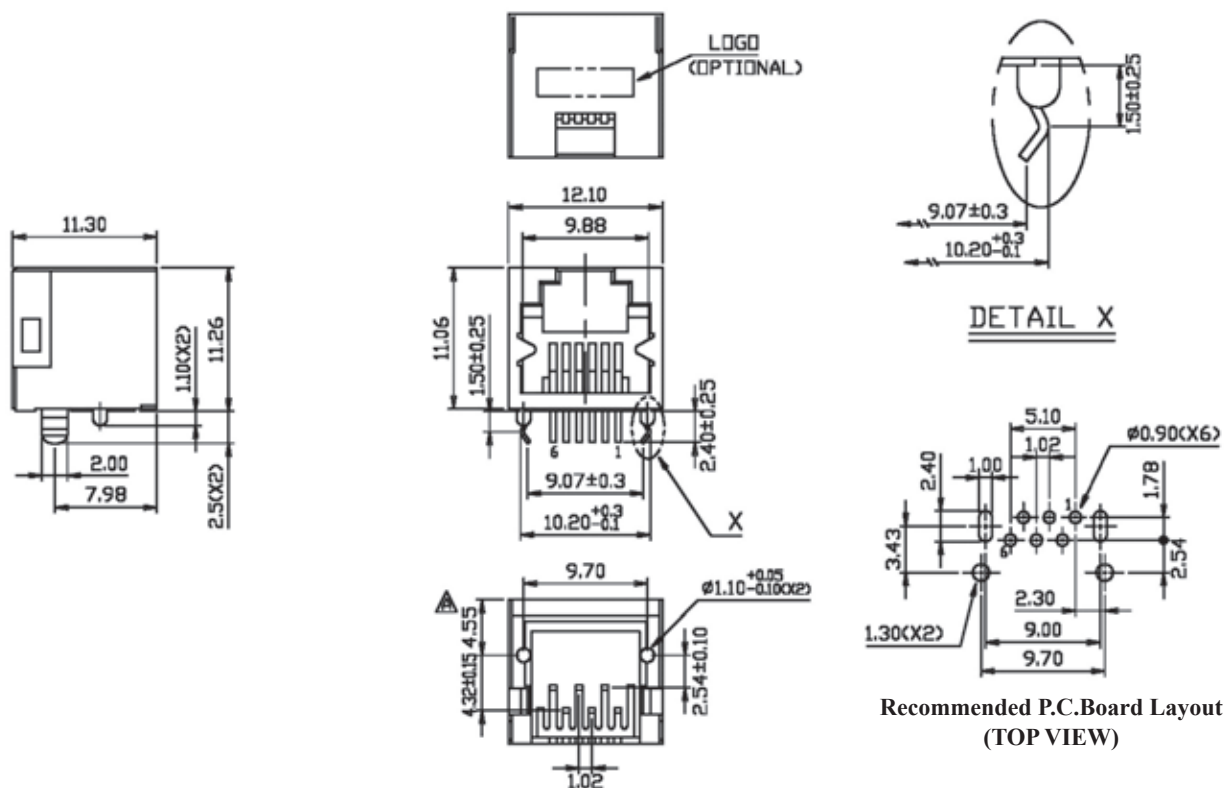
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J Y M - 6 6 x B
 1 2 3 4

1. MODULAR JACK TYPE:
"YM" RJ11 JACK
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

tel. 02.3361.1626 info@elitaliaweb.it
fax 02.2626.1009 www.elitaliaweb.it

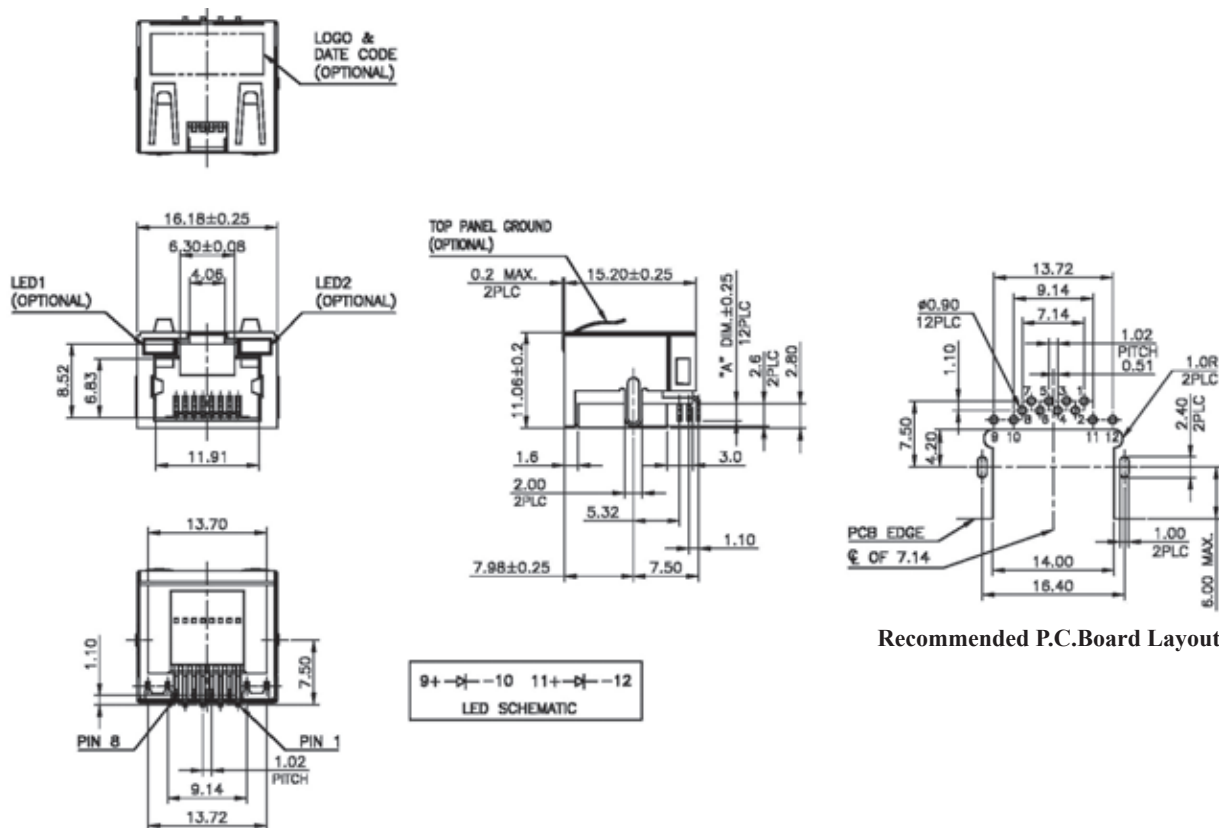
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$ $\frac{xx}{5}$

- MODULAR JACK TYPE:
 "NA" WITH TOP PANEL GROUP
 "NB" WITHOUT PANEL GROUP
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- LED COLORS:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

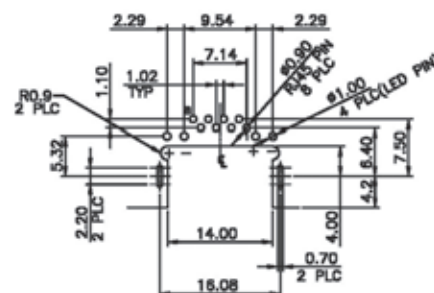
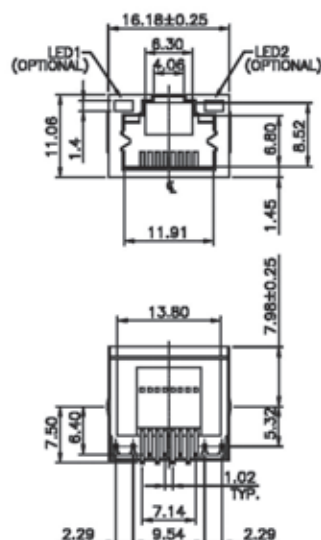
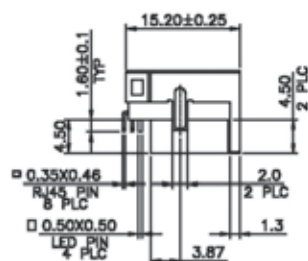
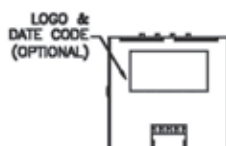
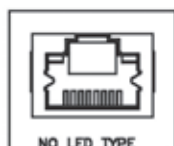
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J NC - 88 x B x X
1 2 3 4 5

1. MODULAR JACK TYPE:

"NC" EMBEDDED PCB JACK

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

5. LED COLORS:

"NN" LED1/2 = GREEN/GREEN

"NY" LED1/2 = GREEN/YELLOW

"YN" LED1/2 = YELLOW/GREEN

"YY" LED1/2 = YELLOW/YELLOW

"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

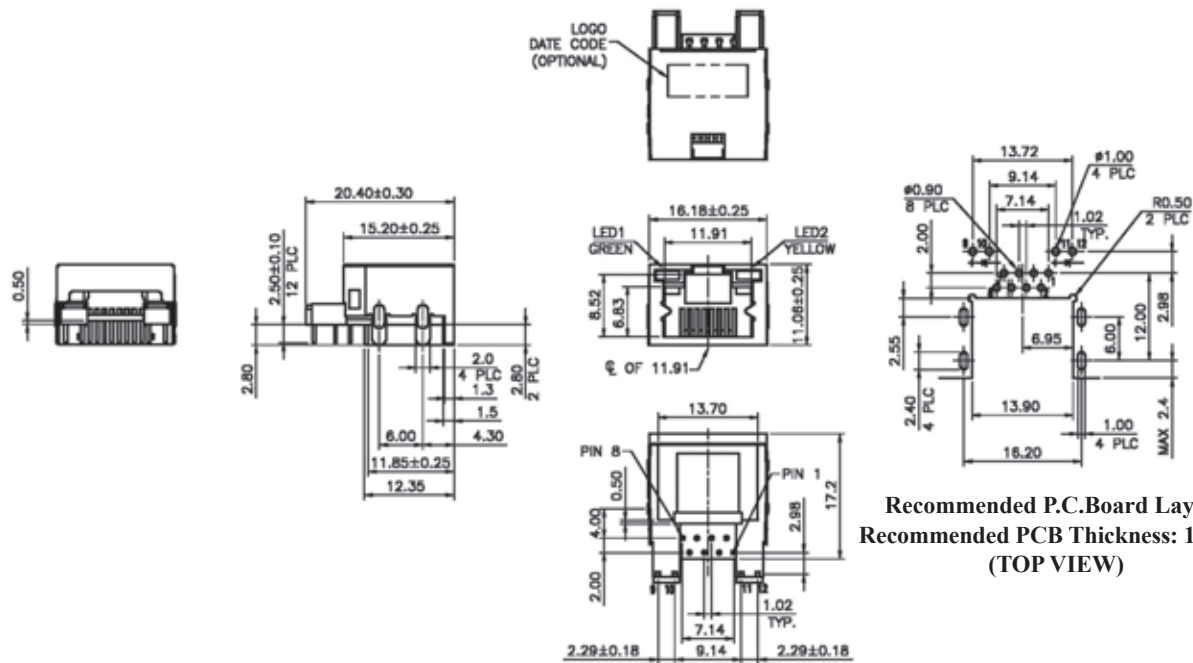
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 1.2mm
(TOP VIEW)

P/N MJNE-88xBNY

ORDERING INFORMATION:

P/N MJNE-88xBNY

- MODULAR JACK TYPE:
"NE" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

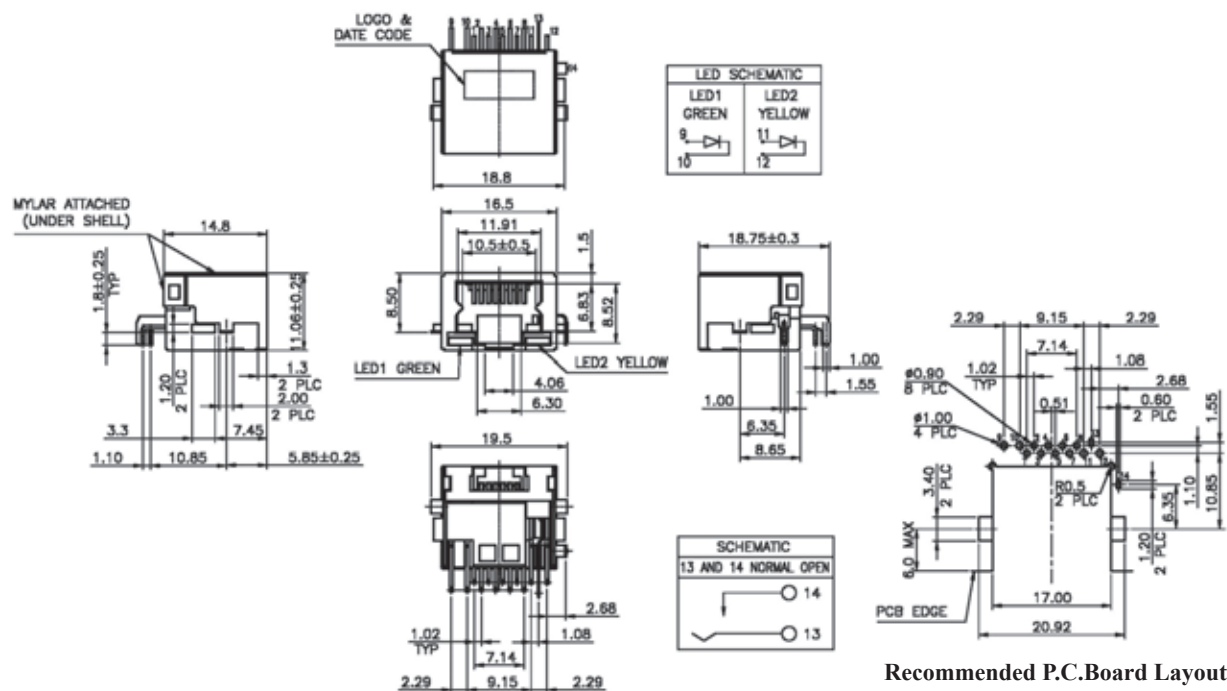
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH SWITCH & LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJYU-88xBNY

ORDERING INFORMATION:

P/N MJYU - 88 x B x X
 1 2 3 4 5

- MODULAR JACK TYPE:
"YU" EMBEDDED PCB JACK WITH SWITCH
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

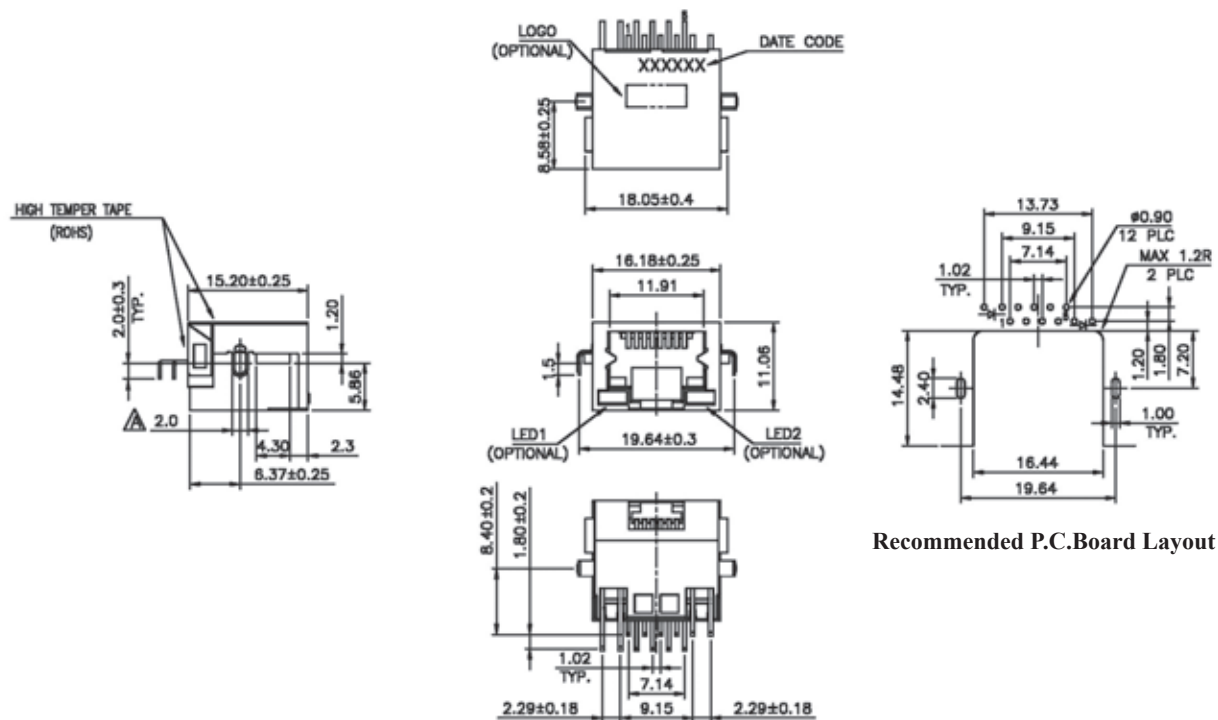
SIDE ENTRY EMBEDDED REVERSE MOUNT MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y V - 8 8 x B x x
1 2 3 4 5

- MODULAR JACK TYPE:
"YV" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

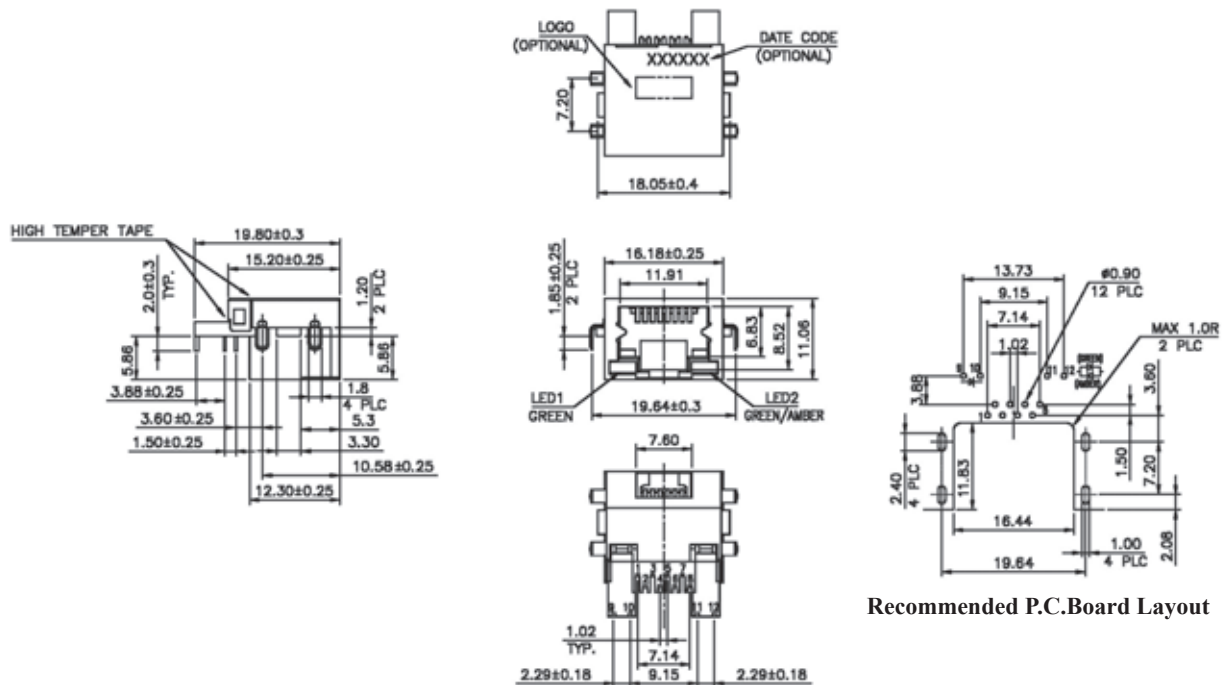
SIDE ENTRY EMBEDDED REVERSE MOUNT MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJYW-88xBNB

ORDERING INFORMATION:

P/N MJYW - 88 x BNB
1 2 3 4 5

- MODULAR JACK TYPE:
"YW" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NB" LED1 = GREEN &
LED2 = GREEN/AMBER

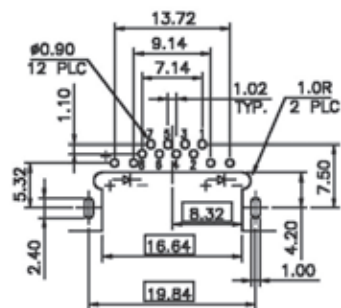
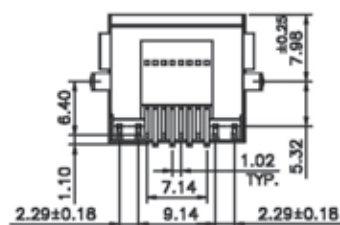
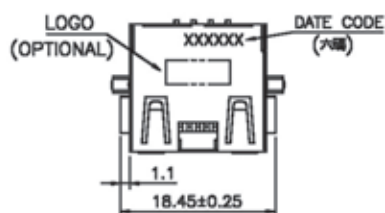
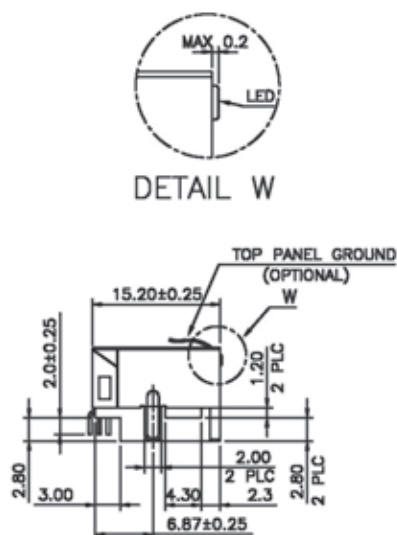
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y X - 8 8 X B X X
 1 2 3 4 5

- MODULAR JACK TYPE:
"YX" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

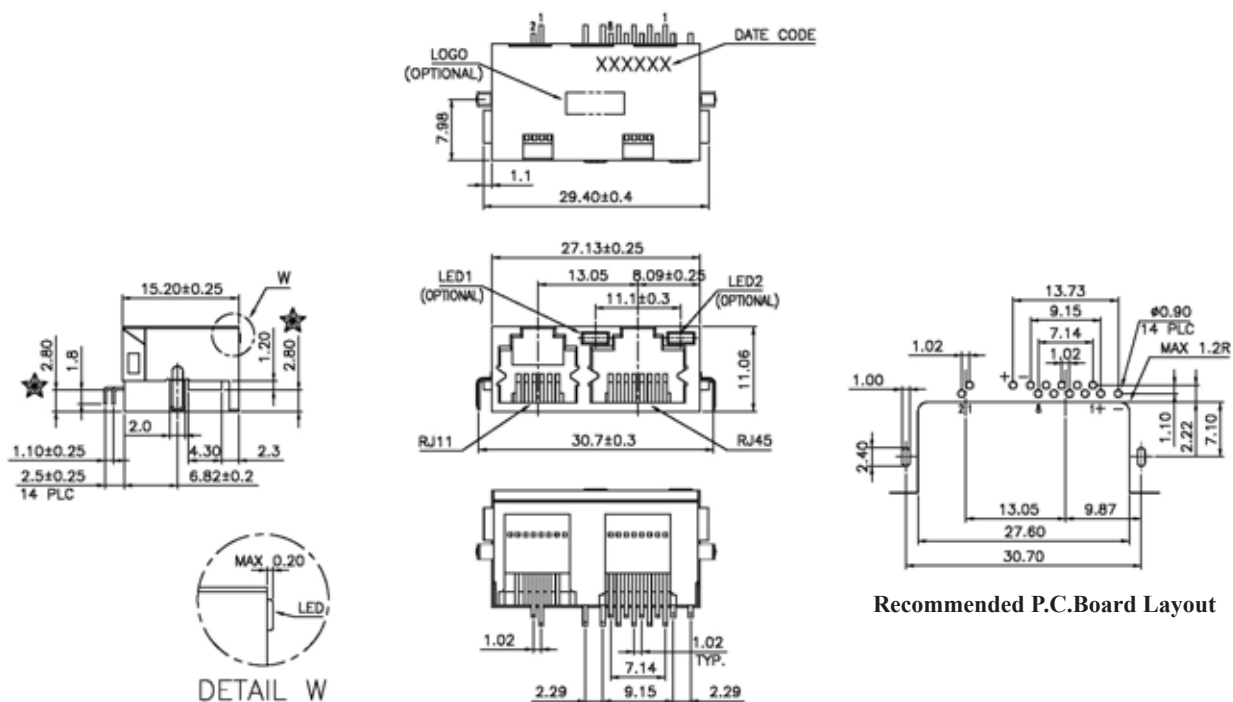
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Z C - 2 8 X B X X 0 2
1 2 3 4 5 6

- MODULAR JACK TYPE:
"ZC" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

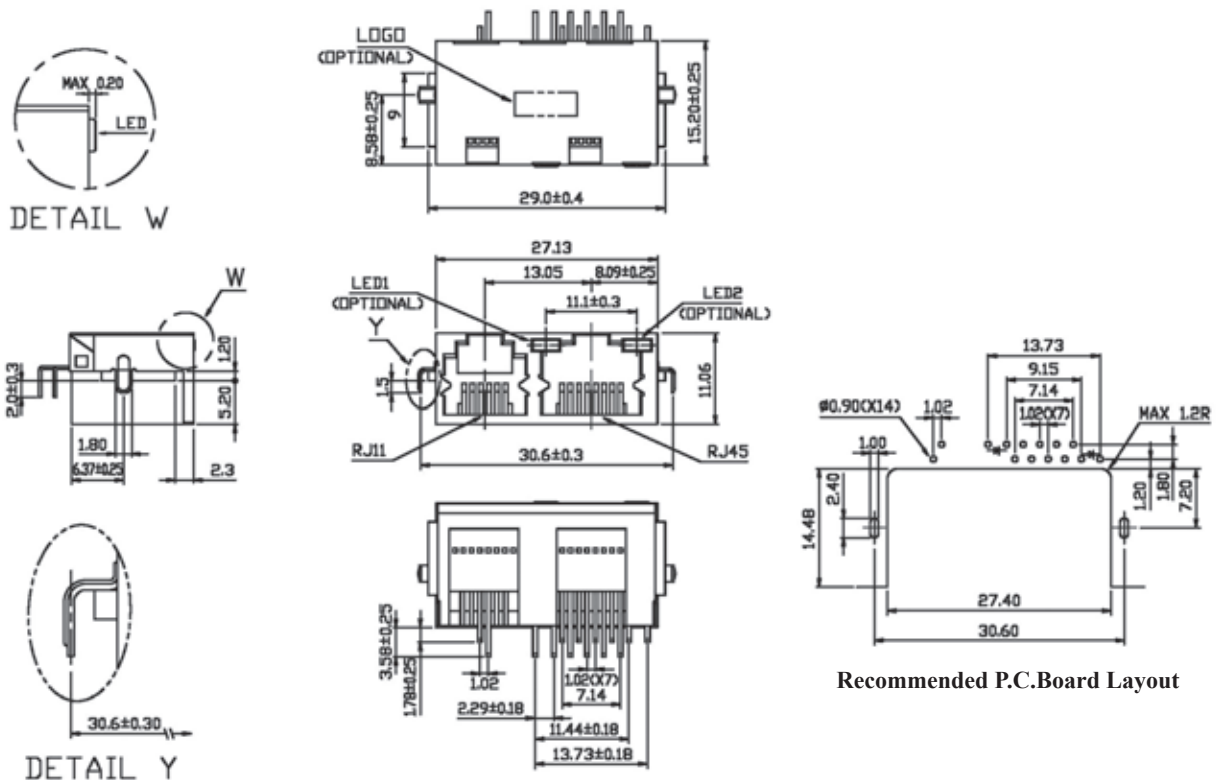
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Y R - 2 8 x B x x 0 2
1 2 3 4 5 6

- MODULAR JACK TYPE:
"YR" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

SIDE ENTRY EMBEDDED MODULAR PCB JACK WITH LED 8P PROFILE=11.12MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

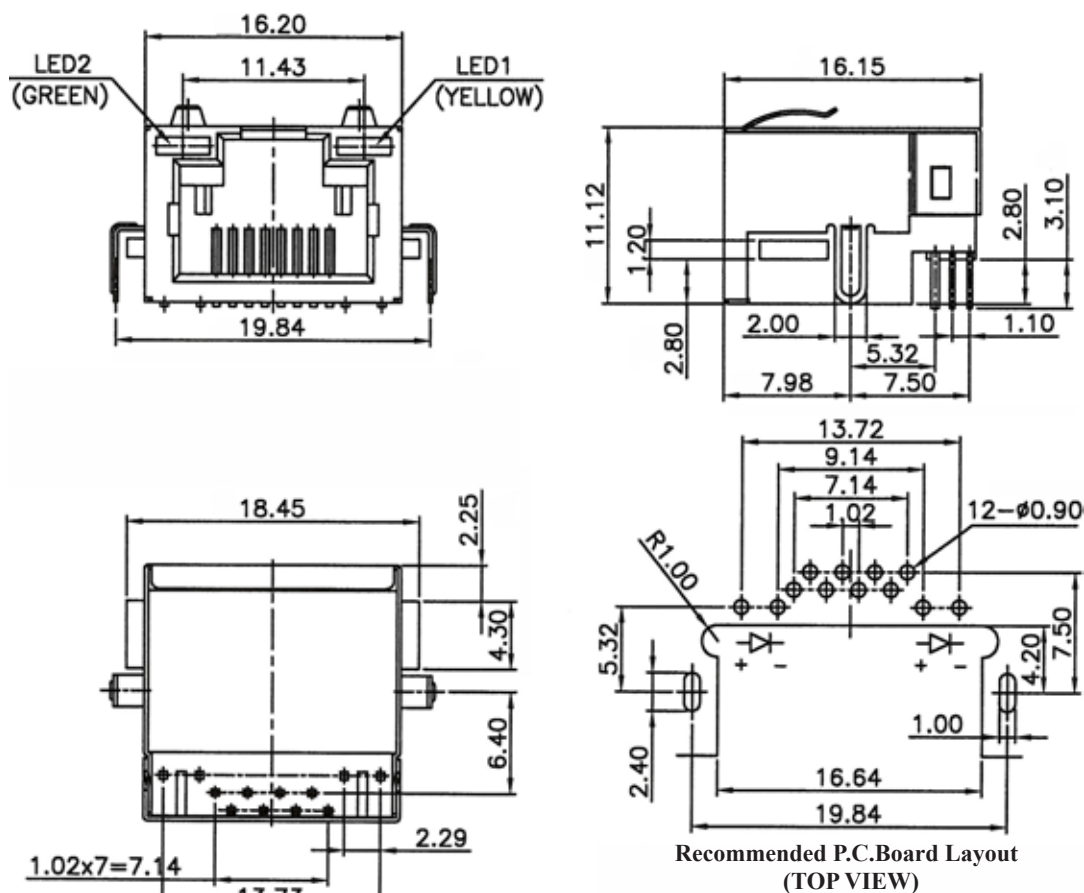
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J B 7 - $\frac{xx}{1} \frac{xx}{2} \frac{xx}{3}$ B $\frac{xx}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LED1: GREEN & LED2: GREEN

"NY" LED1: GREEN & LED2: YELLOW

"YN" LED1: YELLOW & LED2: GREEN

"YY" LED1: YELLOW & LED2: YELLOW

"XX" W/O LED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

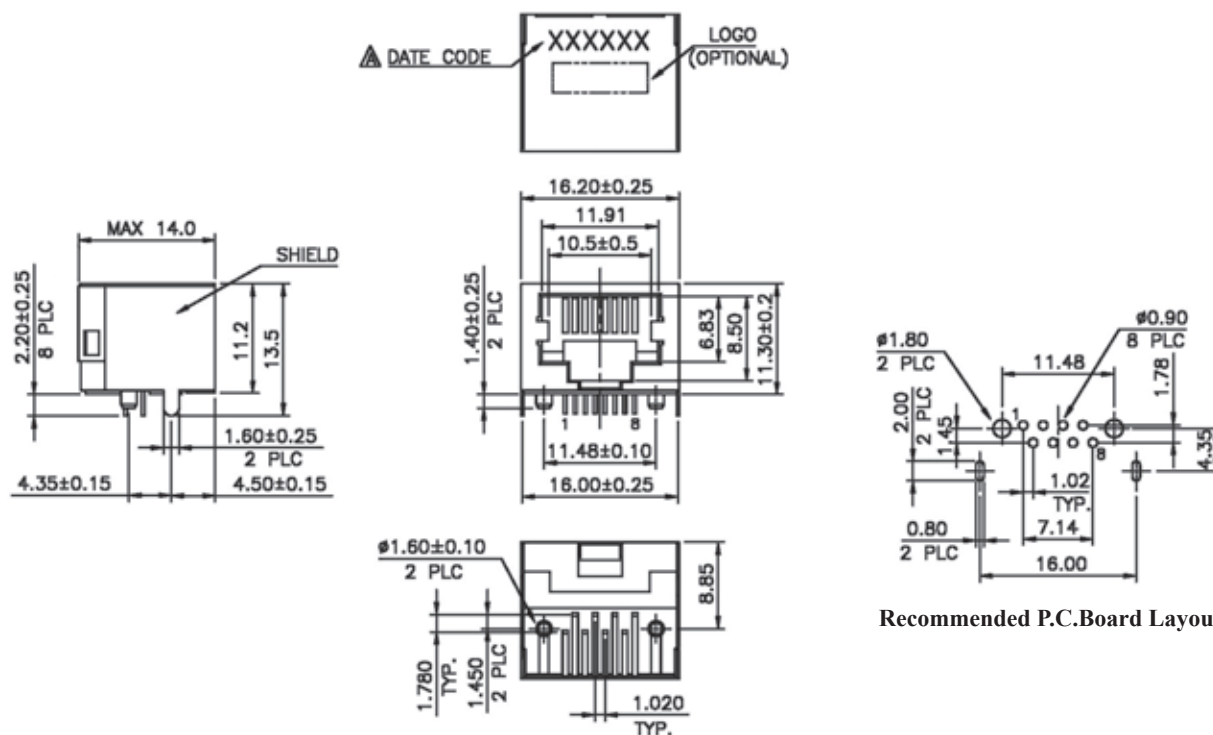
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N P - 88 x B
I 2 3 4

1. MODULAR JACK TYPE:
"NP" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

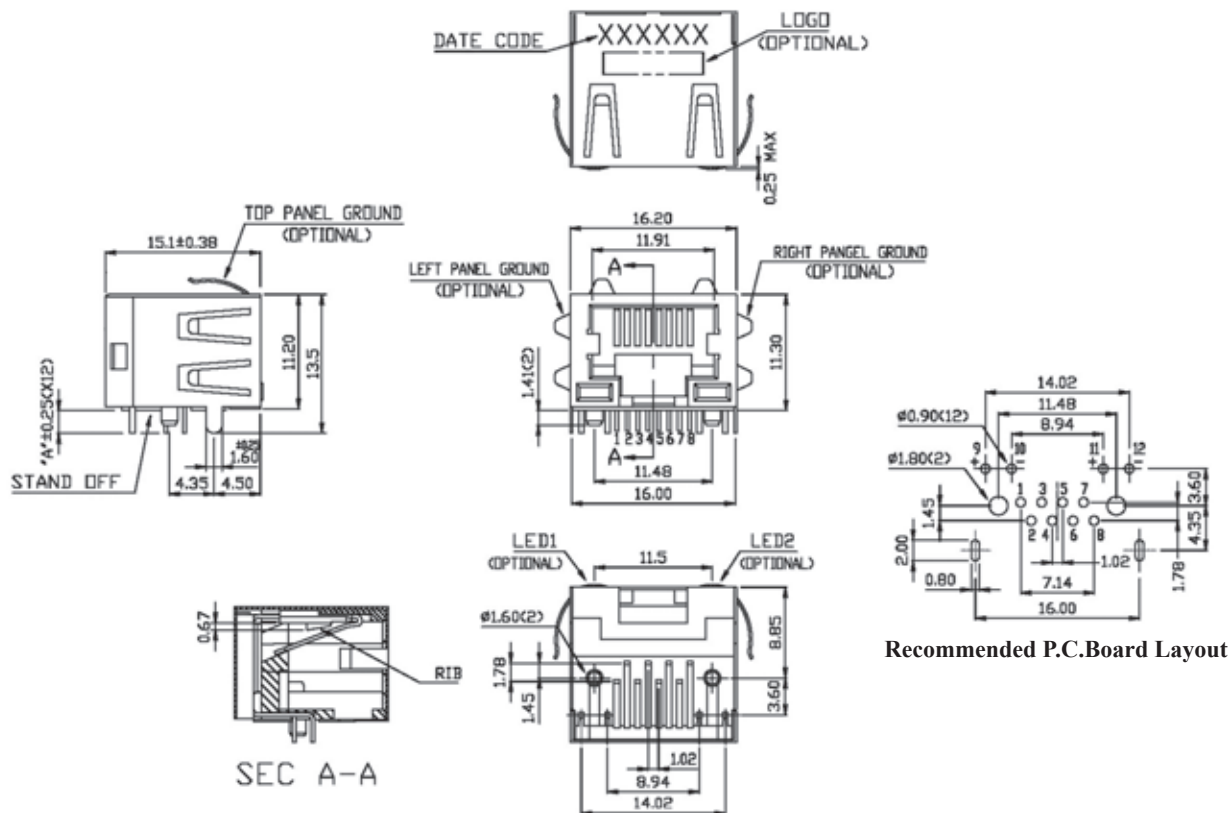
SIDE ENTRY MODULAR PCB JACK 8P WITH LED PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J xx - 88 x B xx
 1 2 3 4 5

- MODULAR JACK TYPE:
"KT" WITH TOP/RIGHT/LEFT SIDE TABS
"KS" WITH RIGHT/LEFT TABS
"KR" WITH TOP SIDE TABS
"KQ" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

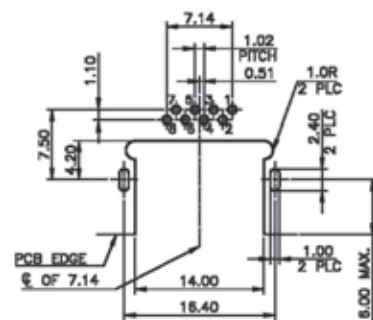
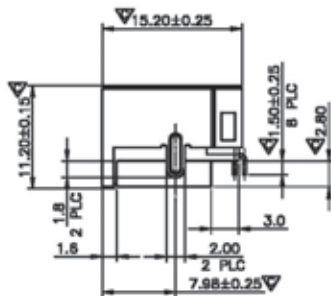
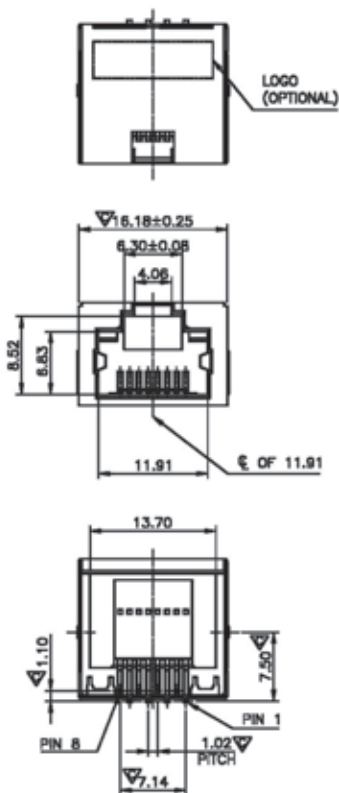
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 1.2mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J Z G - 88 x B
1 2 3 4

- MODULAR JACK TYPE:
"ZG" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P2C PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

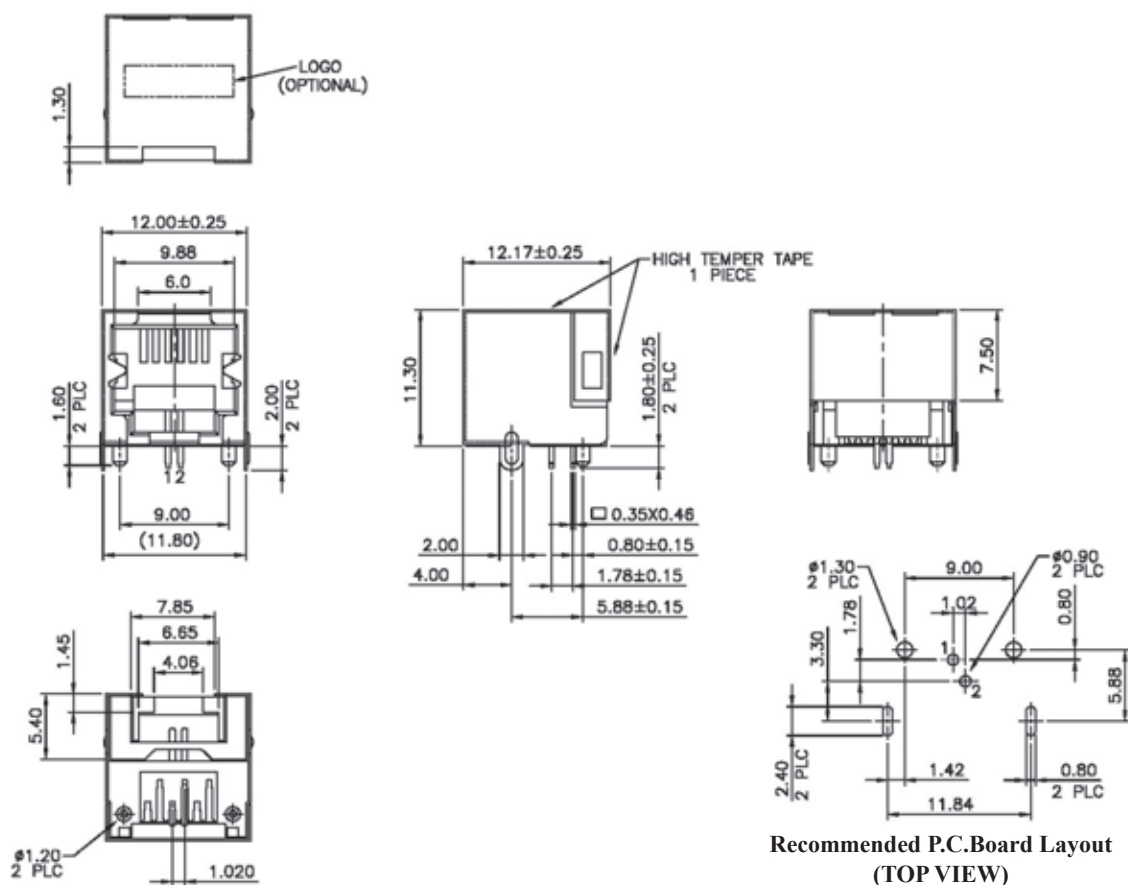
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{VZ}{1}$ - $\frac{62}{2}$ x $\frac{B}{34}$

1. MODULAR JACK TYPE:
"VZ" 6P2C JACK
2. NO. OF POSITIONS & CONTACTS:
"62" 6P2C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

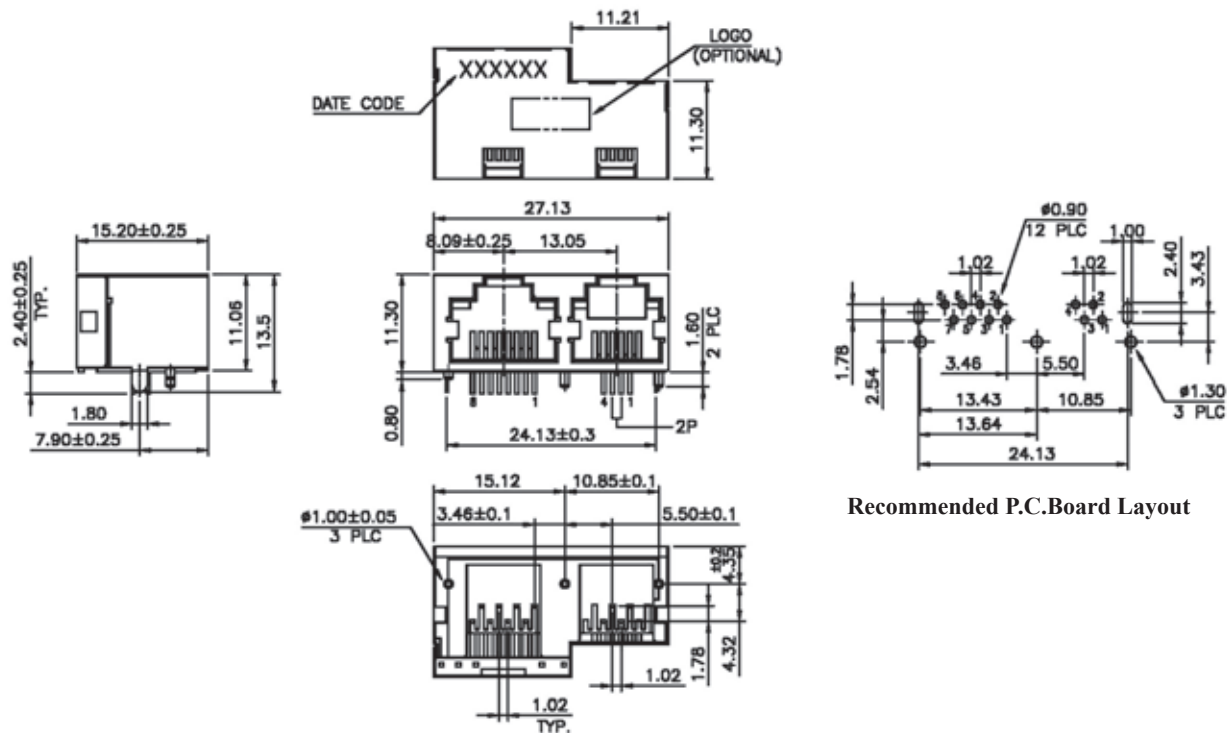
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 4P+8P PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J KG - 48 x B 02
1 2 3 4 5

- MODULAR JACK TYPE:
"KG" RJ11/RJ45 SIDE BY SIDE JACK
- NO. OF POSITIONS & CONTACTS:
"48" 4P4C & 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- NO. OF PORTS:
02

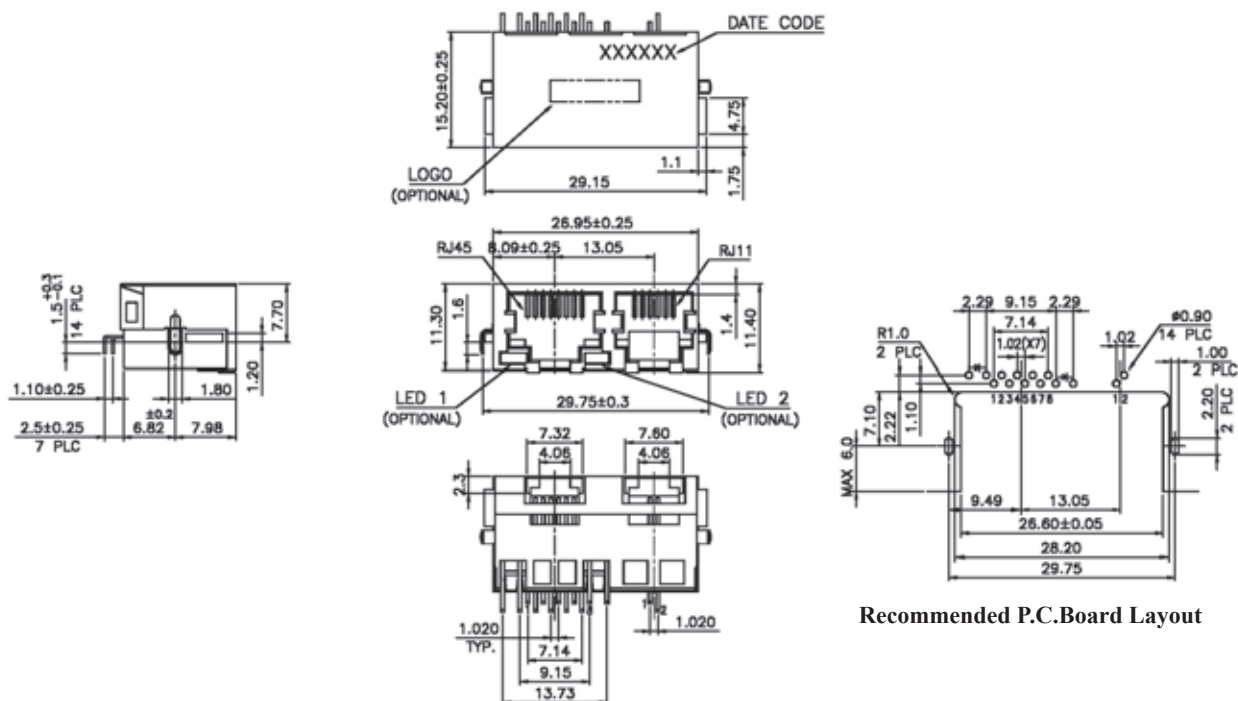
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y Q - 2 8 x B x x 0 2
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"YQ" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

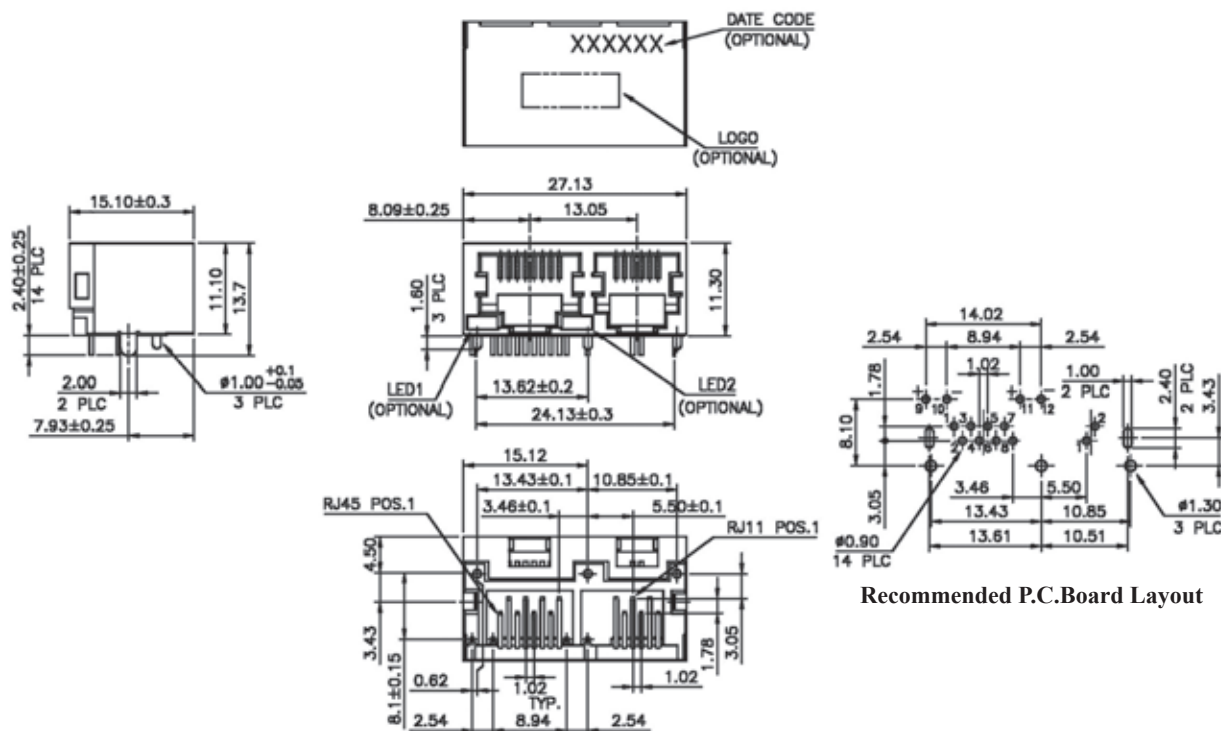
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P+2P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N Q - 2 8 x B x x 0 2
1 2 3 4 5 6

- MODULAR JACK TYPE:
"NQ" RJ45+RJ11 SIDE BY SIDE JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C & 8P8C JACK
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

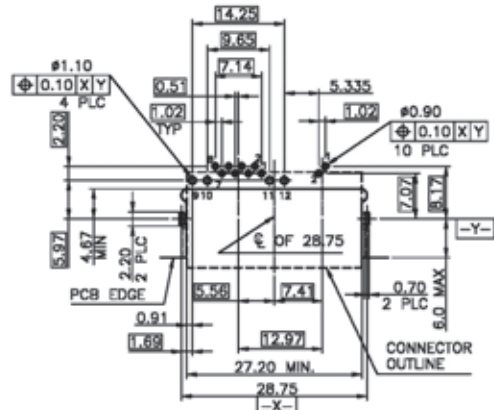
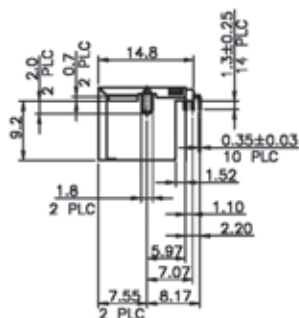
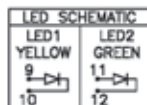
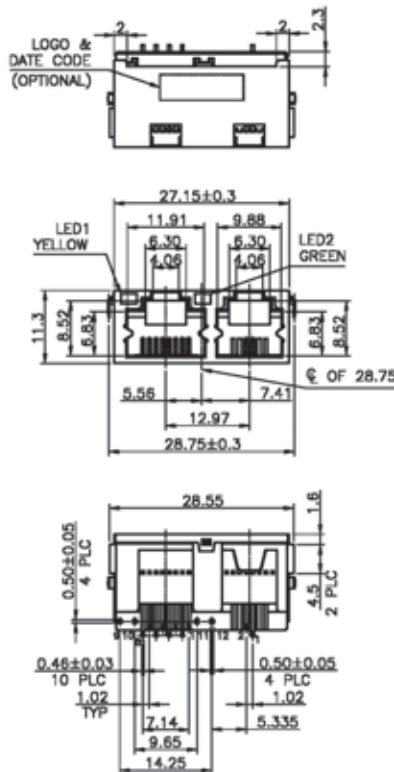
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

P/N MJYP-28xBYN02

ORDERING INFORMATION:

P/N MJYP - 28 x B x x 02
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"YP" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

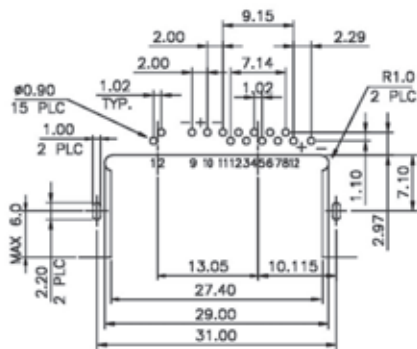
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 2P+8P WITH LED PROFILE=11.40MM (FULLY SHIELDED)

SPECIFICATIONS

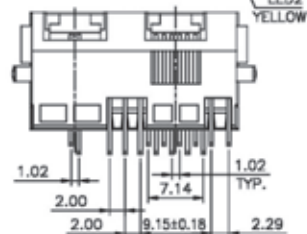
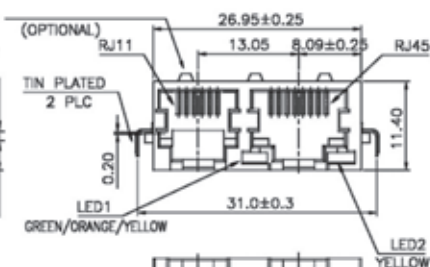
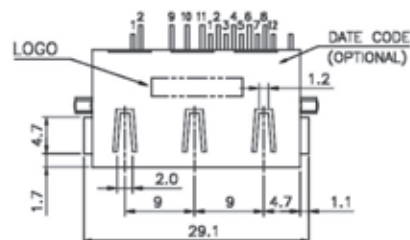
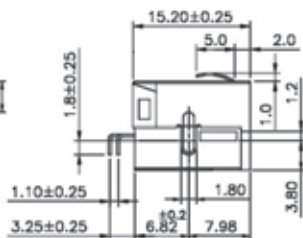
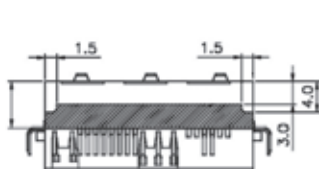
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout



P/N MJZB-28xBTY02

ORDERING INFORMATION:

P/N MJZB-28xBTY02
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"ZB" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"TY" LED1 = GREEN/ORANGE/YELLOW &
LED2 = YELLOW
- NO. OF PORTS:
02

SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

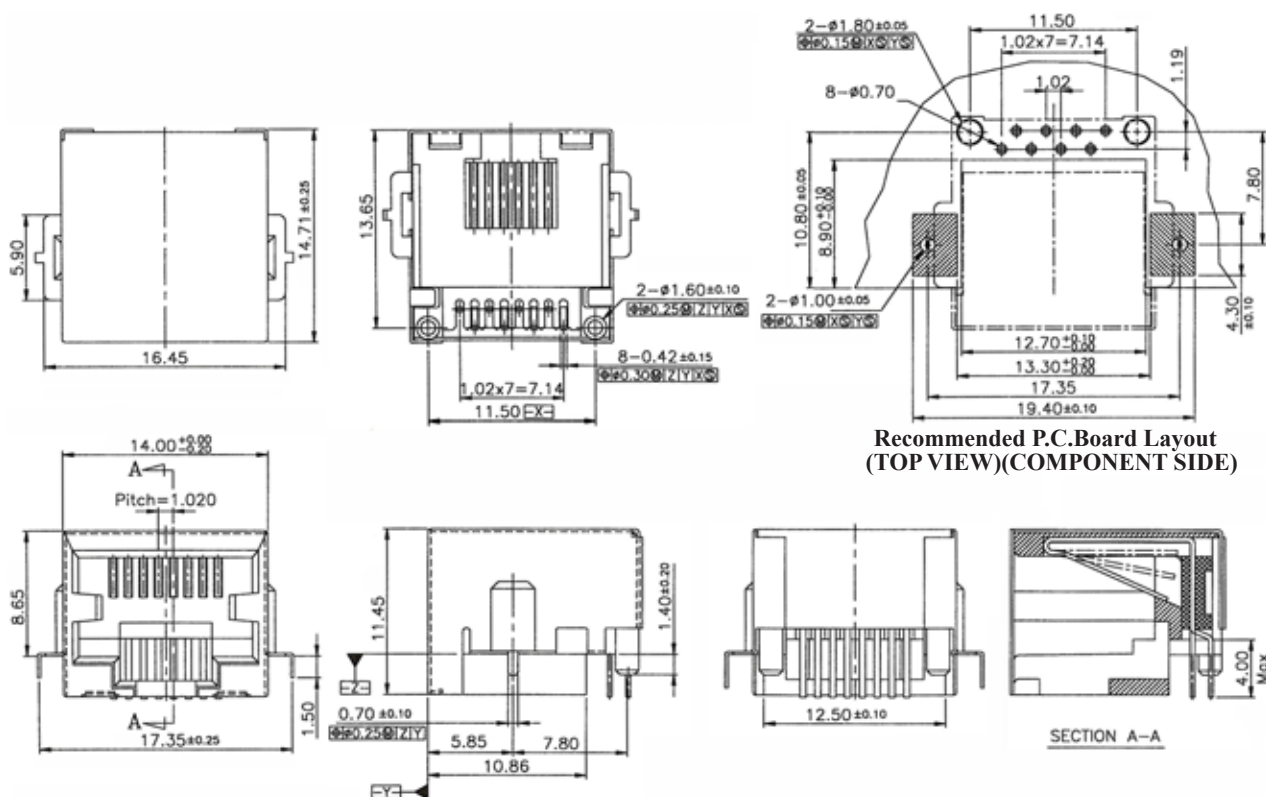
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ8S- $\frac{88}{12}$ xB

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

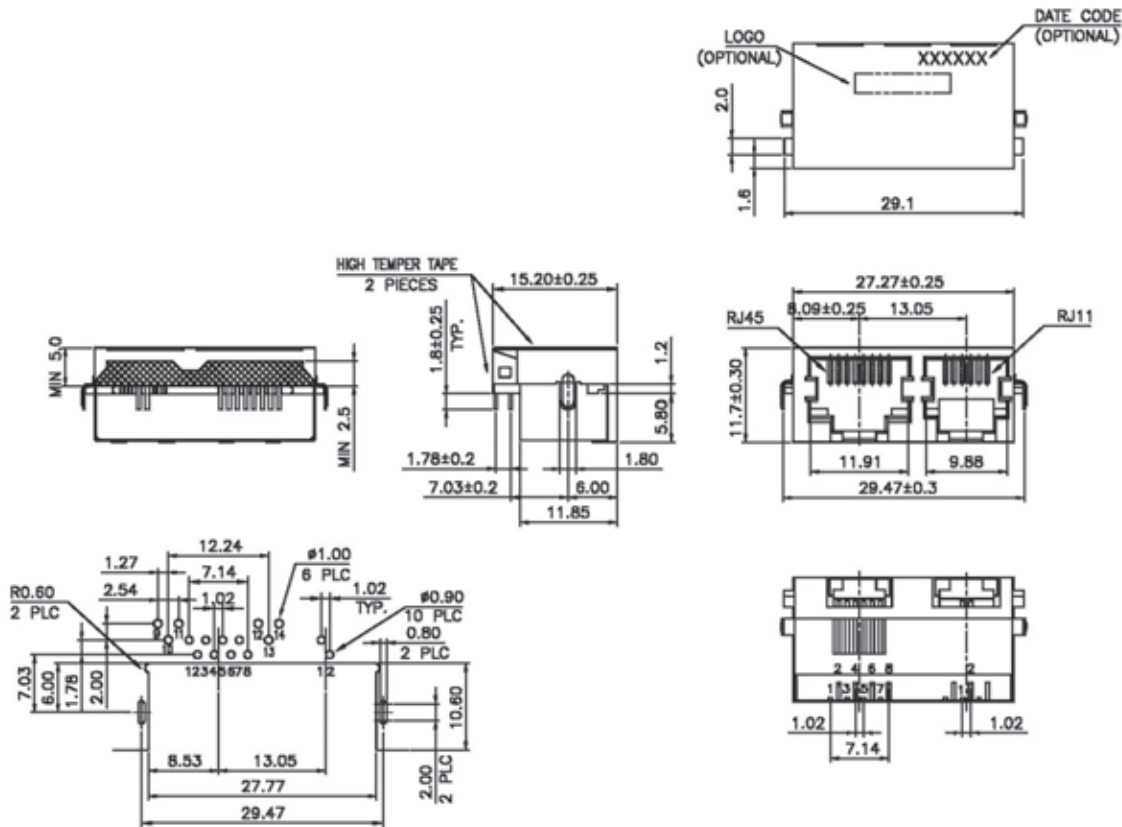
SIDE ENTRY 2-PORT EMBEDDED REVERSE TYPE MODULAR PCB JACK 6P+8P PROFILE=11.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Z D - 28 x B 02
1 2 3 4 5

1. MODULAR JACK TYPE:
"ZD" EMBEDDED PCB JACK REVERSE TYPE
2. NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. NO. OF PORTS:
02

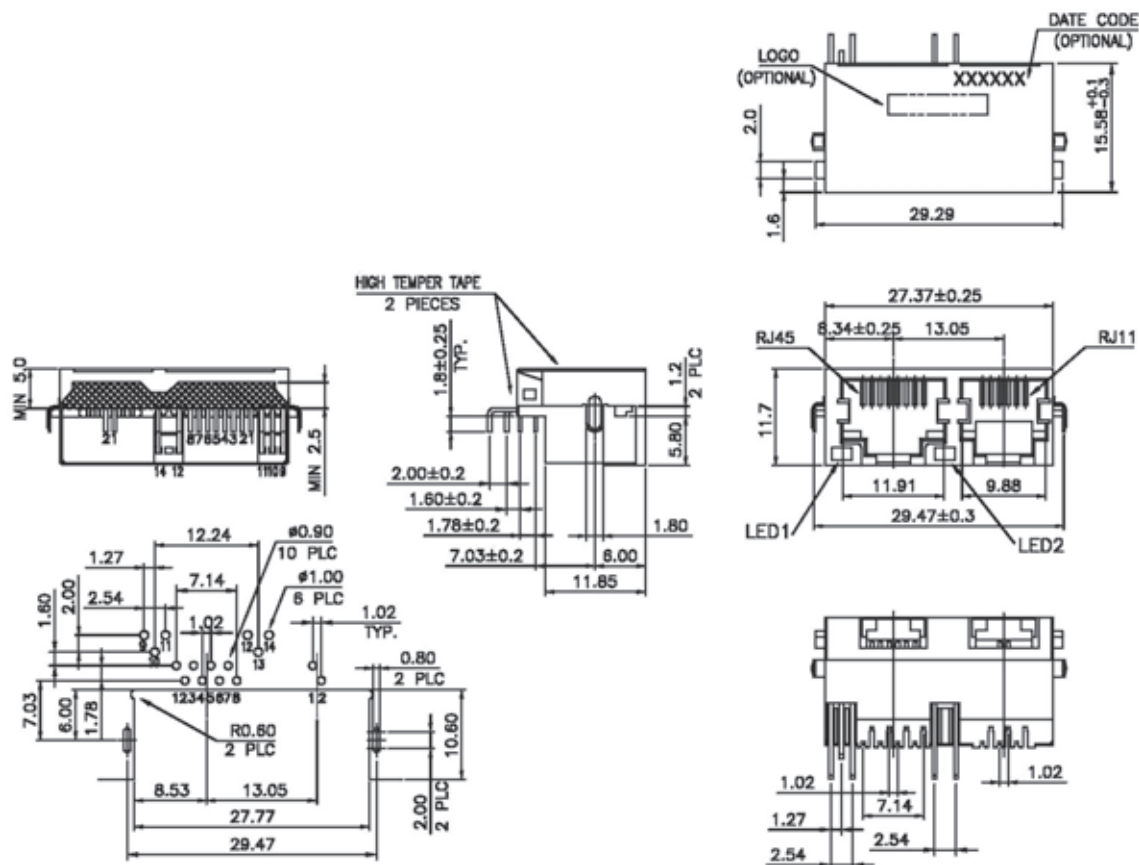
SIDE ENTRY 2-PORT EMBEDDED REVERSE TYPE MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J ZE - 28 x B x x 02
1 2 3 4 5 6

- MODULAR JACK TYPE:
"ZE" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

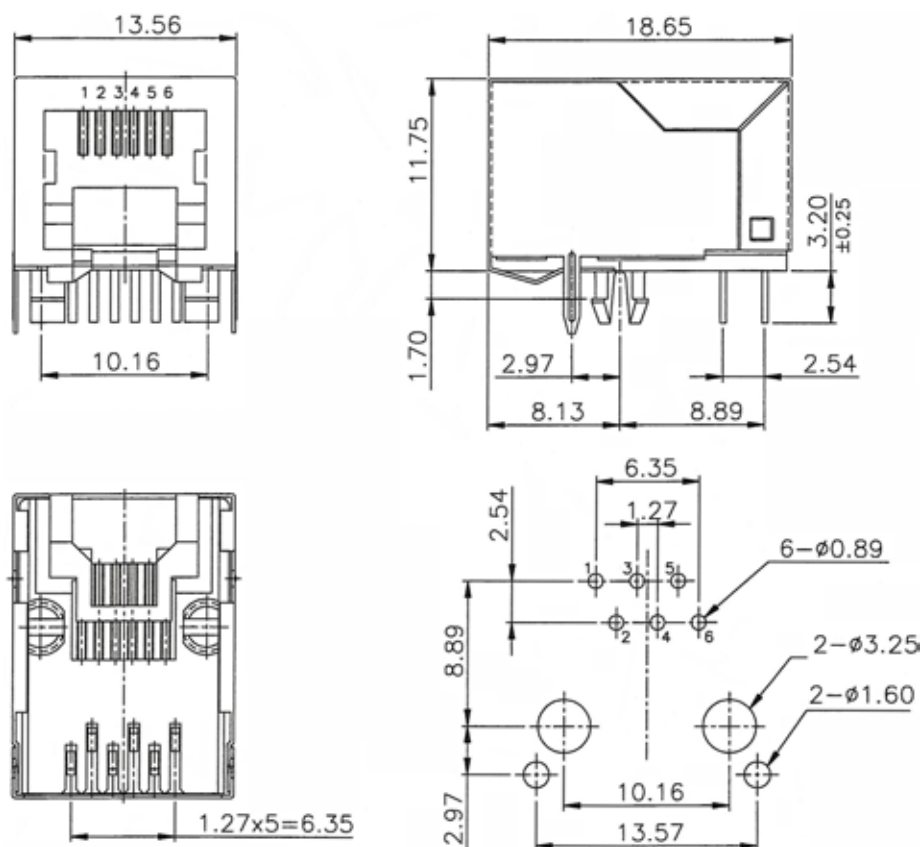
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"64" 6P4C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

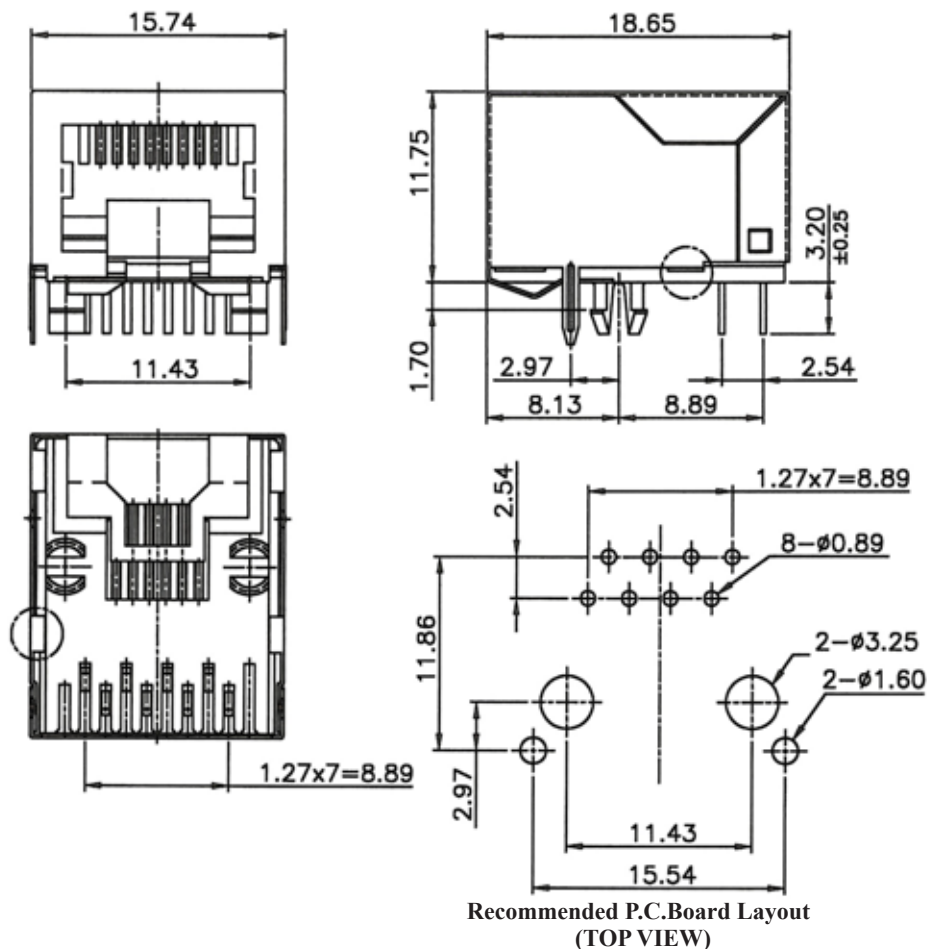
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x}{T} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

DRAWING REVISED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

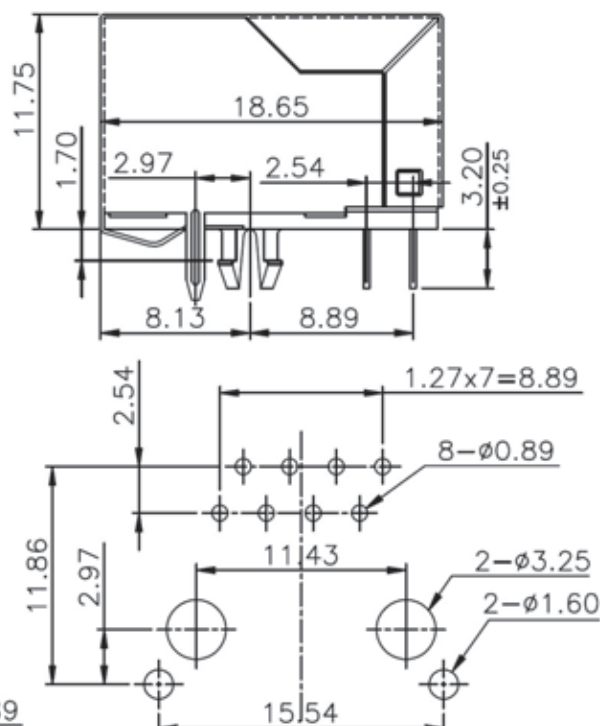
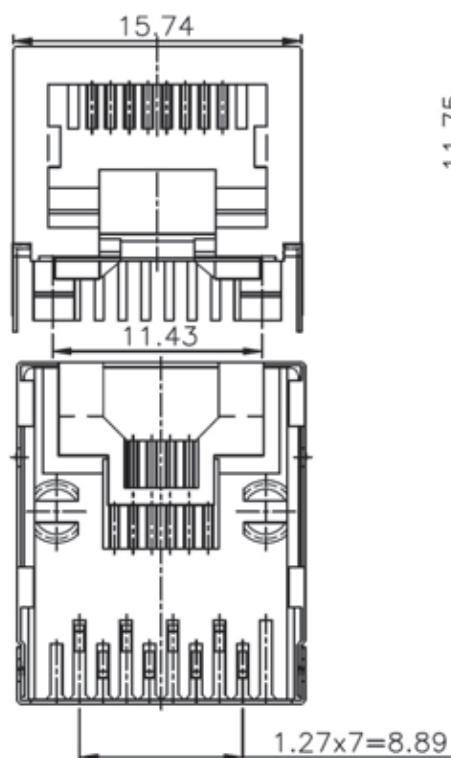
Plastic Housing: Engineering Thermoplastic
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ $\frac{18J}{1} - \frac{88}{2} \times \frac{B}{3}$

1. MODULAR JACK TYPE:
"18J" F2.97 TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: IT CAN BE USED FOR REPLACING P/N MJ18-88xB.

NOTE 2: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

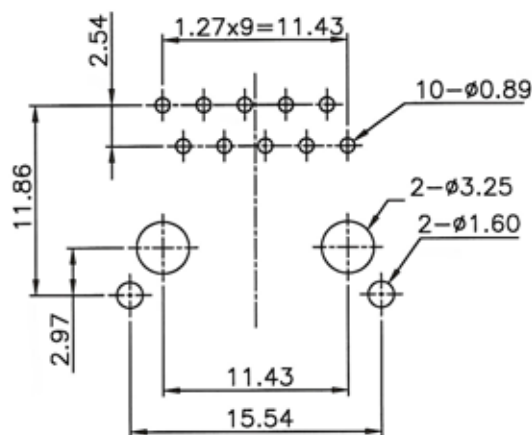
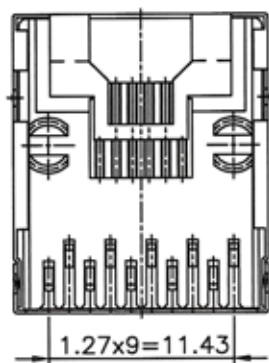
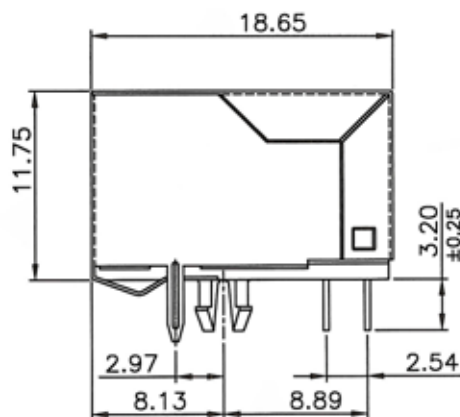
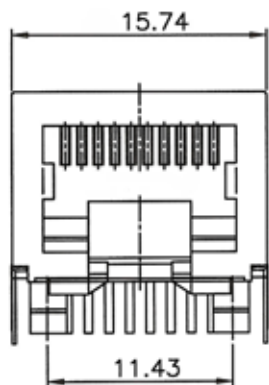
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 2.97MM SPACING BEFORE PEG

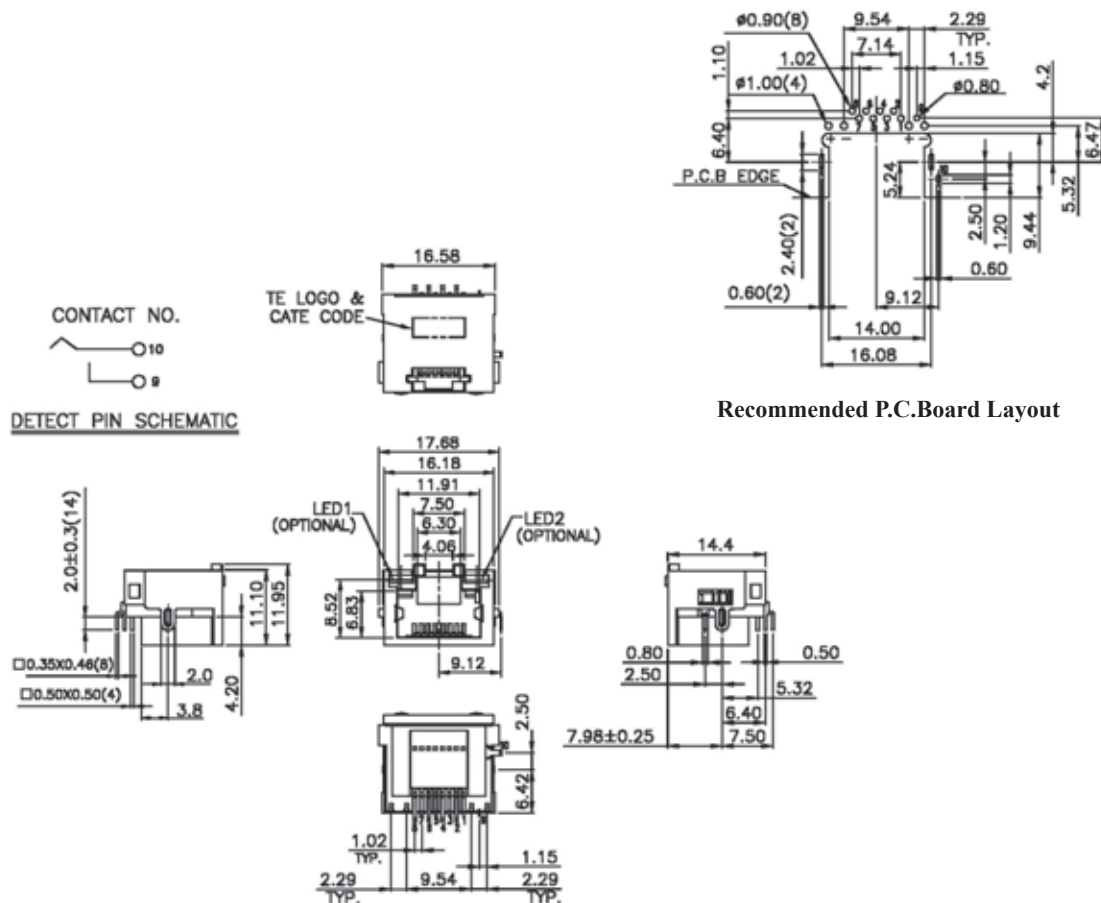
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J YY - 88 x B x X
 1 2 3 4 5

- MODULAR JACK TYPE:
"YY" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

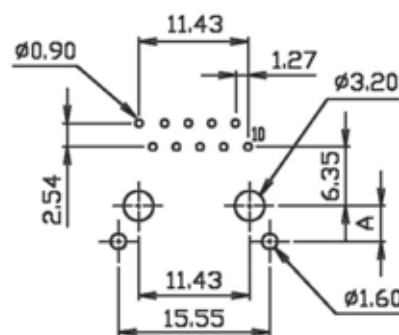
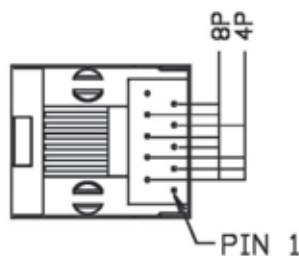
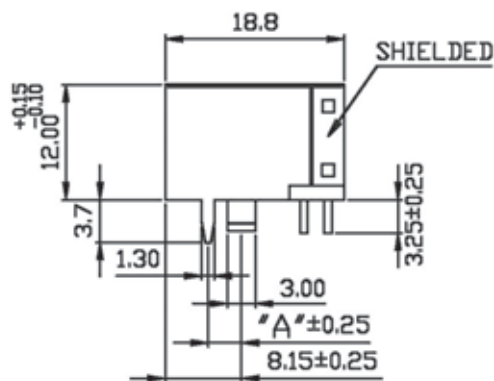
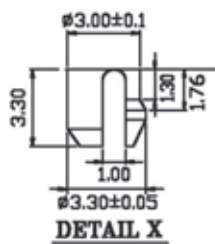
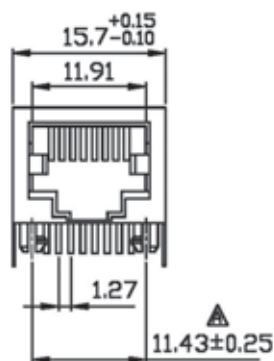
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H F - x x x B
1 2 3 4

1. MODULAR JACK TYPE:
"HF" DIM.A = 3.05MM BEFORE PEG
2. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

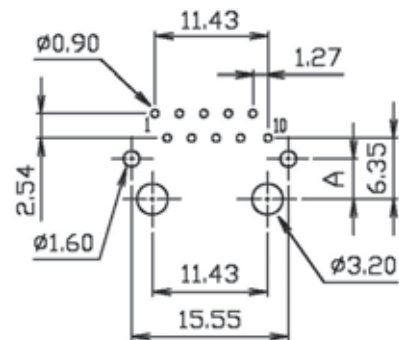
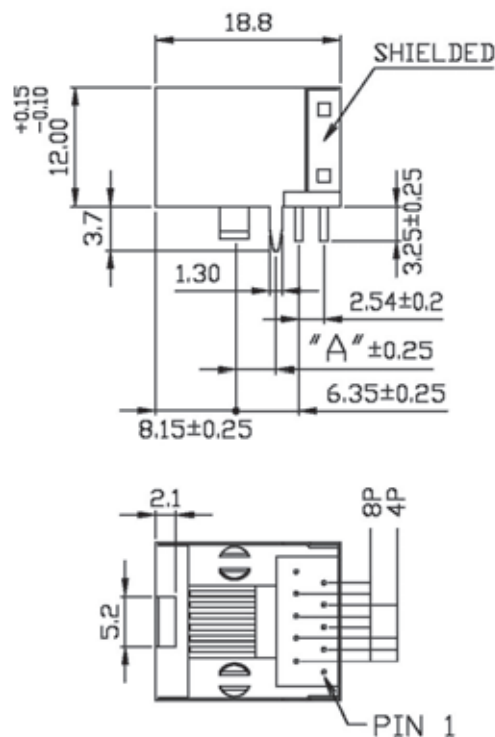
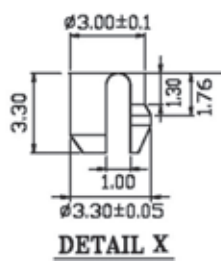
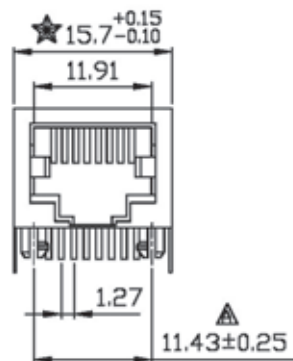
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H P - x x x B
1 2 3 4

1. MODULAR JACK TYPE:
"HP" DIM.A = 3.05MM BEHIND PEG
2. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

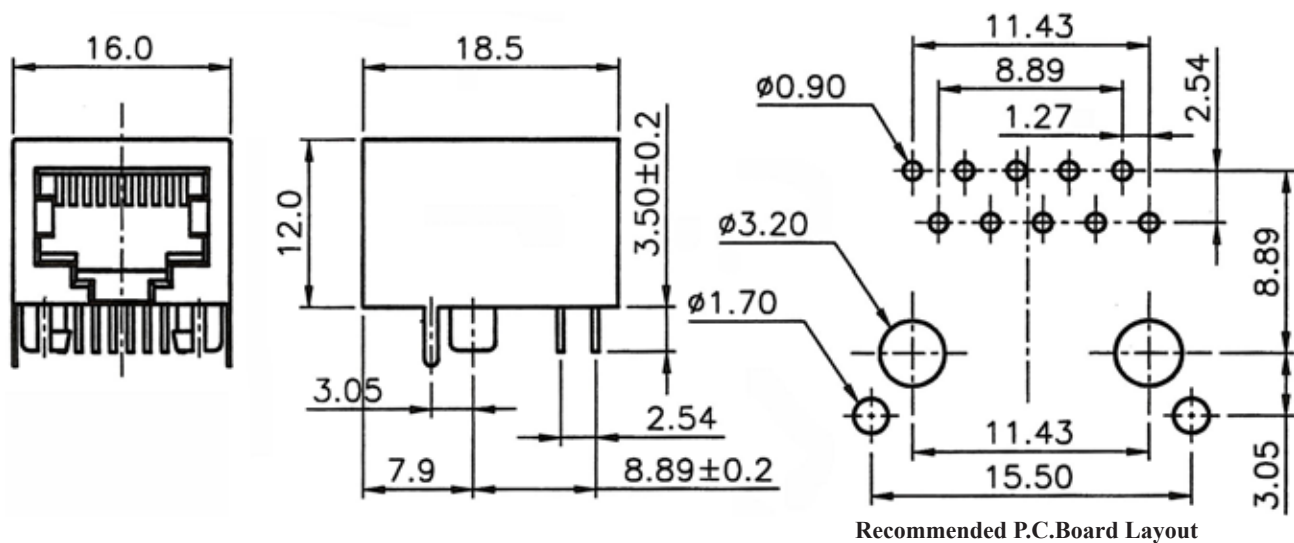
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 8 7 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

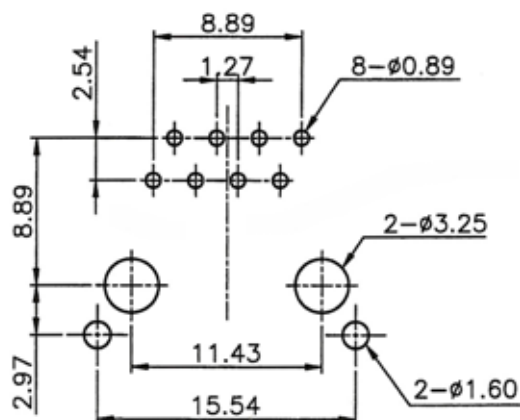
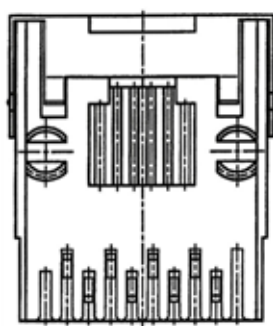
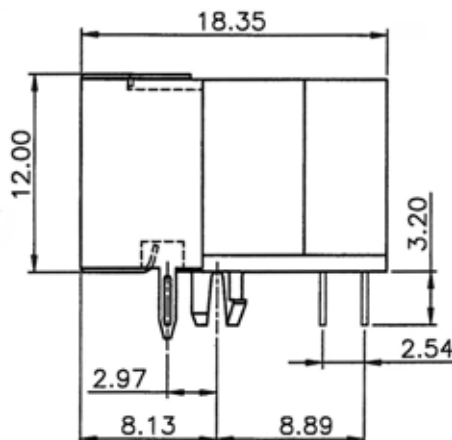
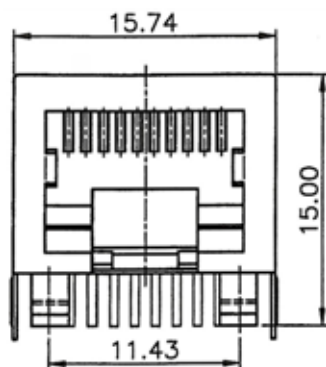
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 3 - $\frac{88}{1} \times \frac{B}{2} \times \frac{3}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

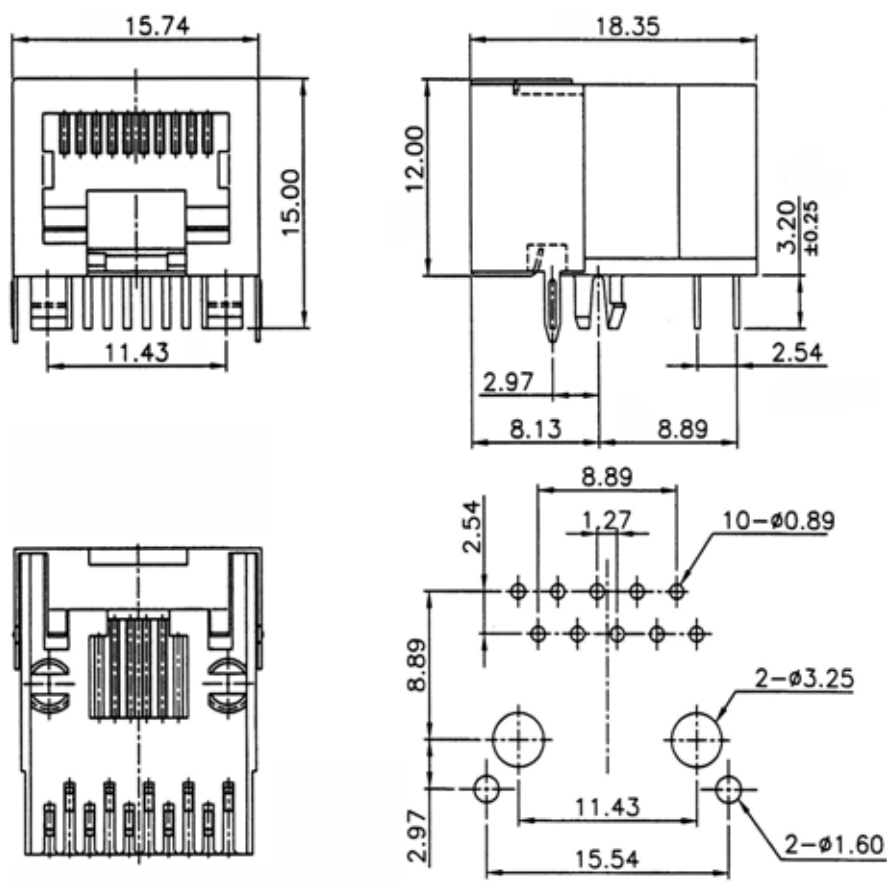
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 7 H - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

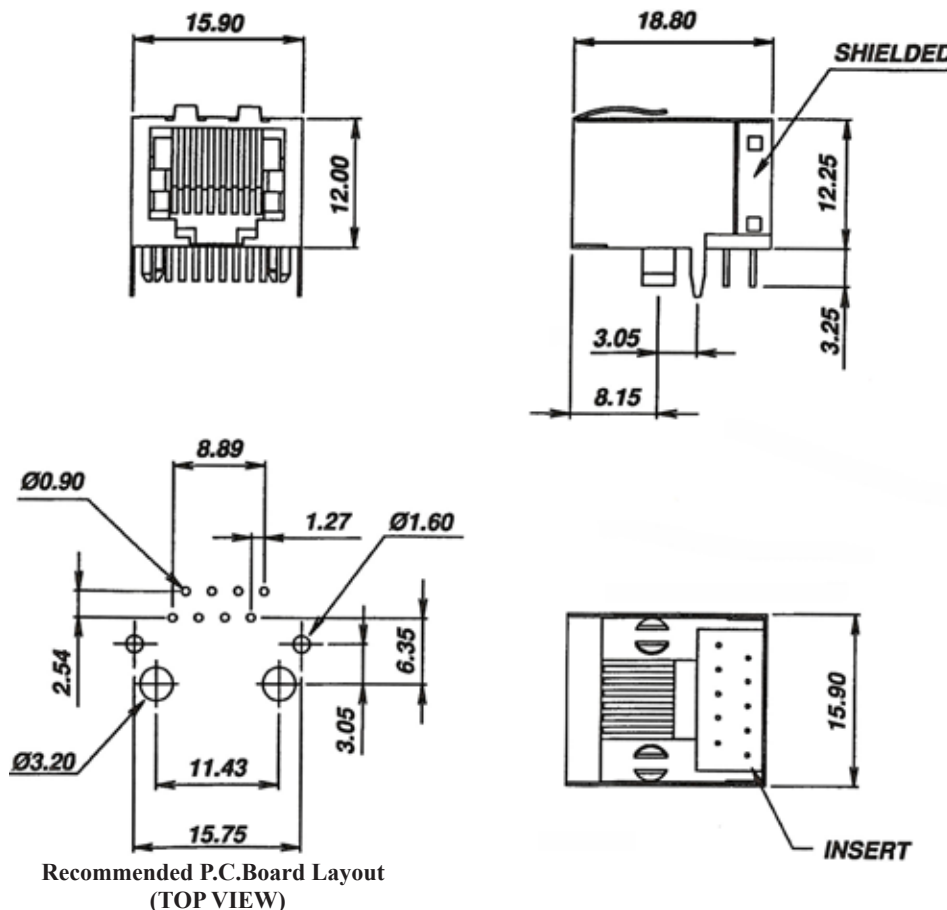
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R X - $\frac{88}{12}$ x B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRXHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

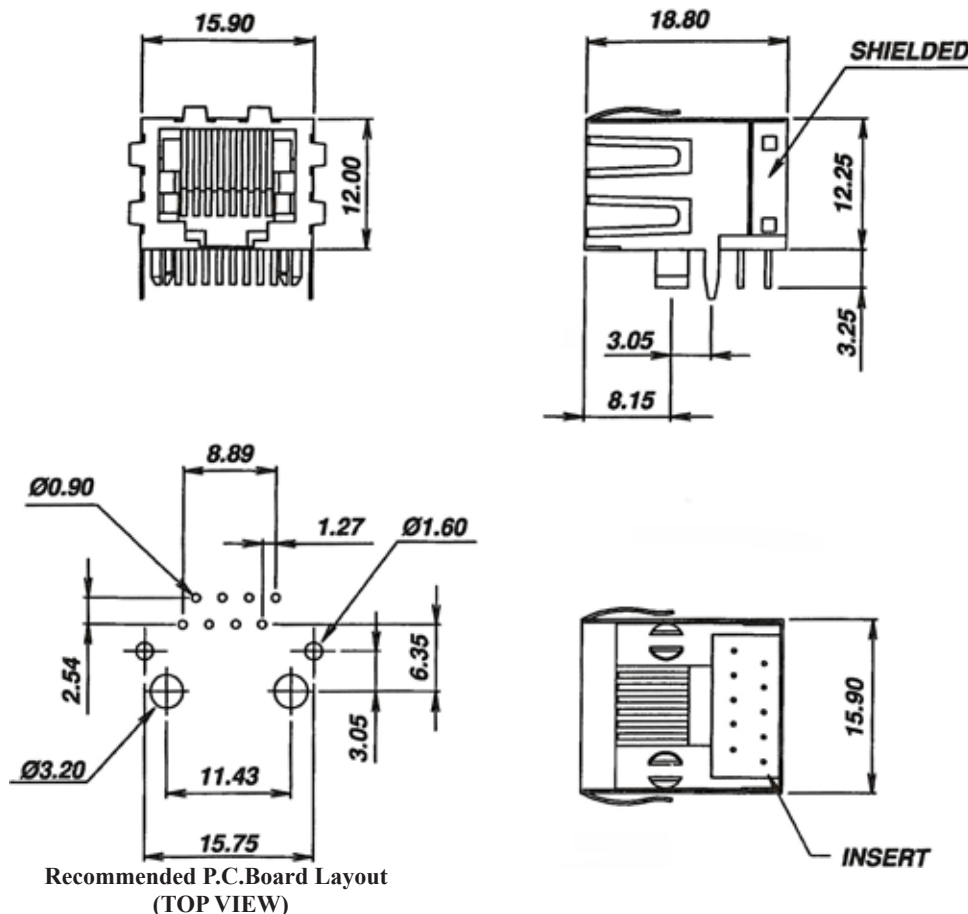
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRY - 88 x B
T 2

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRYHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

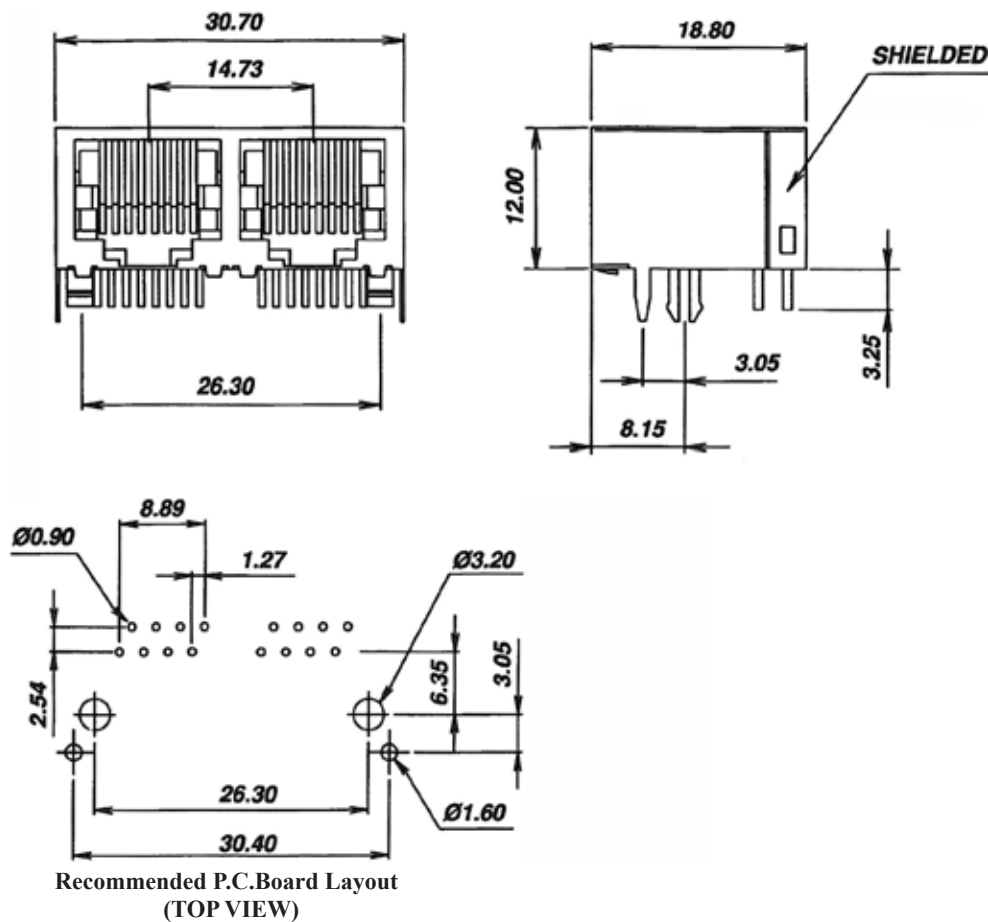
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S A - $\frac{8}{1} \frac{8}{2} \times \frac{B}{3} \frac{0}{3} \frac{2}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

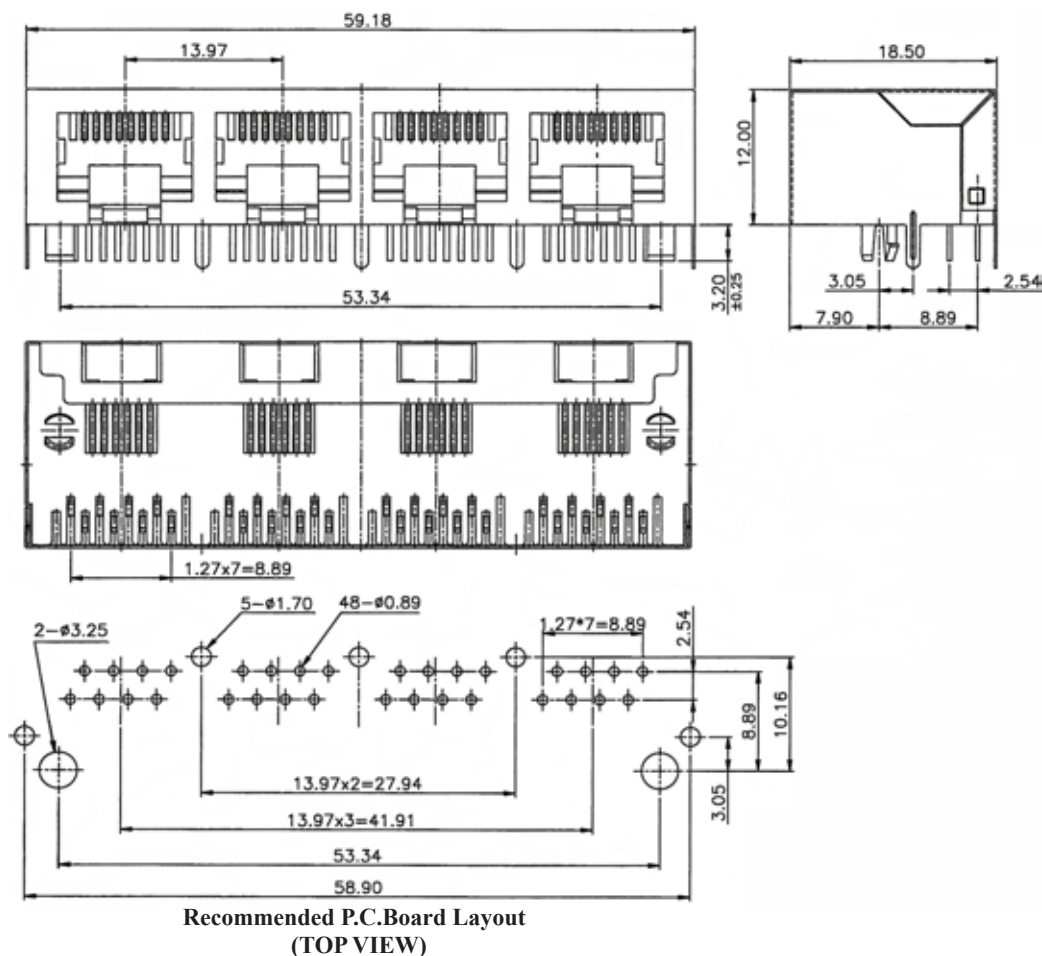
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 4$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

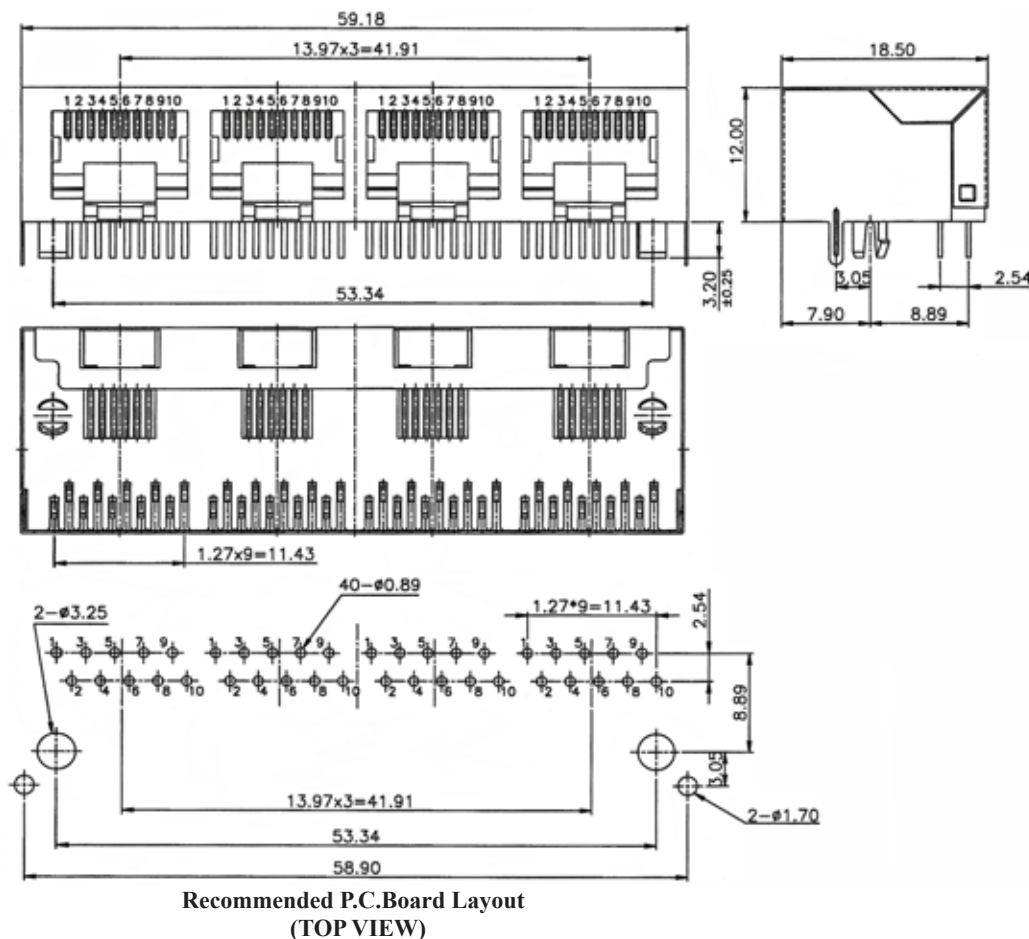
SIDE ENTRY 4-PORT MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 J - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} \frac{4}{3}$

1. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "08" 10P8C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 04

NOTE: GROUNDING PIN SPACING= 3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

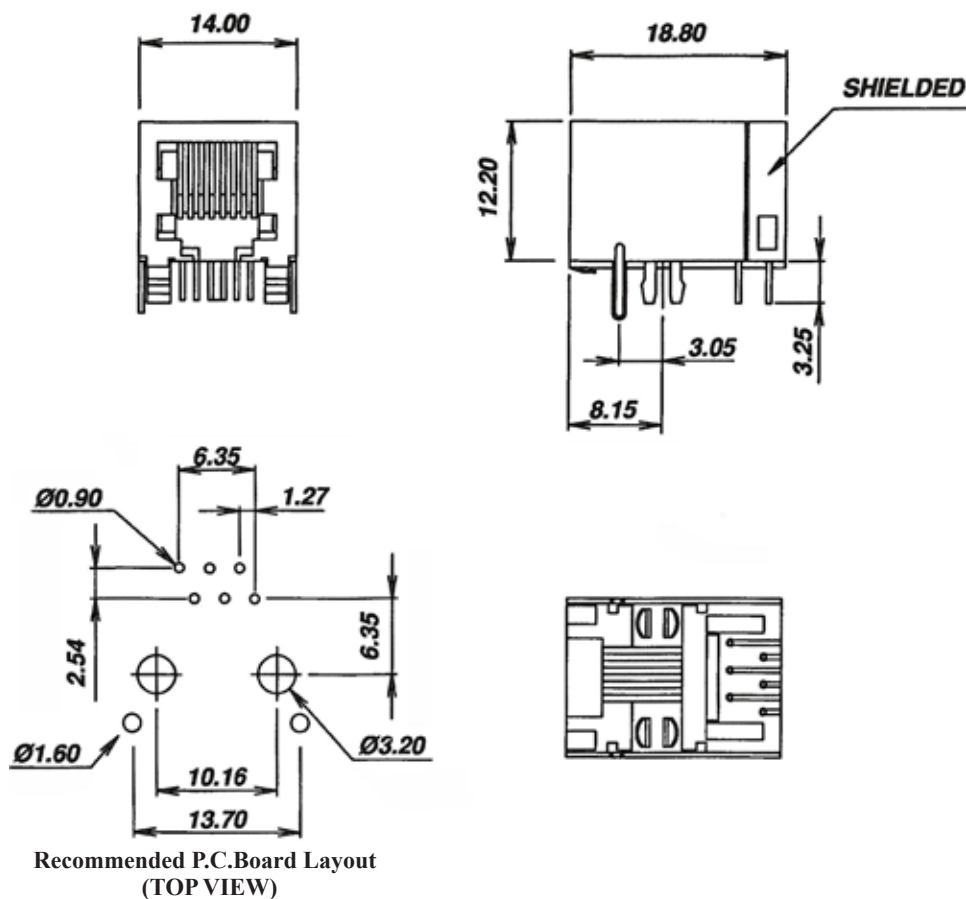
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R T - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRTH-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

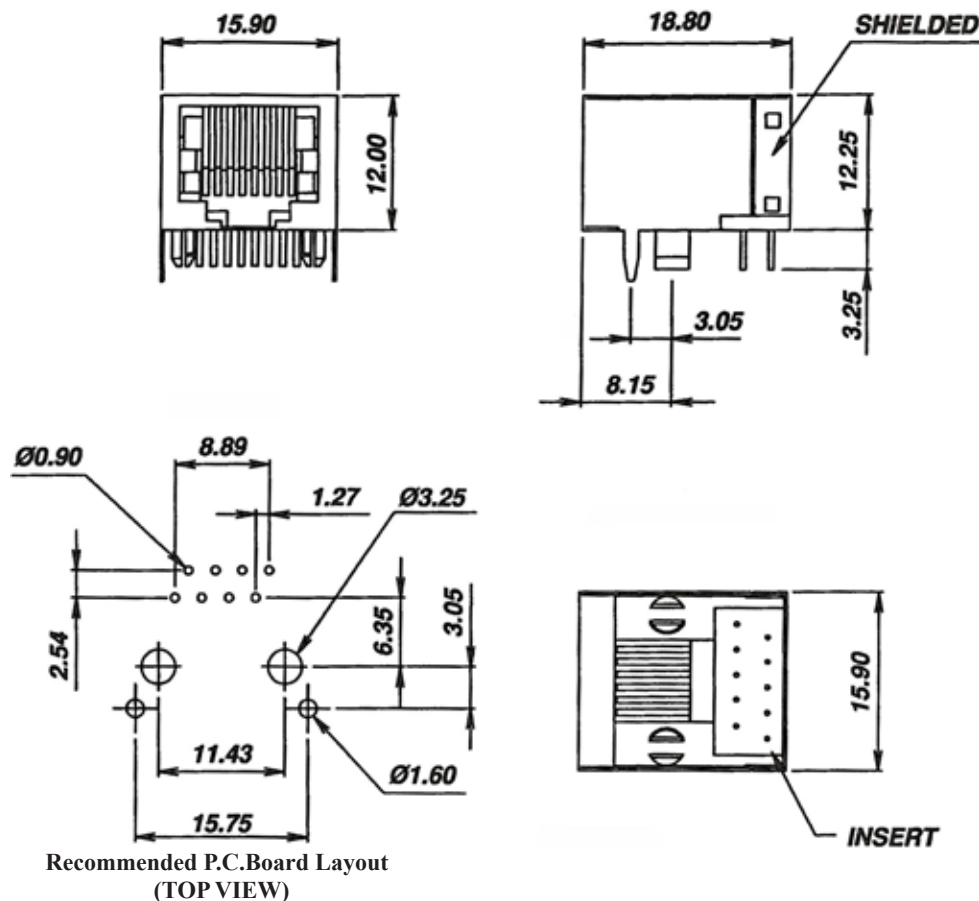
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRT - 88 x B
T 2

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRTH-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

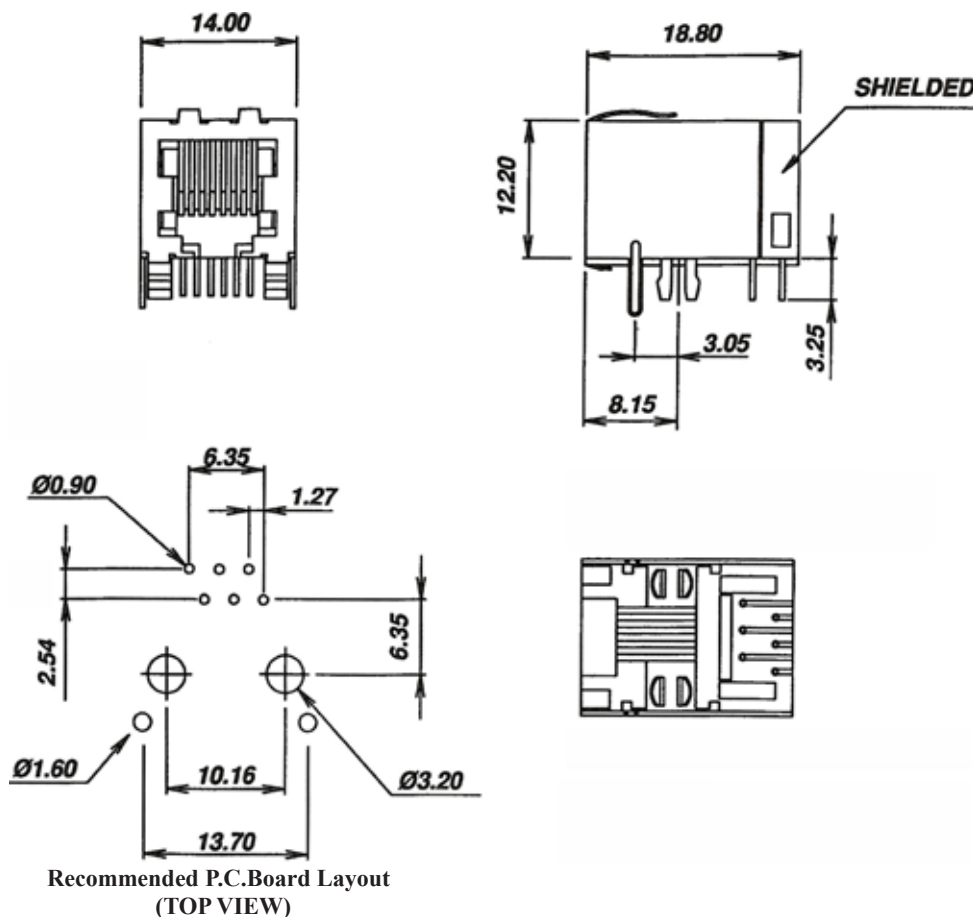
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R U - 1 2 B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

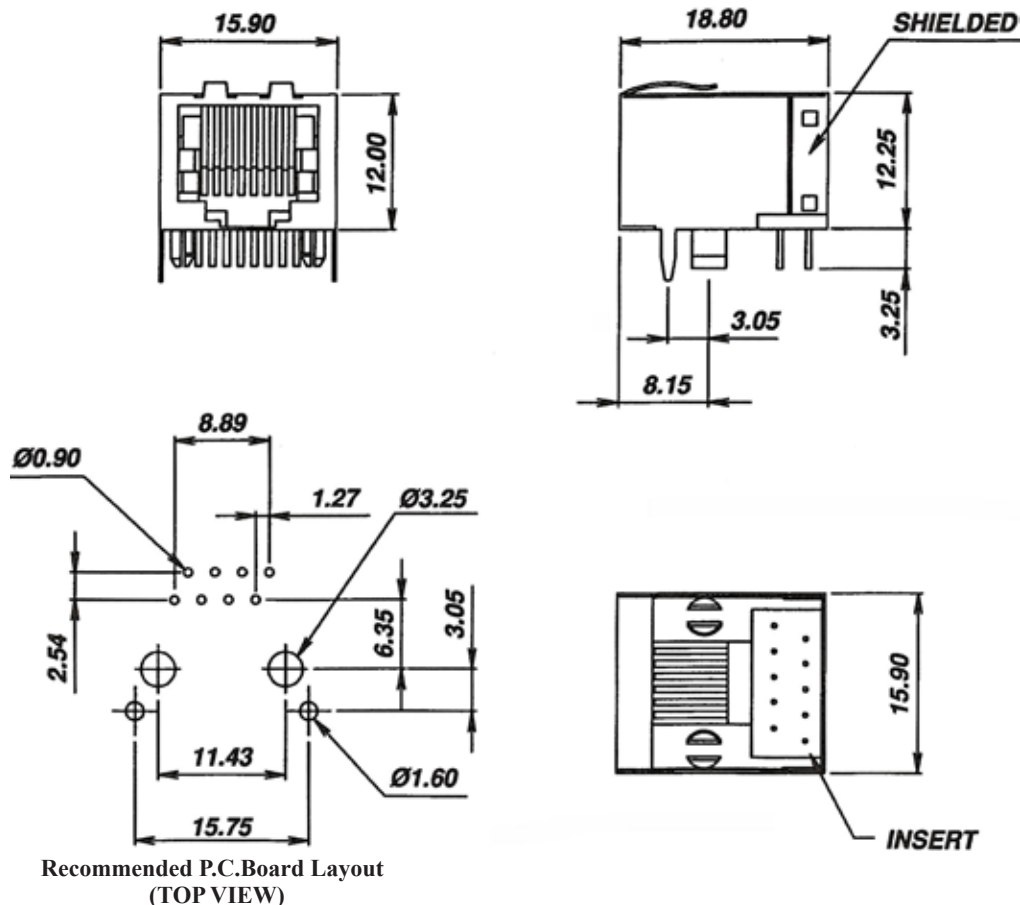
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRU - $\frac{88 \times B}{T 2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

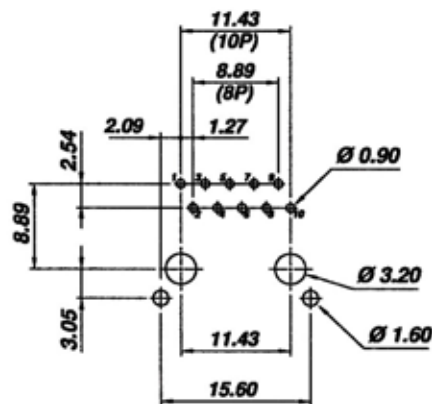
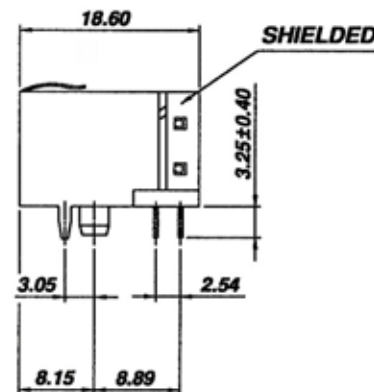
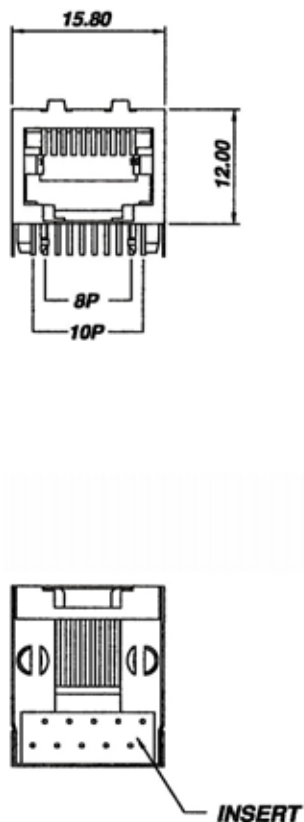
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJRU - $\frac{xxxB}{T2}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-0xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

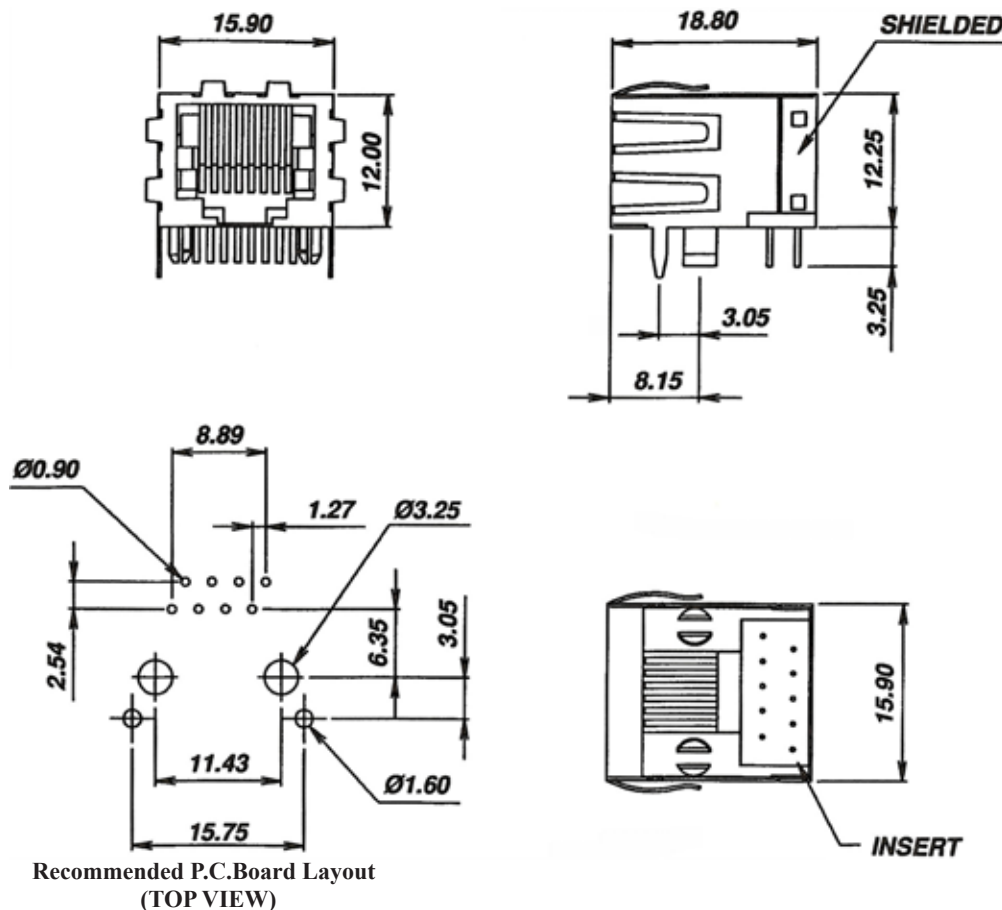
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R V - $\frac{88}{1} \frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRVHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

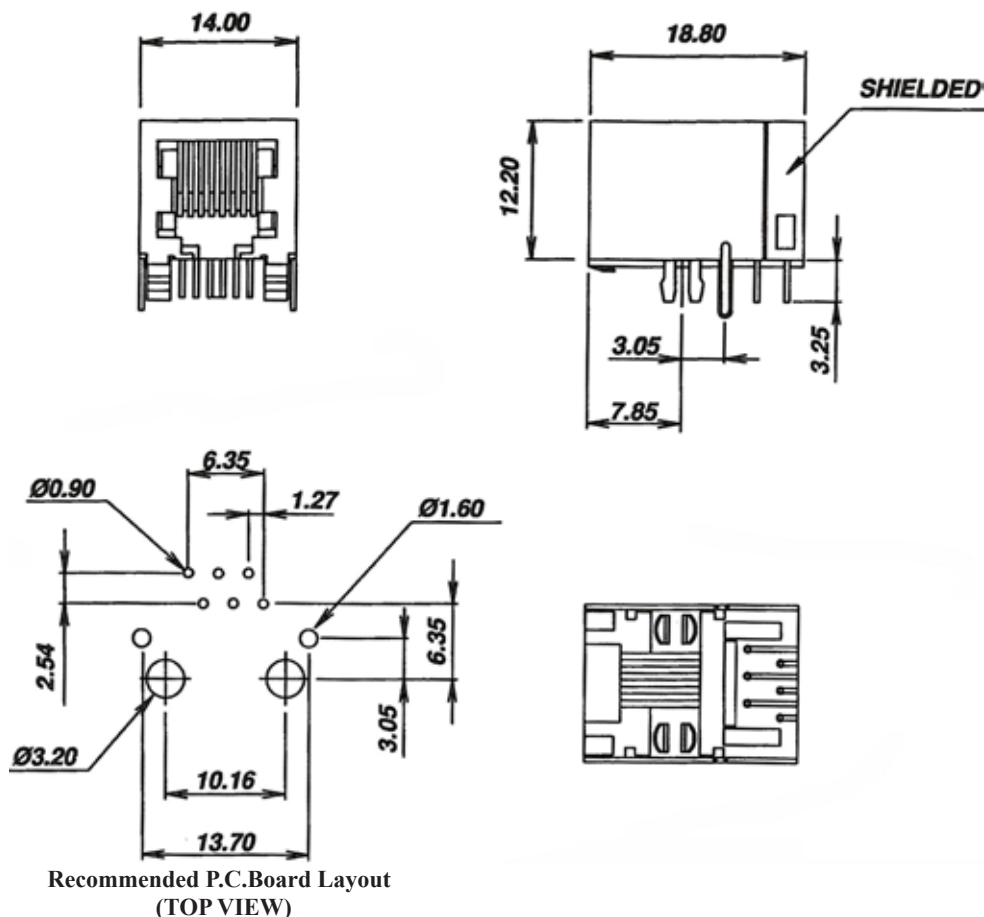
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

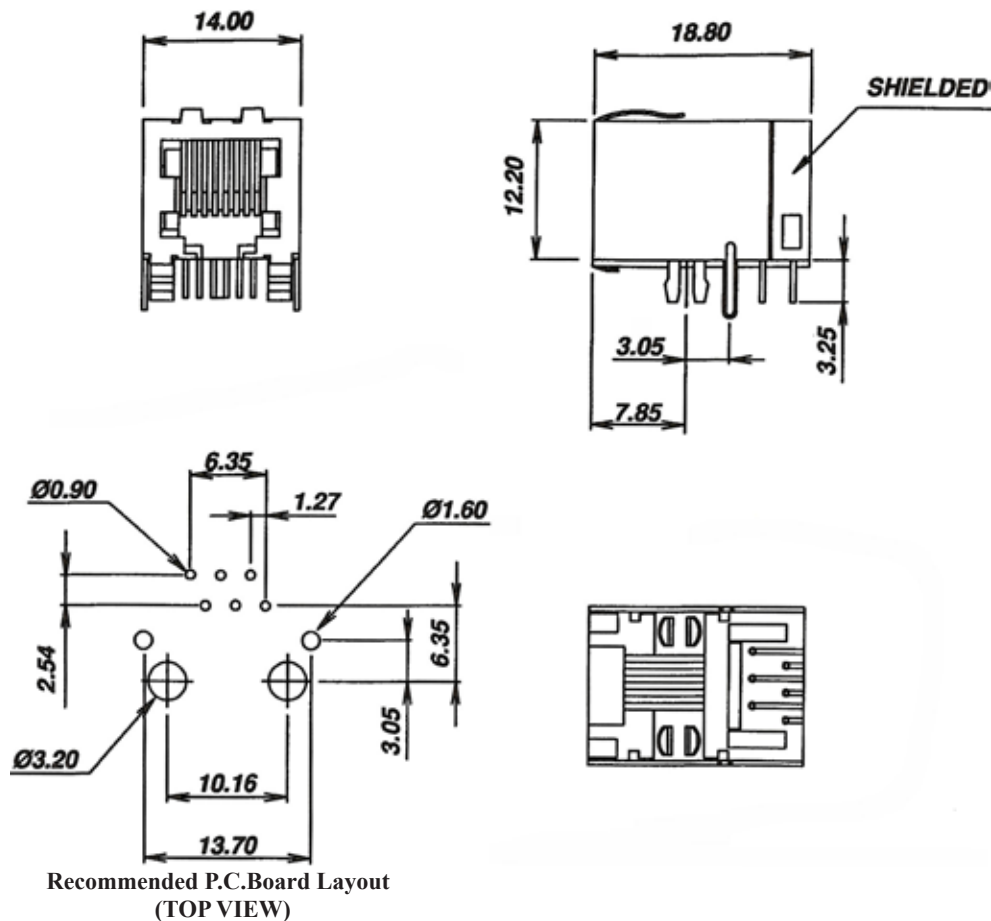
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R X - $\frac{x \times x}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRXHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

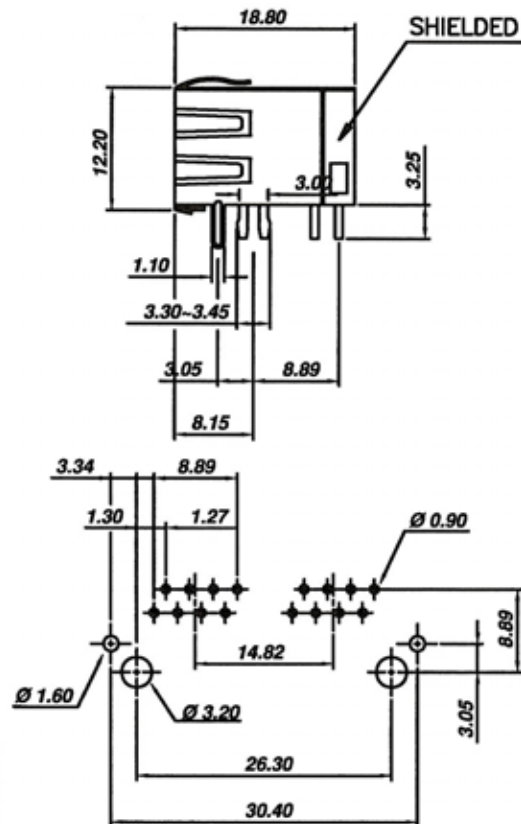
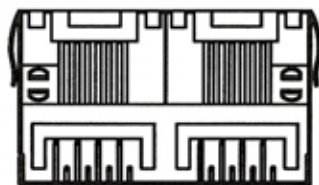
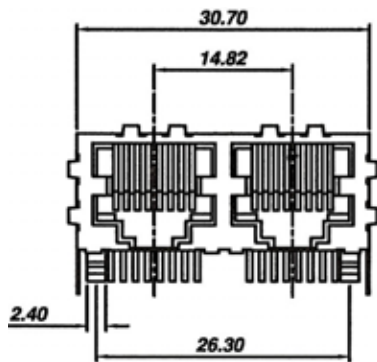
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J S B - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

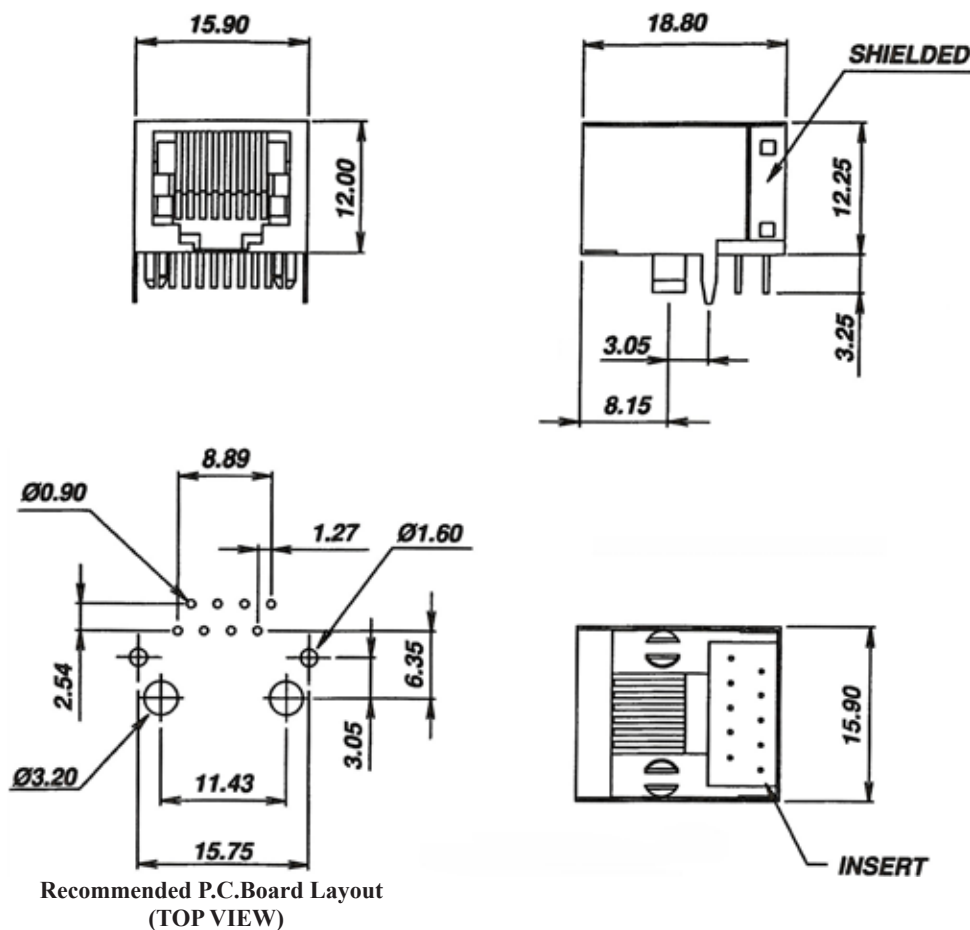
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

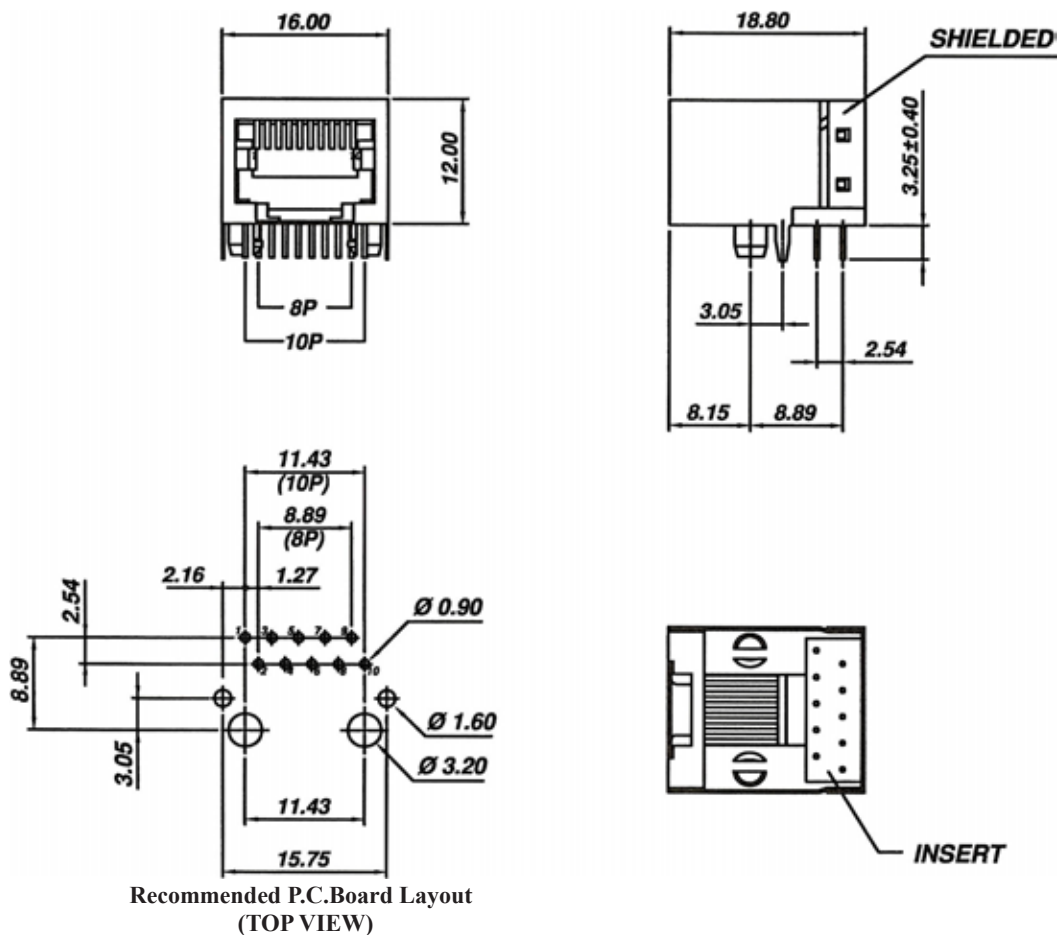
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-0xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

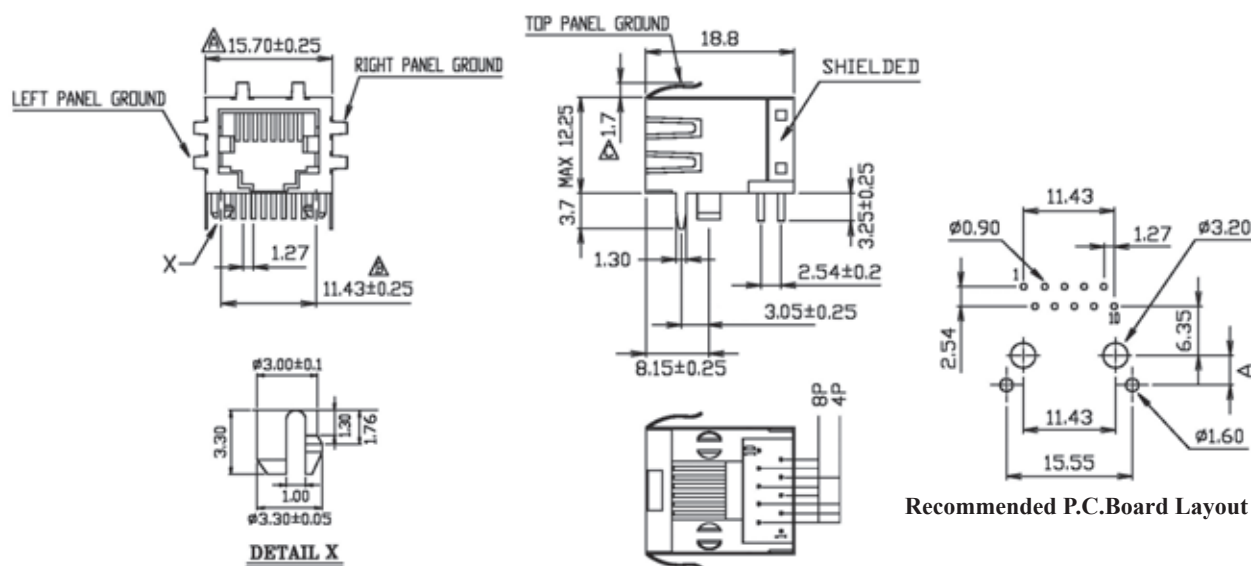
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3} \frac{4}{4}$

- MODULAR JACK TYPE:
 "HM" A=3.05MM WITH FLAT PINS
 "HJ" A=3.05MM WITH ROUND PINS
- NO. OF POSITIONS & CONTACTS:
 "08" 10P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

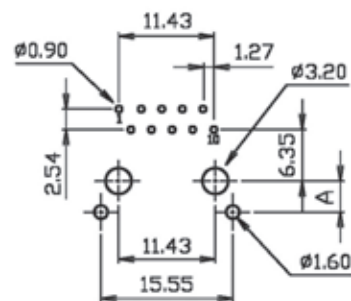
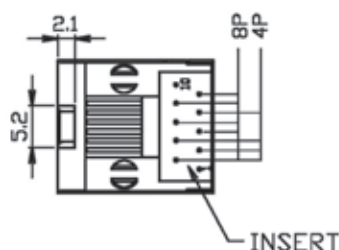
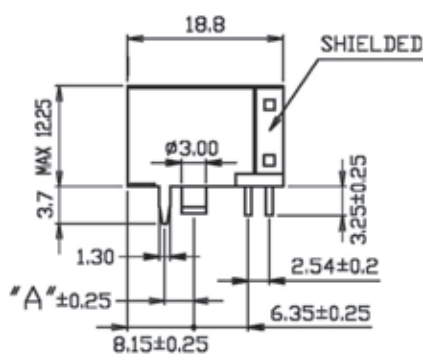
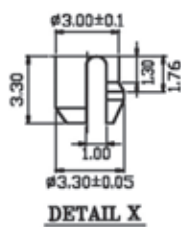
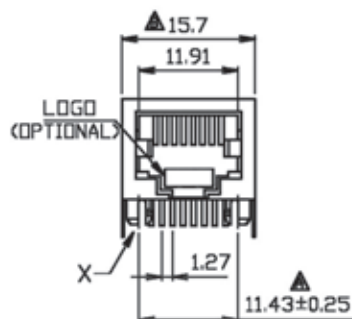
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H G - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} B$

- MODULAR JACK TYPE:
"HG" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

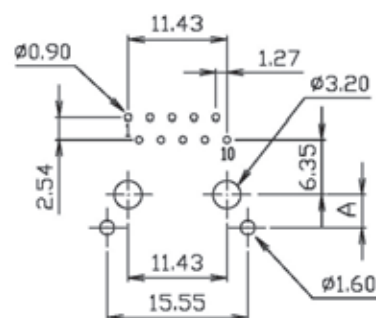
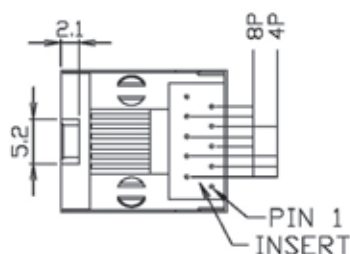
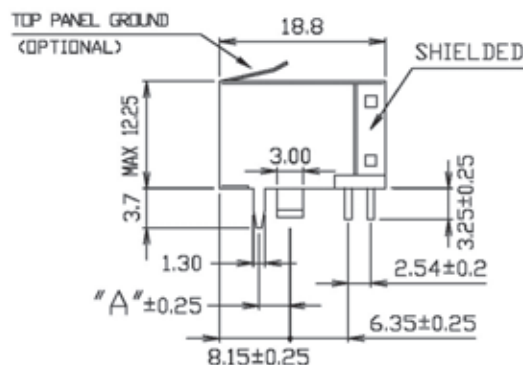
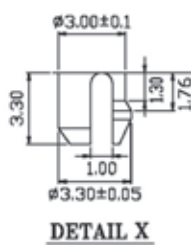
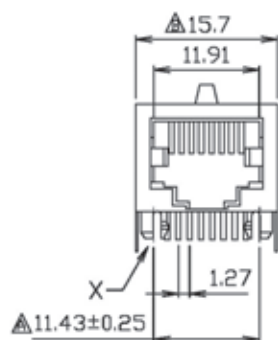
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J HL - xx x B
 1 2 3 4

- MODULAR JACK TYPE:
"HL" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

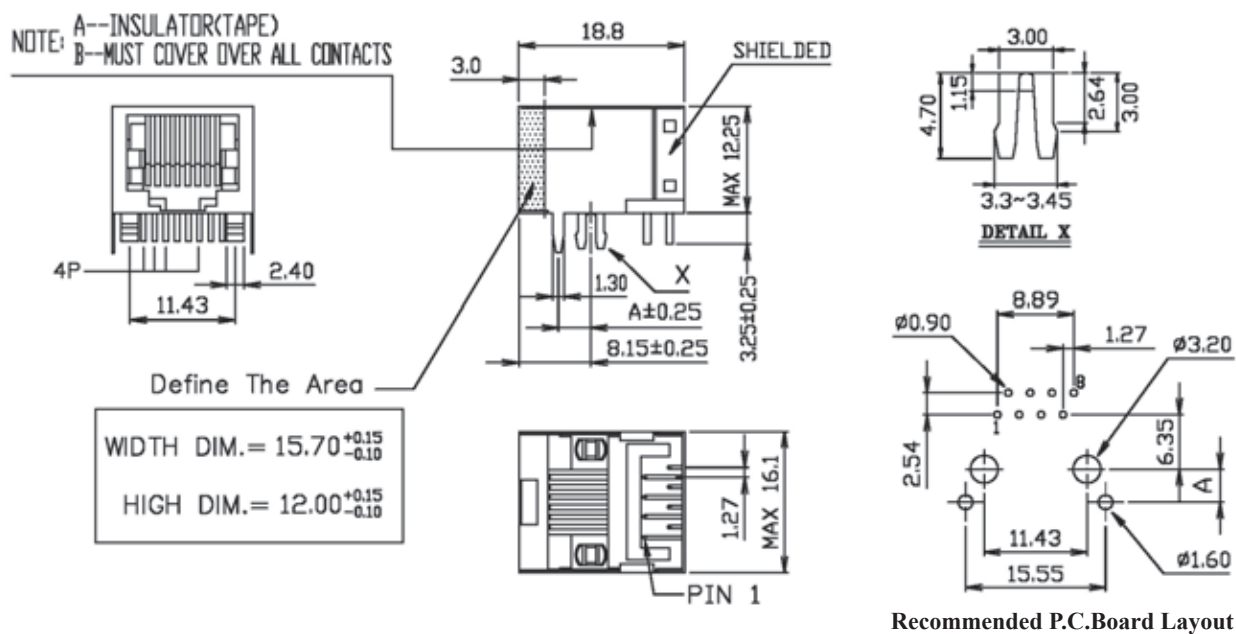
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J HH - 88 x B
 1 2 3 4

1. MODULAR JACK TYPE:

"HH" DIM.A = 3.05MM

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

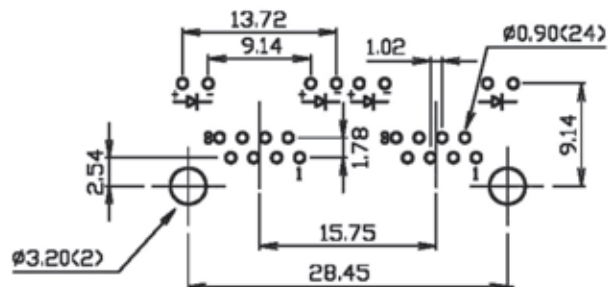
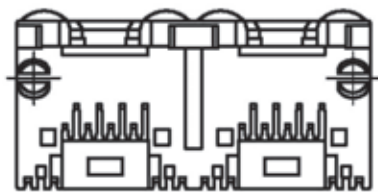
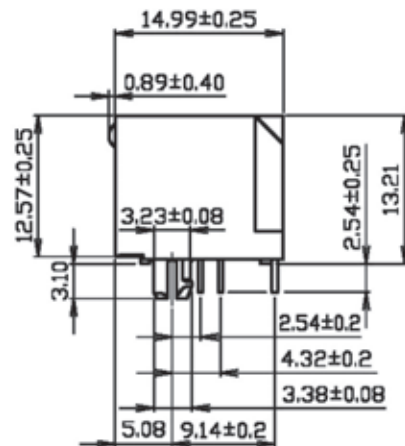
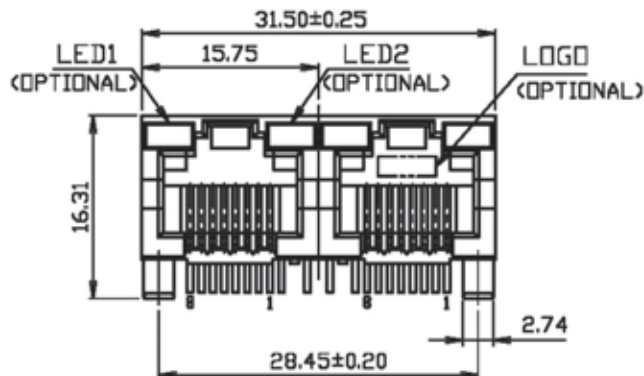
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K F - 8 8 x B x x 0 2
1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

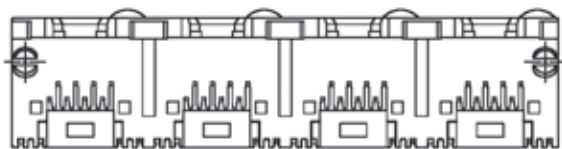
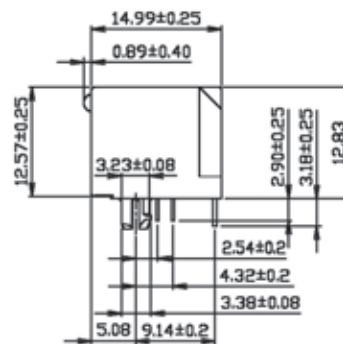
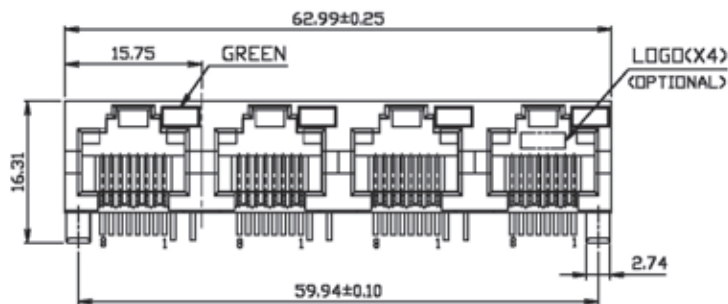
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

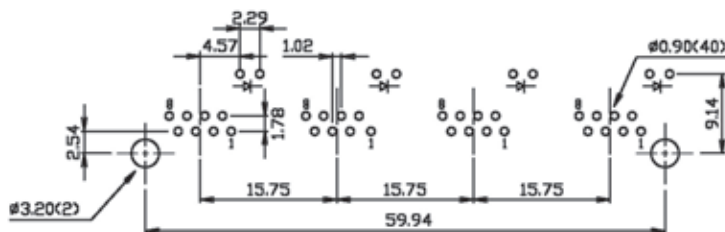
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJKF-88xBXN04



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N MJKF-88xBXN04
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"XN" LED1/2 = NIL/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

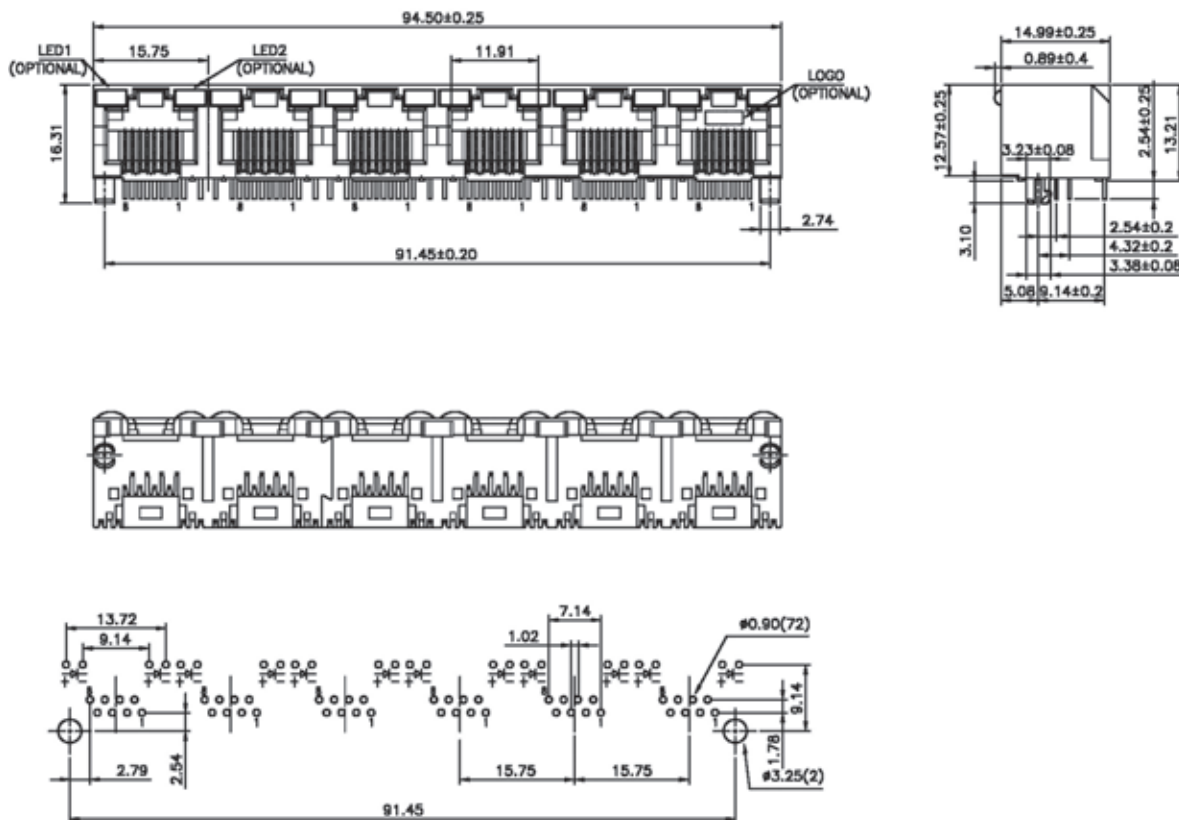
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K F - 8 8 x B x x 0 6
1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
06

NOTE: OTHER LED COLORS UPON REQUEST!

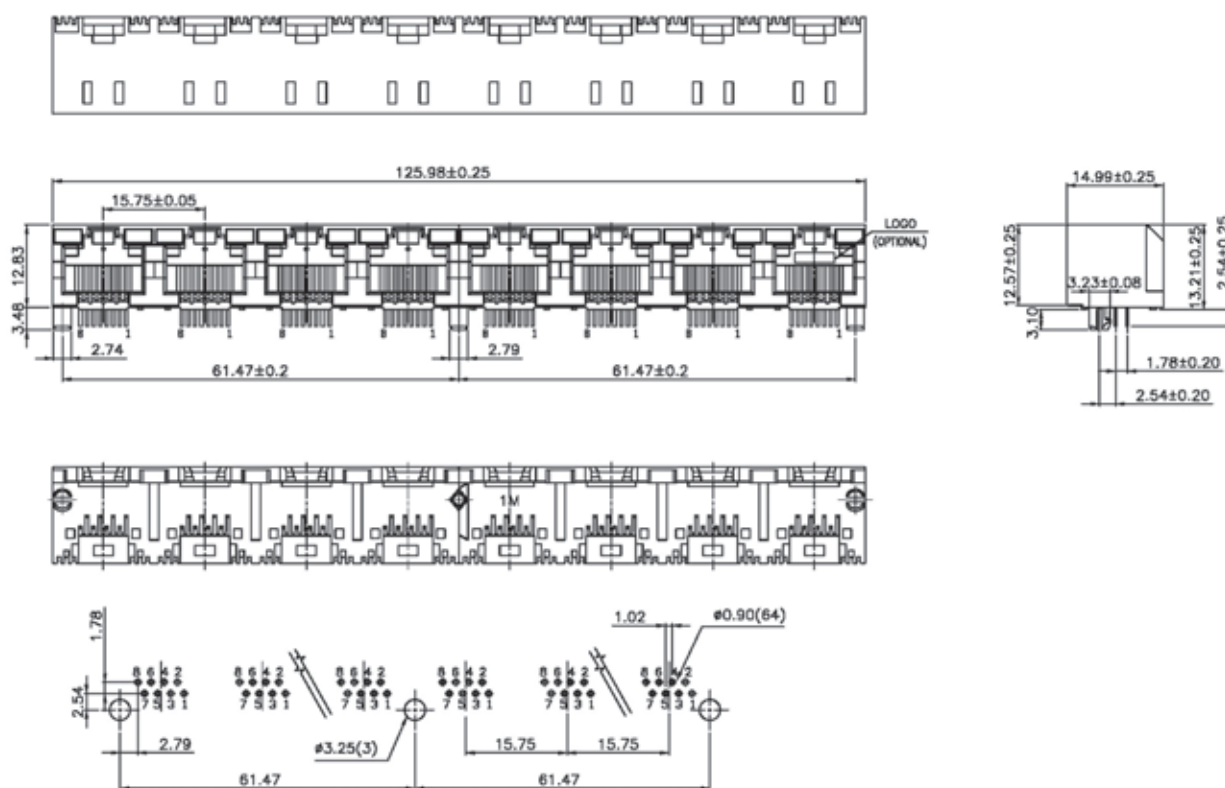
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K F - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4} \times \frac{08}{5} \times \frac{08}{6}$

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
08

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY MODULAR PCB JACK 6P WITH FERITTE PROFILE=12.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

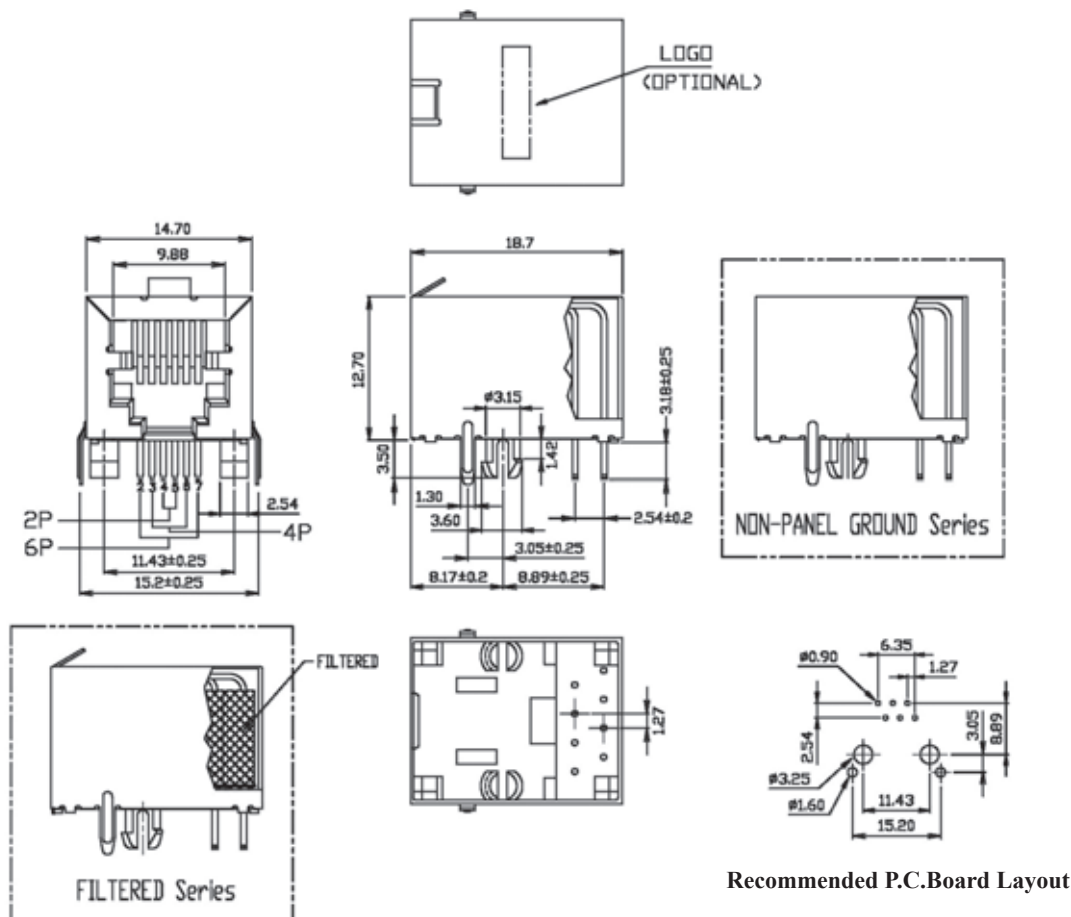
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{xx}{T}$ - $\frac{xxx}{2}$ $\frac{B}{34}$

- MODULAR JACK TYPE:
"YK" FILTERED WITH TOP PANEL GROUND
"YL" FILTERED WITHOUT PANEL GROUND
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

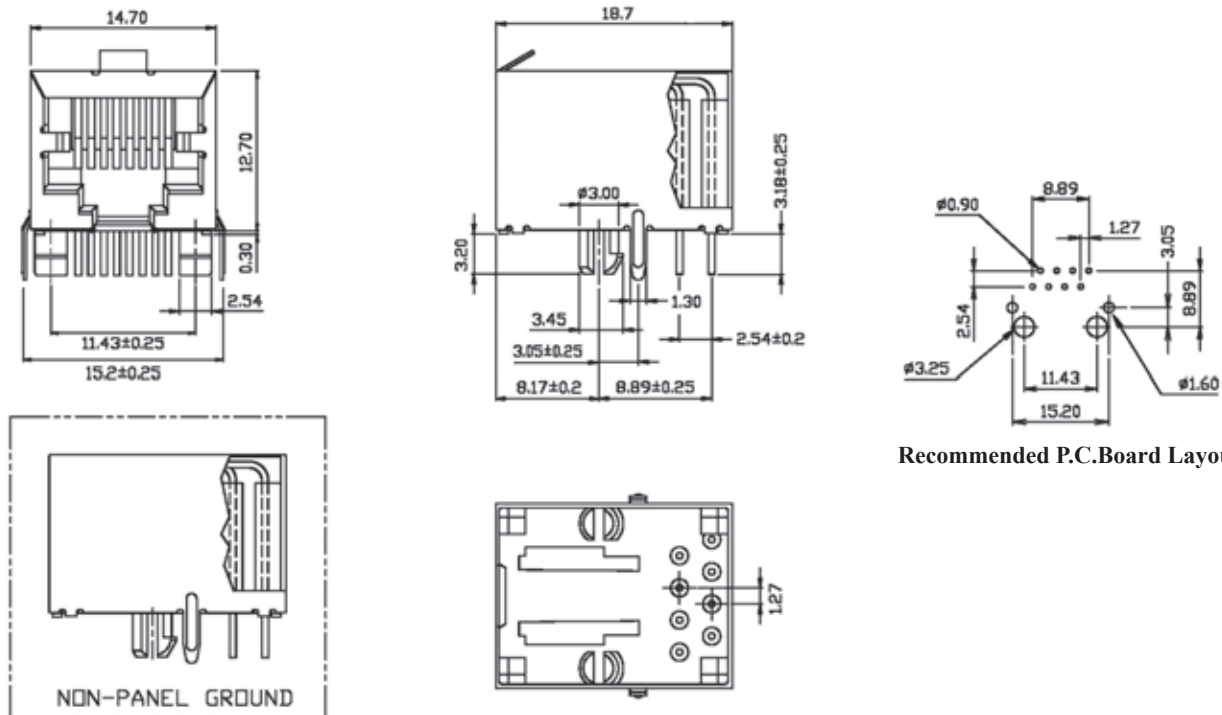
SIDE ENTRY MODULAR PCB JACK 8P WITH FERITTE PROFILE=12.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{XX}{T}$ - $\frac{88}{2}$ $\frac{X}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
 "YK" FILTERED WITH TOP PANEL GROUND
 "YL" FILTERED WITHOUT PANEL GROUND
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=12.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

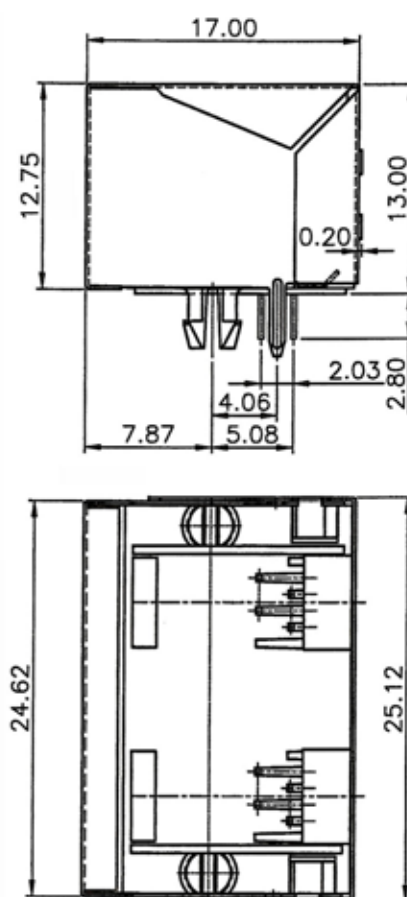
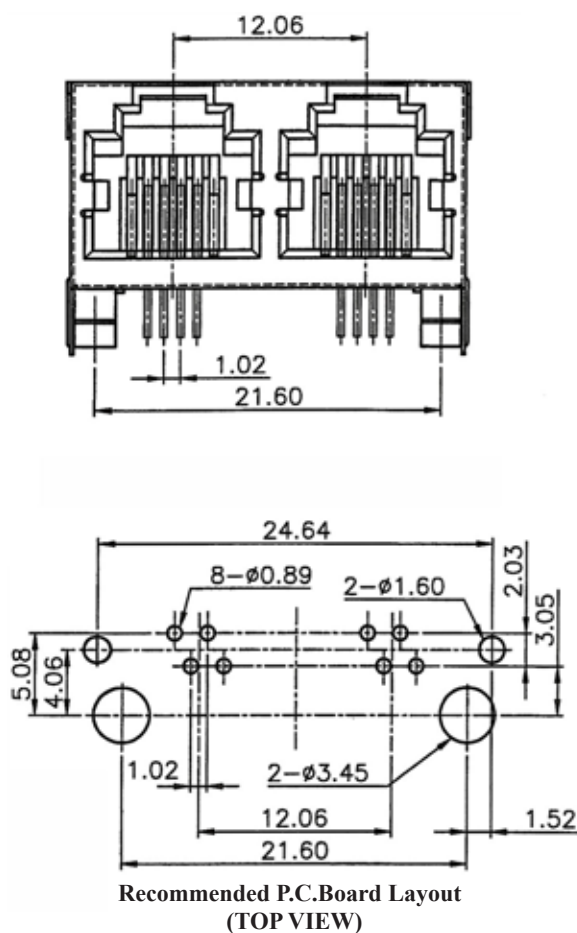
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 Q - $\frac{x}{1} \frac{x}{2} B \frac{0}{3} \frac{2}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: 4.06MM SPACING BEHIND PEG

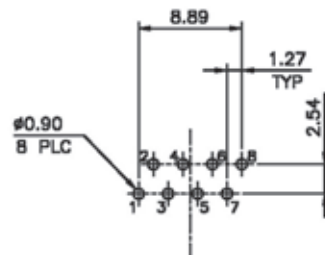
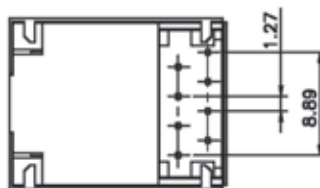
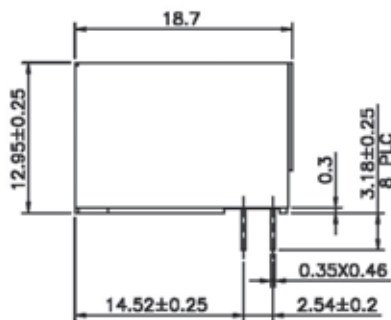
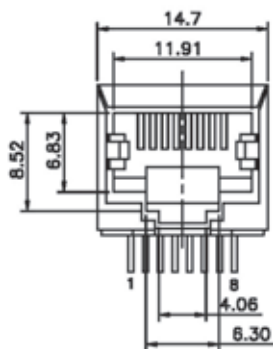
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{K}{I}$ J - $\frac{88}{2}$ x $\frac{B}{34}$

1. MODULAR JACK TYPE:
"KJ" W/O LOCATING PEGS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

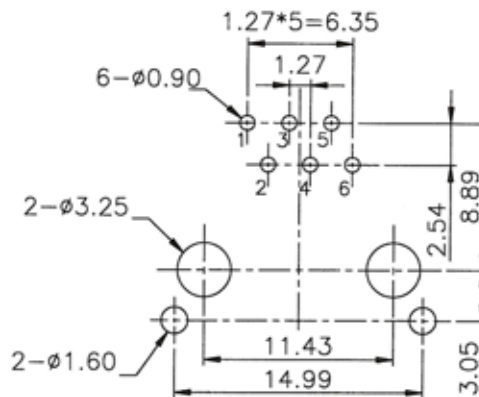
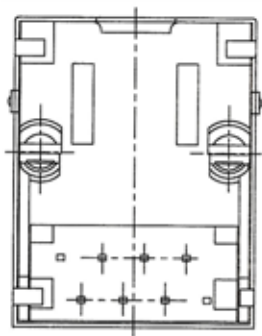
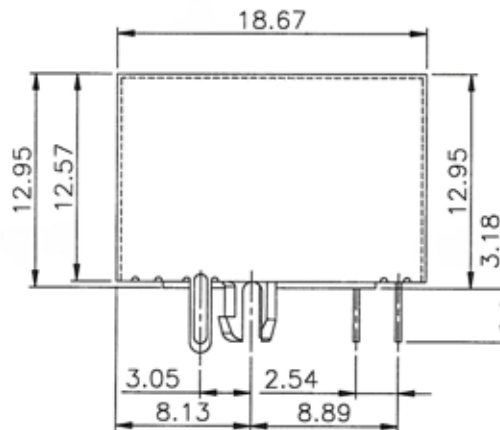
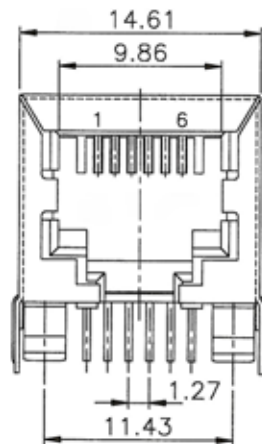
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 4 5 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

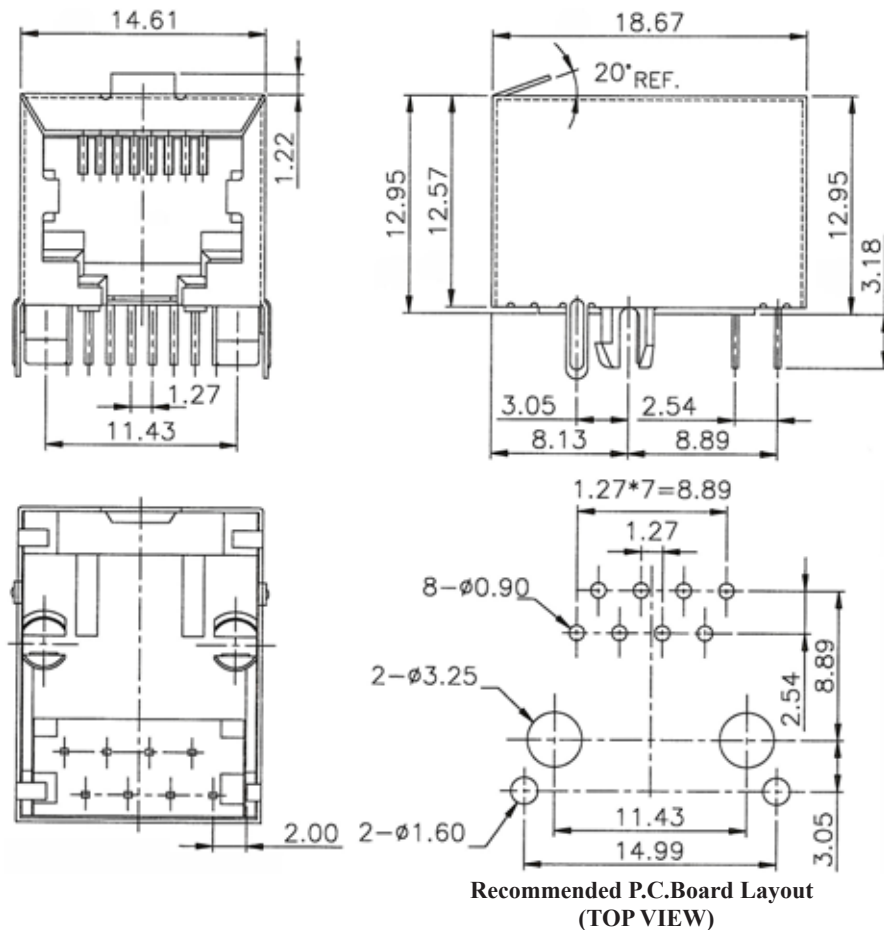
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 5 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK WITH FERRITE 6P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

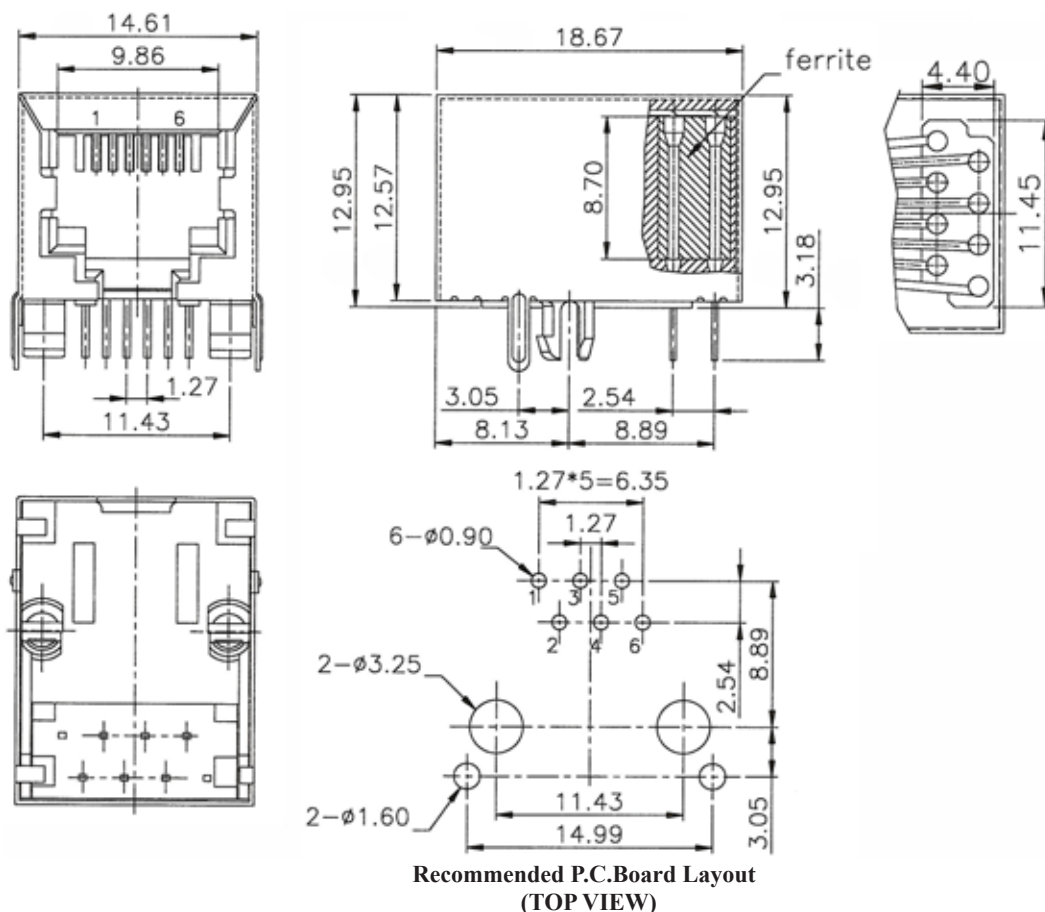
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 T - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

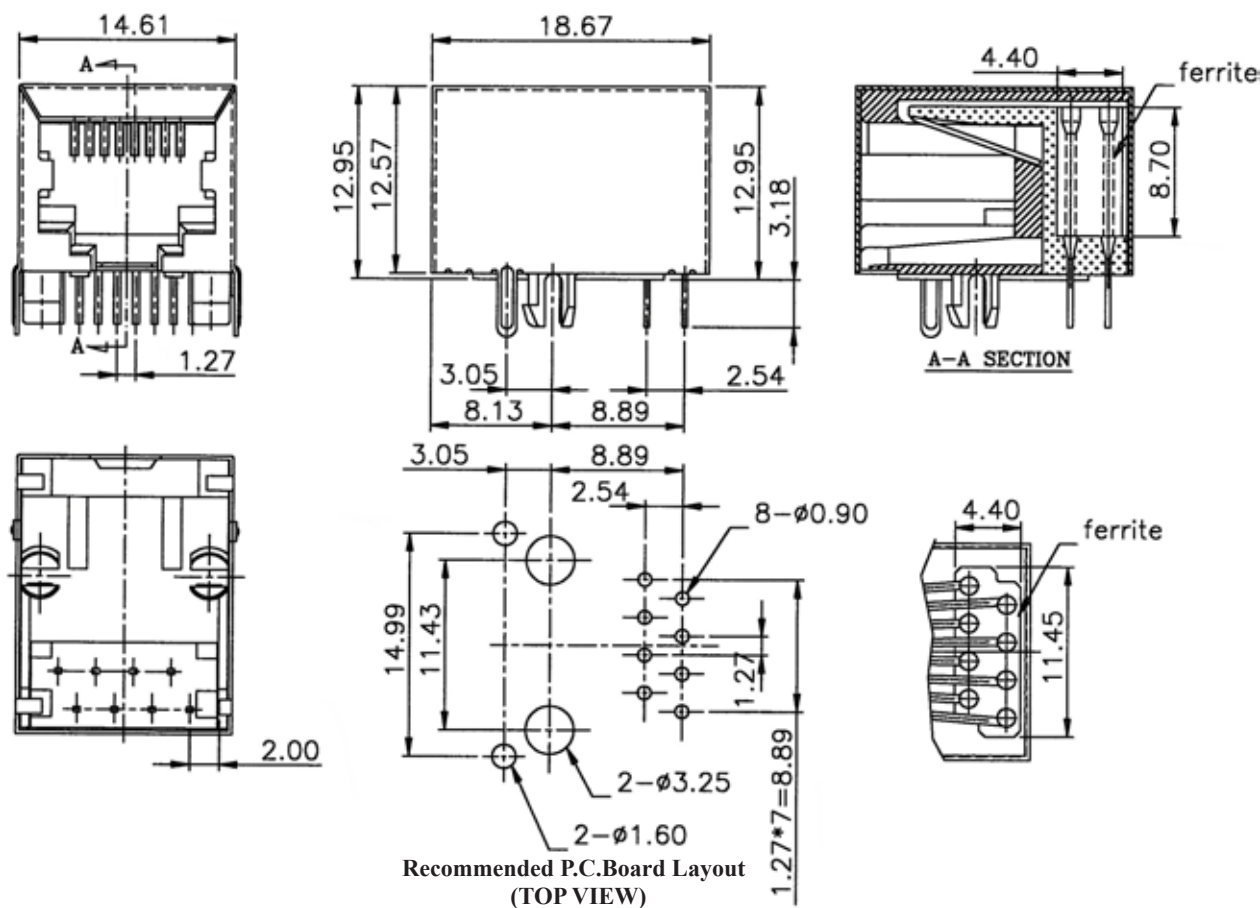
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 T - $\frac{88}{T} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

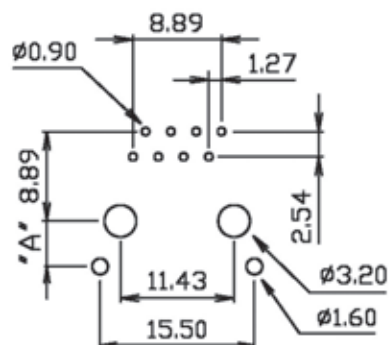
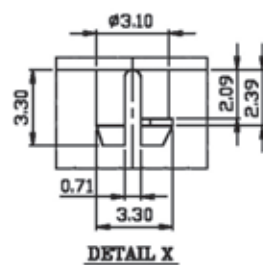
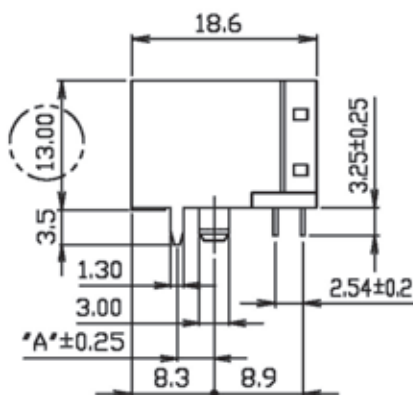
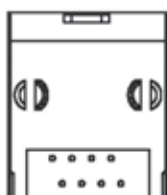
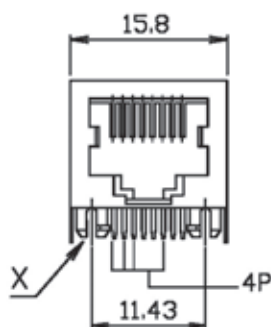
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J HS - 88 x B
 I 2 3 4

- MODULAR JACK TYPE:
"HS" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

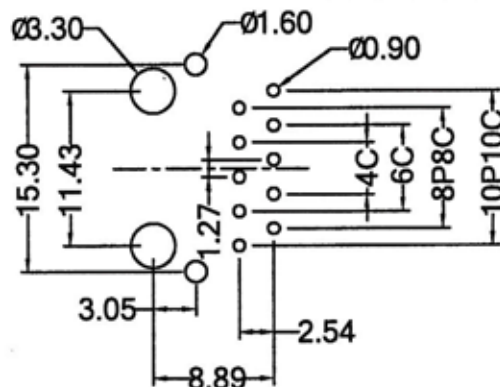
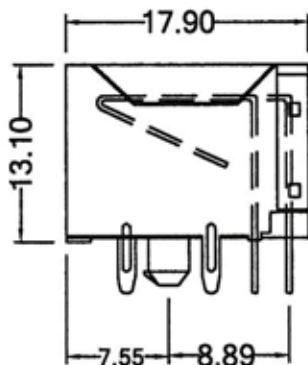
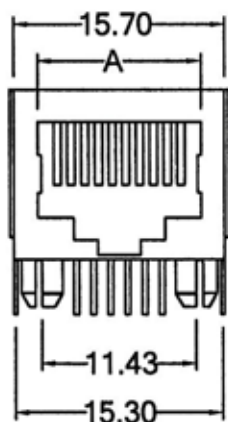
SIDE ENTRY MODULAR PCB JACK 6P+8P+10P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

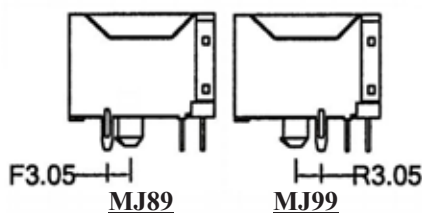
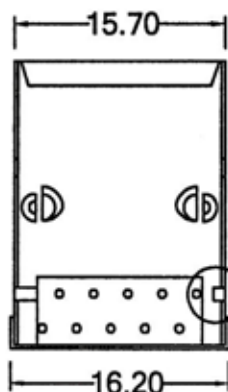
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

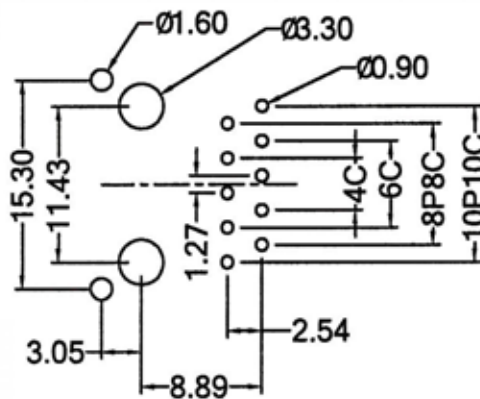
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout(TOP VIEW) **MJ99**



No. of Positions	No. of Contacts	A
6P	2C/4C/6C	9.90
8P	4C/6C/8C	11.95
10P	10C	11.95



Recommended P.C.Board Layout(TOP VIEW) **MJ89**

ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B$

- TYPE OF JACK:
 "89" F3.05
 "99" R3.05
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 8P+10P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

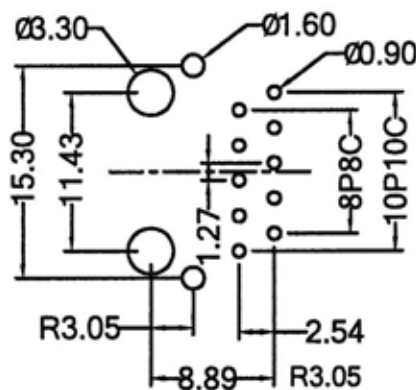
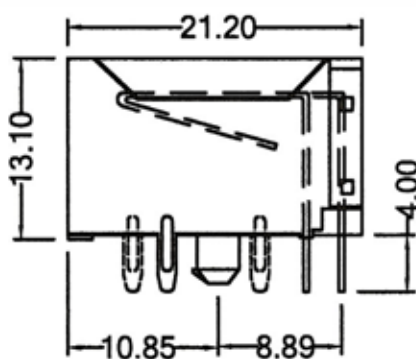
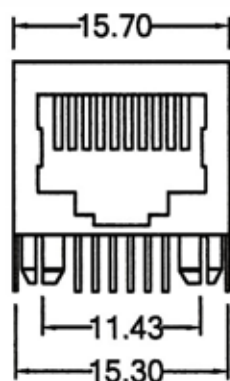
Color: Black

Spring Wire: Phosphor Bronze

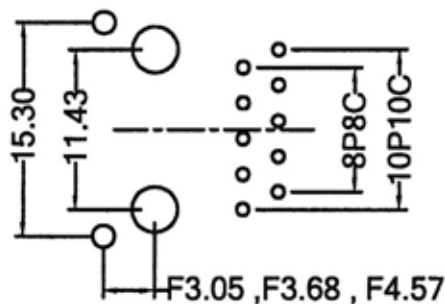
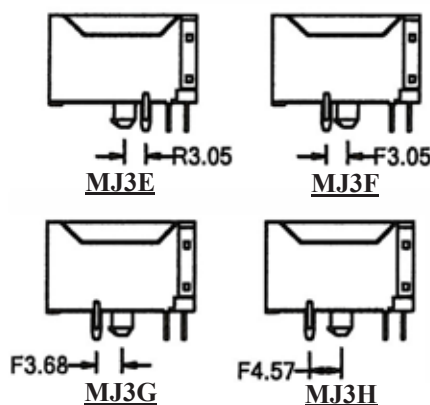
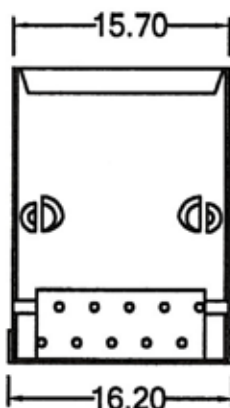
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout **MJ3E**
(TOP VIEW)



Recommended P.C.Board Layout
(TOP VIEW)
MJ3F, MJ3G, MJ3H

ORDERING INFORMATION:

P/N M J $\frac{xx}{1} - \frac{xxx}{2} \frac{x}{3} B$

1. PANEL STOP OPTION:

"3E" R3.05 TYPE

"3F" F3.05 TYPE

"3G" F3.68TYPE

"3H" F4.57 TYPE

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"00" 10P10C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P+8P+10P PROFILE=13.10MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

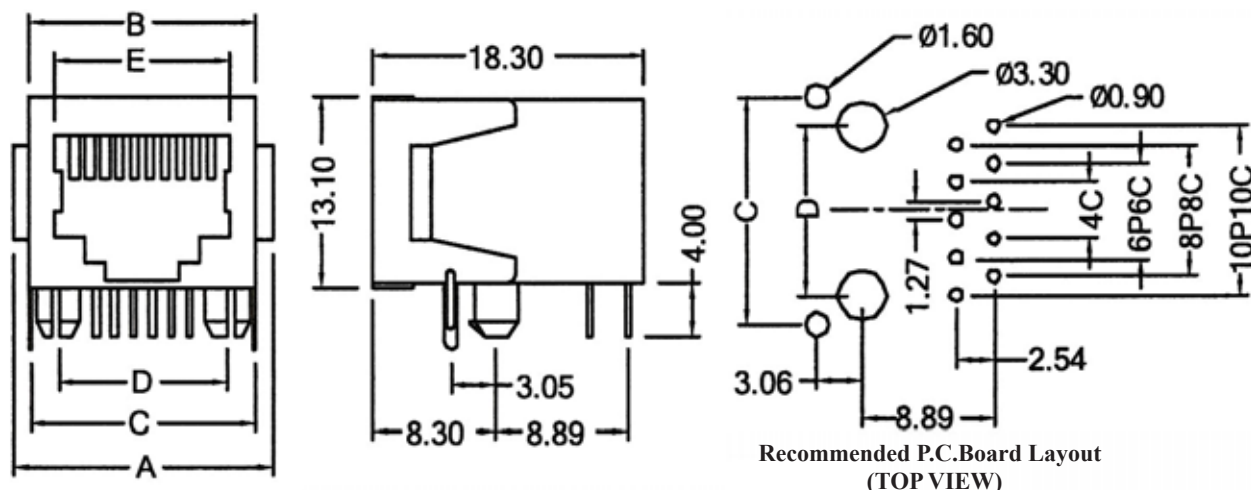
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A	B	C	D	E
6P	2C/4C/6C	15.60	13.65	13.40	10.16	9.90
8P	8C	17.50	15.65	15.40	11.43	11.85
10P	10C	17.50	15.65	15.40	11.43	11.85

ORDERING INFORMATION:

P/N M J 8 0 - x x x B
 1 2

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

"88" 8P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

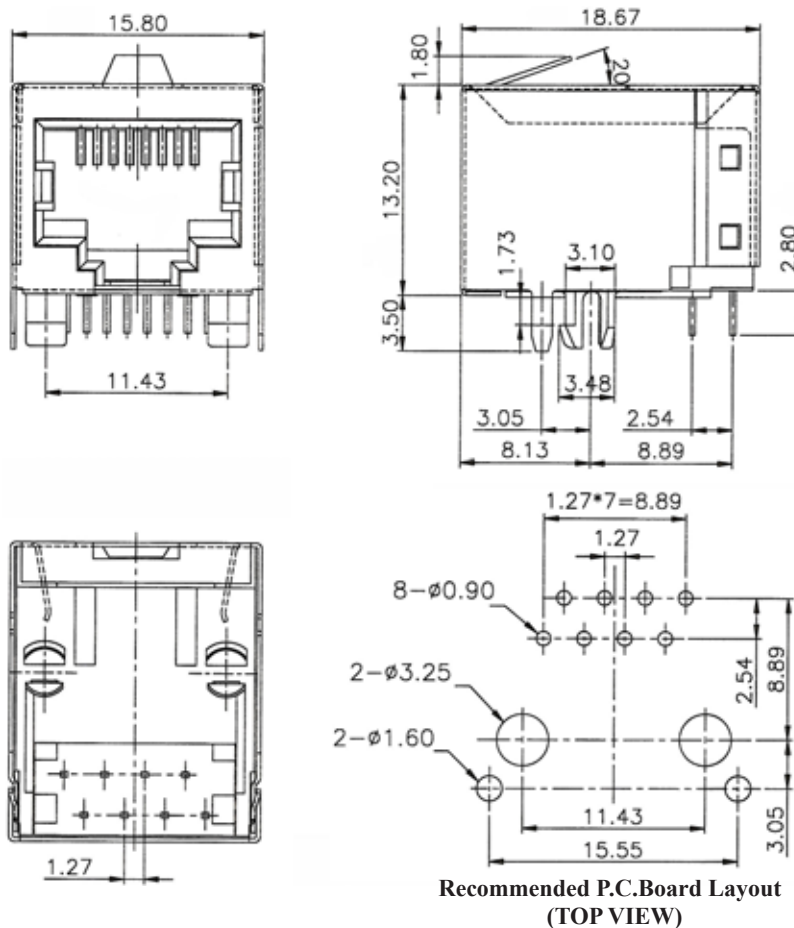
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 V - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

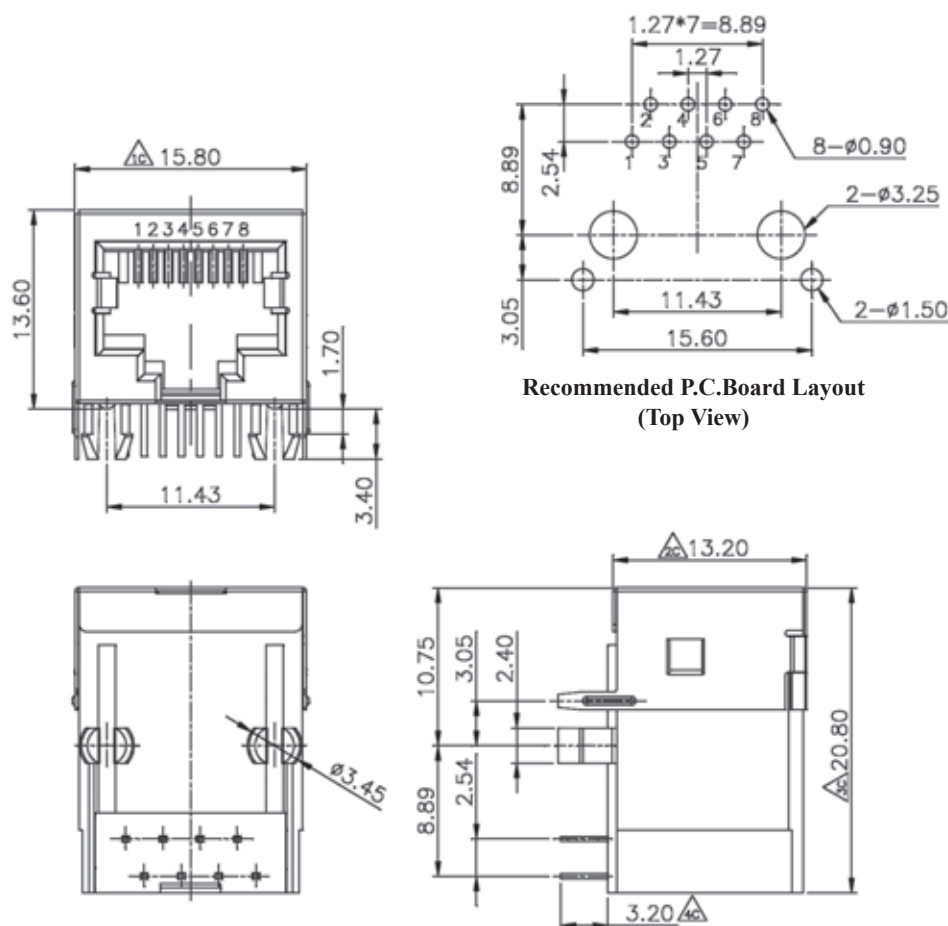
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J T V - $\frac{x \times x}{1} \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

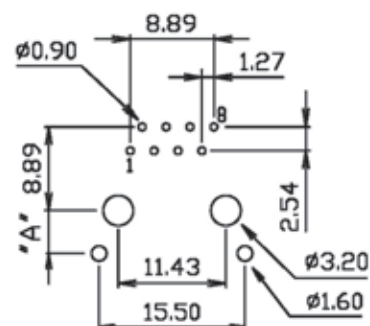
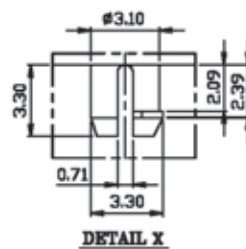
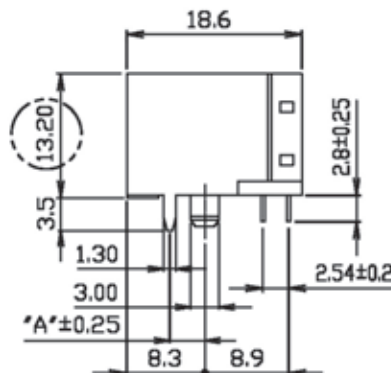
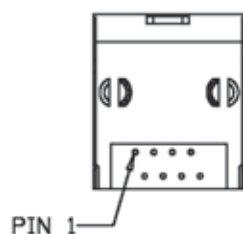
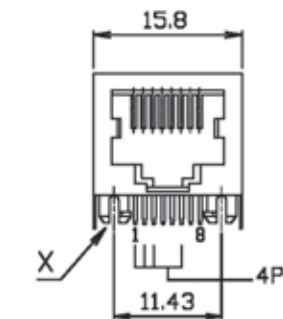
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H T - 8 8 x B
1 2 3 4

1. MODULAR JACK TYPE:
"HT" DIM.A = 3.05MM
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

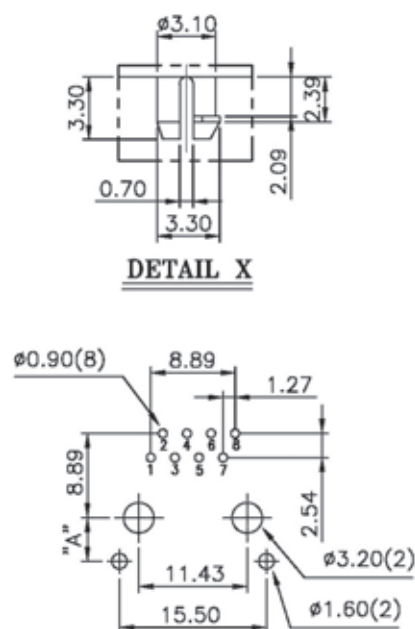
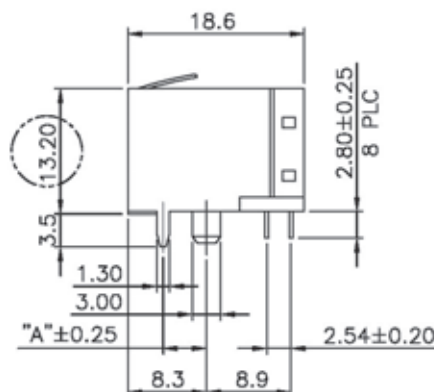
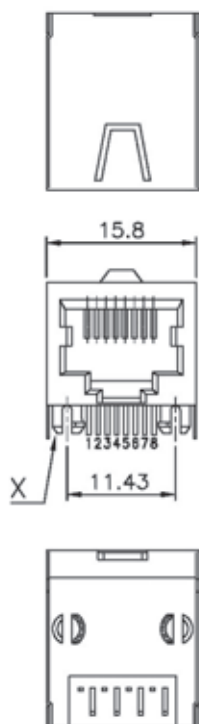
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{HN}{I}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
"HN" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

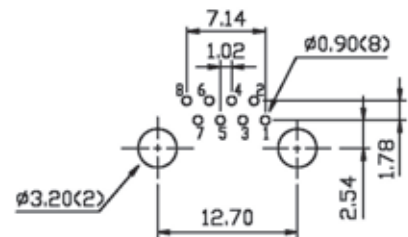
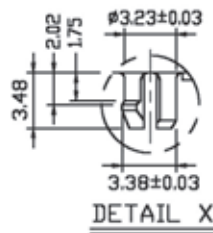
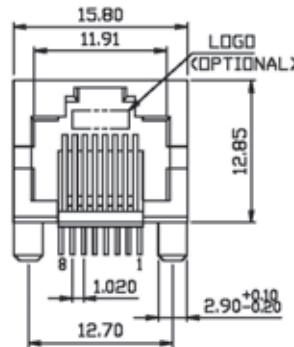
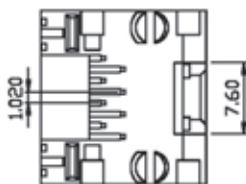
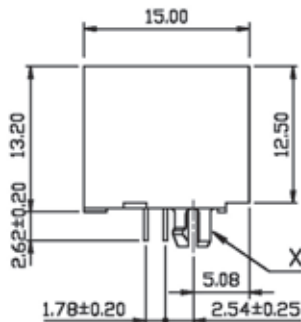
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H R - 8 8 x B
1 2 3 4

- MODULAR JACK TYPE:
"HR" WITH ROUND PINS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

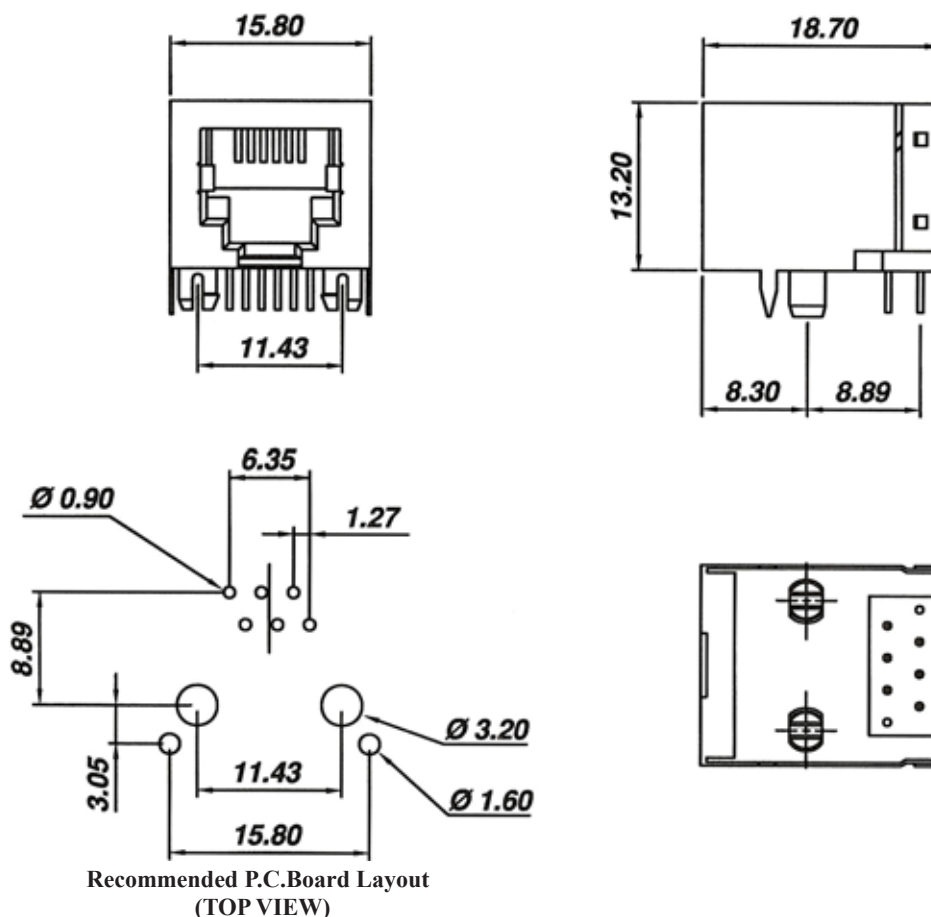
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S L - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY DATA LINK MODULAR PCB JACK 4P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

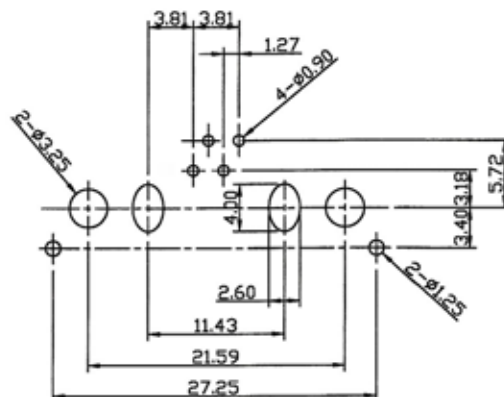
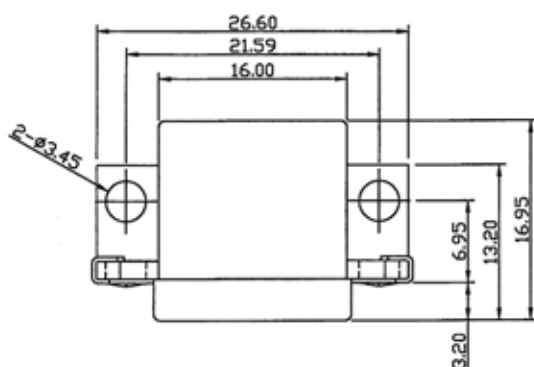
Color: Black

Spring Wire: Phosphor Bronze

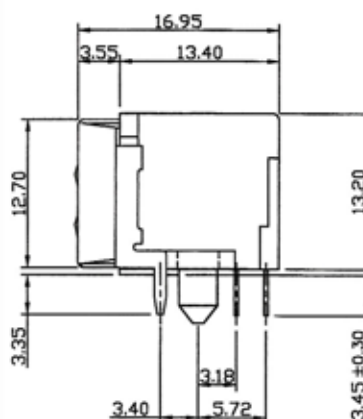
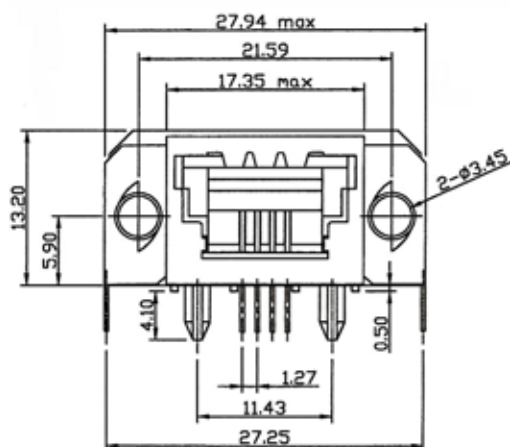
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 4 F - $\frac{44}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

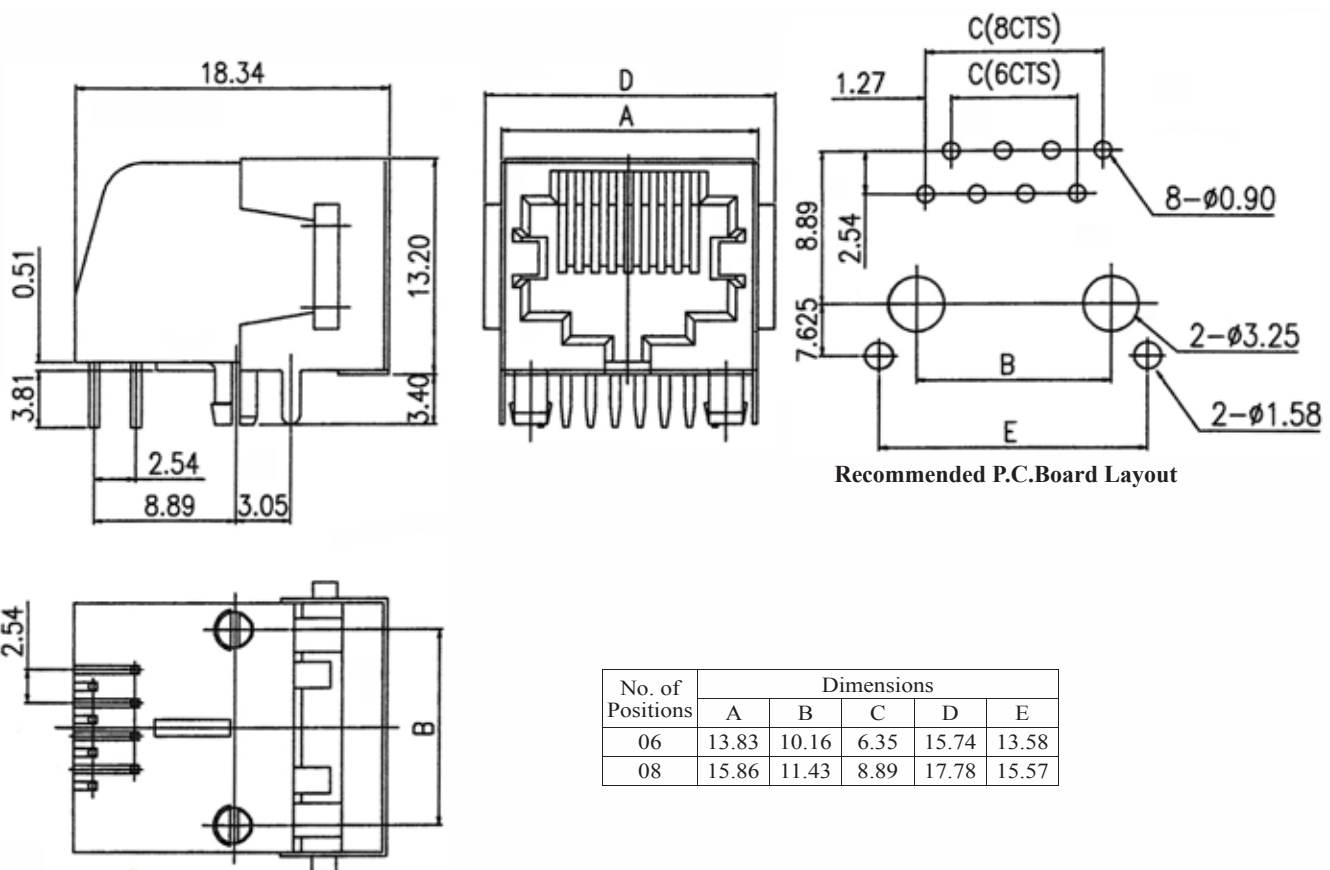
SIDE ENTRY MODULAR PCB JACK 6P+8P PROFILE=13.20MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



No. of Positions	Dimensions				
	A	B	C	D	E
06	13.83	10.16	6.35	15.74	13.58
08	15.86	11.43	8.89	17.78	15.57

ORDERING INFORMATION:

P/N M J 1 5 - $\frac{x x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P W/O LED PROFILE=13.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

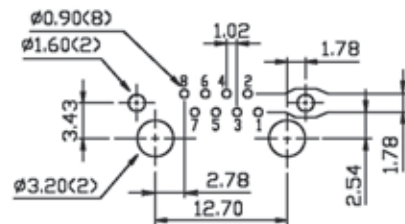
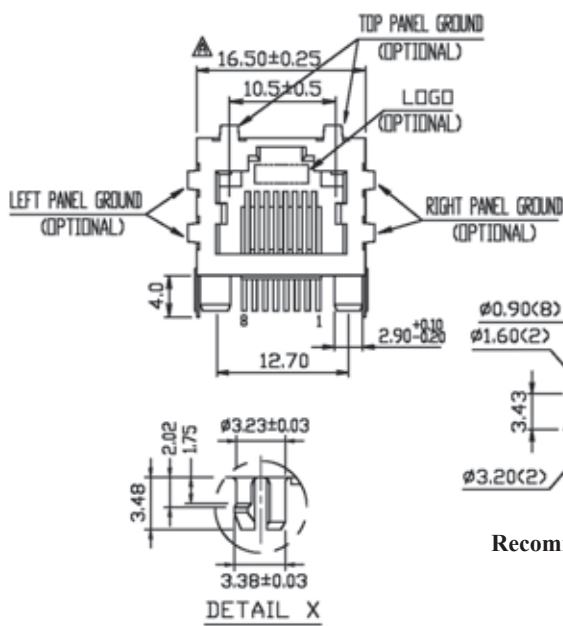
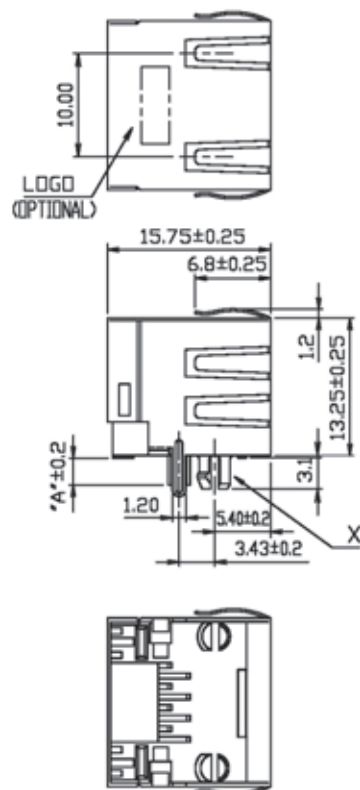
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{88}{2}$ $\frac{X}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
"JA" WITH TOP/RIGHT/LEFT SIDE TABS
"JB" WITH RIGHT/LEFT TABS
"JC" WITH TOP SIDE TABS
"JD" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

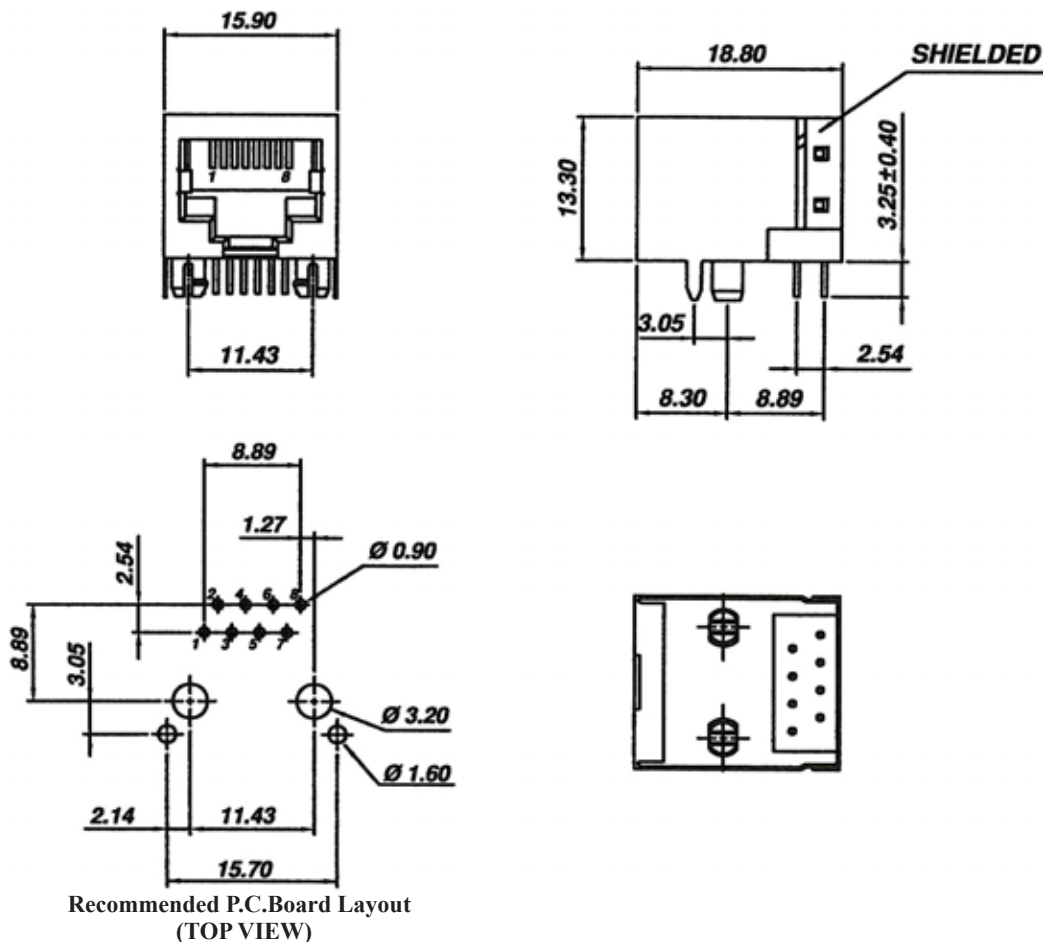
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S L - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJSLHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

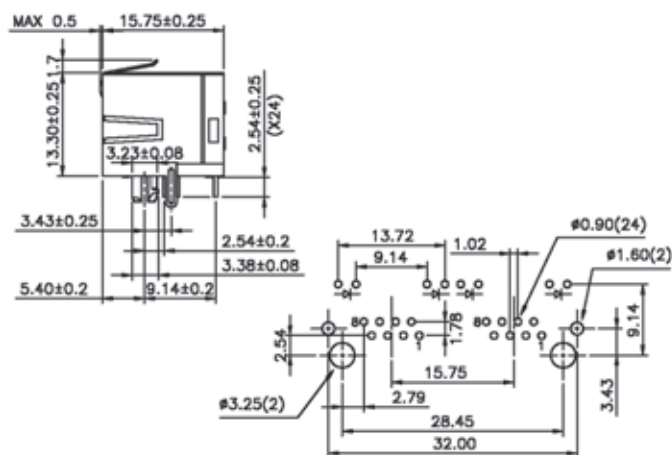
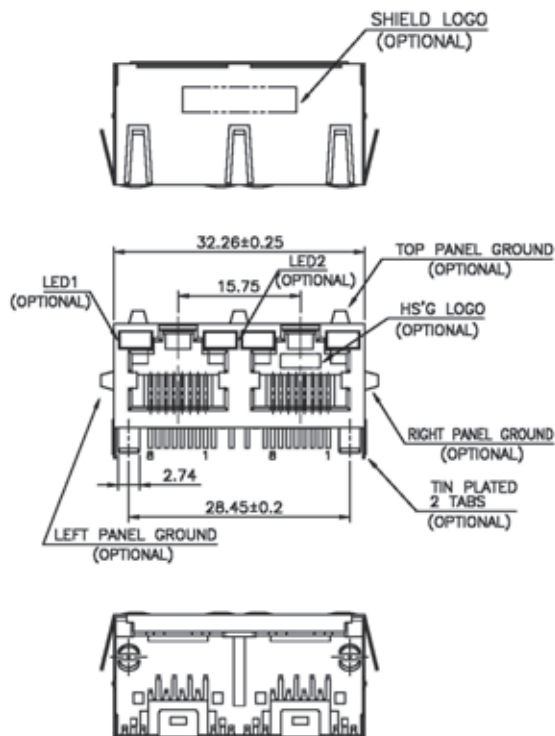
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED PROFILE=13.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{88}{2} \frac{X}{3} \frac{B}{4} \frac{XX}{5} \frac{02}{6}$

- MODULAR JACK TYPE:
 "JJ" WITH TOP/RIGHT/LEFT SIDE TABS
 "JK" WITH RIGHT/LEFT TABS
 "JL" WITH TOP SIDE TABS
 "JM" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- COLORS OF LED:
 "NN" LED1: GREEN & LED2: GREEN
 "NY" LED1: GREEN & LED2: YELLOW
 "YN" LED1: YELLOW & LED2: GREEN
 "YY" LED1: YELLOW & LED2: YELLOW
 "XX" W/O LED
- NO. OF PORTS:
 02

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

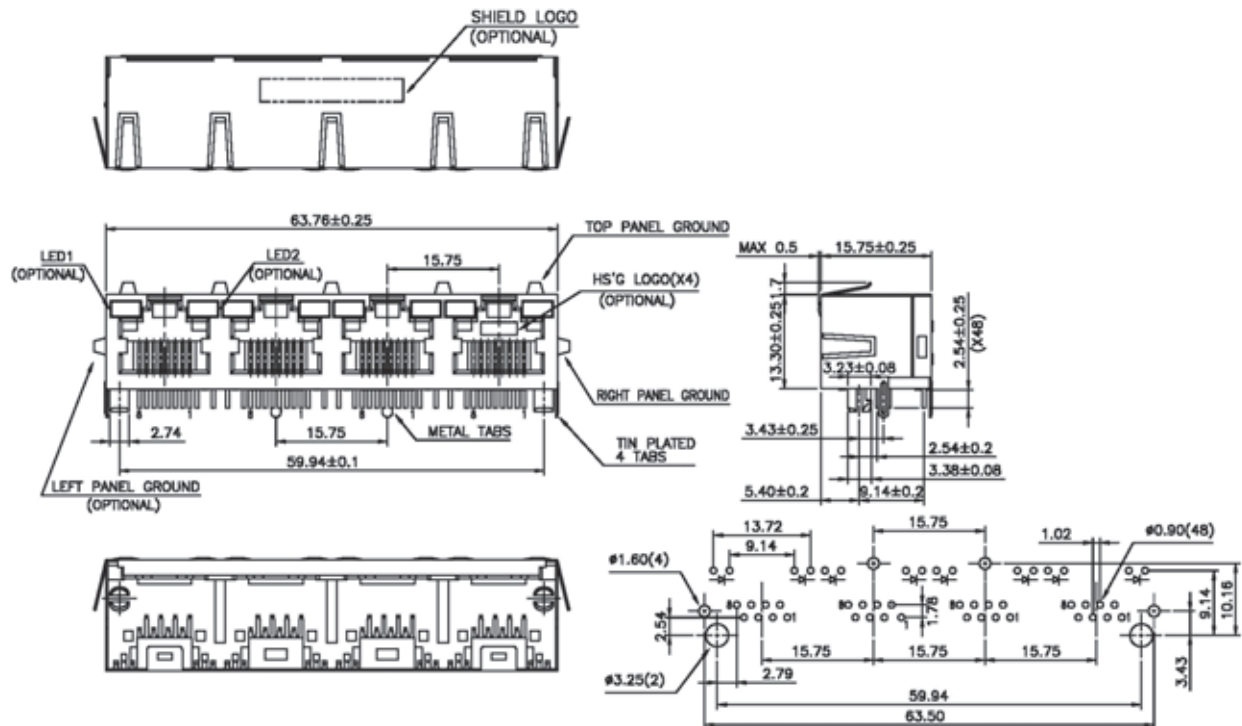
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{88}{2}$ $\frac{X}{3}$ $\frac{B}{4}$ $\frac{XX}{5}$ $\frac{04}{6}$

1. MODULAR JACK TYPE:

"BE" WITH TOP/RIGHT/LEFT SIDE TABS

"BF" WITH RIGHT/LEFT TABS

"BG" WITH TOP SIDE TABS

"BH" WITHOUT GROUNDING TABS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

5. COLORS OF LED:

"NN" LED1/2 = GREEN/GREEN

"NY" LED1/2 = GREEN/YELLOW

"YN" LED1/2 = YELLOW/GREEN

"YY" LED1/2 = YELLOW/YELLOW

"XX" WITHOUT LED

6. NO. OF PORTS:

04

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=13.30MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

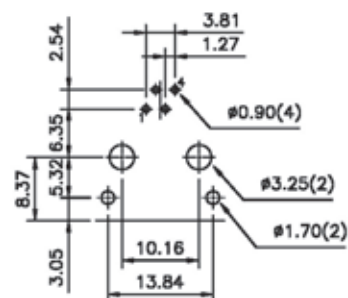
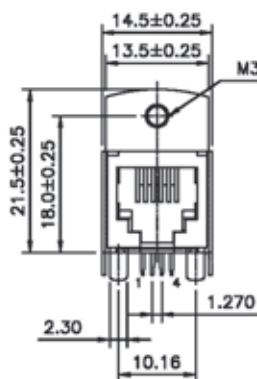
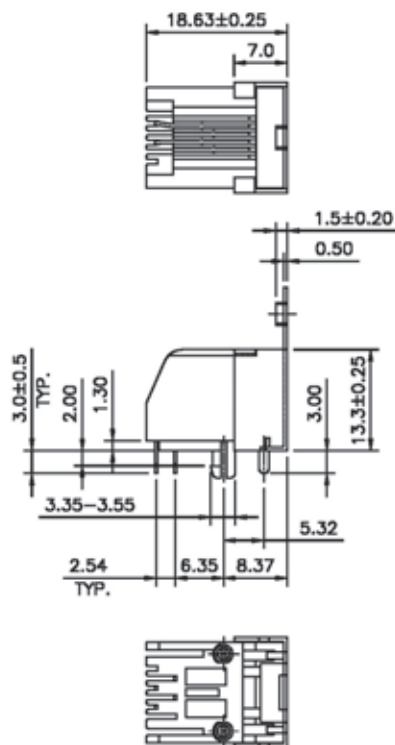
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H W - 4 4 x B
1 2 3 4

1. MODULAR JACK TYPE:
"HW" WITH M3 SCREW HOLE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

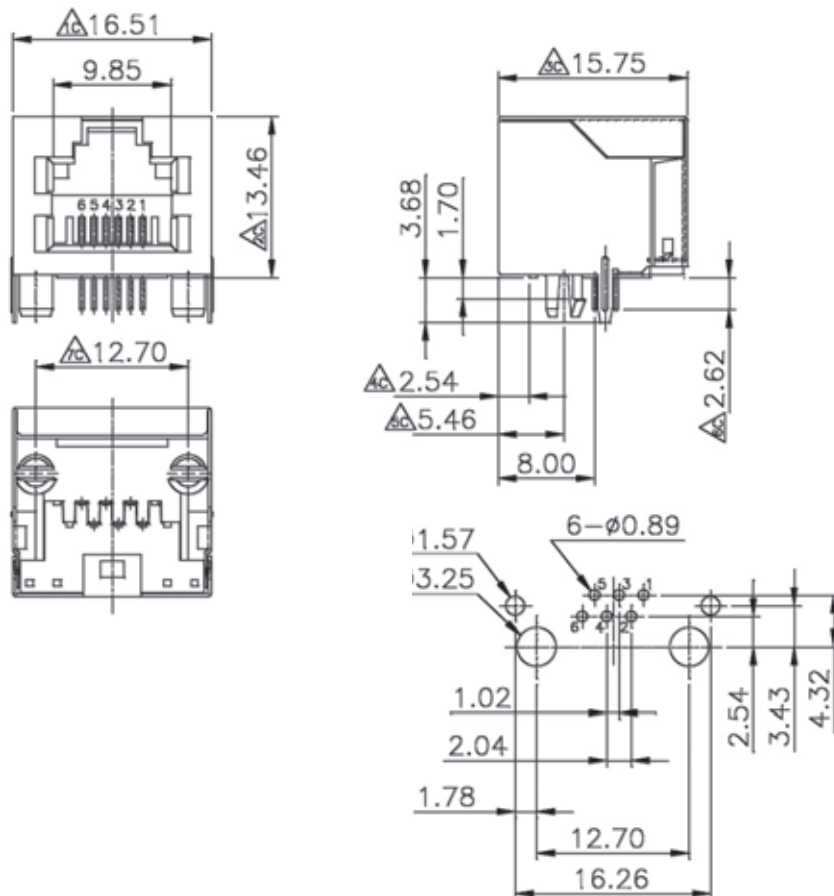
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 2 A - $\frac{x}{1} \frac{x}{2} \frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"64" 6P4C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

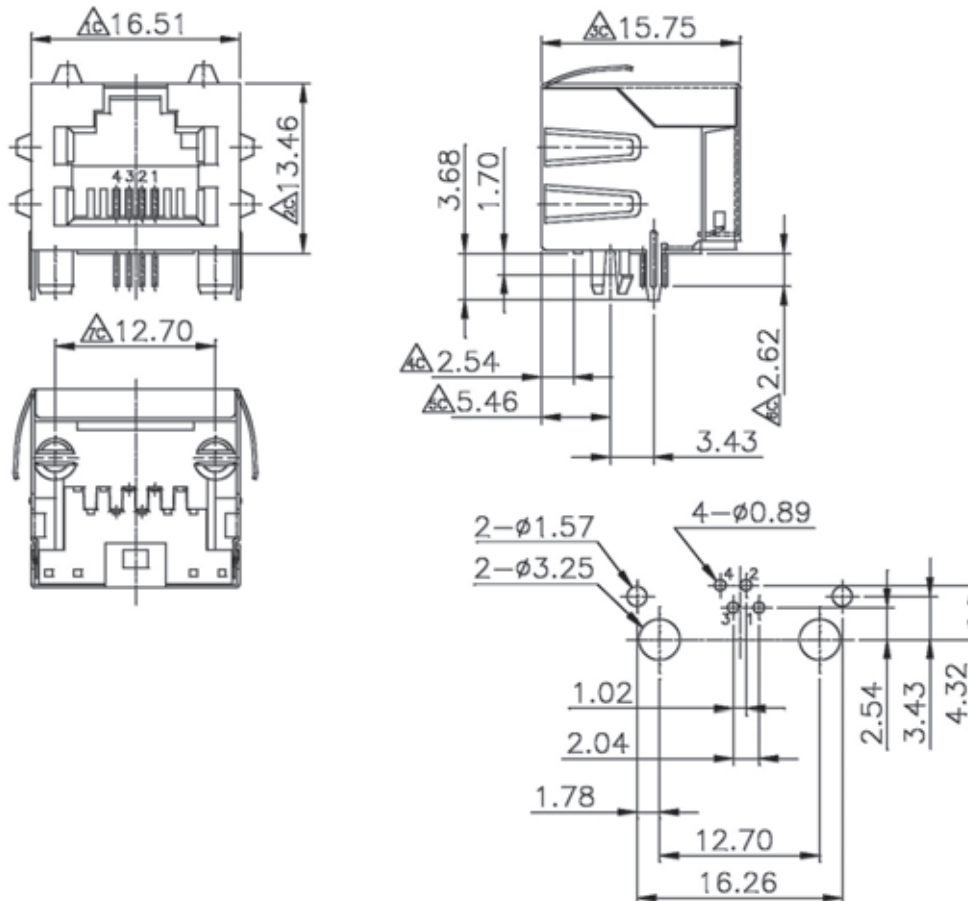
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 2 D - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"64" 6P4C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

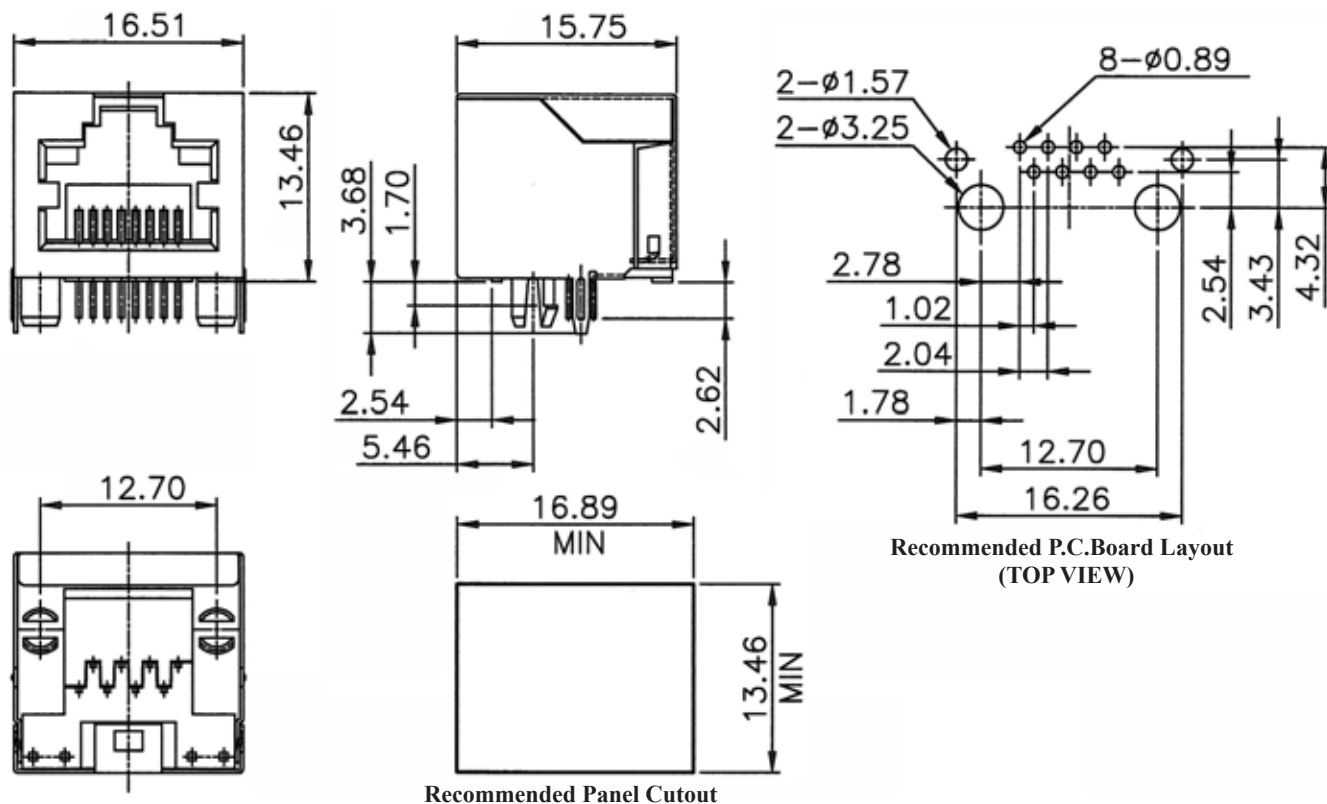
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 A - $\frac{x}{1} \frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

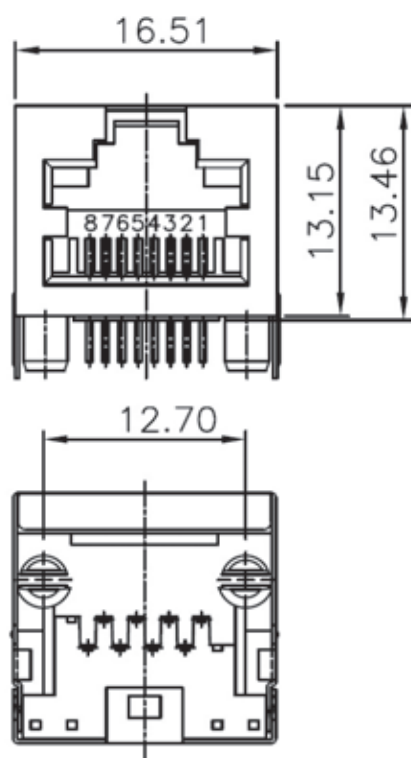
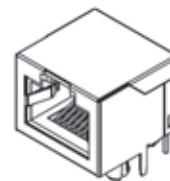
Plastic Housing: Engineering Thermoplastic

Contacts: Phosphor Bronze

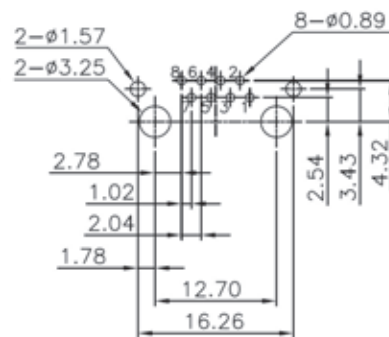
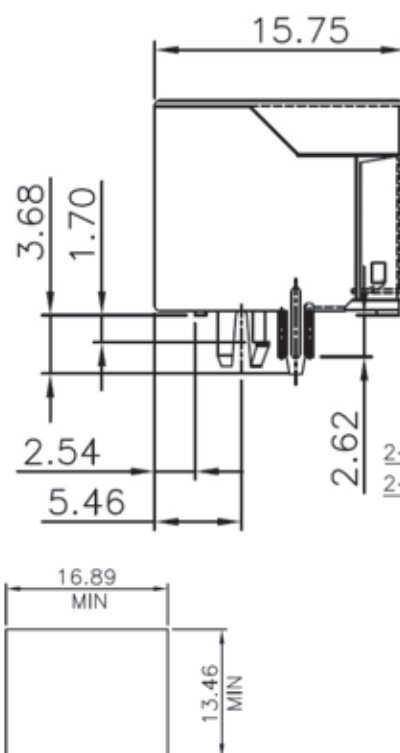
Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended Panel Cutout



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ $\frac{2AJ}{1}$ - $\frac{88}{2} \frac{x}{3}$ B

1. MODULAR JACK TYPE:
"2AJ" UP LATCH TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: IT CAN BE USED FOR REPLACING P/N MJ2A-88xB.

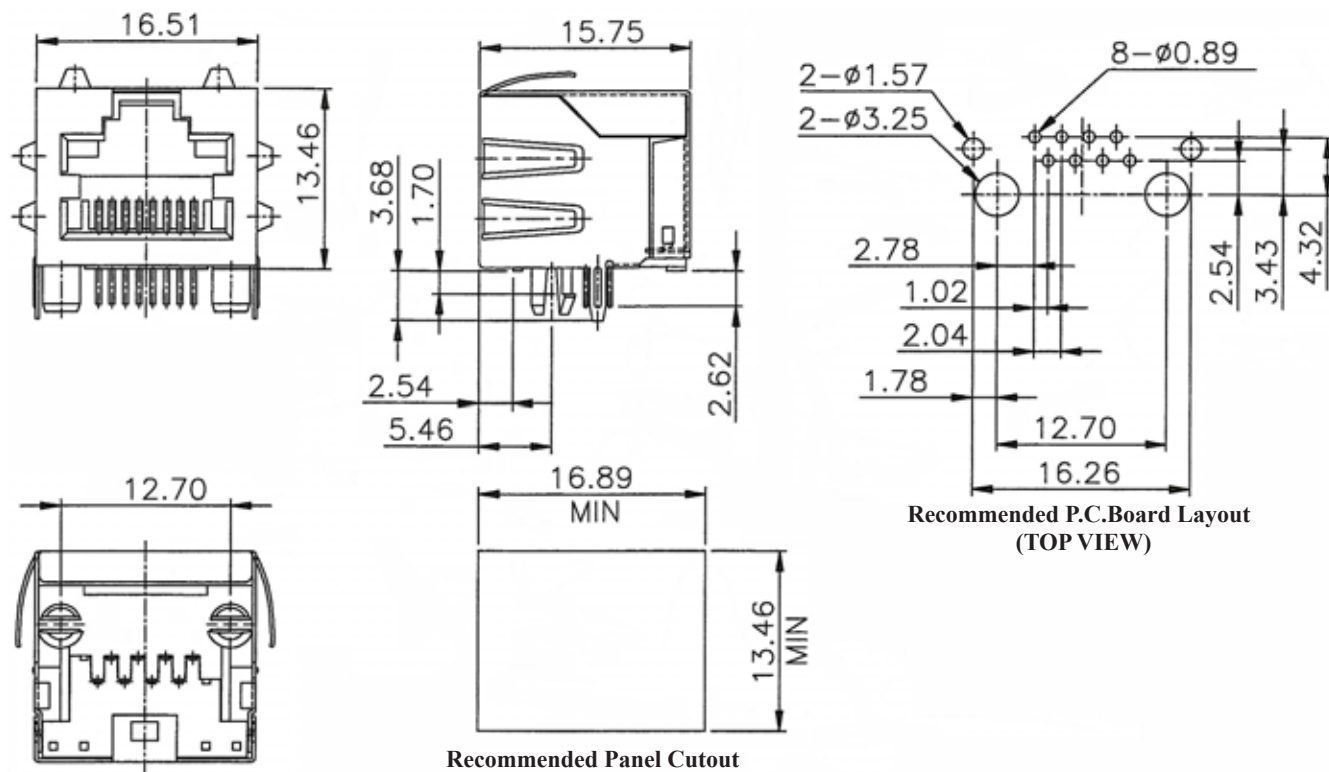
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 D - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

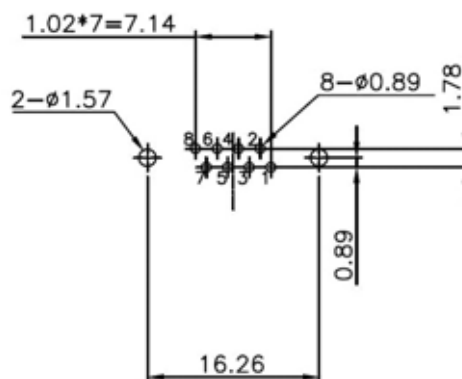
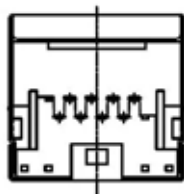
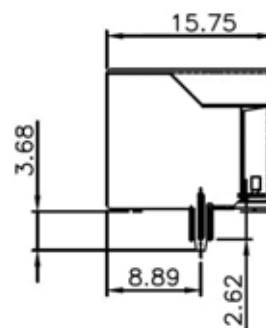
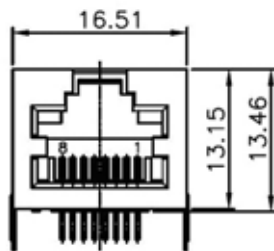
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J 3 X - $\frac{x}{1} \frac{x}{2} x$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

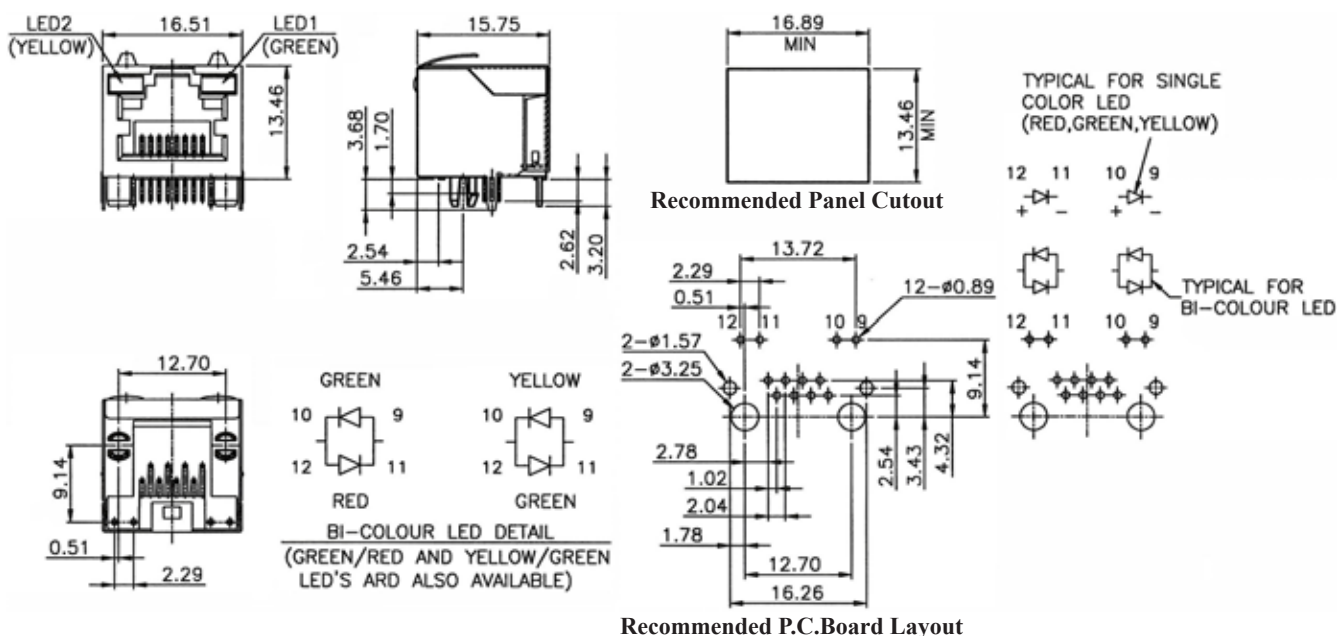
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 3 A - $\frac{8}{1} \frac{8}{2} \frac{B}{3} \frac{X}{4} \frac{0}{5} \frac{1}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

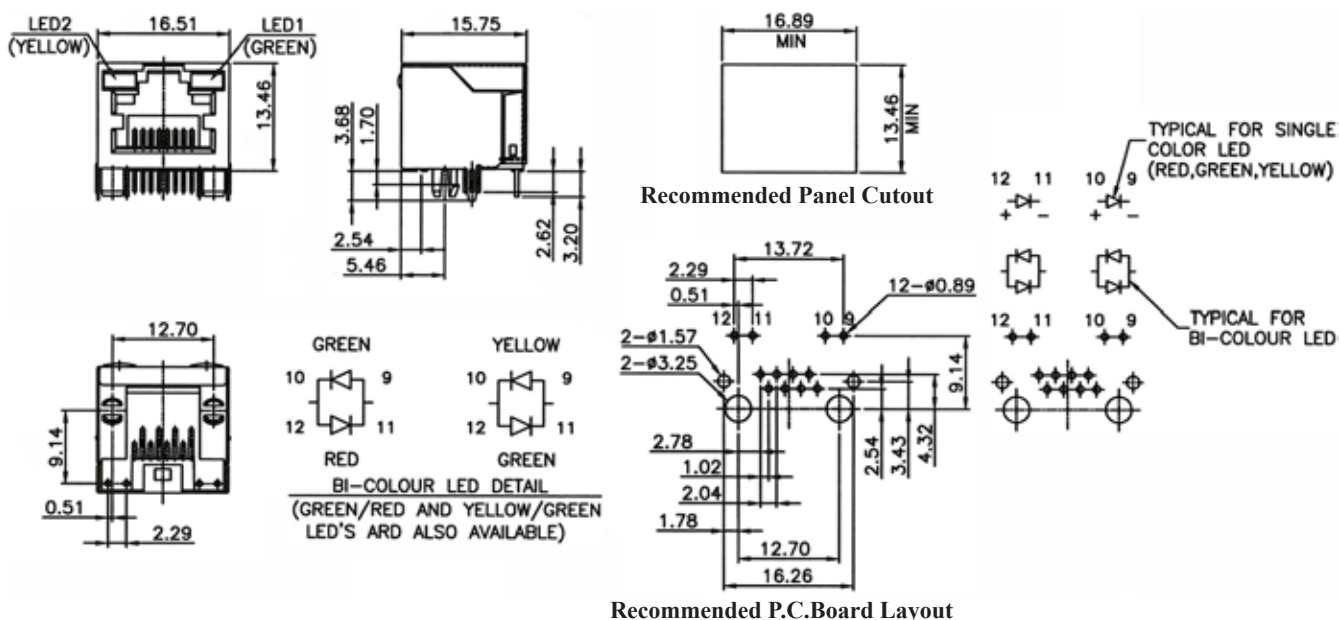
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 3 B - $\frac{8}{1} \frac{8}{2} \times \frac{B}{3} \times \frac{0}{4} \frac{1}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

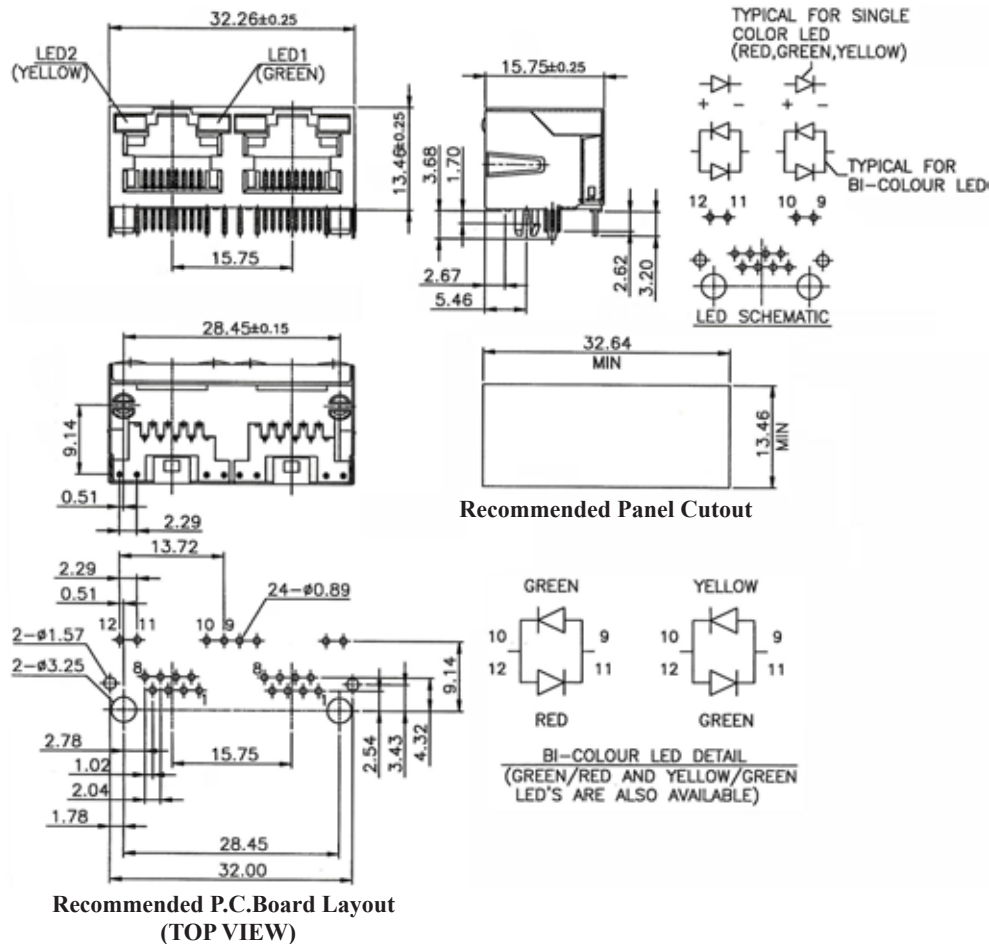
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 3 B - $\frac{88}{1} \times \frac{B}{2} \times \frac{02}{345}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

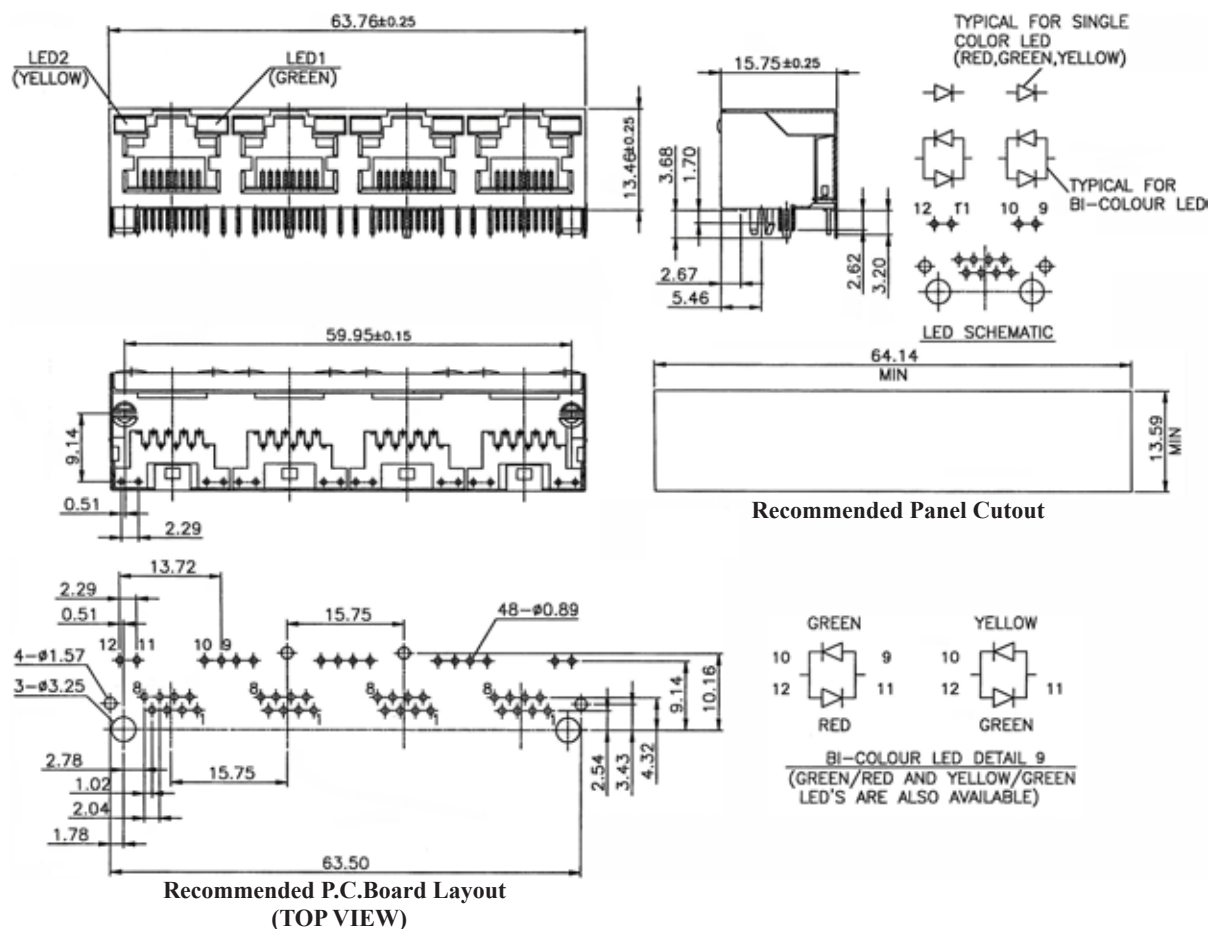
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ3B-88xBxx04
1 2 3 4 5

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

NOTE: P/N MJ3BHT-88xBxx04 FOR HIGH TEMP. VERSION

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

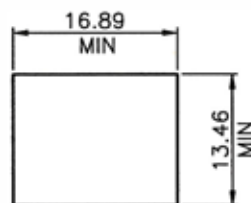
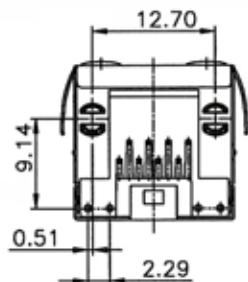
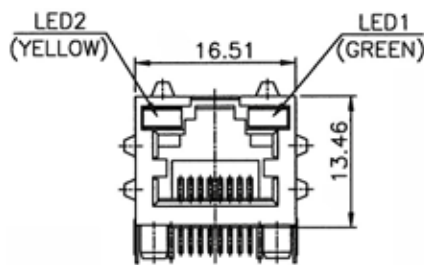
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

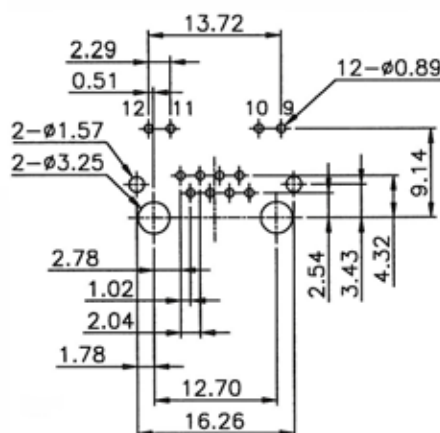
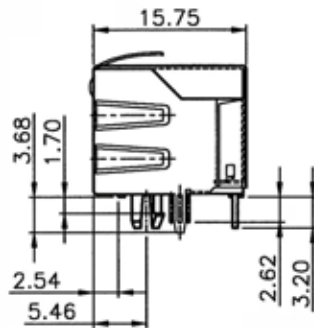
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

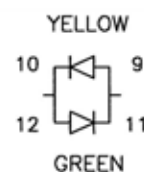
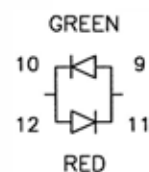
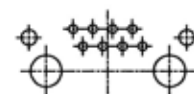
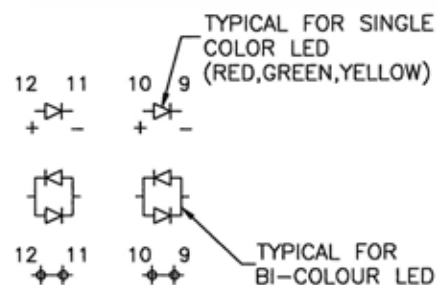
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended Panel Cutout



Recommended P.C.Board Layout



BI-COLOUR LED DETAIL
 (GREEN/RED AND YELLOW/GREEN
 LED'S ARE ALSO AVAILABLE)

ORDERING INFORMATION:

P/N M J 2 T - $\frac{88}{1} \times \frac{B}{2} \times \frac{01}{345}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
 LED 2 = LEFT LED

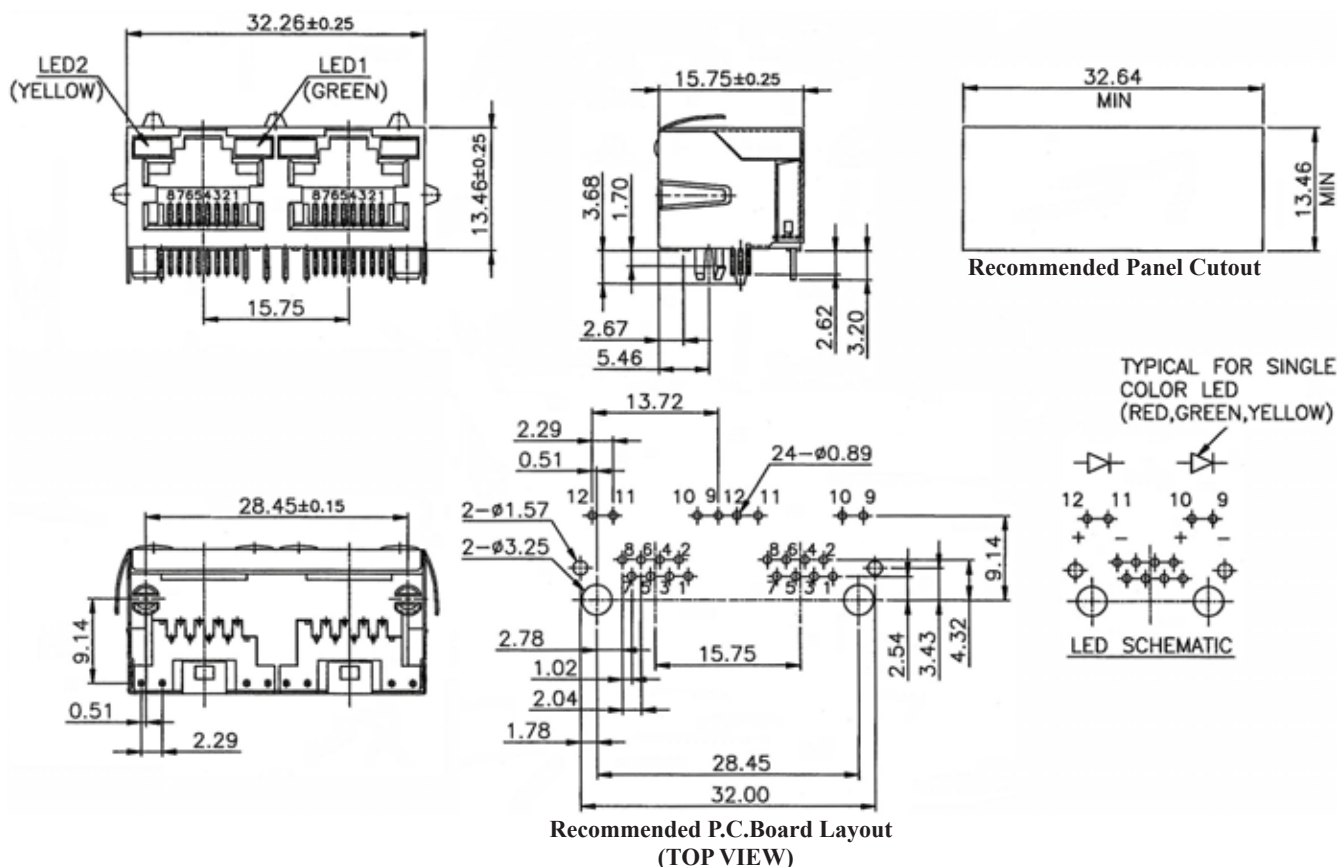
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 T - 8 8 x B x x 0 2
1 2 3 4 5

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

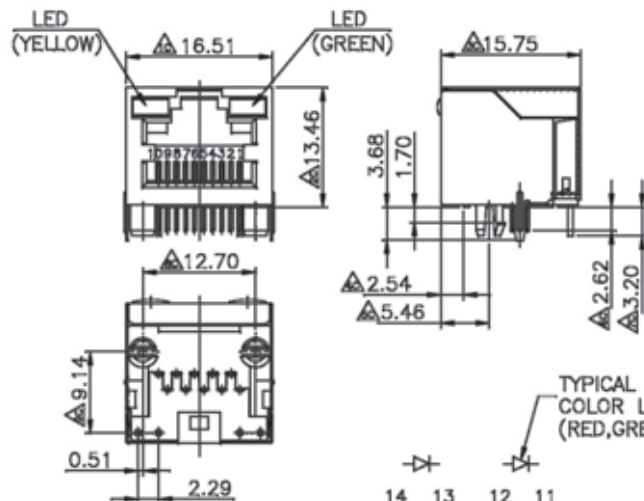
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 10P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

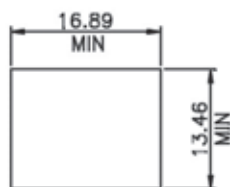
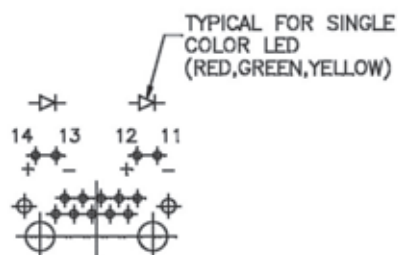
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

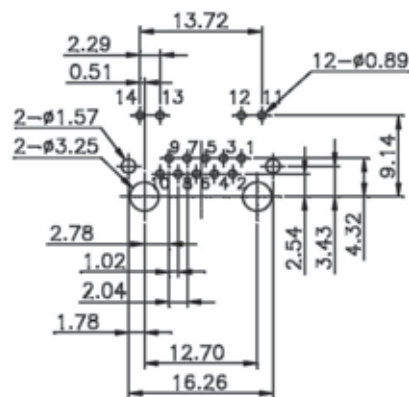
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJ2A-00xBYN



RECOMMENDED PANEL CUTOUT



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N MJ2A - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LEFT/RIGHT LED = GREEN/GREEN

"NY" LEFT/RIGHT LED = YELLOW/GREEN

"YN" LEFT/RIGHT LED = GREEN/YELLOW

"YY" LEFT/RIGHT LED = YELLOW/YELLOW

"XX" WITHOUT LED

OTHER LED COLORS UPON REQUEST!

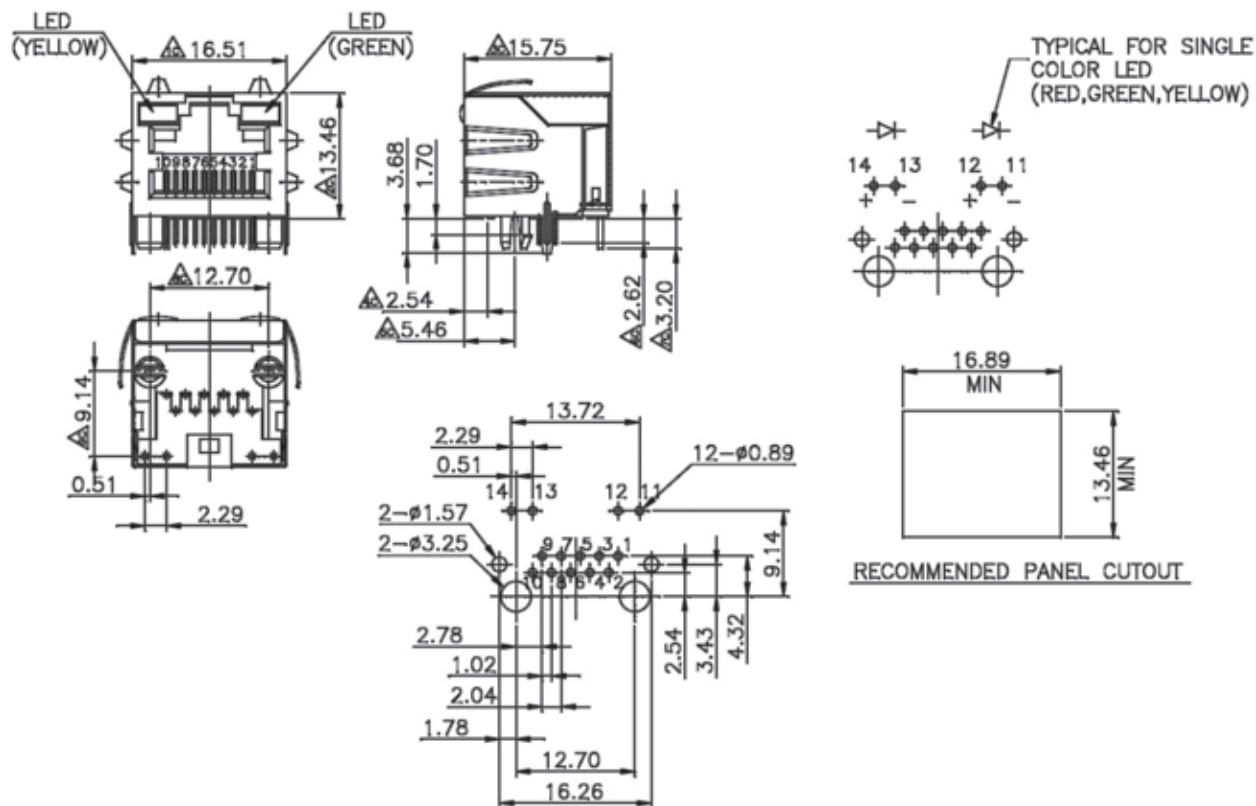
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 10P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJ2T-00xBYN

Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N MJ2T - $\frac{xx}{1} \frac{xx}{2} B \frac{xx}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C
 "08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LEFT/RIGHT LED = GREEN/GREEN
 "NY" LEFT/RIGHT LED = YELLOW/GREEN
 "YN" LEFT/RIGHT LED = GREEN/YELLOW
 "YY" LEFT/RIGHT LED = YELLOW/YELLOW
 "XX" WITHOUT LED

OTHER LED COLORS UPON REQUEST!

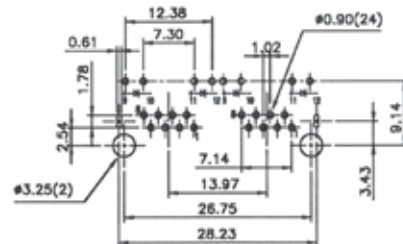
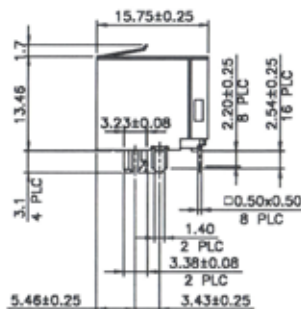
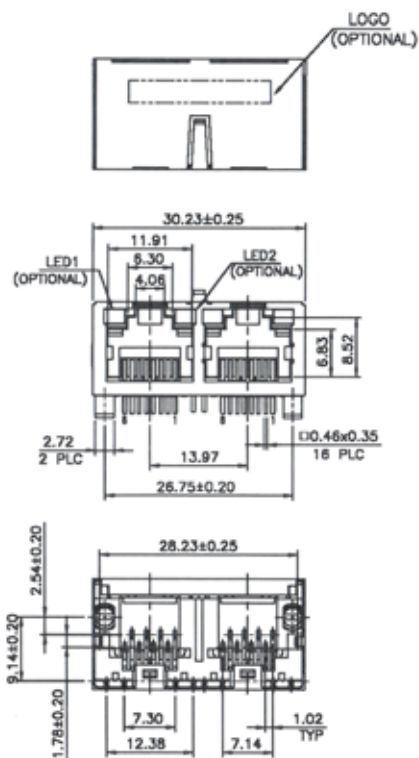
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J HY - 88 x B x x 02
1 2 3 4 5 6

- MODULAR JACK TYPE:
"HY" 2 PORTS WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

Plastic Housing: Engineering Thermoplastic

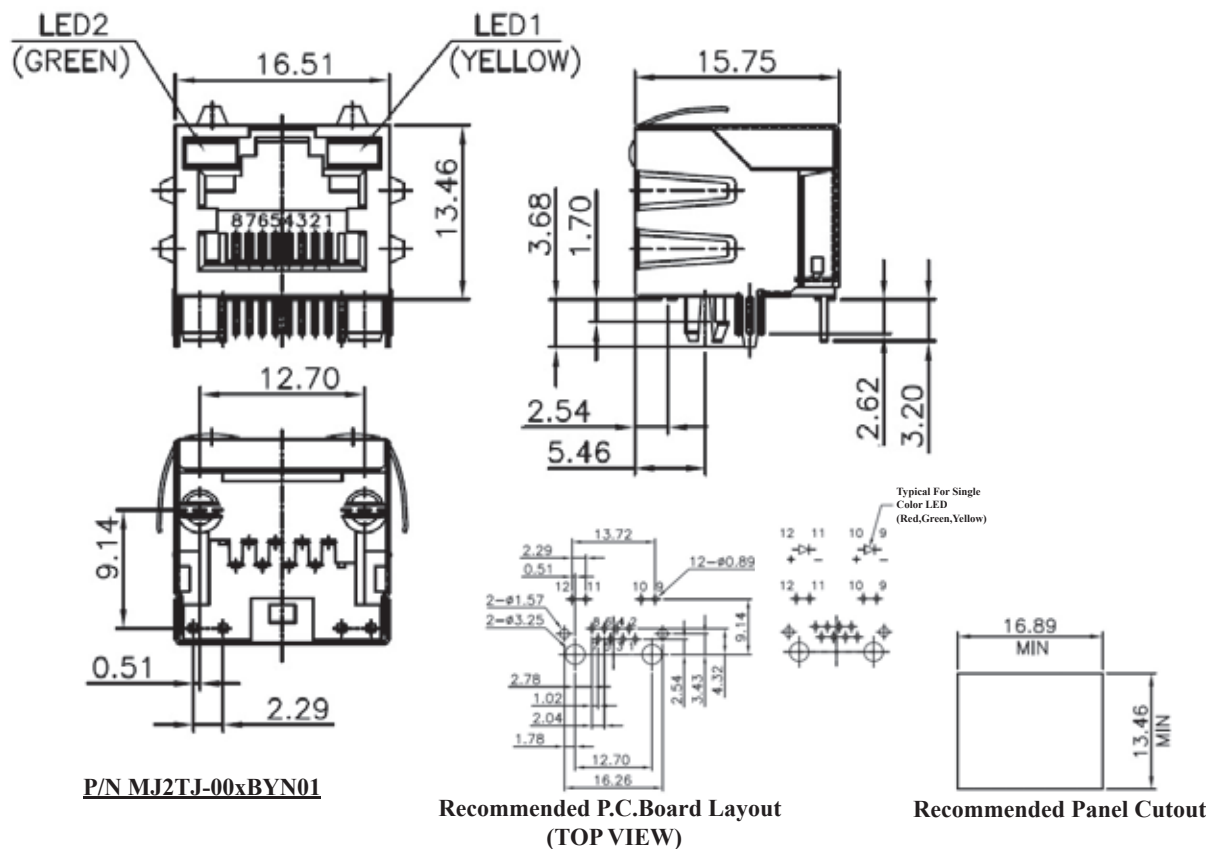
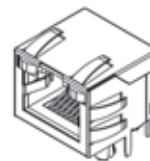
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 T J - 88 X B XX 01
 1 2 3 4

- MODULAR JACK TYPE:
"2TJ" WITH TOP & SIDE PANEL GROUNDS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

- COLOR OF LED:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

NOTE: IT CAN BE USED FOR REPLACING P/N MJ2T-88xBxx01.

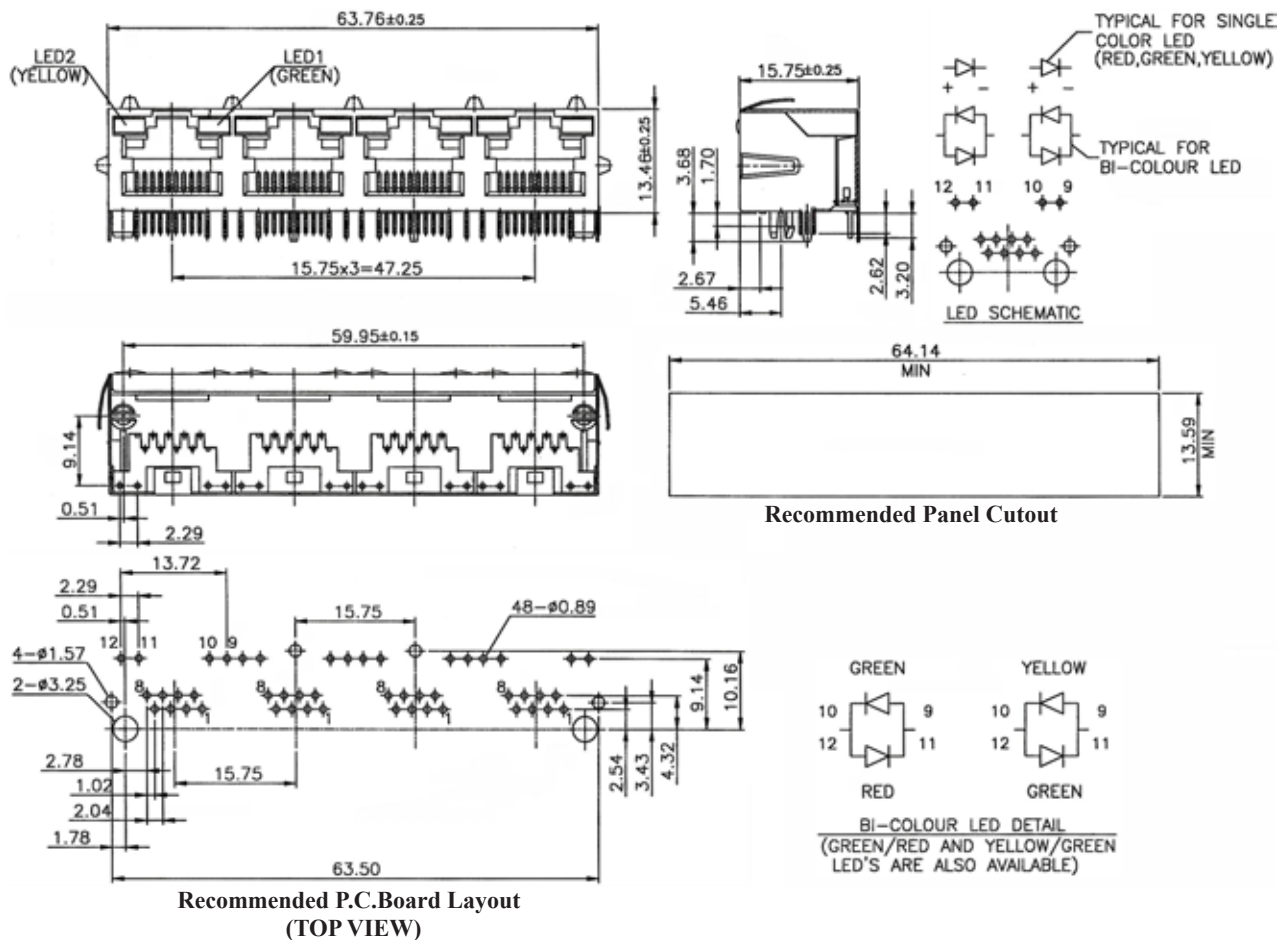
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ2T-88xBx04
T 2 3 4 5

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

NOTE: P/N MJ2T-88xUxx04 for Color in Blue

LED Designation:					
Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

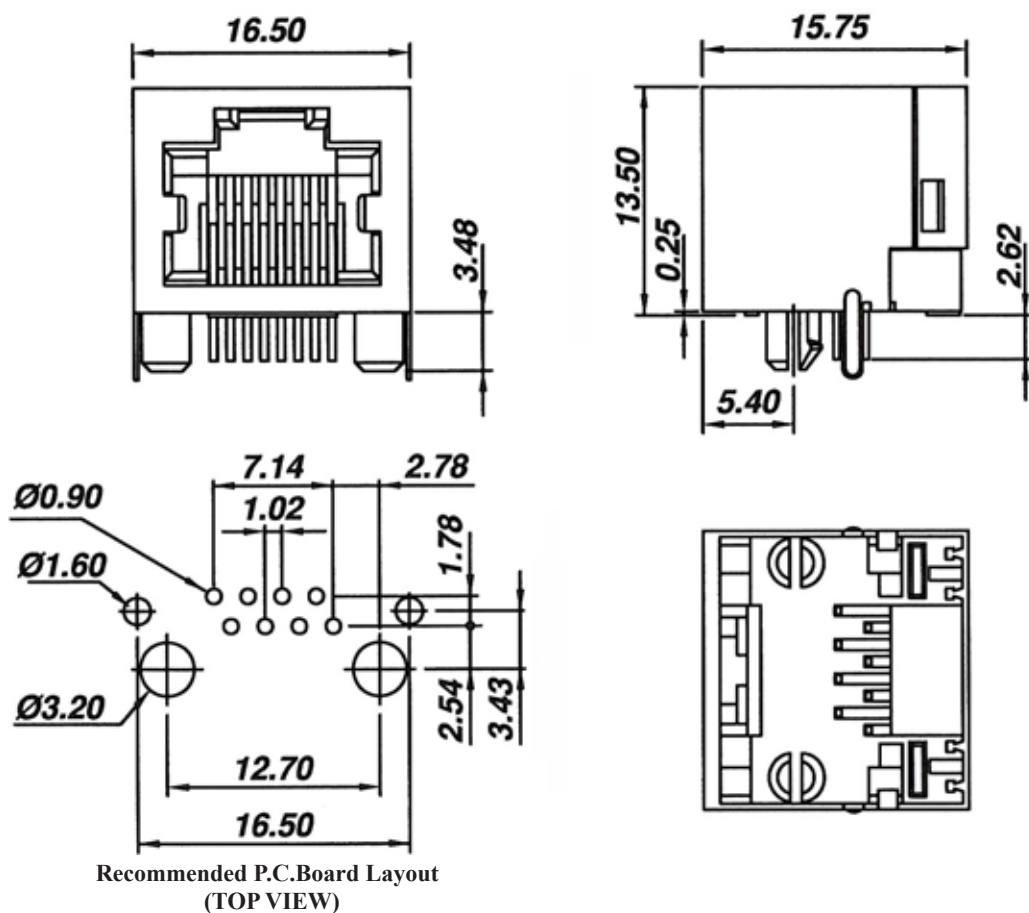
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R G - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

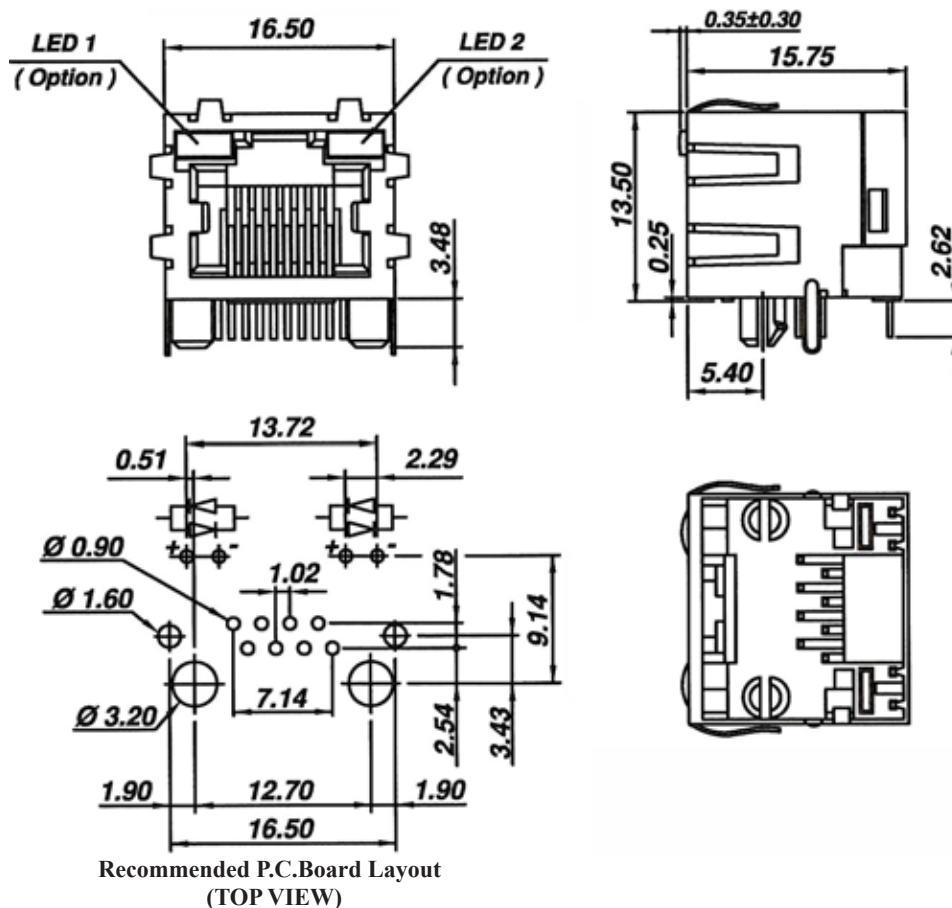
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R L - $\frac{88}{T} \frac{x}{2} \frac{B}{3} \frac{x}{4}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. CODE OF LED1 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

4. CODE OF LED2 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY CAT. 5 UP LTACH MODULAR PCB JACK WITH LED 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

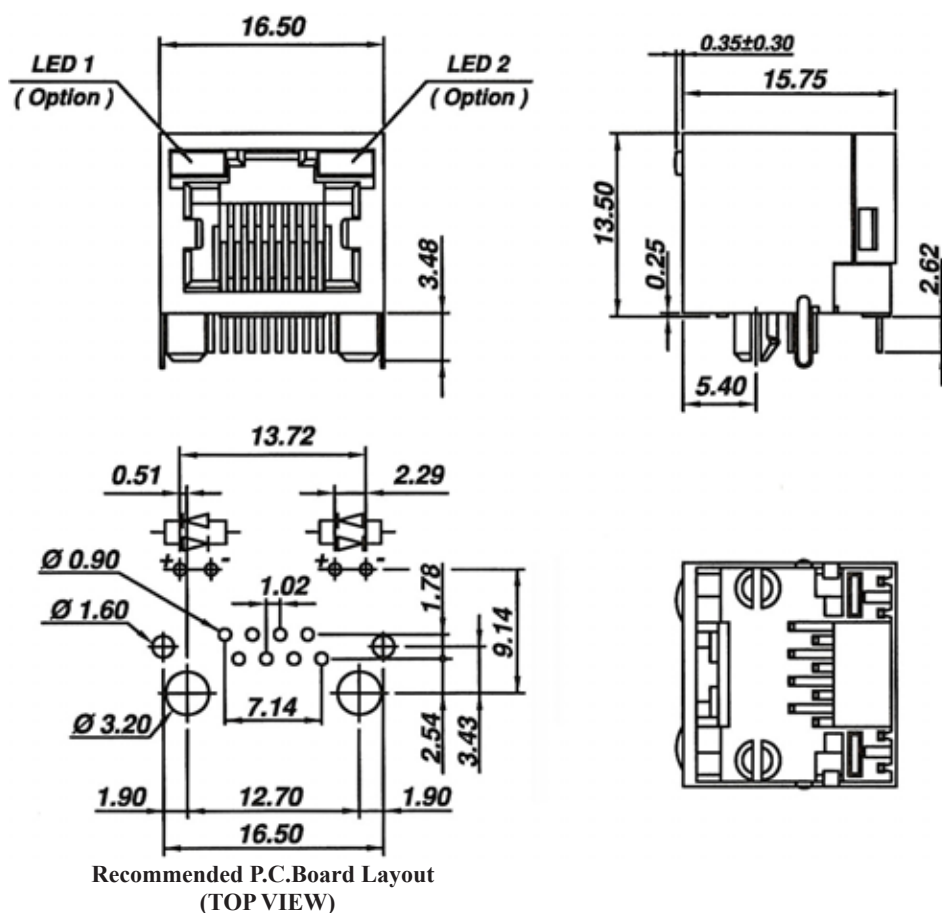
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R K - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. CODE OF LED1 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

4. CODE OF LED2 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.50MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

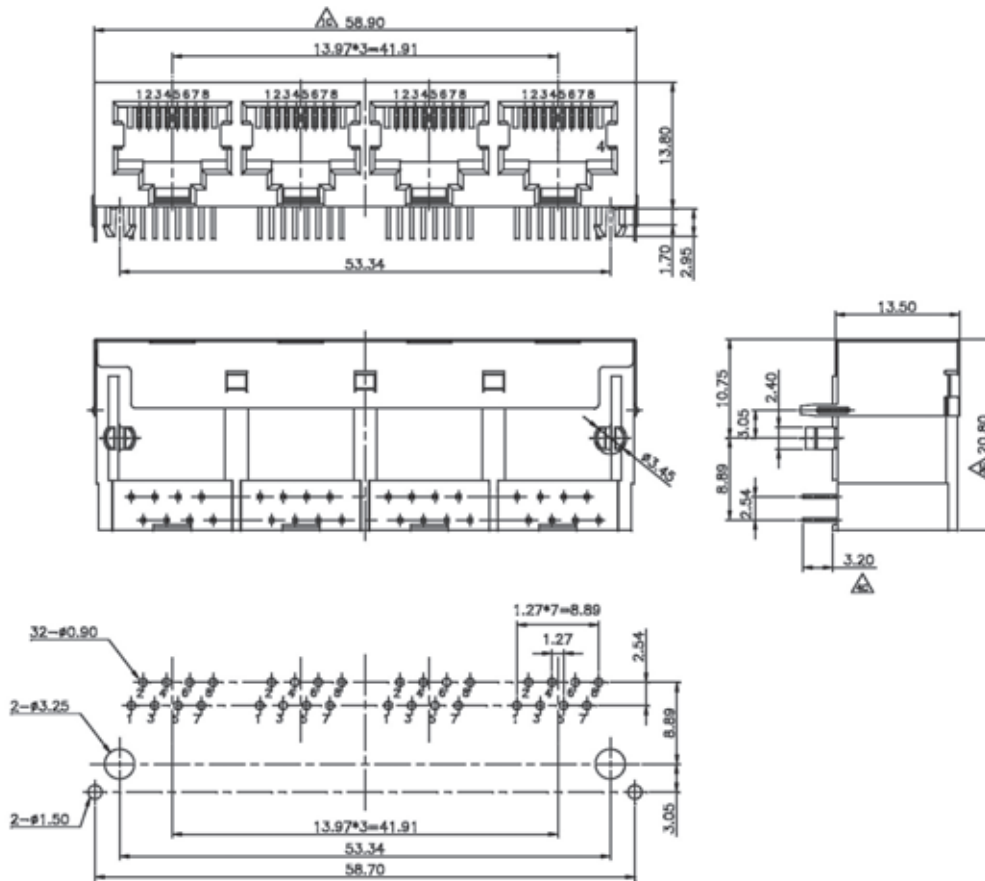
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J T W - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} \frac{4}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 3.05MM SPACING BEFORE PEG

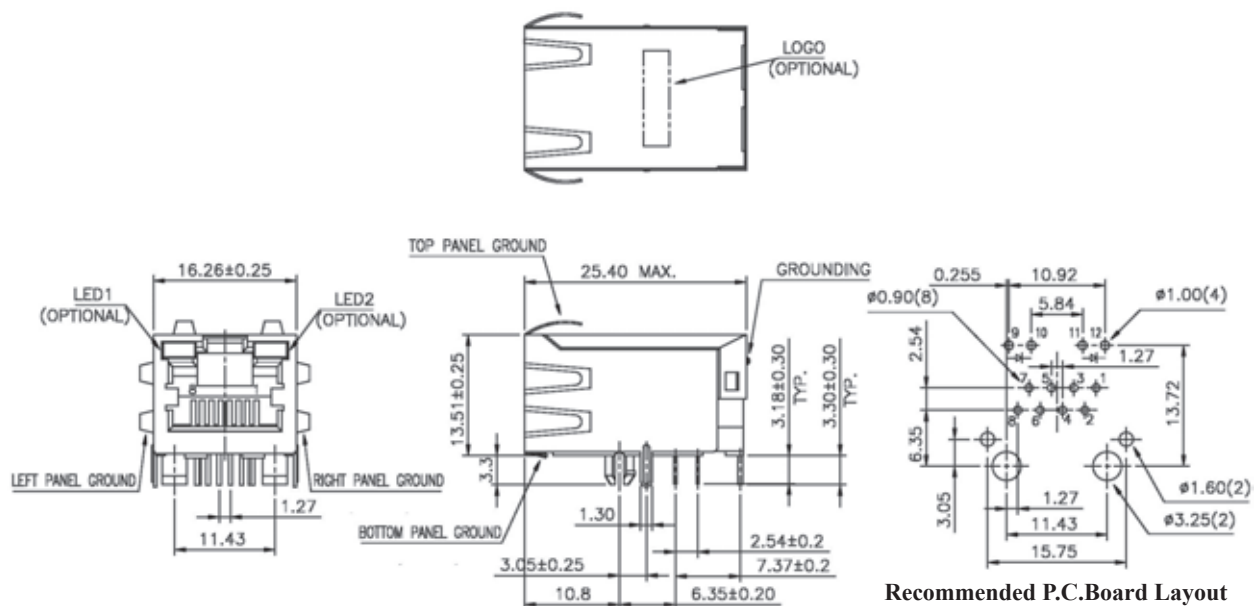
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.51MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{88}{2}$ $\frac{X}{3}$ $\frac{B}{4}$ $\frac{XX}{5}$

- MODULAR JACK TYPE:
 "WA" NO PANEL GROUNDS
 "WB" TOP PANEL GROUNDS
 "WC" SIDE PANEL GROUNDS
 "WD" TOP & SIDE PANEL GROUNDS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- COLORS OF LED:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

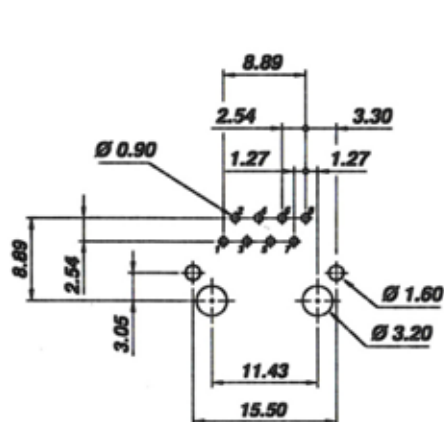
Color: Black

Spring Wire: Phosphor Bronze

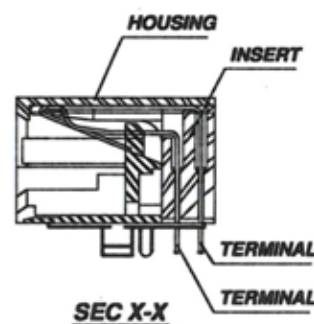
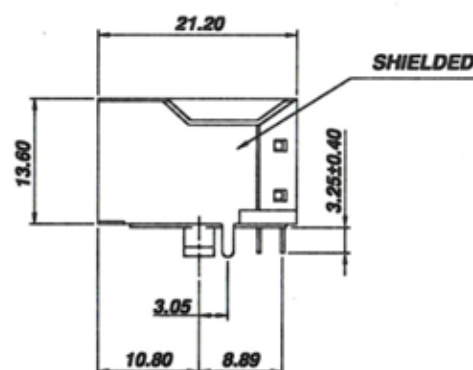
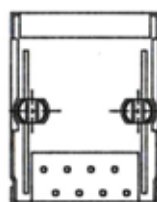
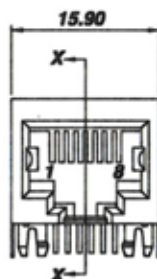
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)



ORDERING INFORMATION:

P/N M J S N - $\frac{88}{12} \times B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

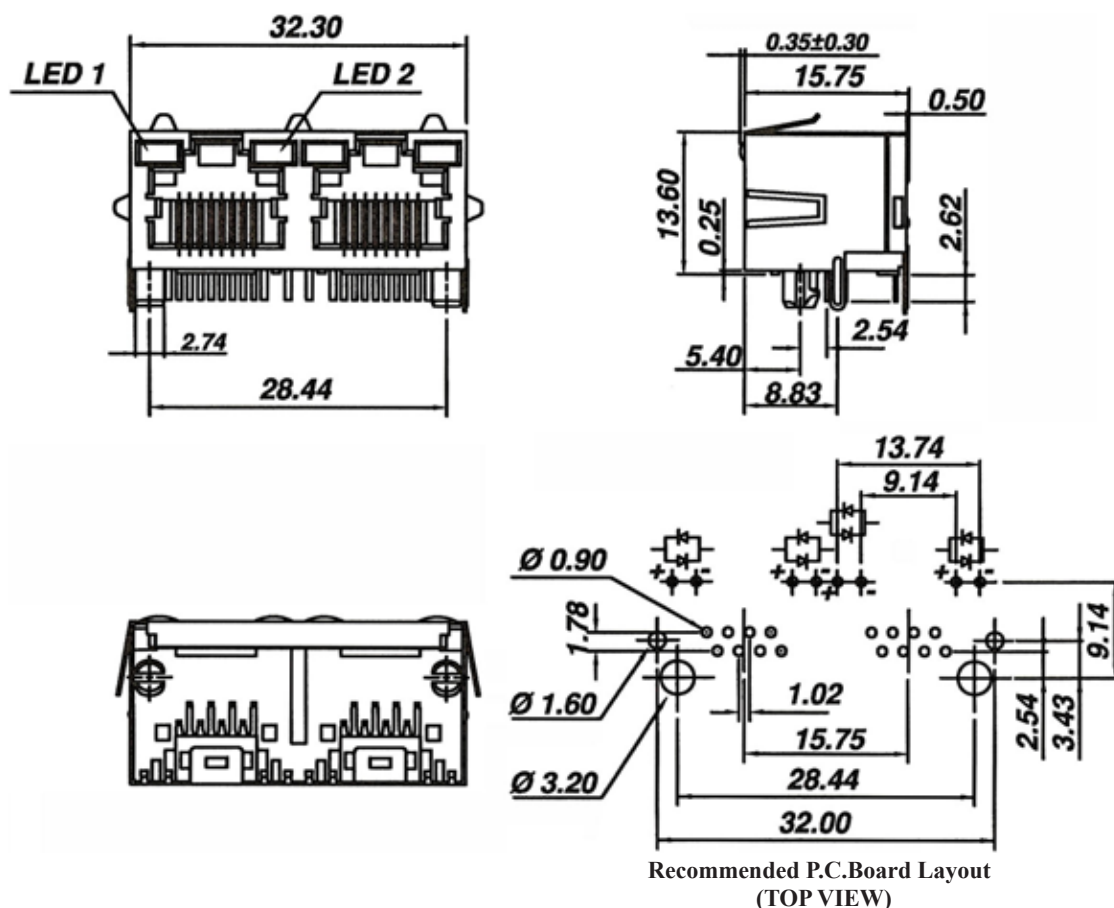
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R S - $\frac{88}{12} \times \frac{B}{34} \times \frac{02}{5}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

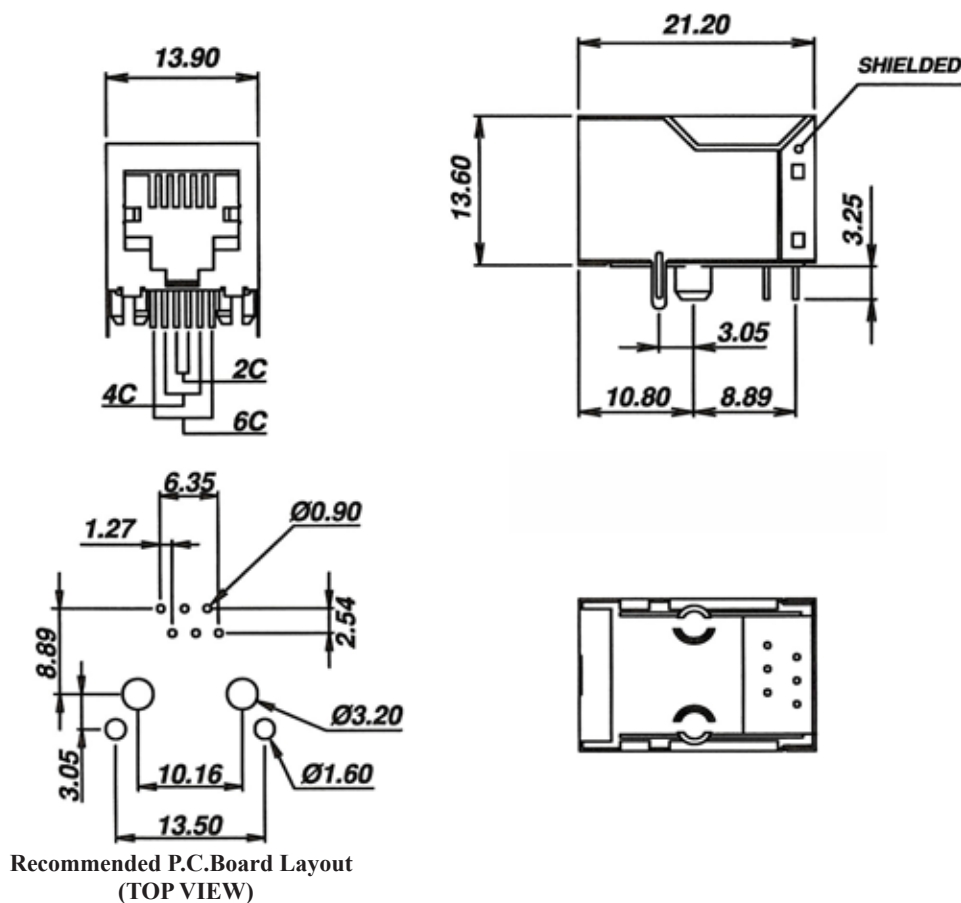
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRA - $\frac{xx}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRAHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

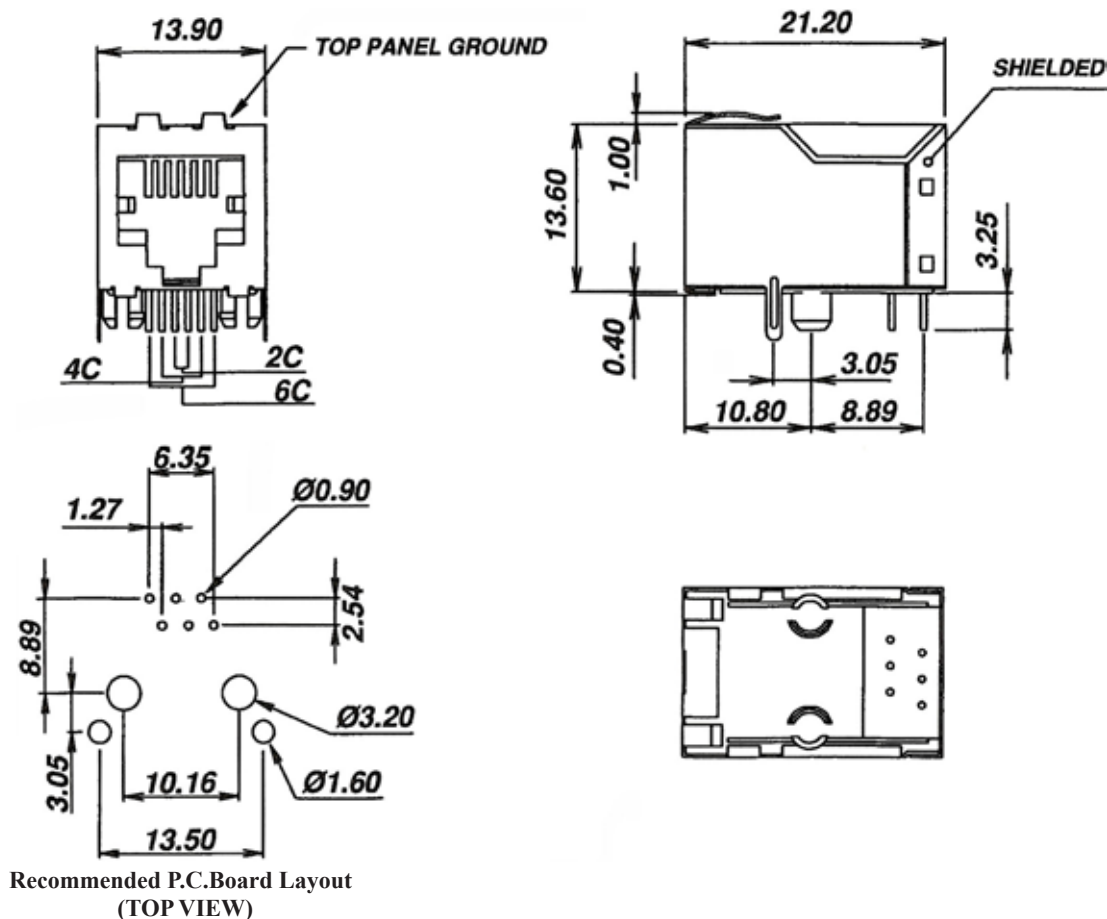
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R B - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRBHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

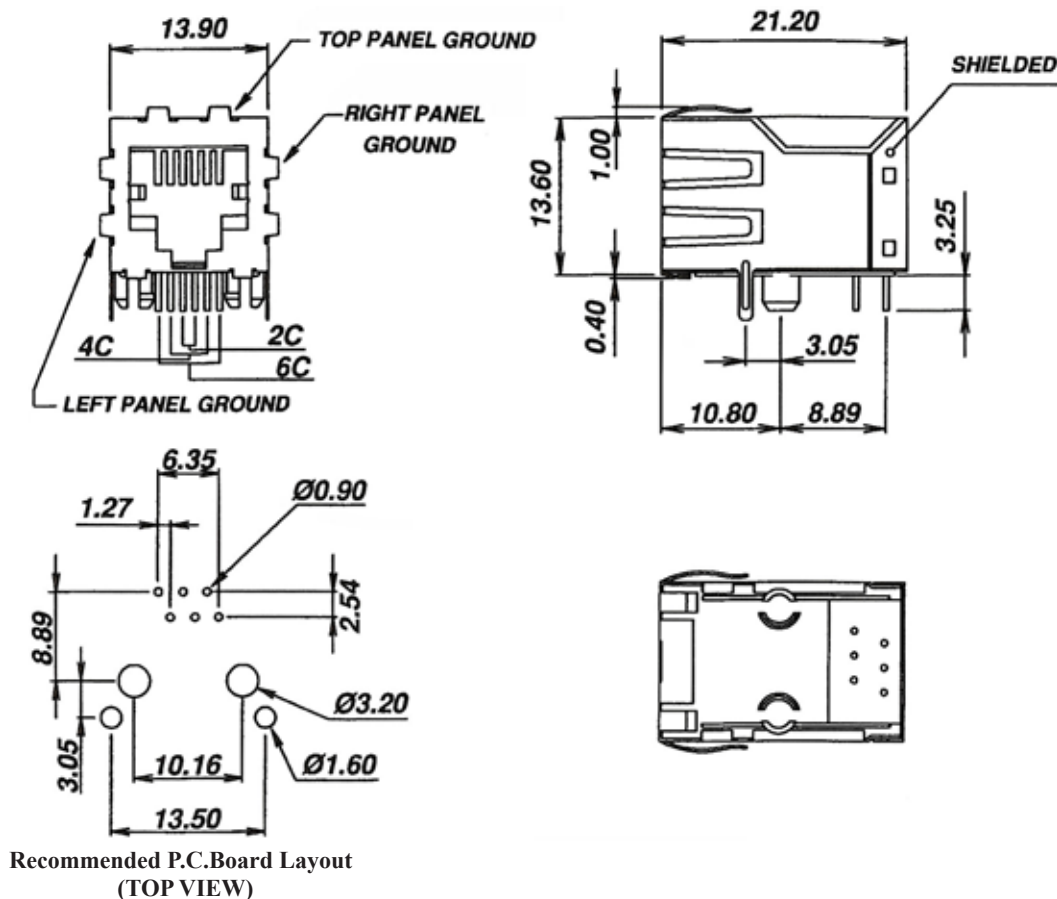
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRC - $\frac{xx}{T} \frac{xB}{2}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRCHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

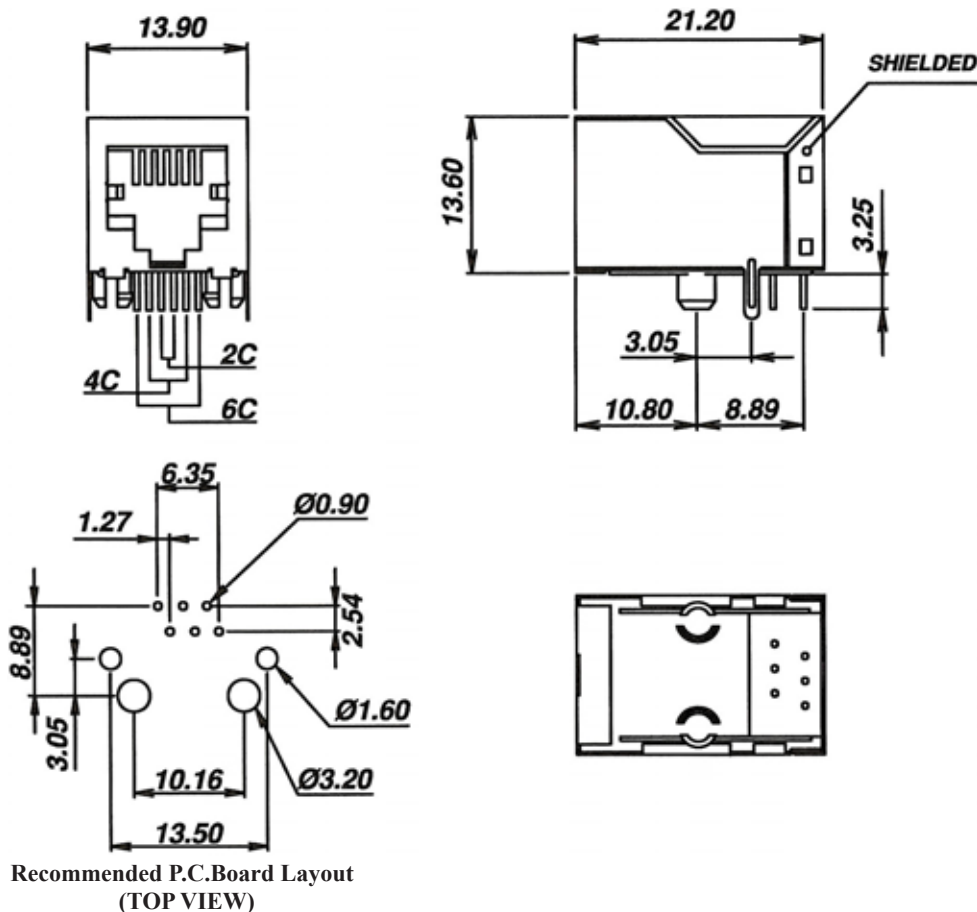
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R D - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRDHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

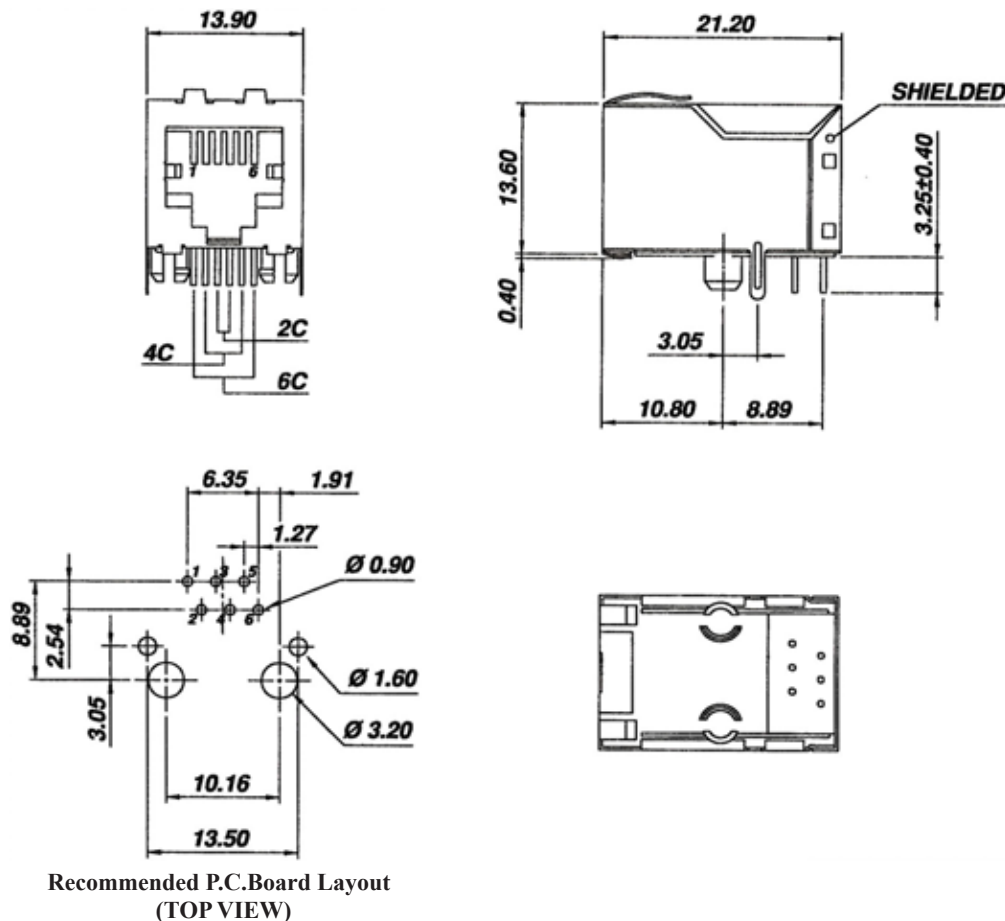
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRE - $\frac{xxxB}{T2}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJREHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

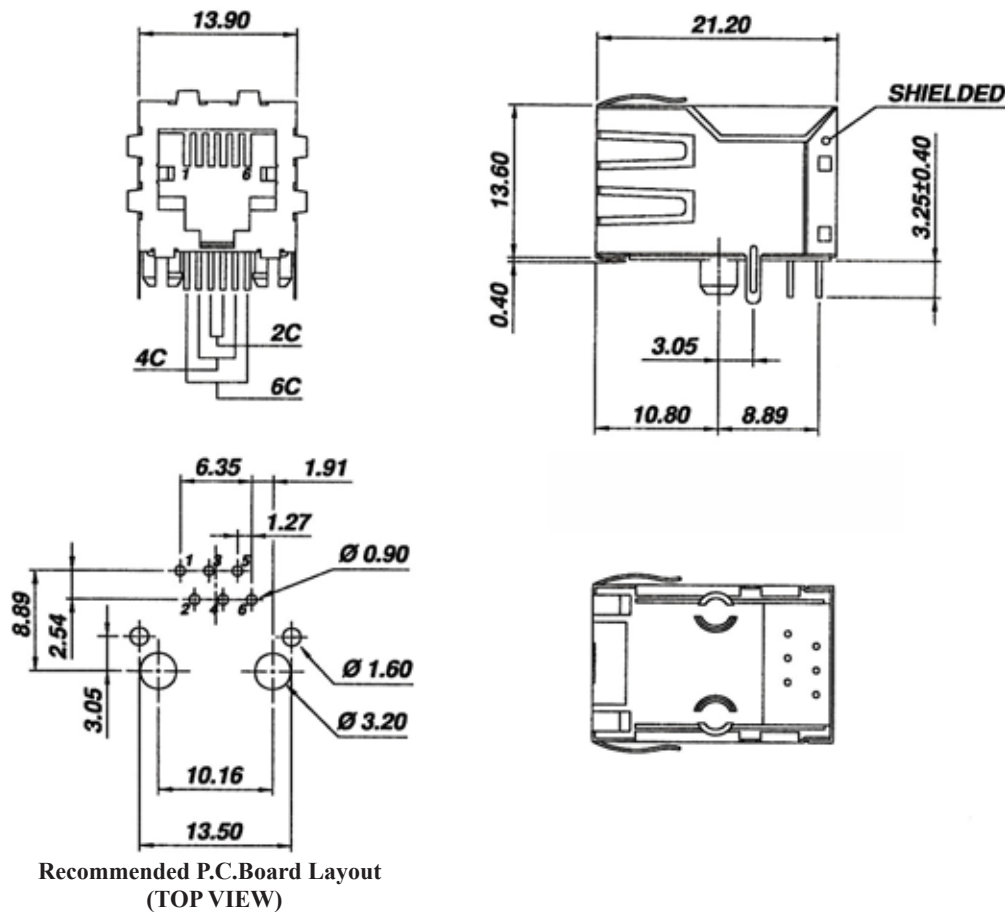
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R F - $\frac{x \times x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRFHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

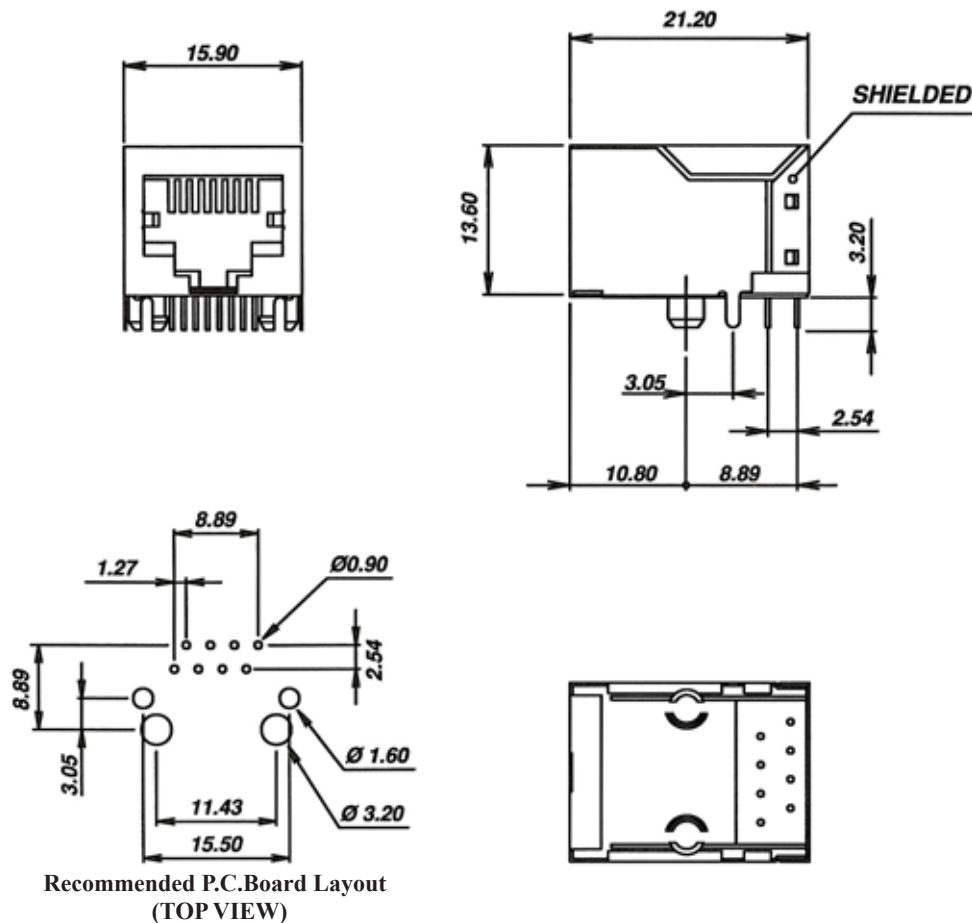
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S C - $\frac{88}{T} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

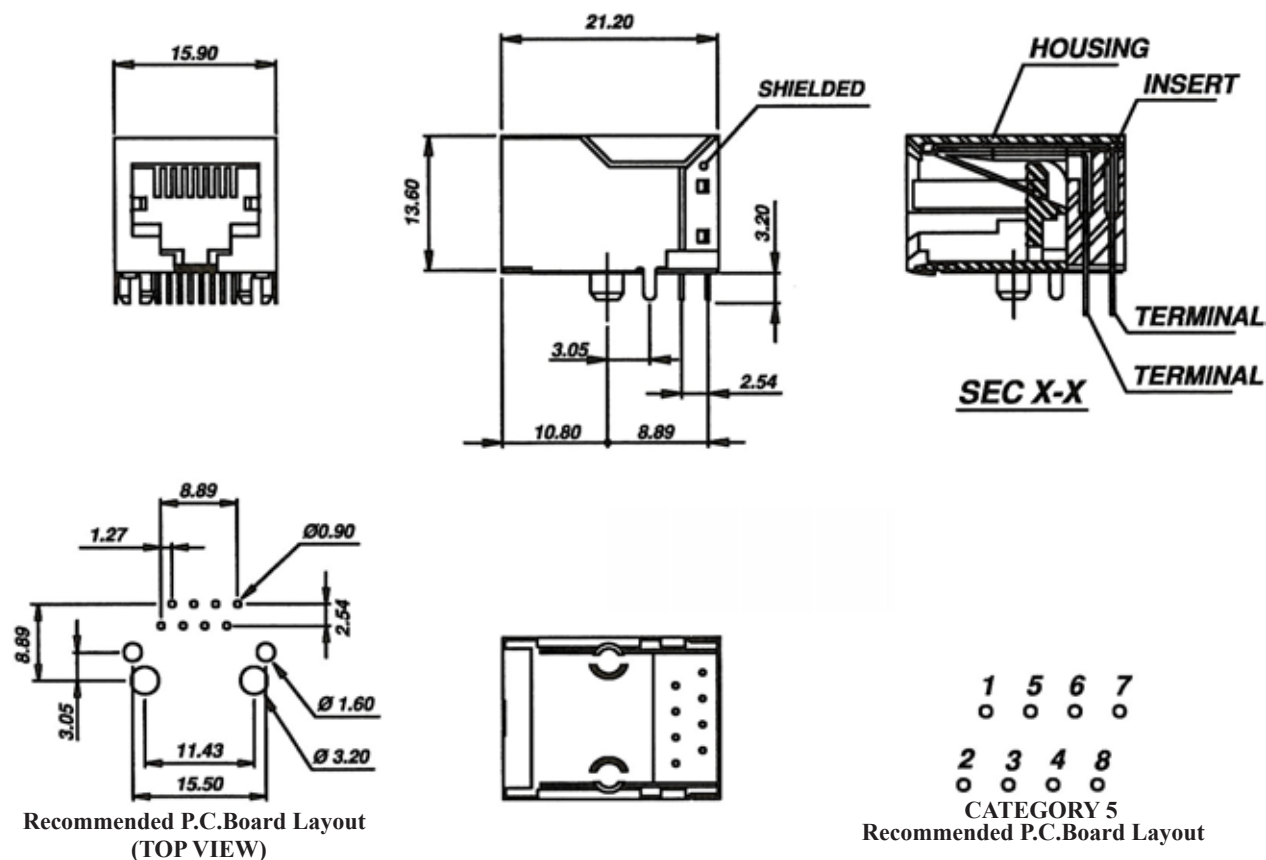
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J S D - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

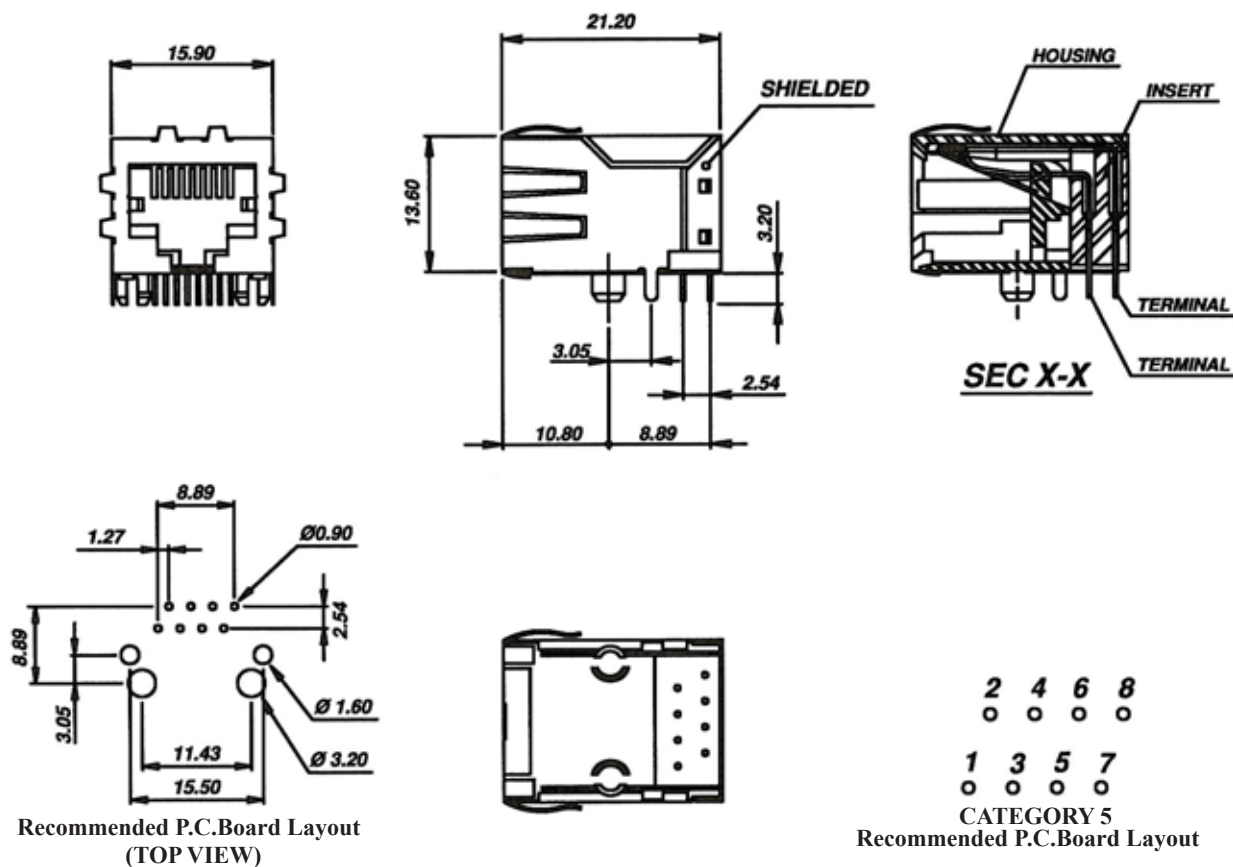
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J S E - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

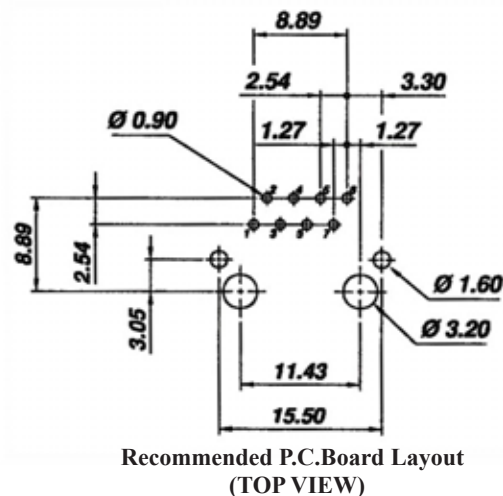
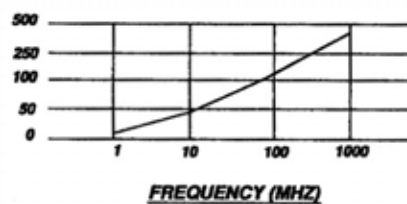
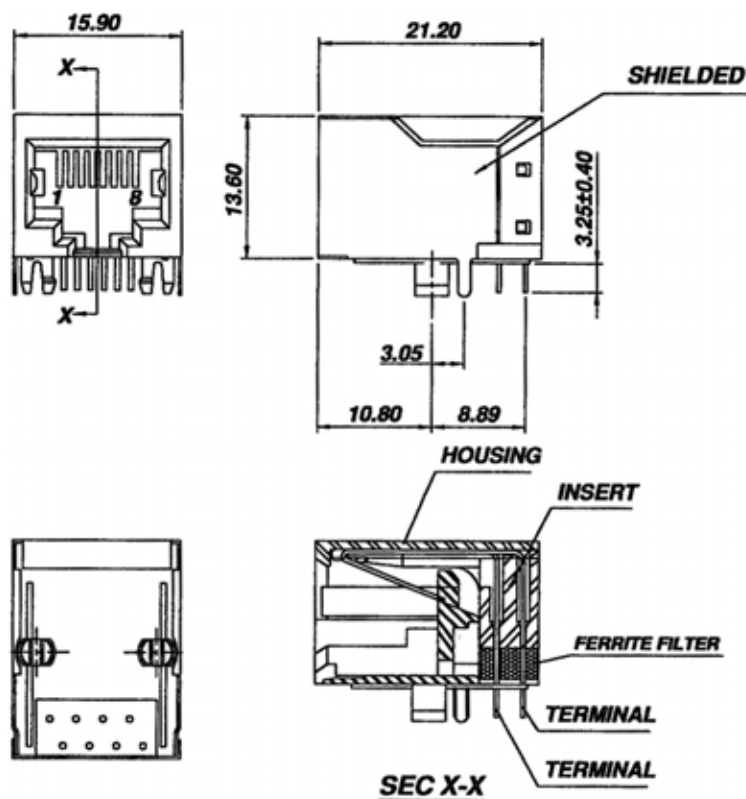
SIDE ENTRY MODULAR PCB JACK WITH FERRITE FILTER 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJSF- $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJSFHT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.05MM SPACING BEHIND PEG

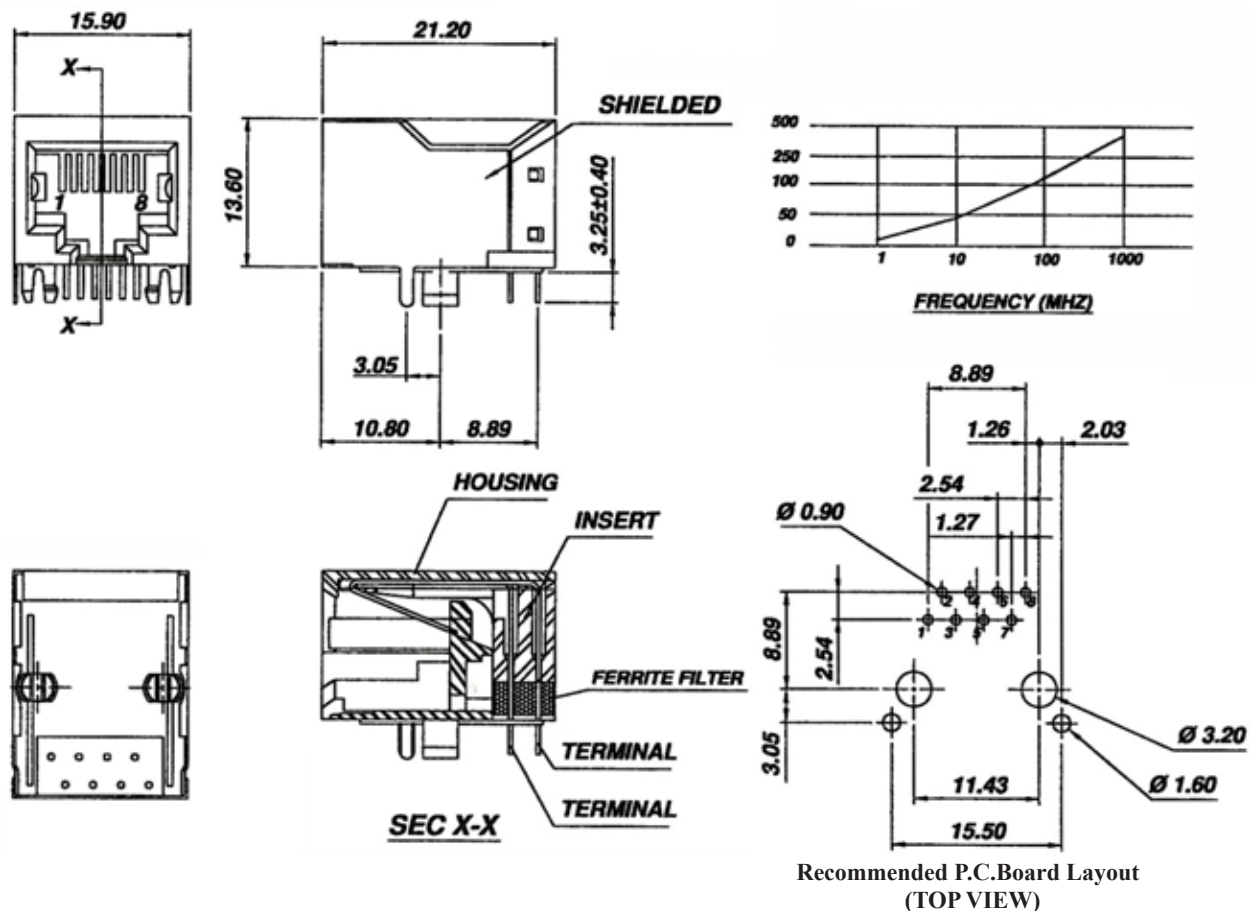
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ76- $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ76HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.05MM SPACING BEFORE PEG

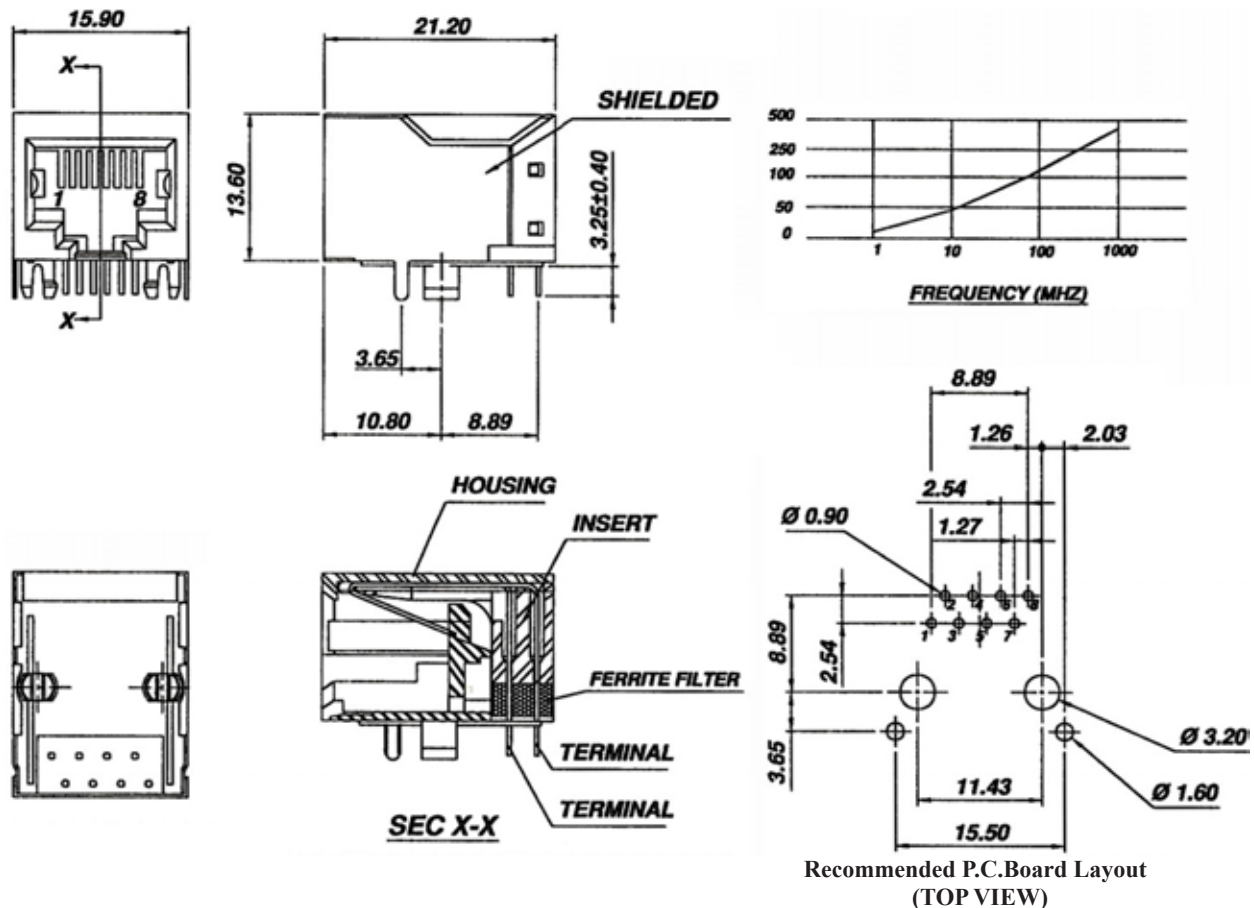
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ77- $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ77HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.65MM SPACING BEFORE PEG

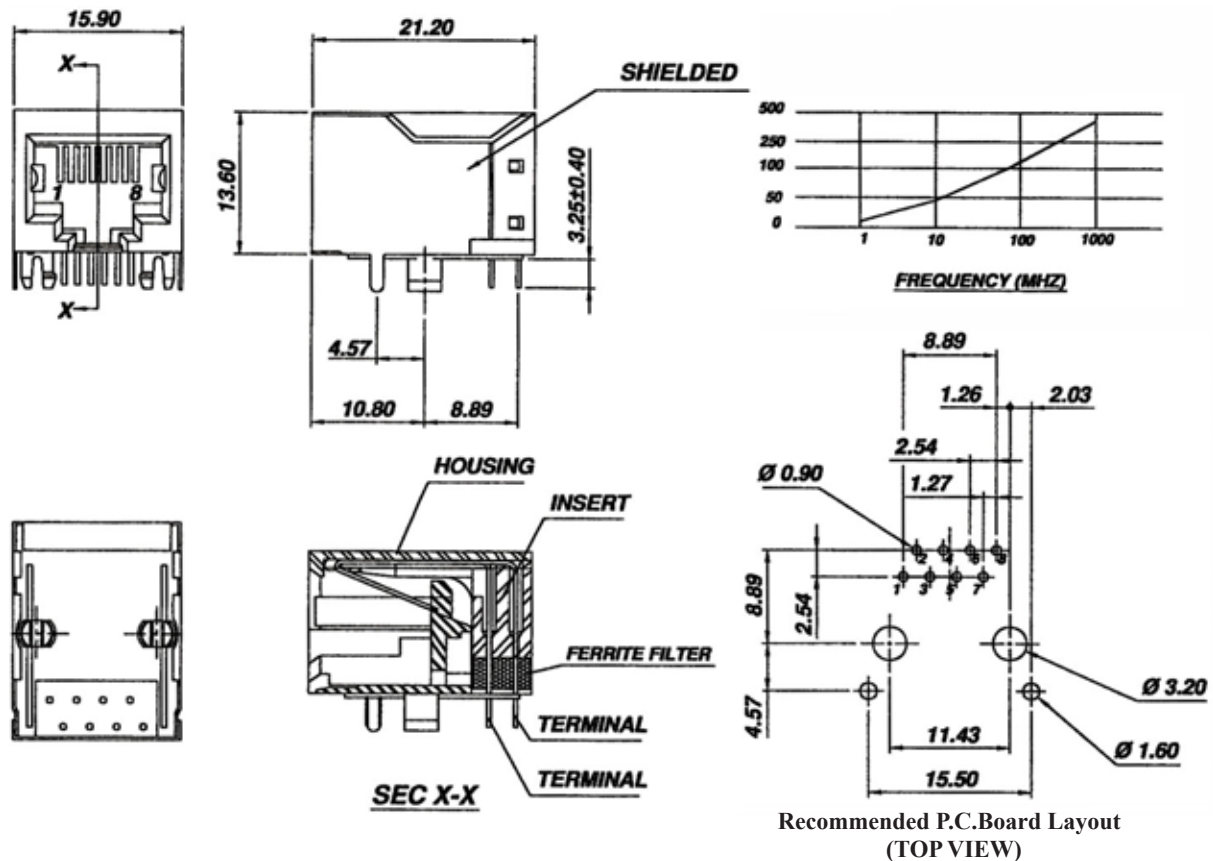
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ53- $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ53HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

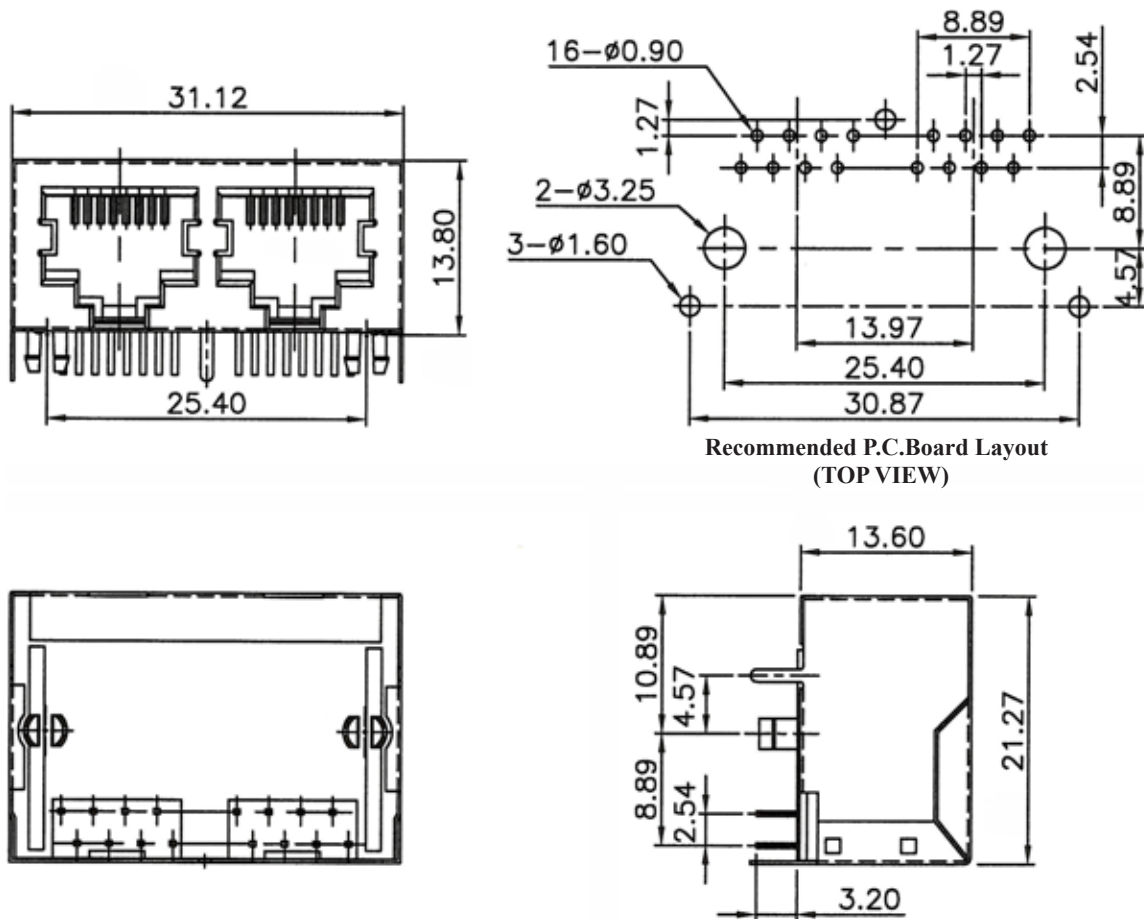
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 8 E - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 3-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

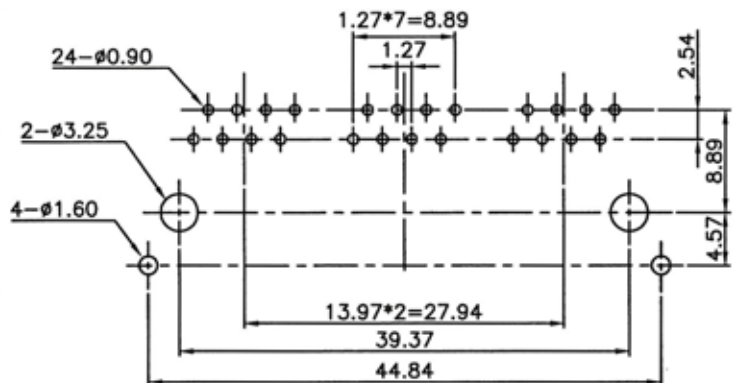
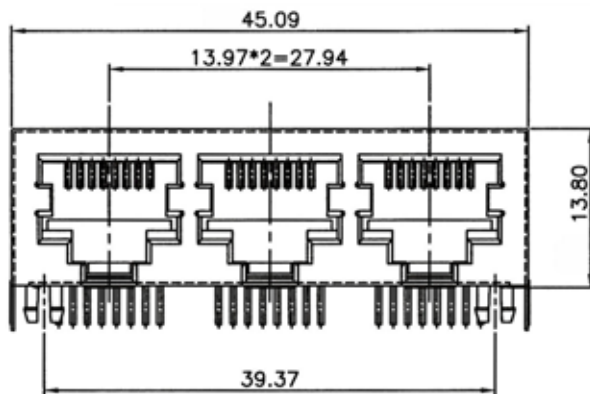
Color: Black

Spring Wire: Phosphor Bronze

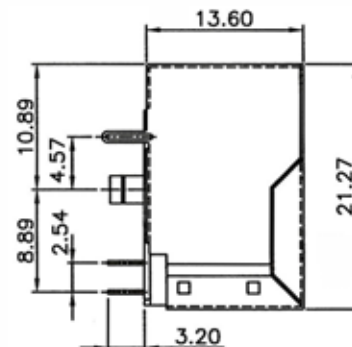
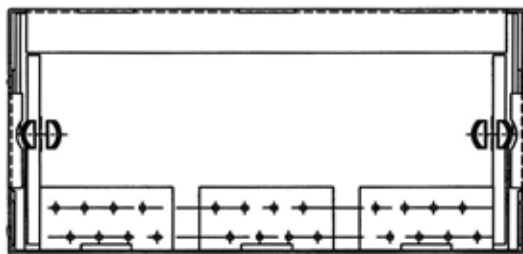
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 8 E - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B $\frac{0}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

03

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

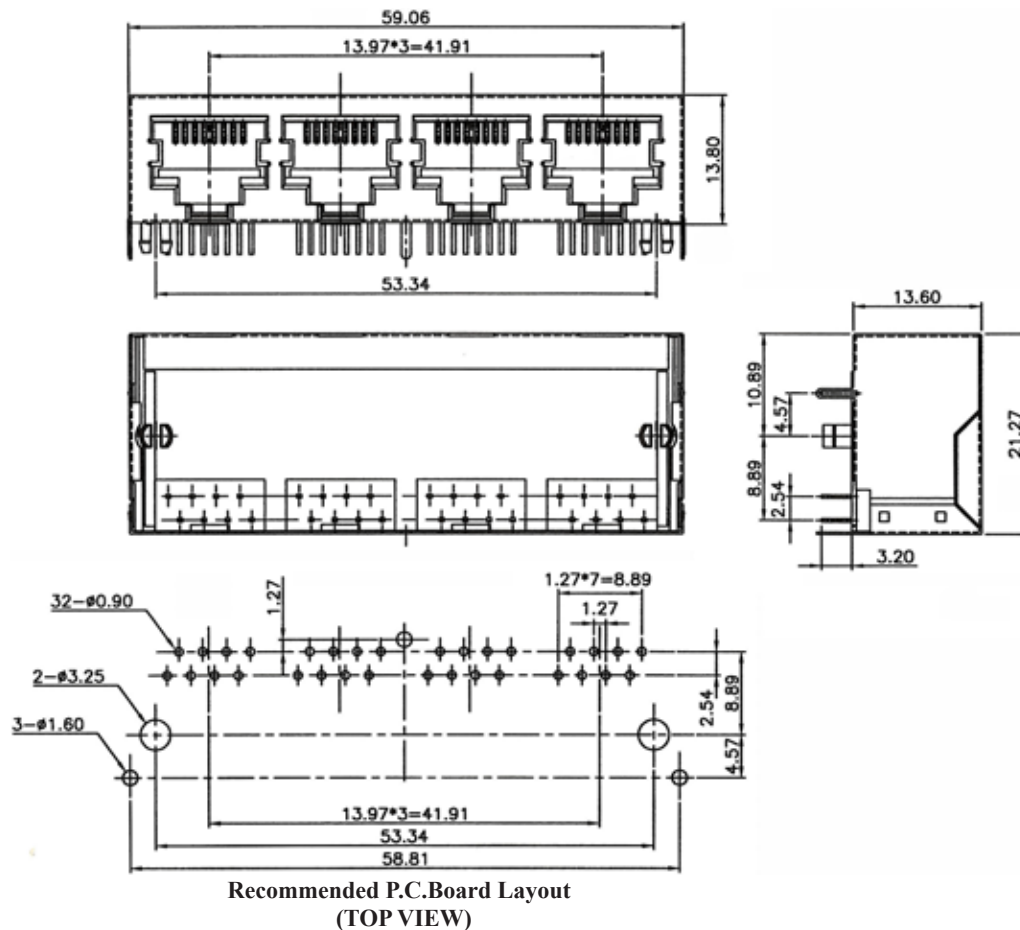
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 8 E - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B $\frac{0}{3}$ $\frac{4}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

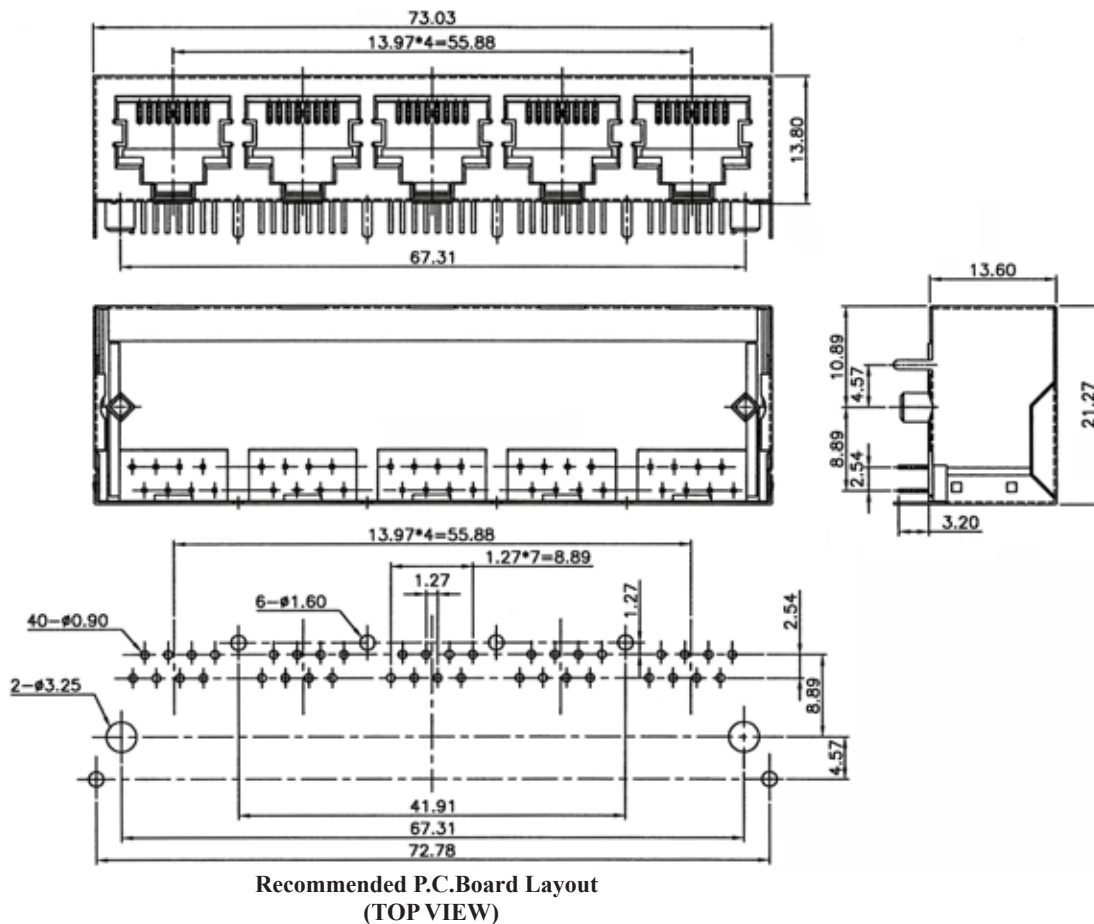
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 8 E - $\frac{88}{1} \times \frac{B}{2} \frac{05}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

05

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

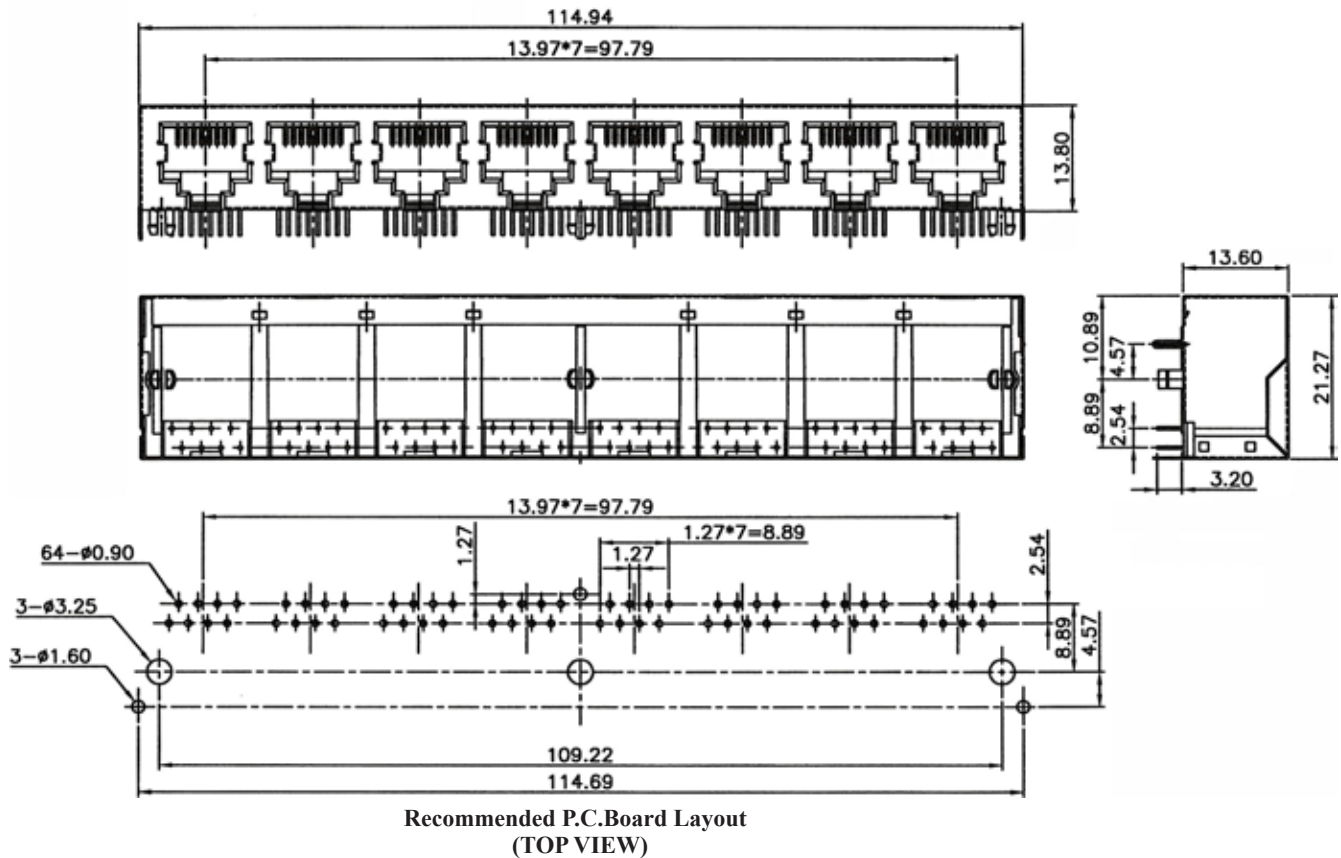
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 8 E - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

NOTE: 4.57MM SPACING BEFORE PEG

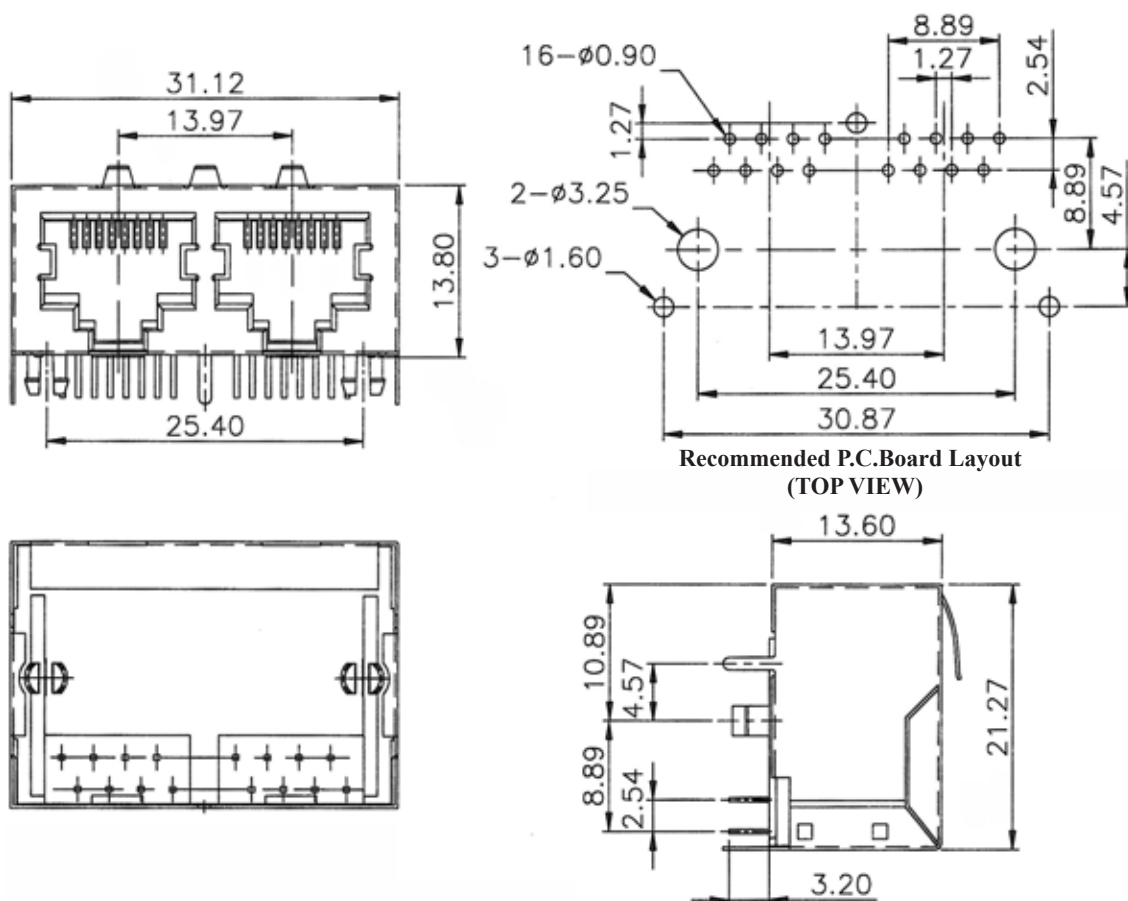
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{23} B \frac{02}{4}$

- CATEGORY TYPE:
"1H" CAT. 3
"Y1" CAT. 5
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- NO. OF PORTS:
02

NOTE: 4.57MM SPACING BEFORE PEG

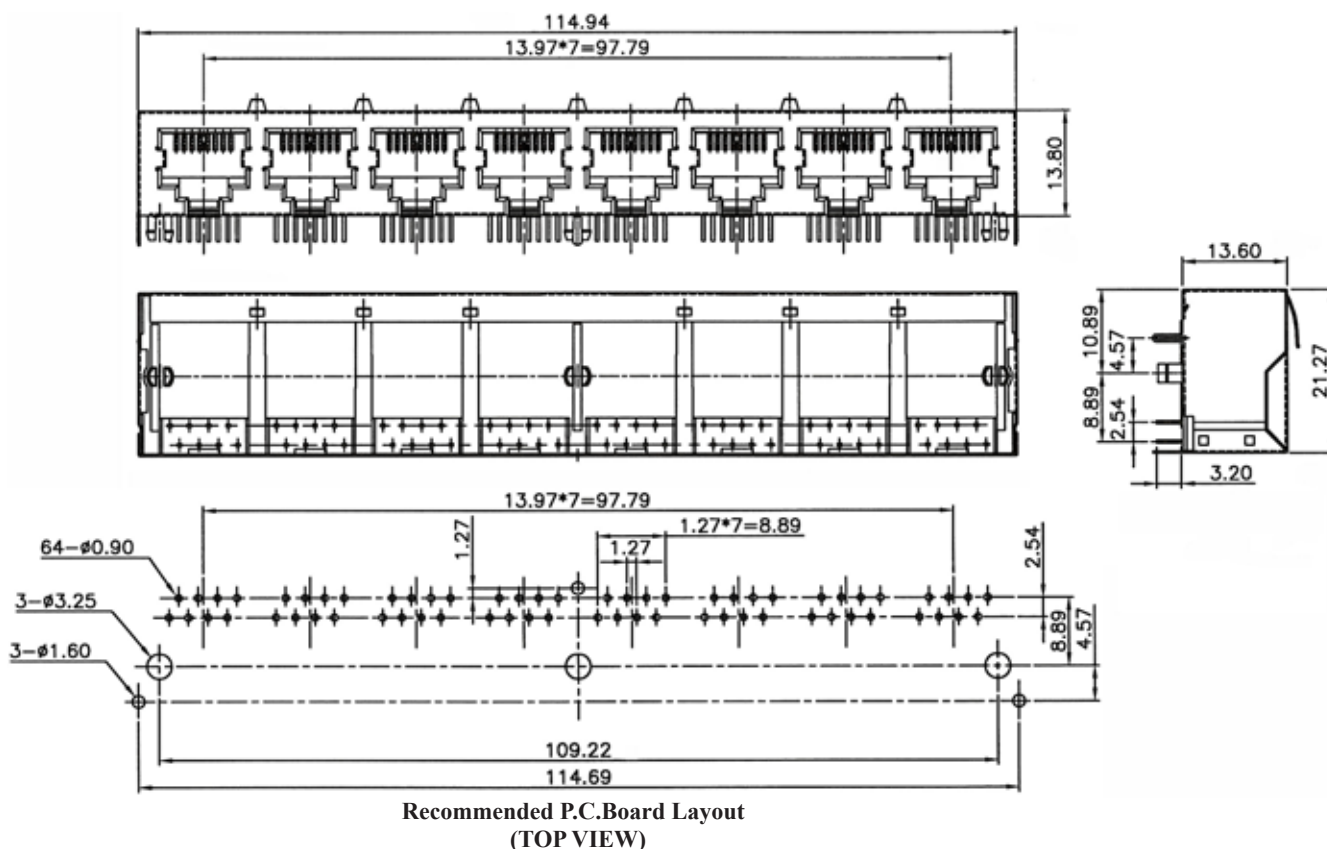
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B \frac{08}{4}$

1. CATEGORY TYPE:

"1H" CAT. 3
 "Y1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

4. NO. OF PORTS:

08

NOTE: 4.57MM SPACING BEFORE PEG

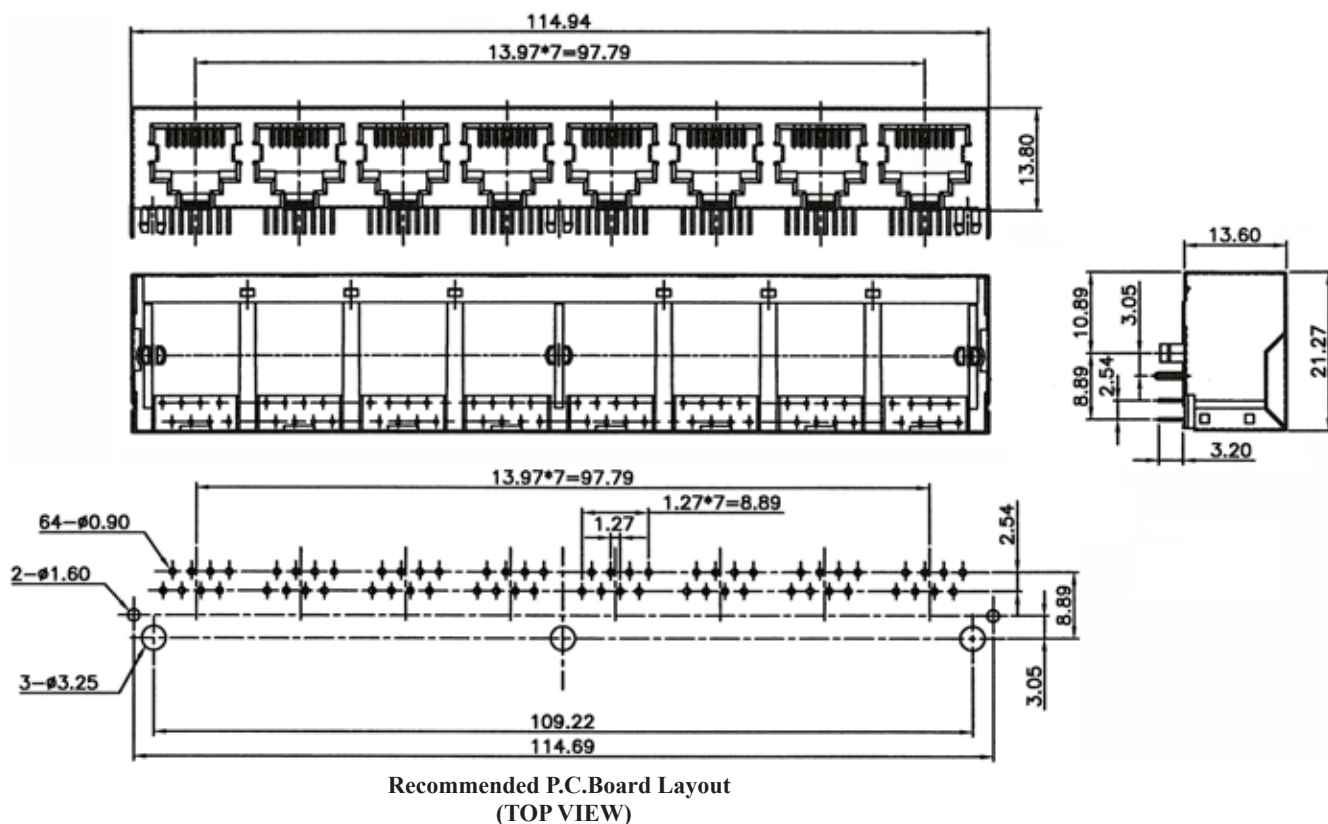
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 L - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE: 3.05MM SPACING BEHIND PEG

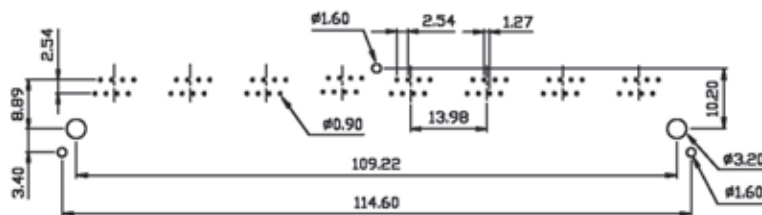
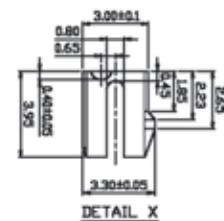
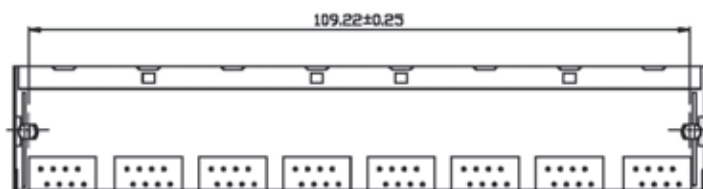
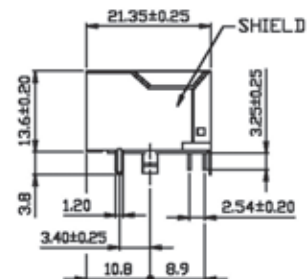
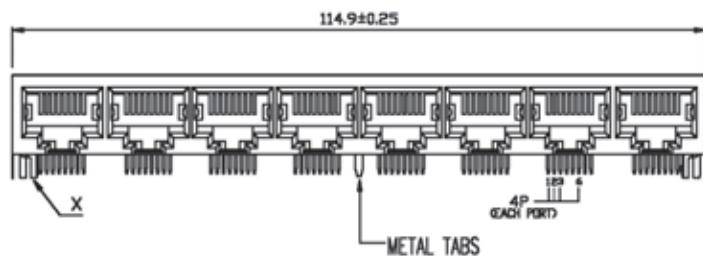
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N R - 88 x B 08
1 2 3 4 5

1. MODULAR JACK TYPE:
"NR" 3.40MM SPACING BEFORE PEG
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. NO. OF PORTS:
08

SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

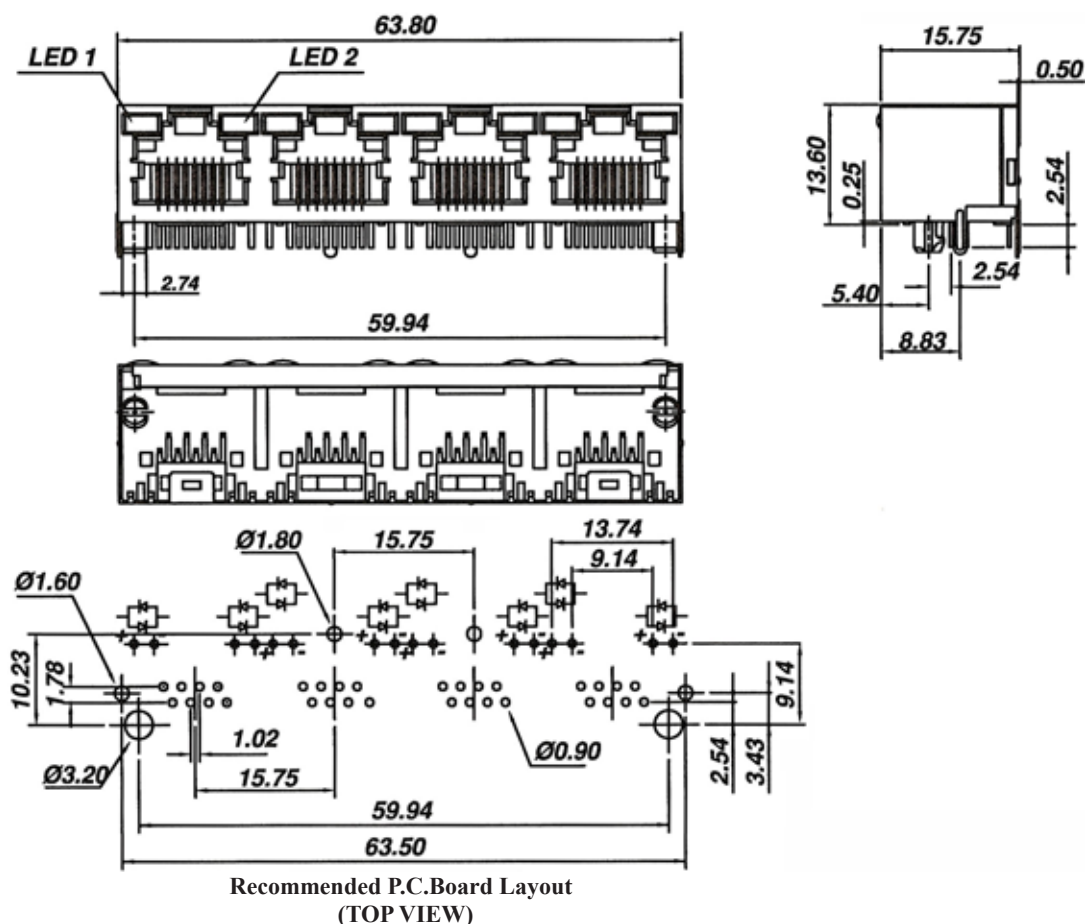
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R R - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4} \frac{04}{5}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. CODE OF LED1 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

4. CODE OF LED2 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

5. NO. OF PORTS:

04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

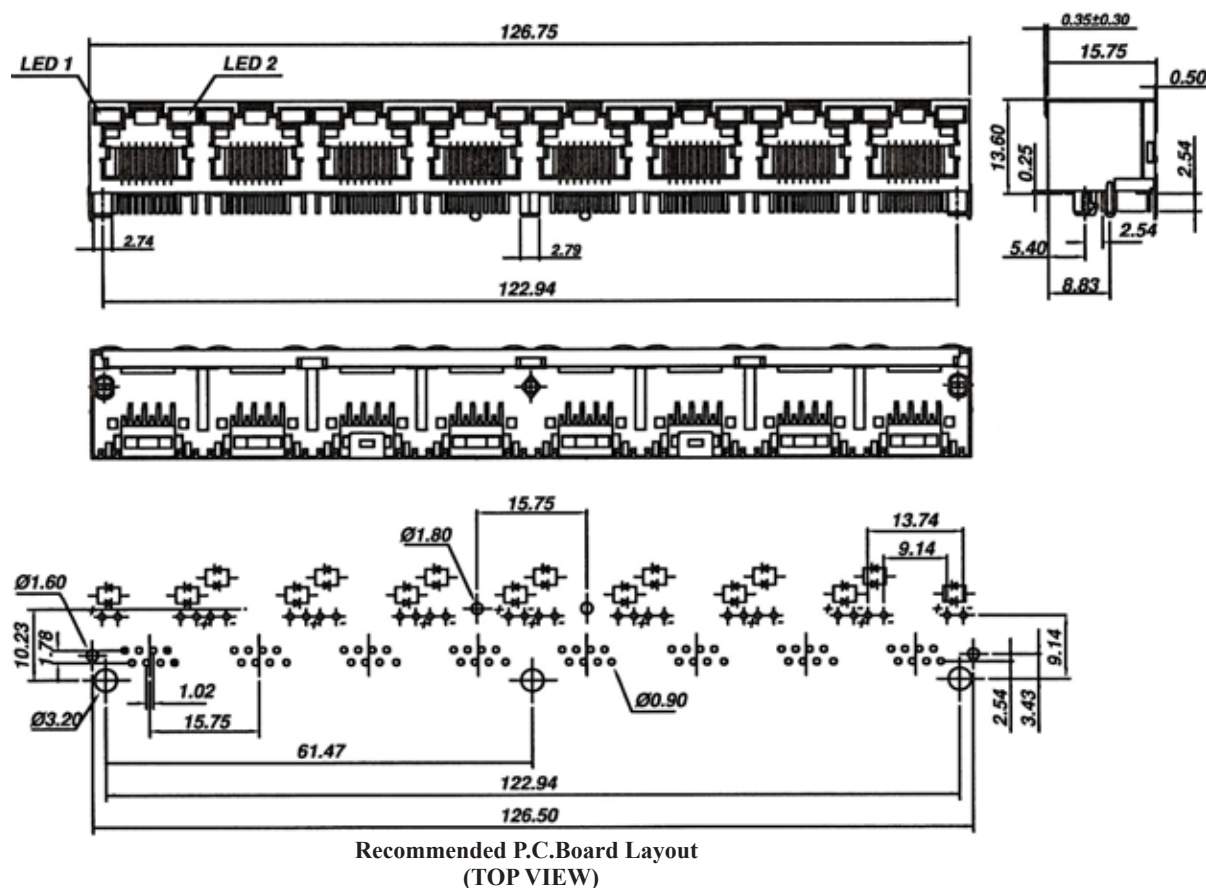
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R R - $\frac{88}{1} \times \frac{B}{2} \times \frac{3}{4} \times \frac{08}{5}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
08

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

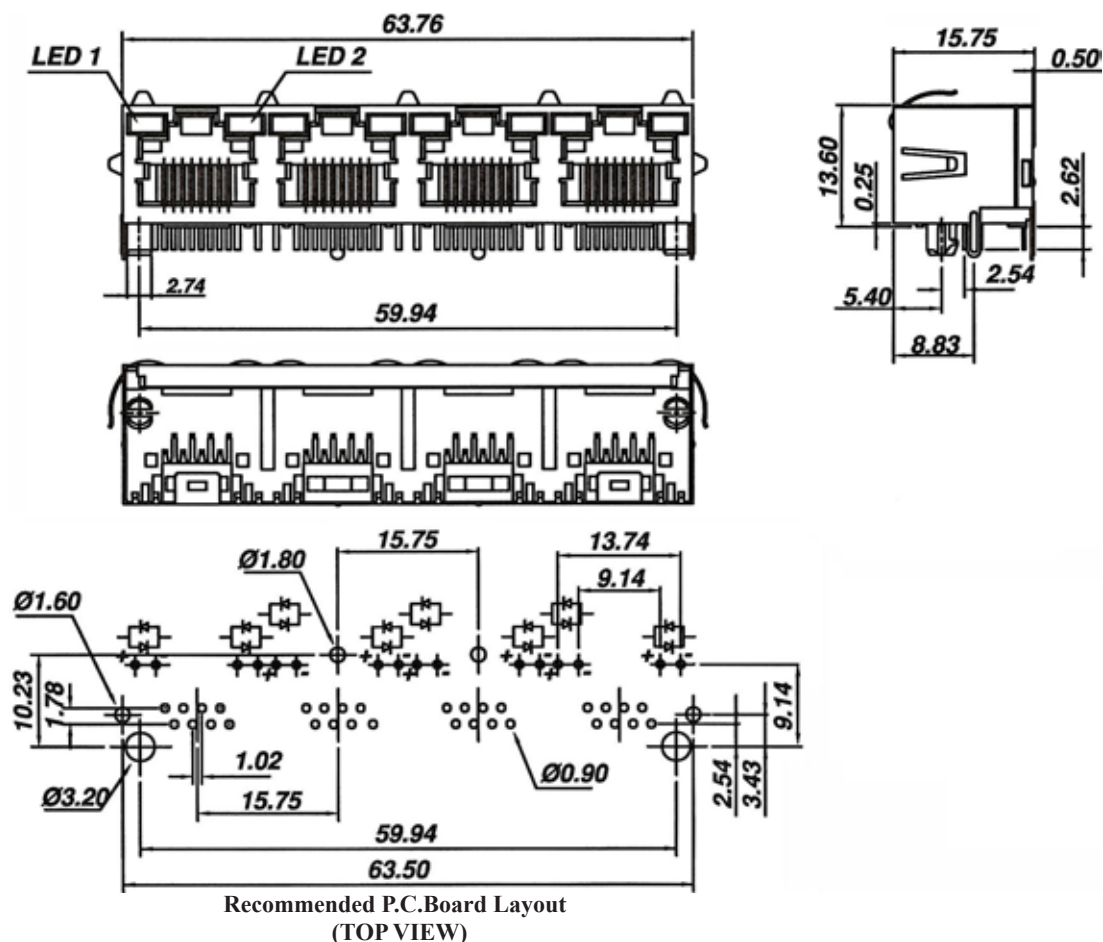
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R S - $\frac{88}{12} \frac{B}{34} \frac{04}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

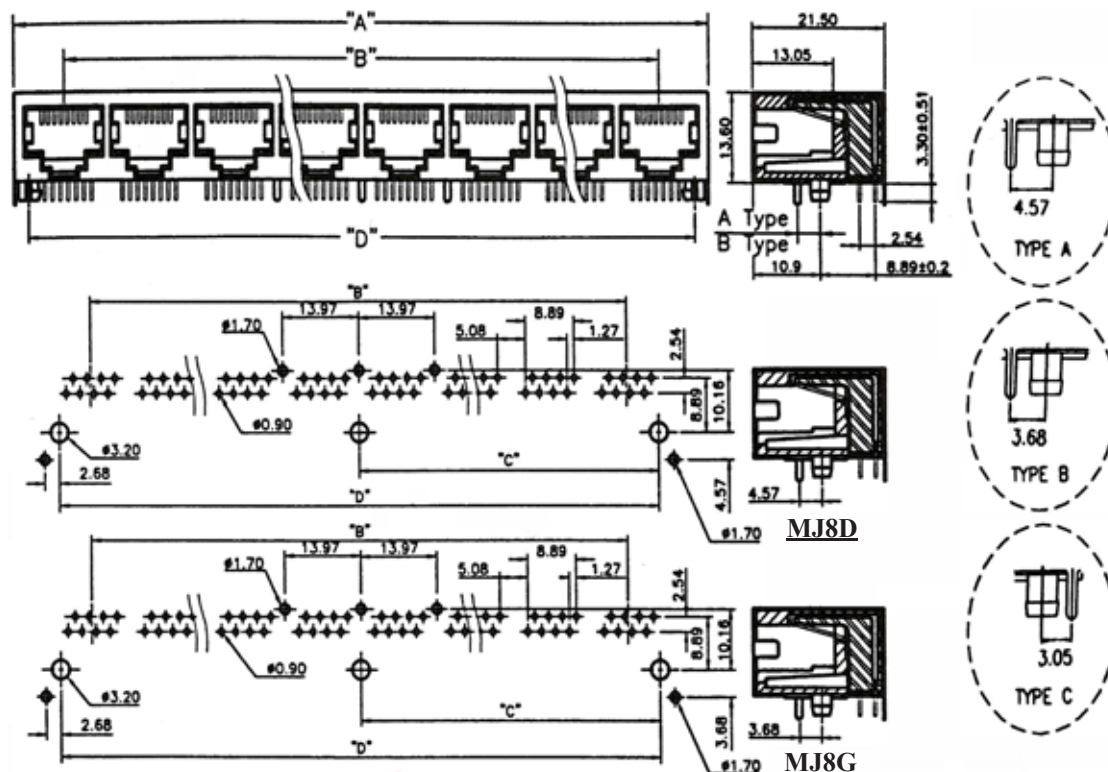
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



No. of Ports	DIM"A"±0.25	DIM"B"±0.20	DIM"C"±0.10	DIM"D"±0.15
02	31.24	13.97	----	25.40
04	59.18	41.91	26.67	53.34
06	87.12	69.85	40.64	81.28
08	115.06	97.79	54.61	109.22

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{88}{23}$ B $\frac{XX}{4}$

1. TYPE OF PIN SPACING:
 "8D" TYPE A
 "8G" TYPE B
 "8X" TYPE C
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 02, 04, 05, 06, 08

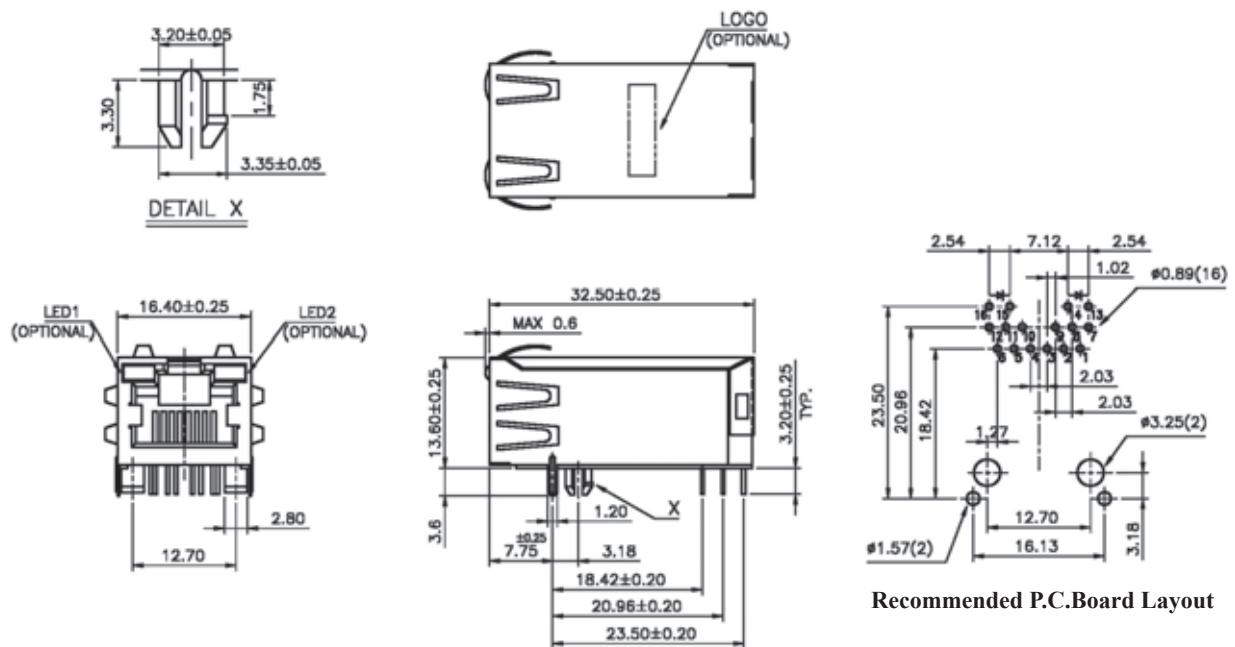
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J H A - $\frac{88}{1} \frac{x}{2} \frac{B}{3} \frac{x}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"B" BLACK

4. COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

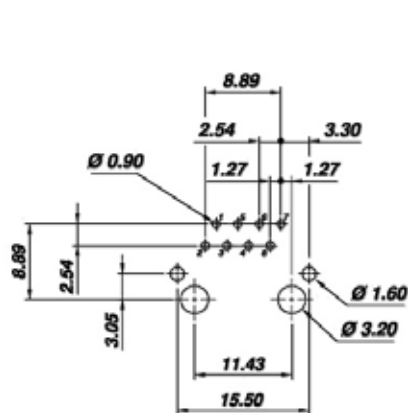
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

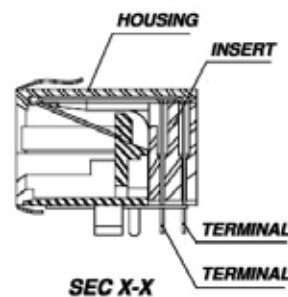
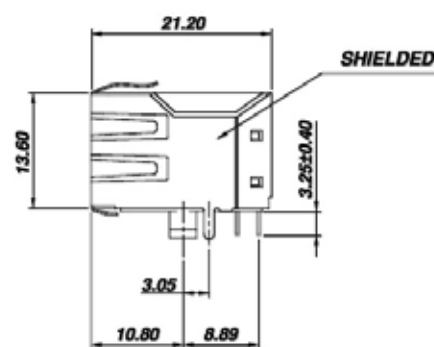
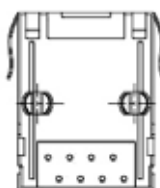
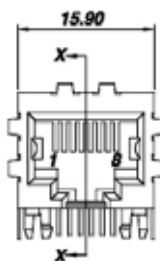
*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

1 5 6 7
2 3 4 8

**CATEGORY 5
PCB LAYOUT**



ORDERING INFORMATION:

P/N M J S M - 88 x B
1 2

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

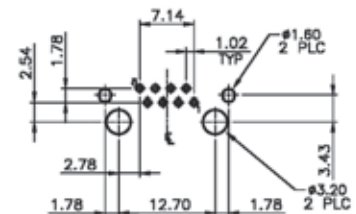
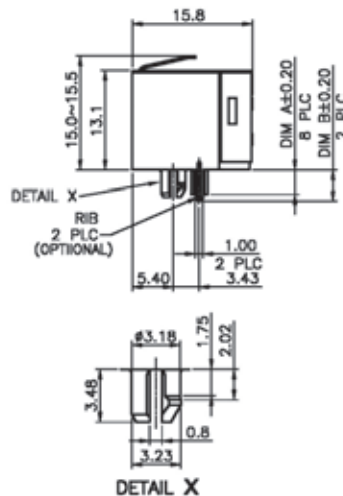
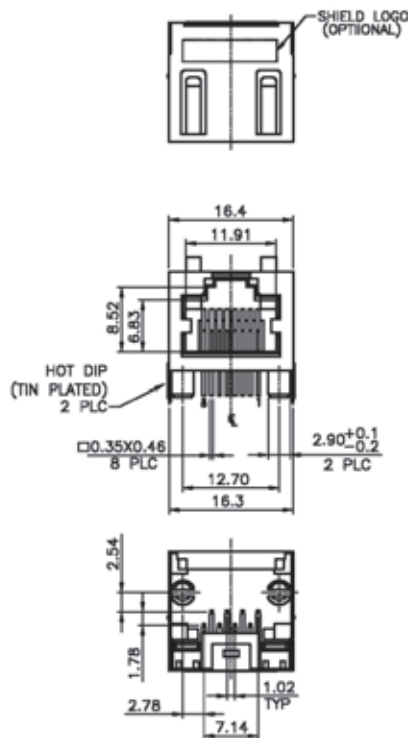
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J H X - 8 8 x B
1 2 3 4

1. MODULAR JACK TYPE:
"HX" WITH TOP PANEL GROUND
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

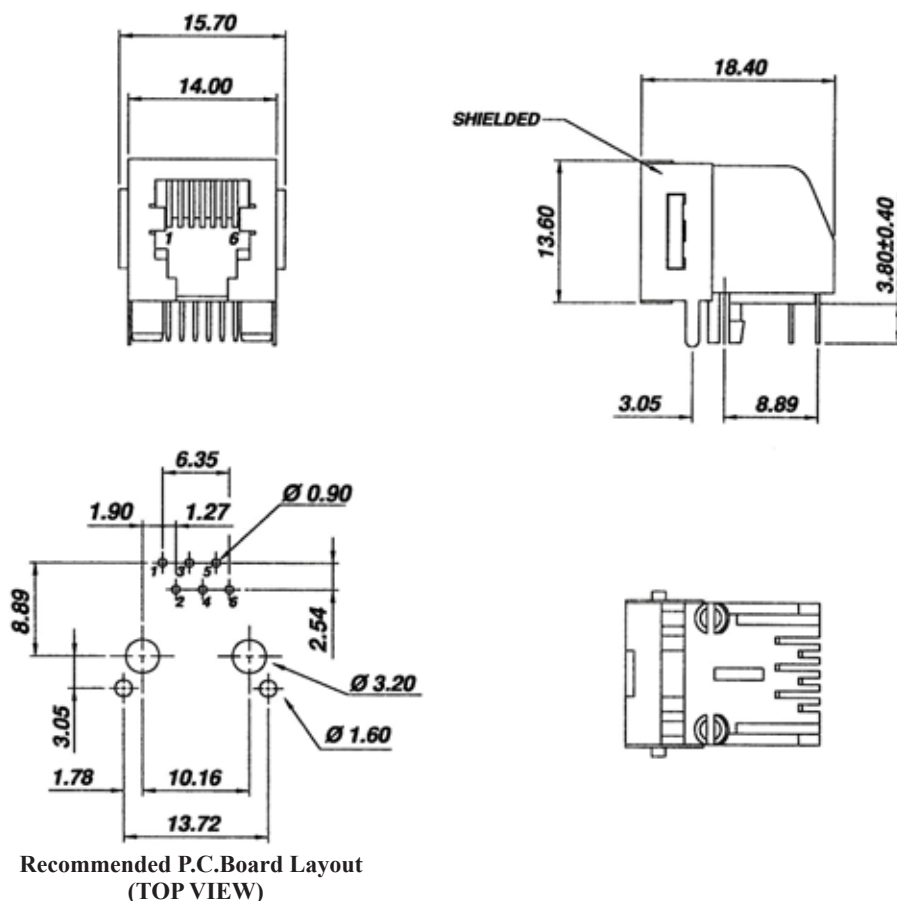
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R H - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJRHHT-6xxB for High Temp. Version

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

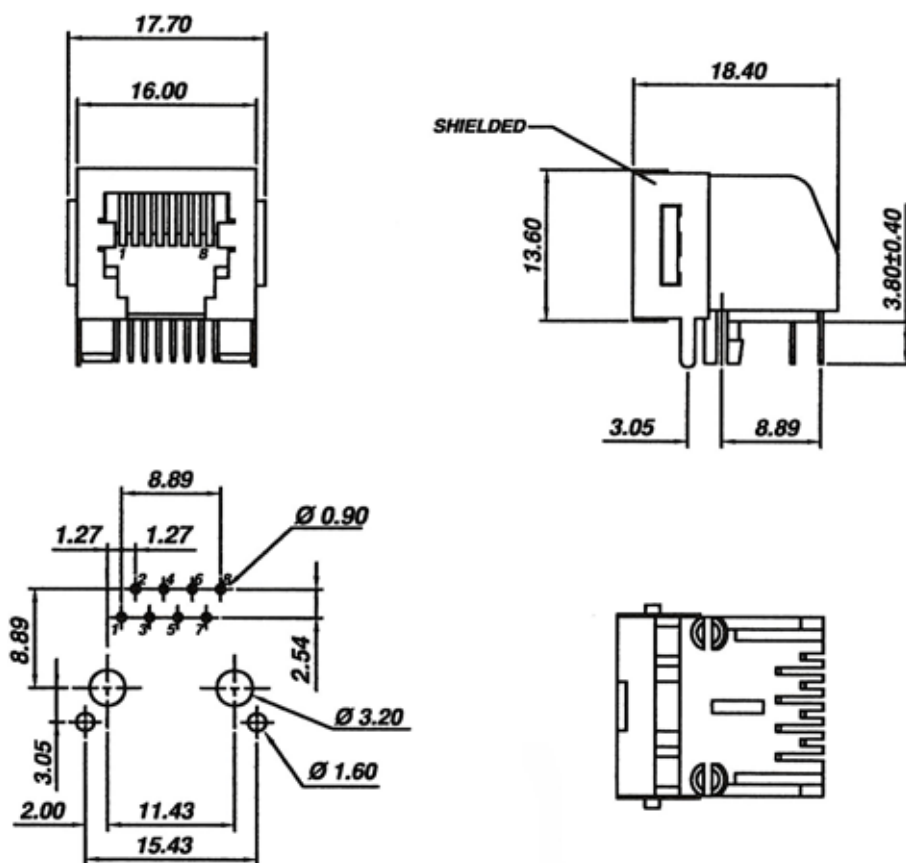
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J R H - $\frac{88}{1} \times \frac{B}{2} \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " WITHOUT KEY

"K" WITH KEY

NOTE: P/N MJRHHT-88xB FOR HIGH TEMP. VERSION

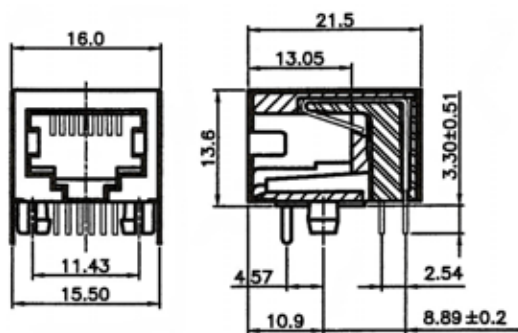
SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

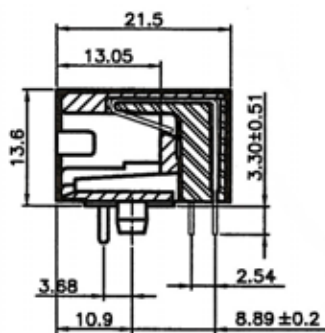
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

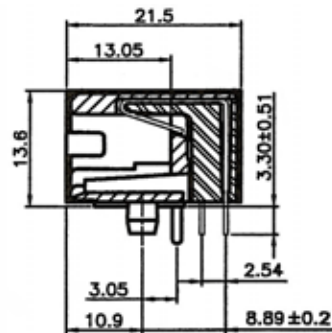
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



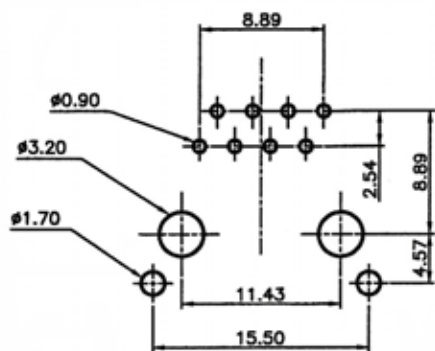
MJ97



MJ98

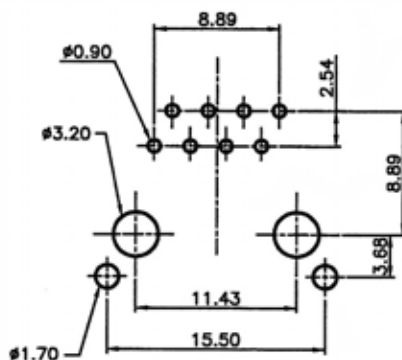


MJ05



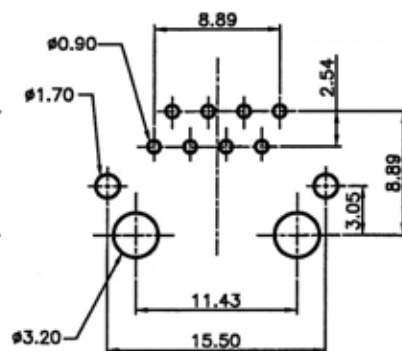
Recommended P.C.Board Layout

MJ97



Recommended P.C.Board Layout

MJ98



Recommended P.C.Board Layout

MJ05

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

1. TYPE OF JACKS:
 "97" A TYPE
 "98" B TYPE
 "05" C TYPE
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

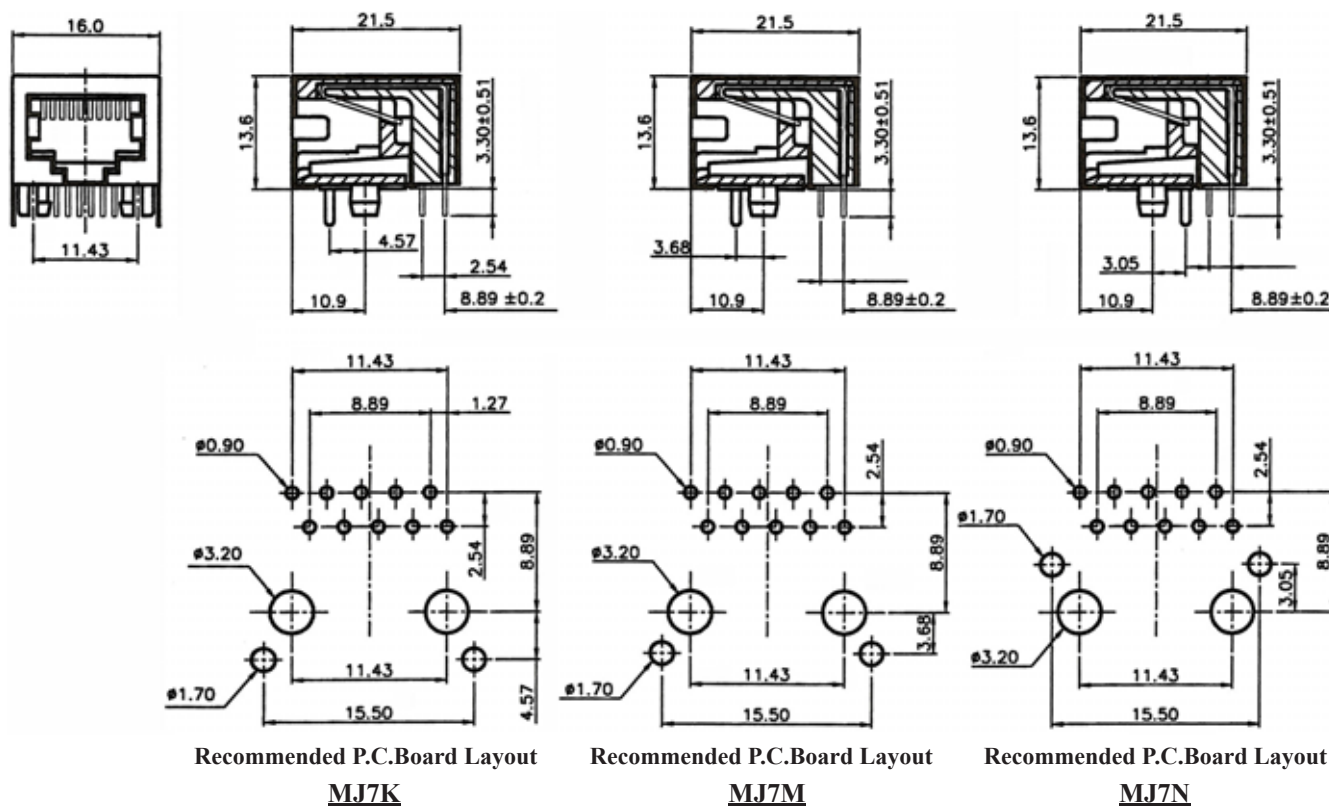
SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 10P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XXX}{2}$ $\frac{X}{3}$ B

1. TYPE OF JACKS:
 "7K" A TYPE
 "7M" B TYPE
 "7N" C TYPE
2. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "08" 10P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

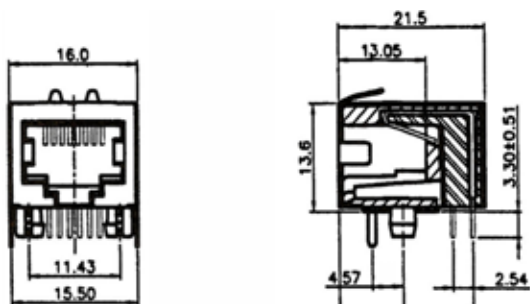
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

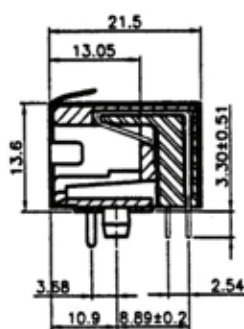
Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

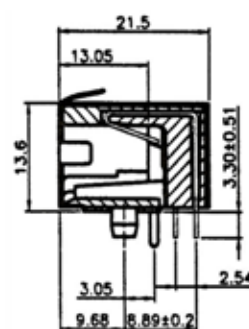
Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



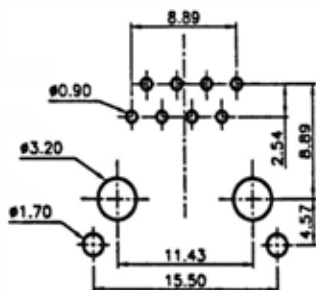
A TYPE



B TYPE

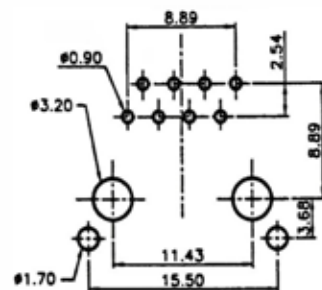


C TYPE



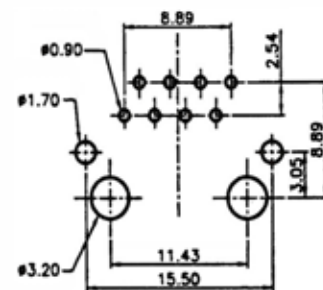
Recommended P.C.Board Layout

A TYPE



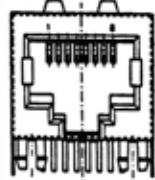
Recommended P.C.Board Layout

B TYPE

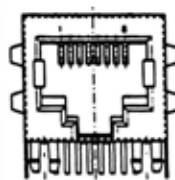


Recommended P.C.Board Layout

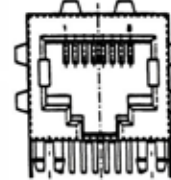
C TYPE



WITH TOP TABS



WITH SIDE TABS



WITH TOP & SIDE TABS

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

1. CONTACT & PANEL GROUND (TAB) TYPE:

95, 96, 06, 1A, 1B, 1C, 1D, 1E, 1F
 V1, V2, V3, V4, V5, V6, V7, V8, V9

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

	STANDARD TYPE			CATEGORY 5		
CONTACT TYPE	A	B	C	A	B	C
WITH TOP TABS	95	96	06	V1	V2	V3
WITH SIDE TABS	1A	1B	1C	V4	V5	V6
WITH TOP & SIDE TABS	1D	1E	1F	V7	V8	V9

NOTE: P/N MJxxHT-88xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

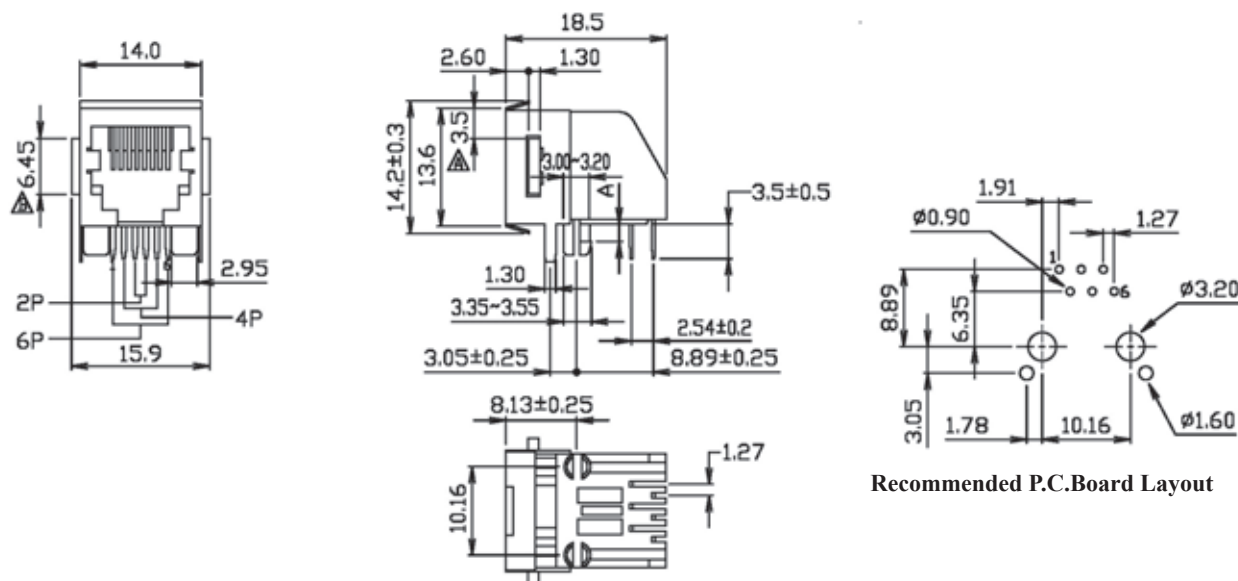
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H U - x x x B
I 2 3 4

1. MODULAR JACK TYPE:
"HU" PANEL GROUND TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

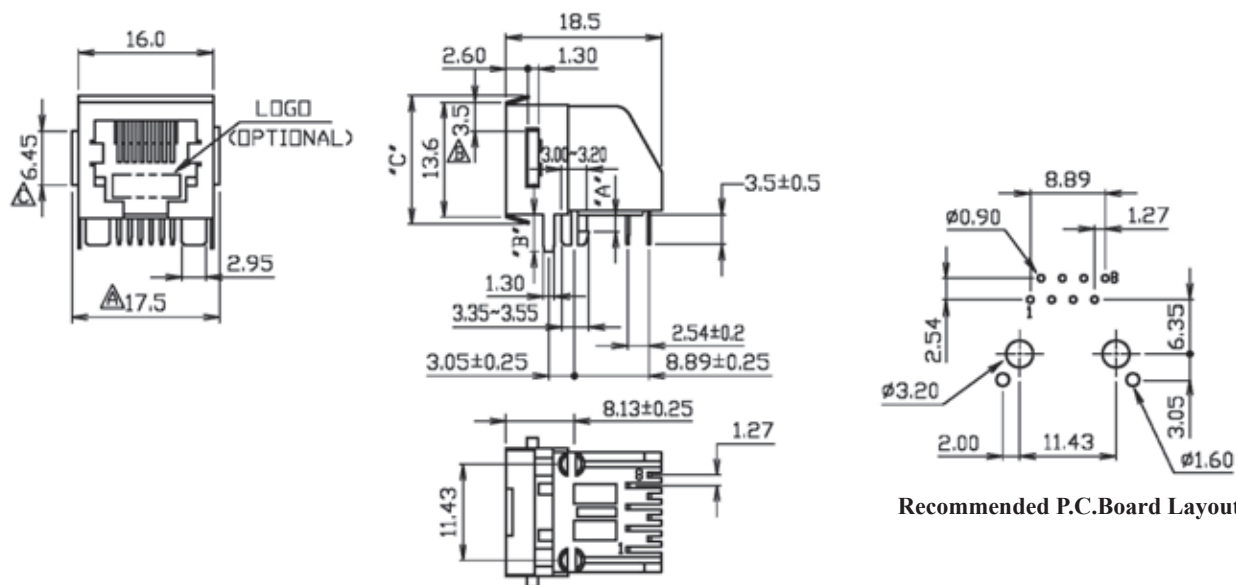
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J H U - 8 8 x B
1 2 3 4

1. MODULAR JACK TYPE:
"HU" PANEL GROUND TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P WITH KEY PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

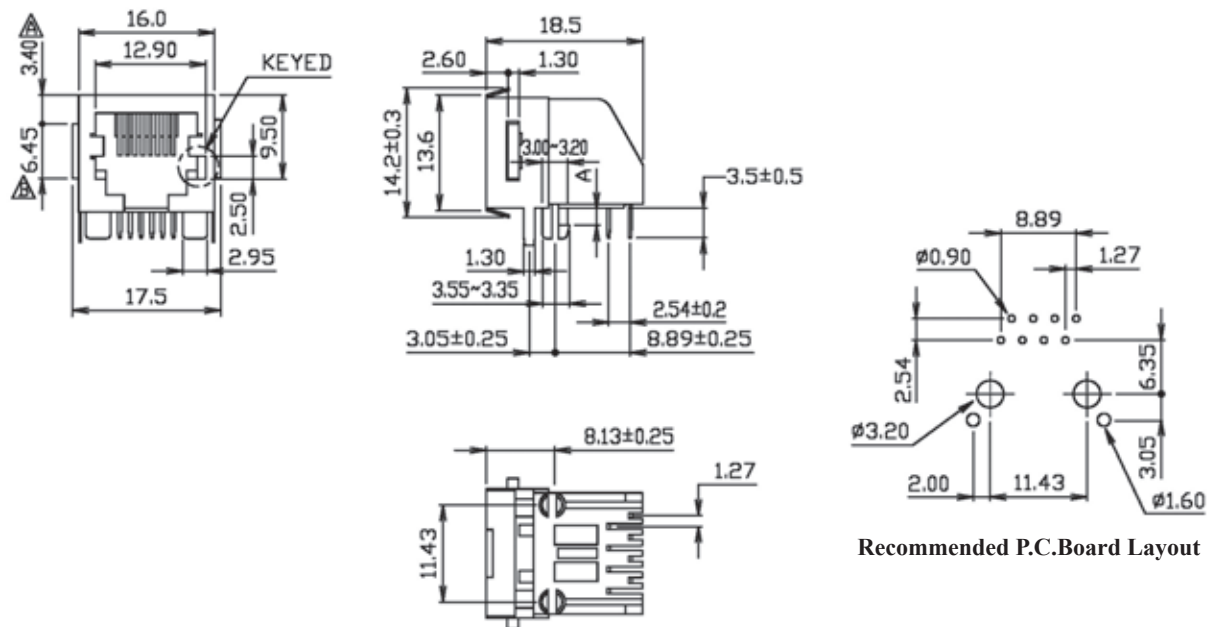
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H V - 88 x B K
1 2 3 4 5

1. MODULAR JACK TYPE:

"HV" PANEL GROUND TYPE

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

5. KEY OPTION:

"K" KEYED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

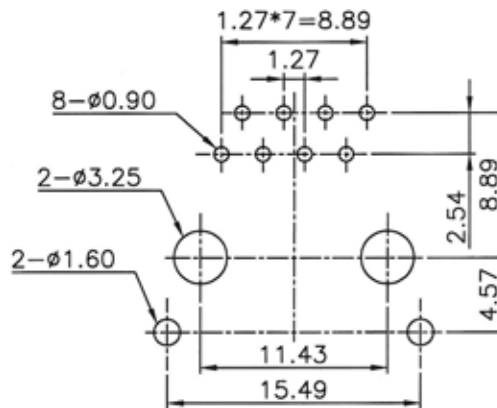
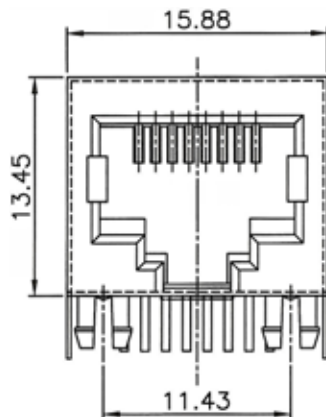
Color: Black

Spring Wire: Phosphor Bronze

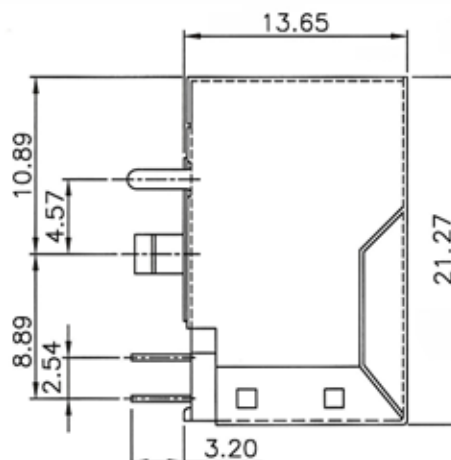
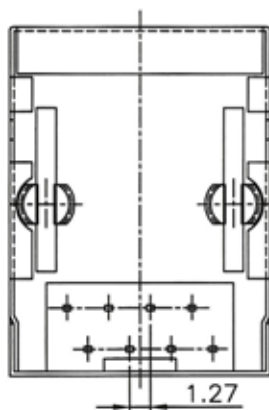
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3}$

1. CATEGORY TYPE:

"8T" CAT. 3

"W1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

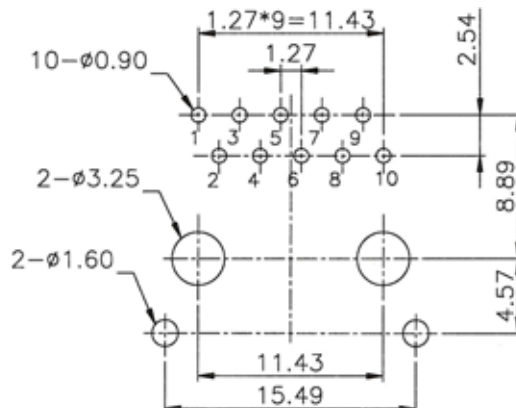
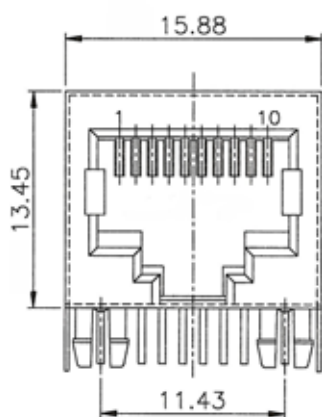
Color: Black

Spring Wire: Phosphor Bronze

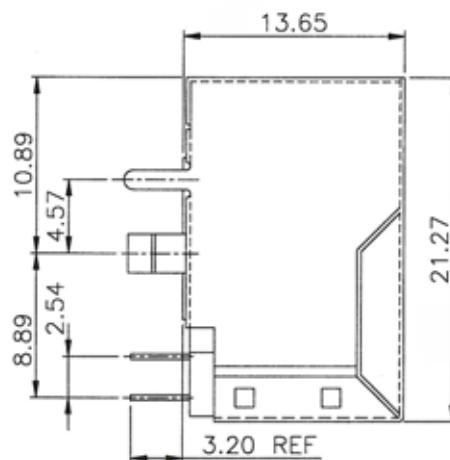
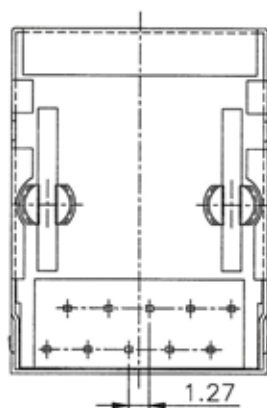
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 8 T - 00 $\frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

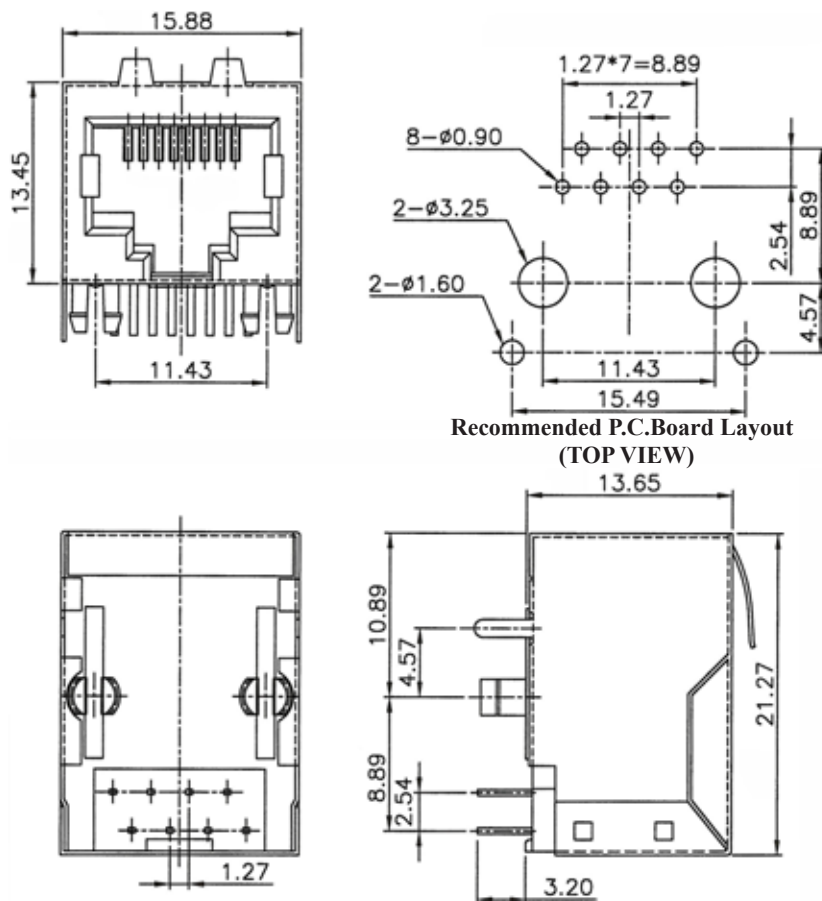
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"5M" CAT. 3

"V1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

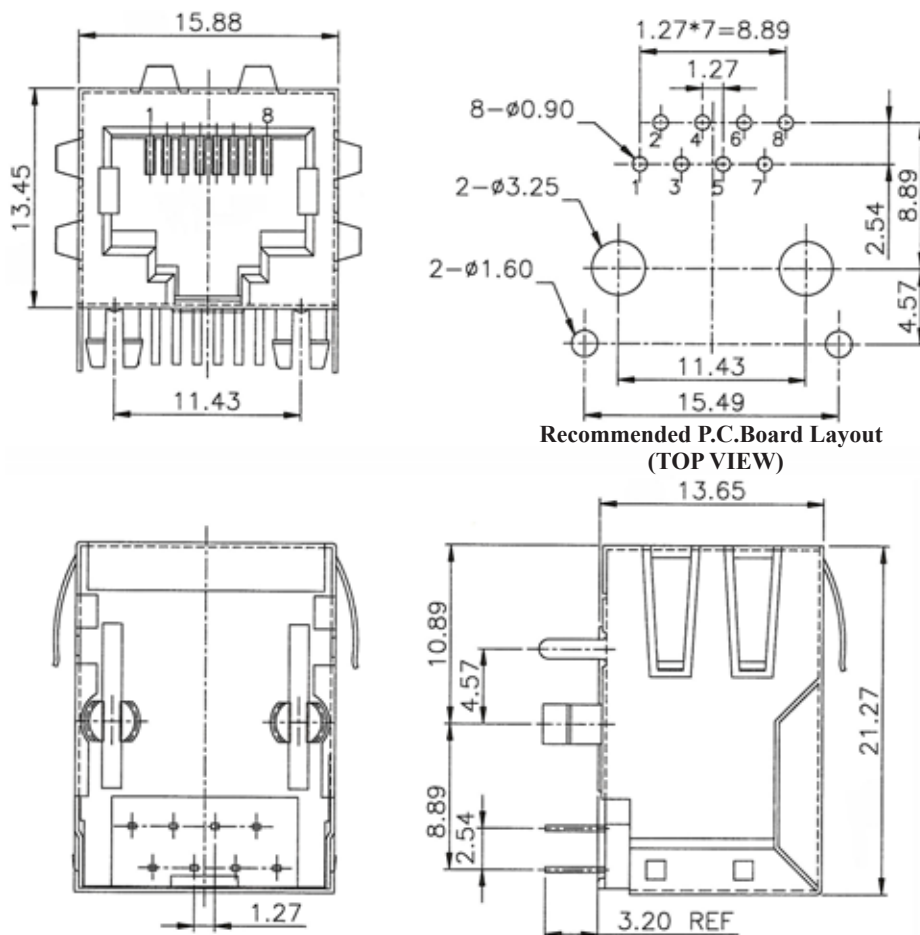
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3}$

1. CATEGORY TYPE:

"5X" CAT. 3

"V7" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

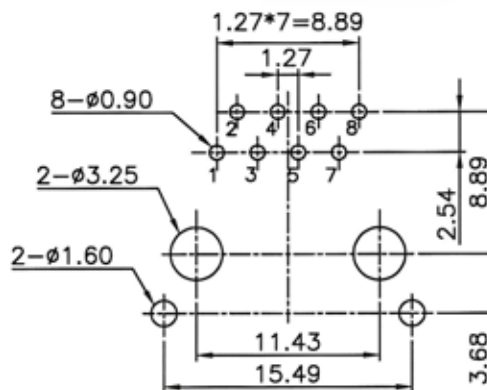
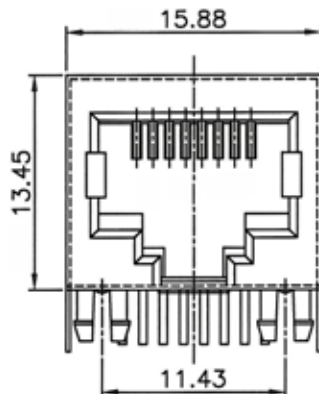
Color: Black

Spring Wire: Phosphor Bronze

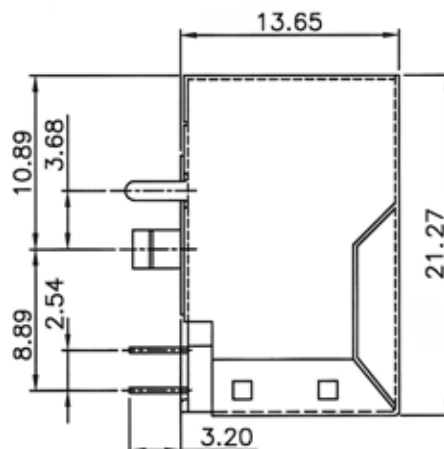
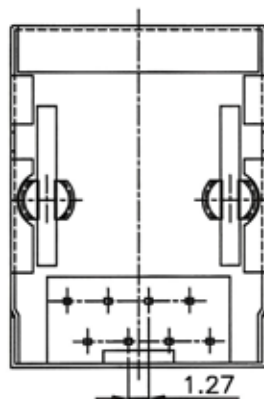
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"8U" CAT. 3

"W2" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

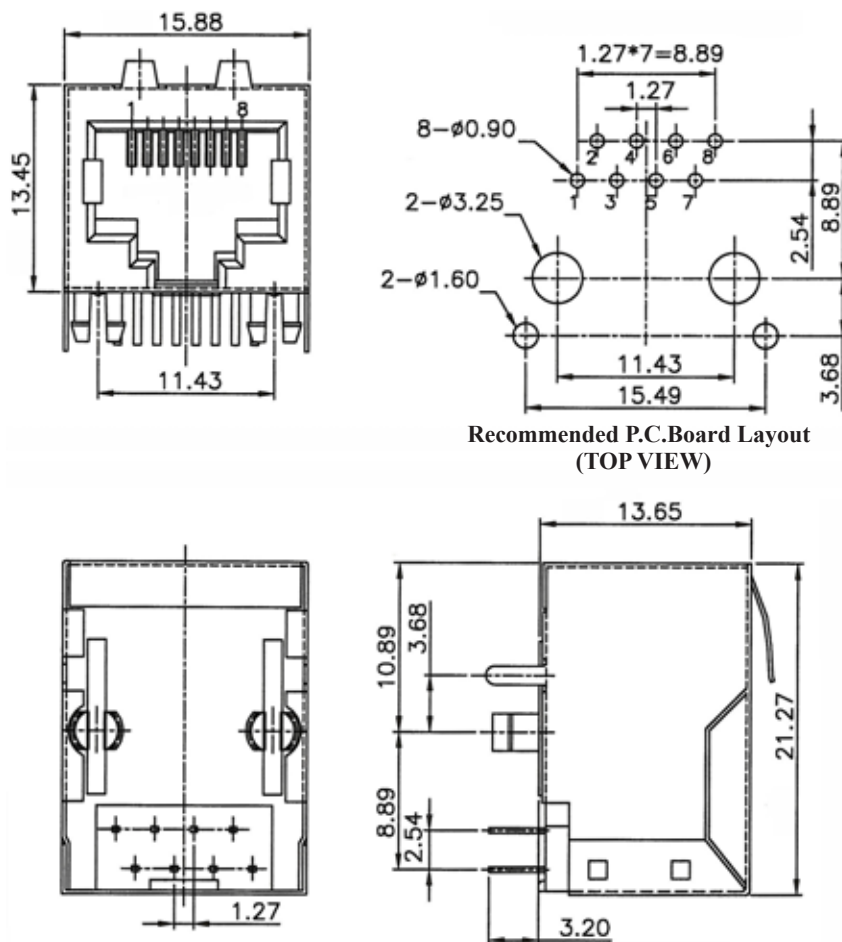
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3}$

1. CATEGORY TYPE:

"5N" CAT. 3

"V2" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

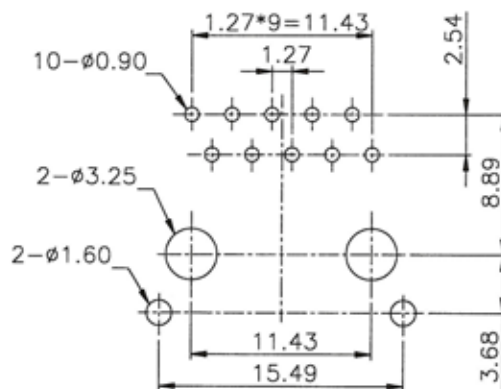
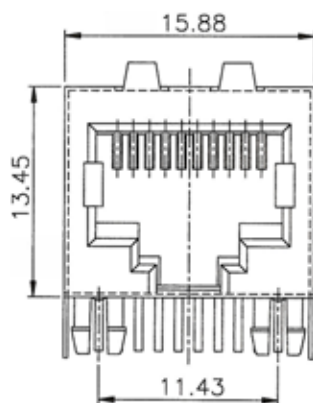
Color: Black

Spring Wire: Phosphor Bronze

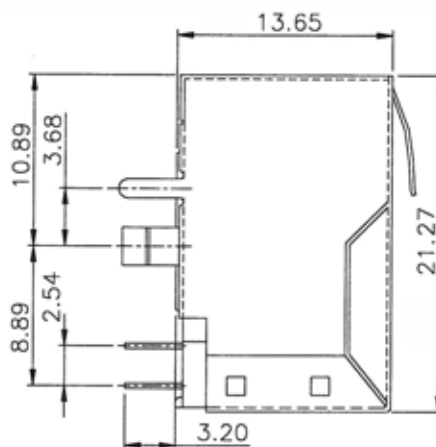
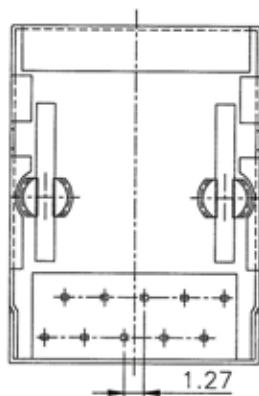
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ5N - $\frac{00}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

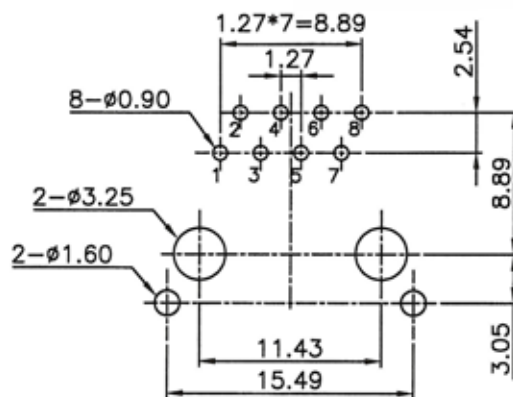
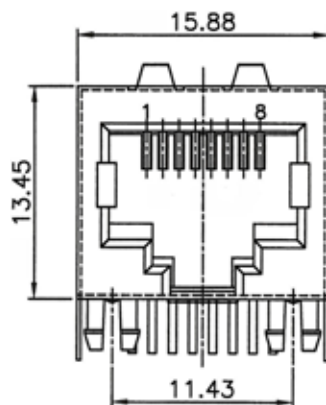
Color: Black

Spring Wire: Phosphor Bronze

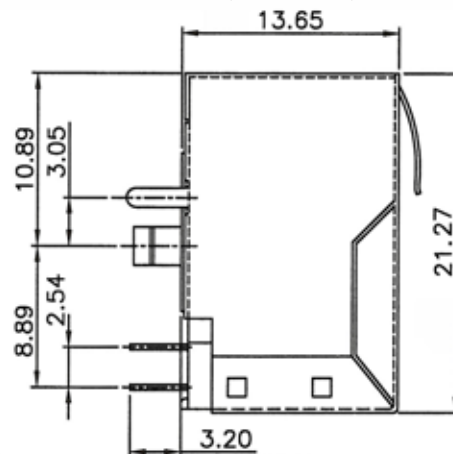
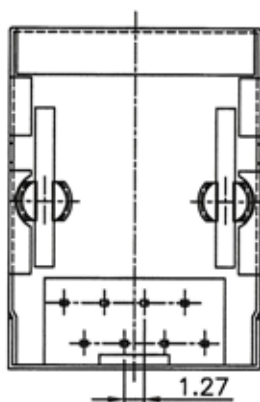
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"5J" CAT. 3

"W4" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

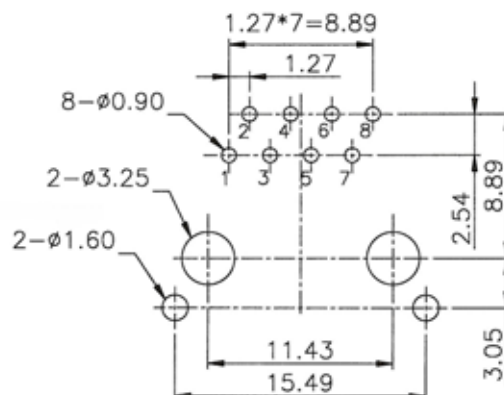
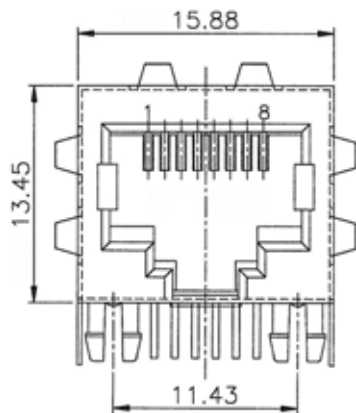
Color: Black

Spring Wire: Phosphor Bronze

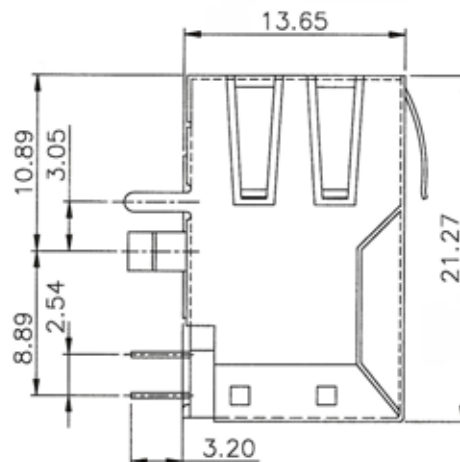
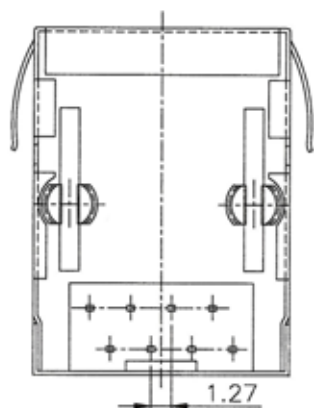
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3}$

1. CATEGORY TYPE:

"5U" CAT. 3

"W5" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

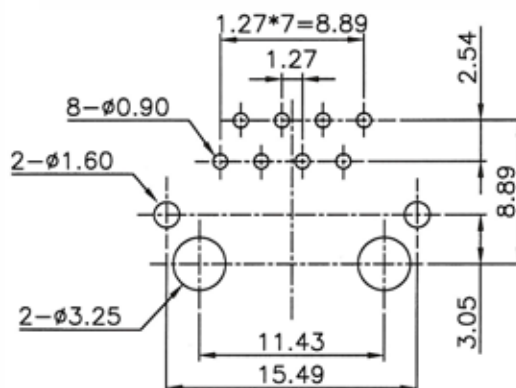
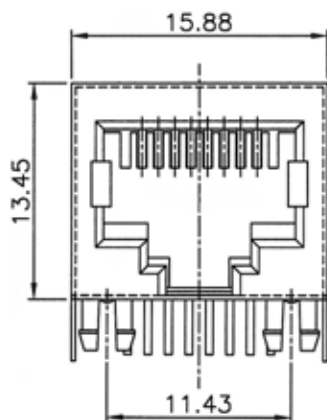
Color: Black

Spring Wire: Phosphor Bronze

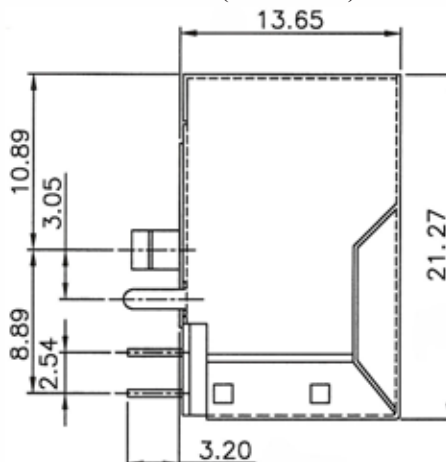
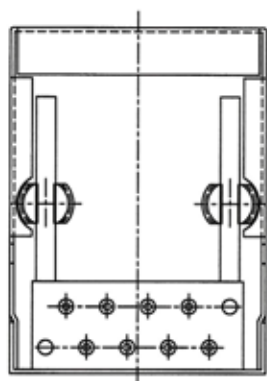
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

1. CONTACT TYPE:

"05" ROUND PINS

"8V" STAMPED PINS

"W3" CAT. 5 STAMPED PINS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

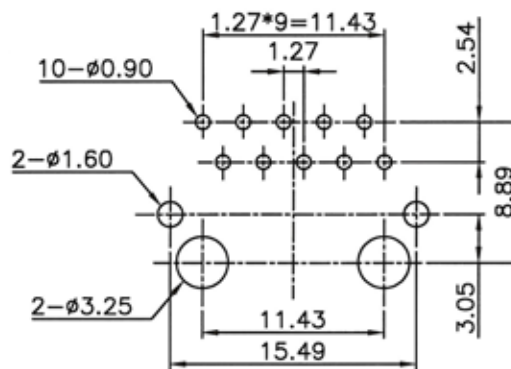
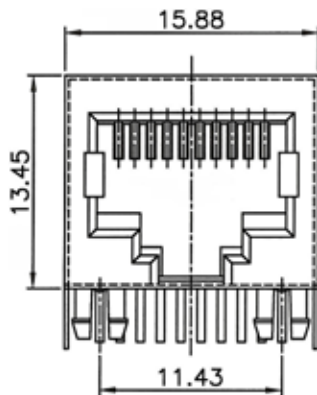
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

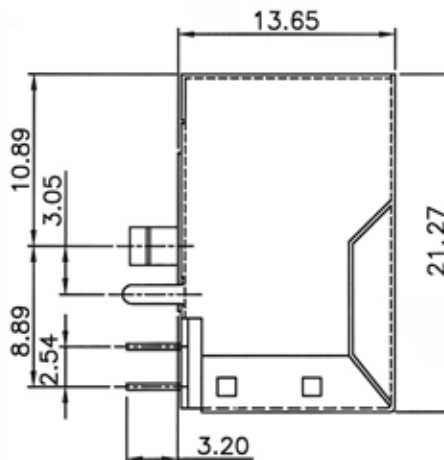
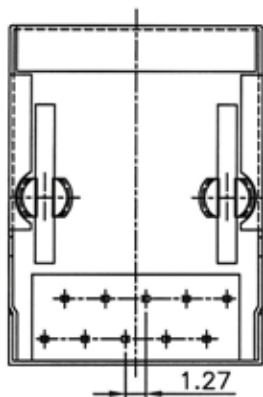
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 8 V - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C
 "08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

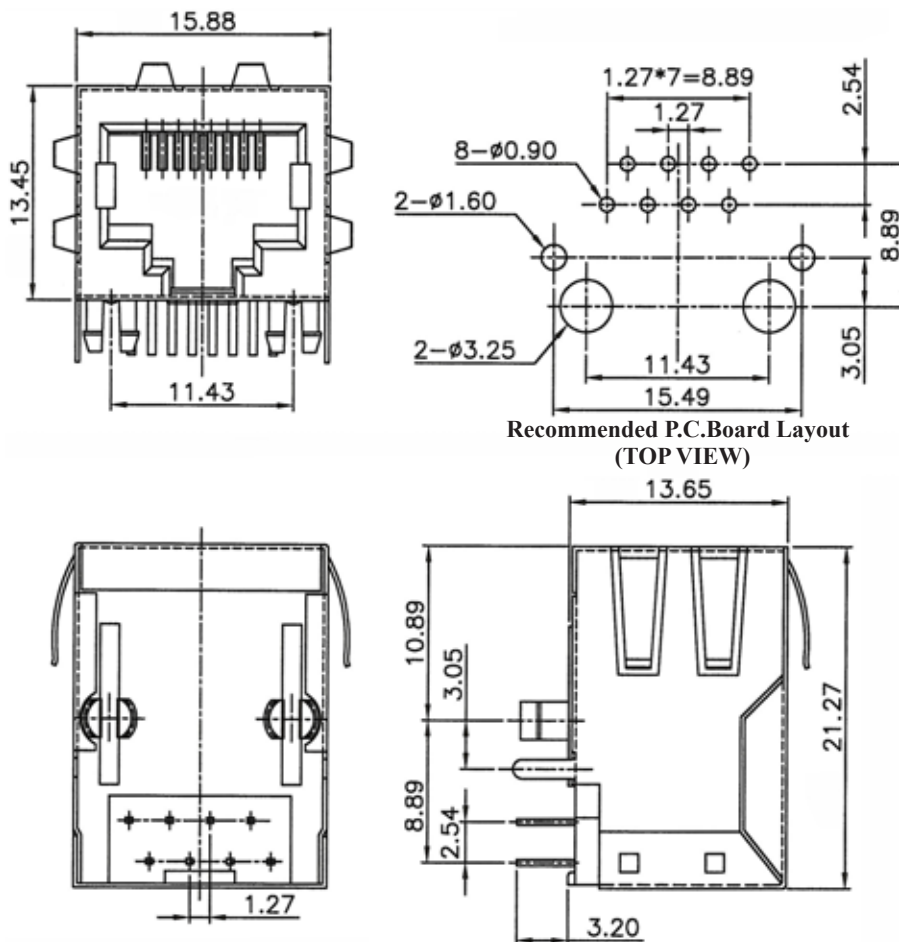
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:
 "5Z" CAT. 3
 "V9" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

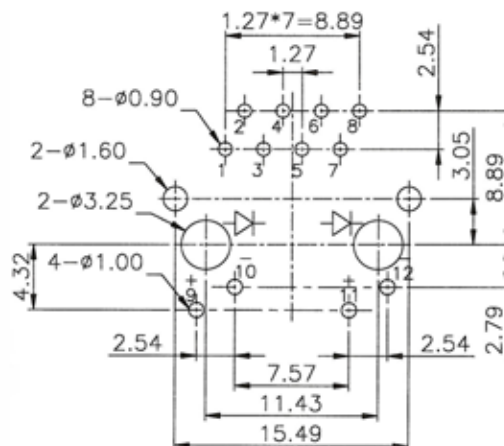
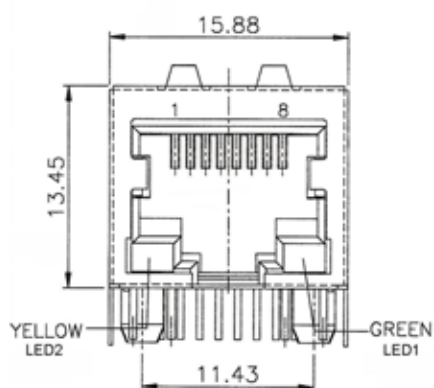
SIDE ENTRY MODULAR PCB JACK WITH LED 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

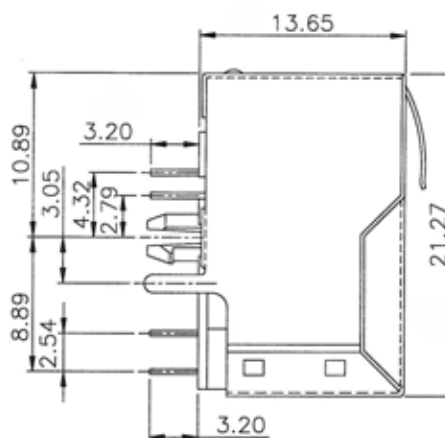
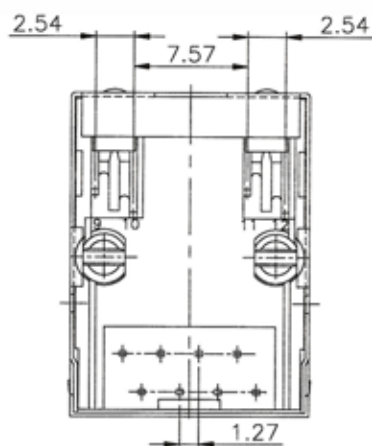
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 1 Y - $\frac{88}{1} \frac{x}{2} \frac{B}{3} \frac{x}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

Plastic Housing: Engineering Thermoplastic

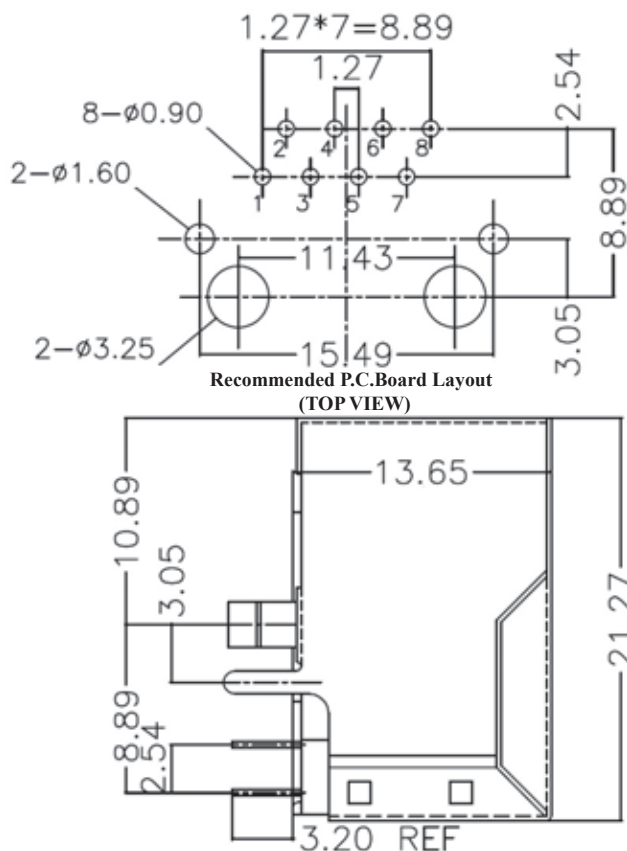
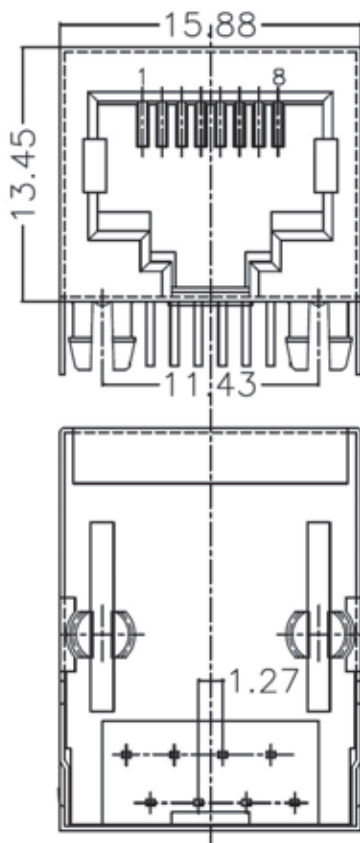
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,

Tin Plating Over Nickel In Solder Area.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ $\frac{8VJ}{1}$ - $\frac{88x}{2}$ B

1. MODULAR JACK TYPE:
"8VJ" 3.05MM SPACING BEHIND PEG
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: IT CAN BE USED FOR REPLACING P/N MJ8V-88xB.

NOTE 2: 3.05MM SPACING BEHIND PEG

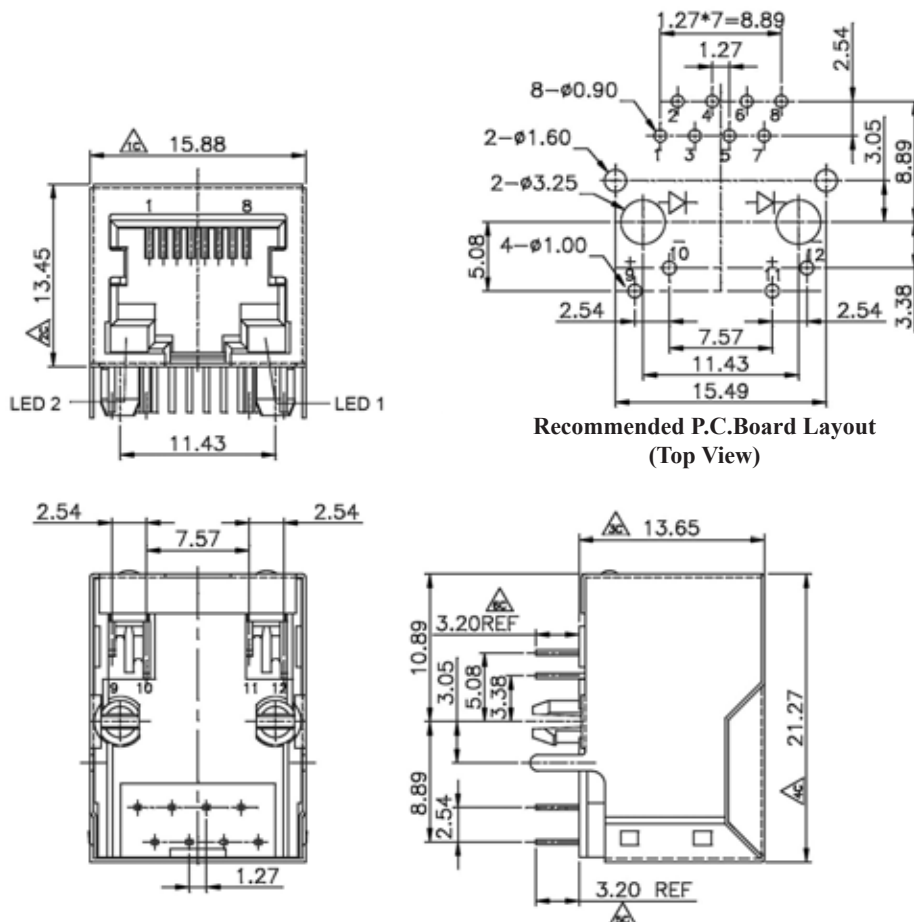
SIDE ENTRY MODULAR PCB JACK WITH LED 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 X - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

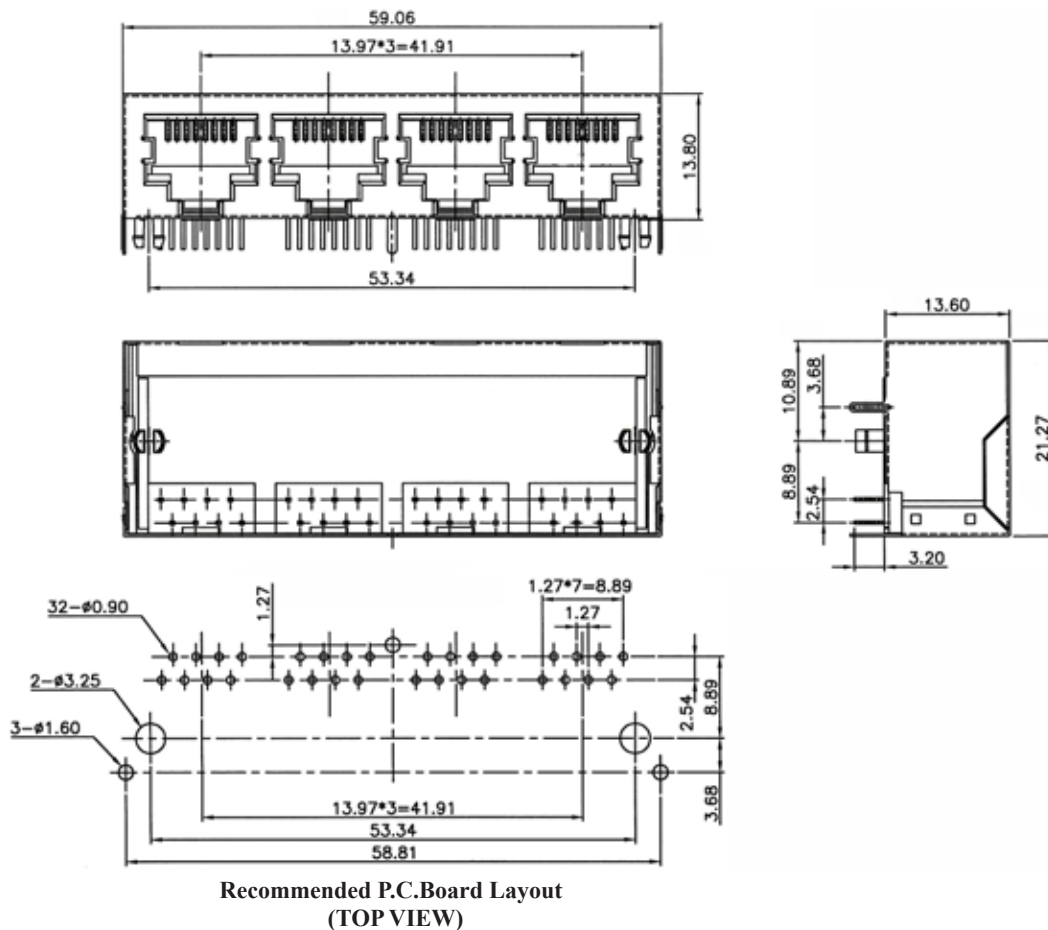
SIDE ENTRY 4-PORT CAT. 3 & 5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XXX}{23}$ B $\frac{04}{4}$

1. CATEGORY TYPE:
 "24" CAT. 3
 "Y3" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 04

NOTE: 3.68MM SPACING BEFORE PEG

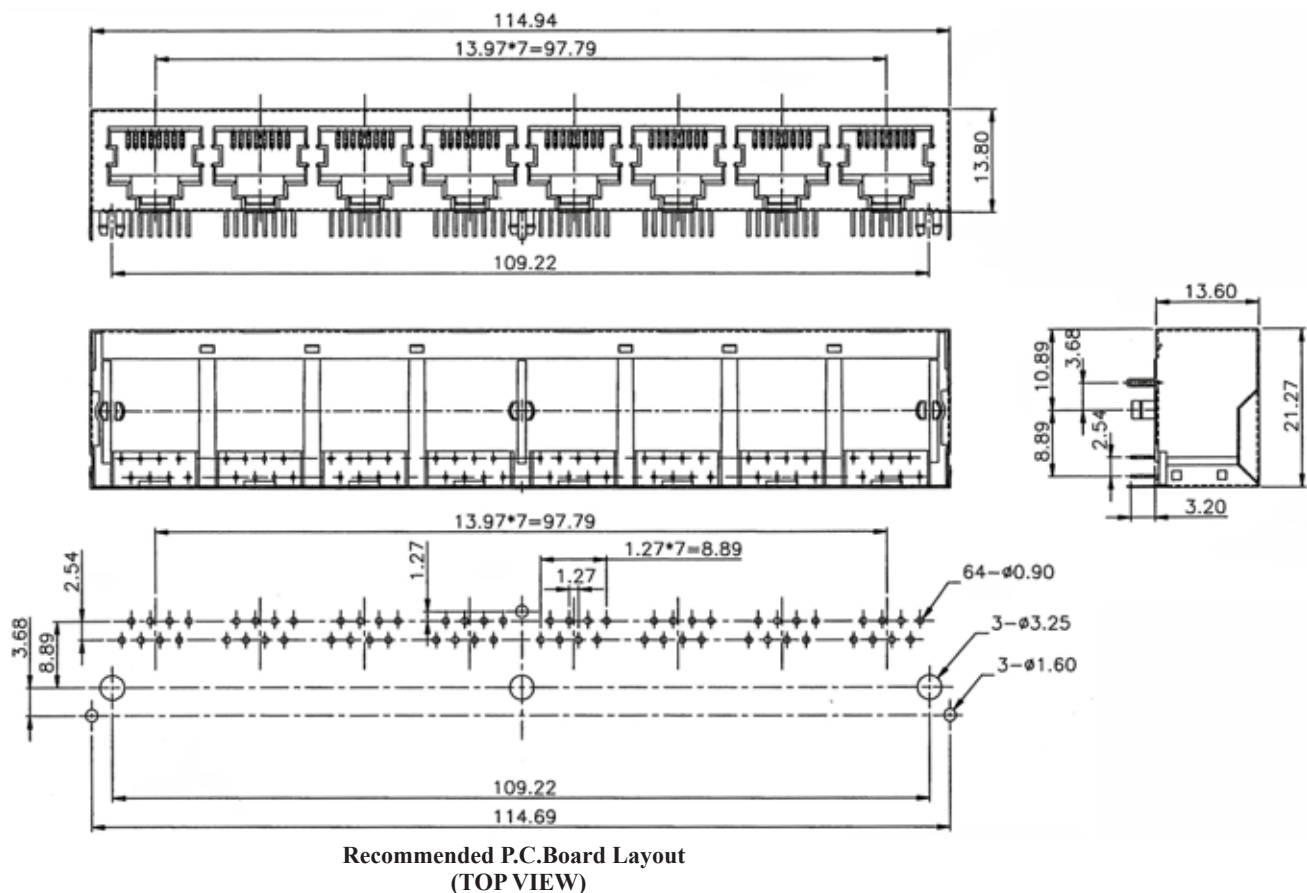
SIDE ENTRY 8-PORT CAT. 3 & 5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XXX}{23}$ B $\frac{08}{4}$

1. CATEGORY TYPE:
 "24" CAT. 3
 "Y3" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 08

NOTE: 3.68MM SPACING BEFORE PEG

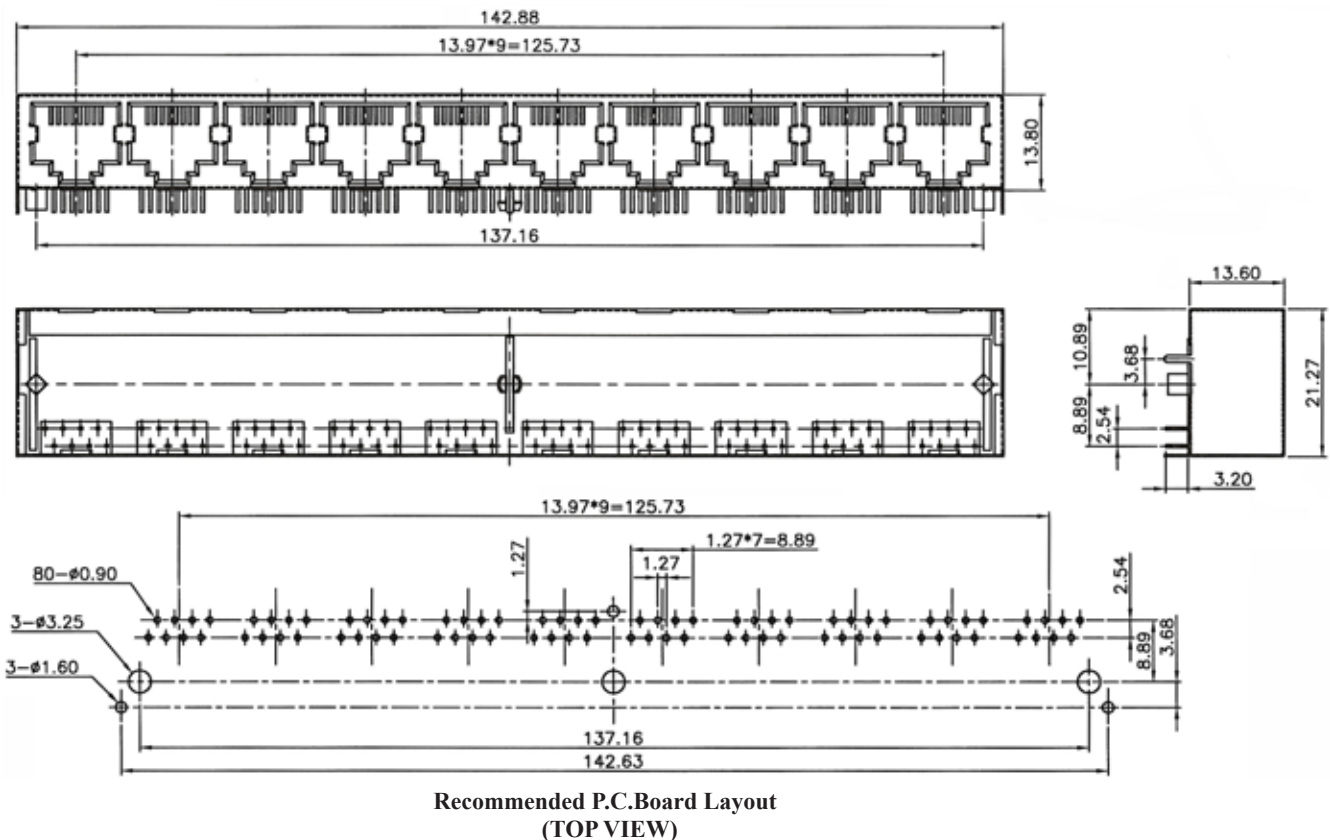
SIDE ENTRY 10-PORT CAT. 3 & 5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B $\frac{10}{4}$

1. CATEGORY TYPE:
 "24" CAT. 3
 "Y3" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 10

NOTE: 3.68MM SPACING BEFORE PEG

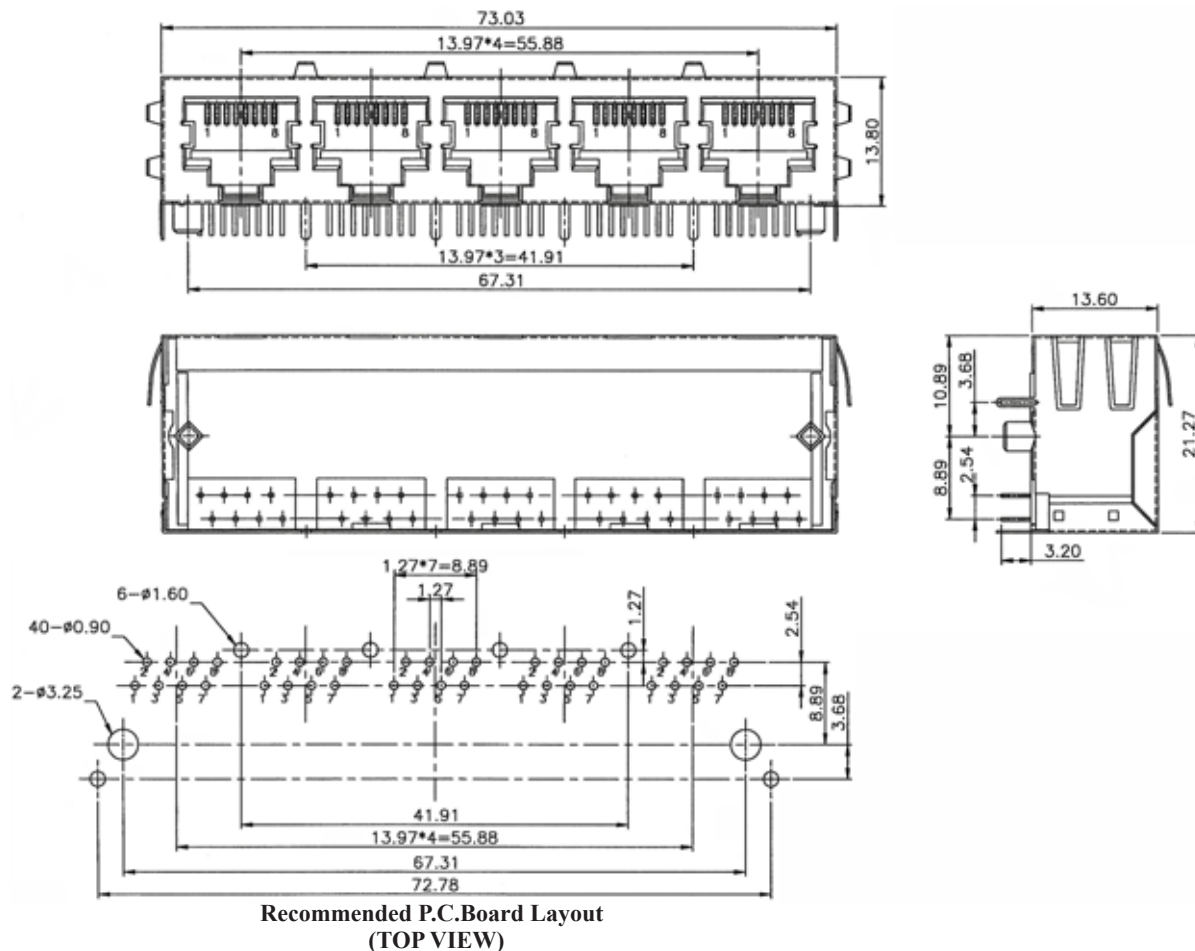
SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1} - \frac{xxx}{23} B \frac{05}{4}$

1. CATEGORY TYPE:
 "25" CAT. 3
 "Y2" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 05

NOTE: 3.68MM SPACING BEFORE PEG

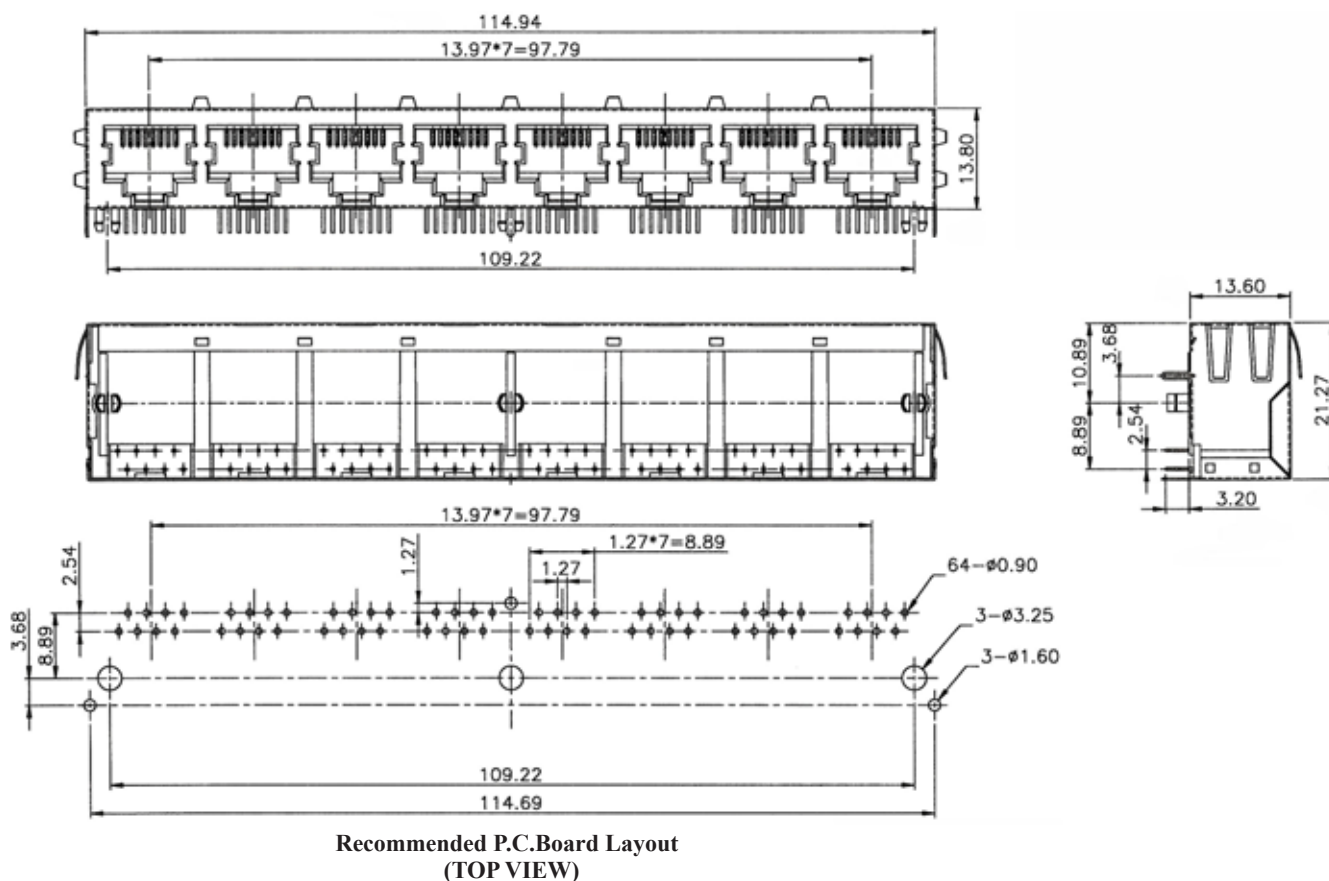
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{xxx}{2}$ $\frac{B}{3}$ $\frac{08}{4}$

1. CATEGORY TYPE:
 "25" CAT. 3
 "Y2" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. NO. OF PORTS:
 08

NOTE: 3.68MM SPACING BEFORE PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

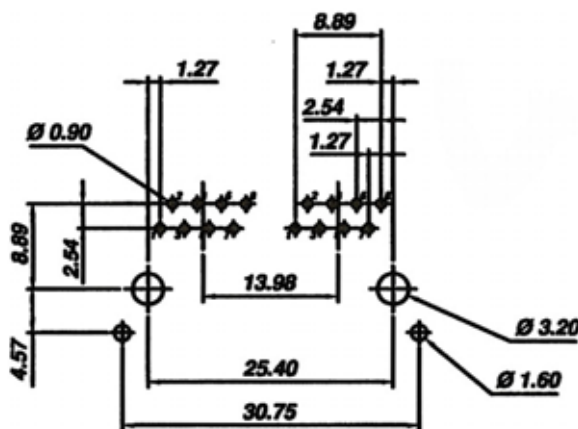
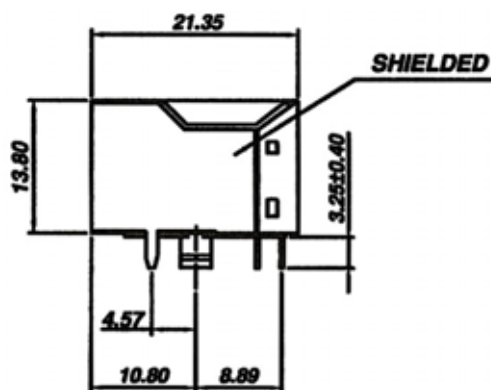
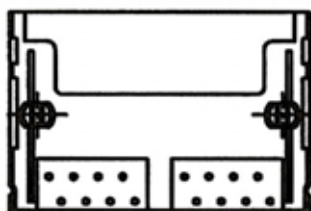
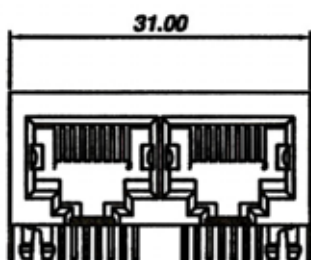
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J S J - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE 1: P/N MJSJHT-88xB02 FOR HIGH TEMP. VERSION

NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

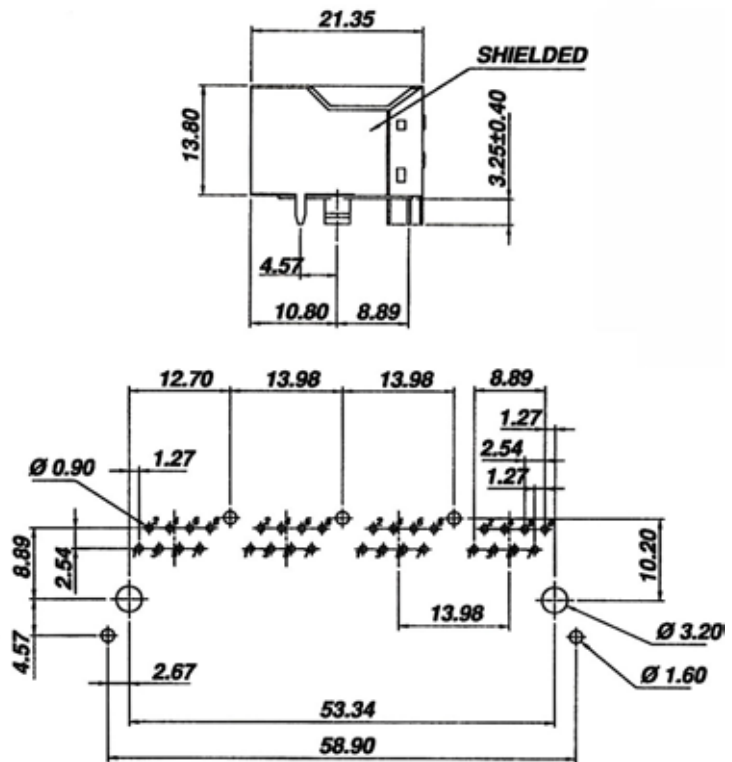
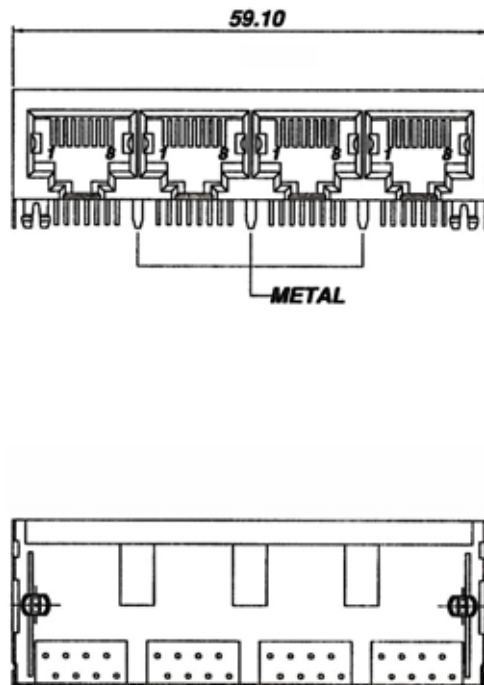
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N M J S J - $\frac{88}{1} \frac{x}{2}$ B $\frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

NOTE 1: P/N MJSJHT-88xB04 FOR HIGH TEMP. VERSION

NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

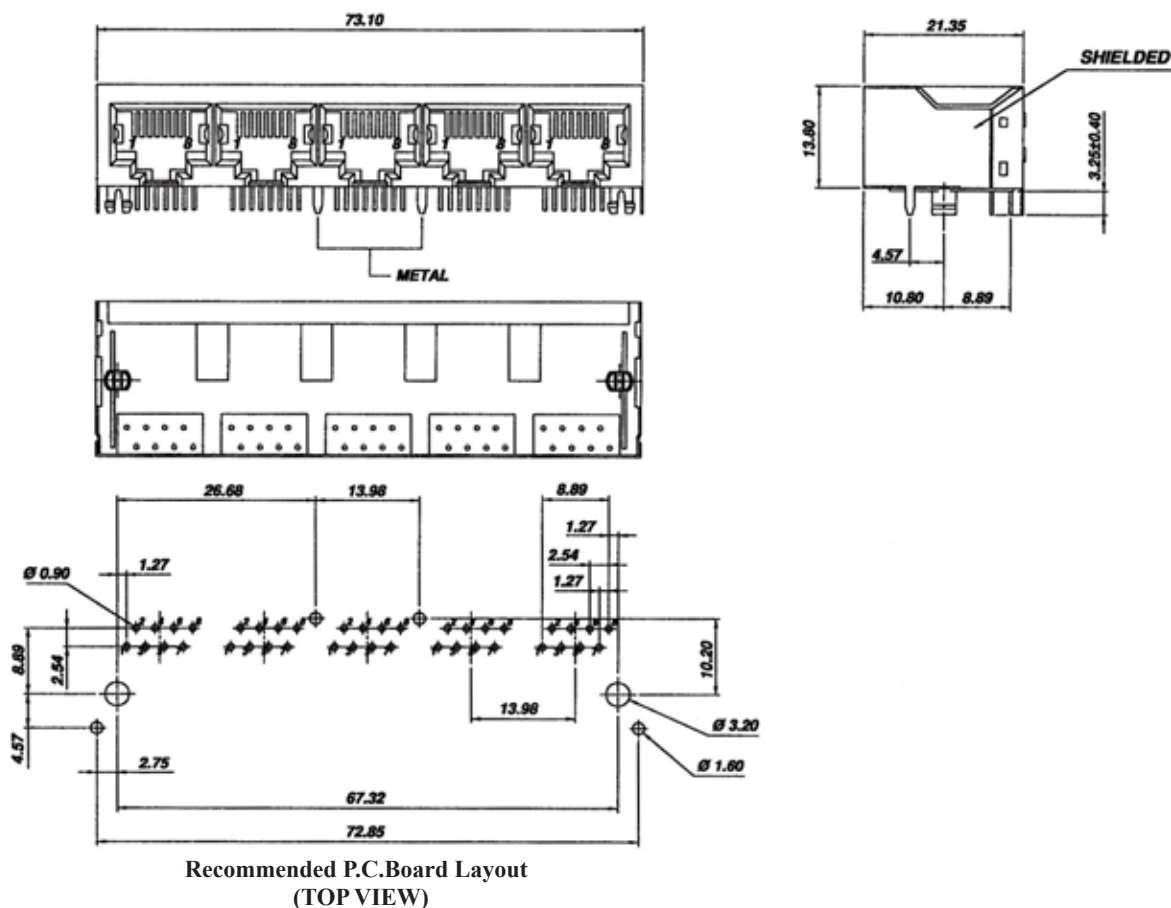
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{05}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

05

NOTE 1: P/N MJSJHT-88xB05 FOR HIGH TEMP. VERSION

NOTE 2: 4.57MM SPACING BEFORE PEG

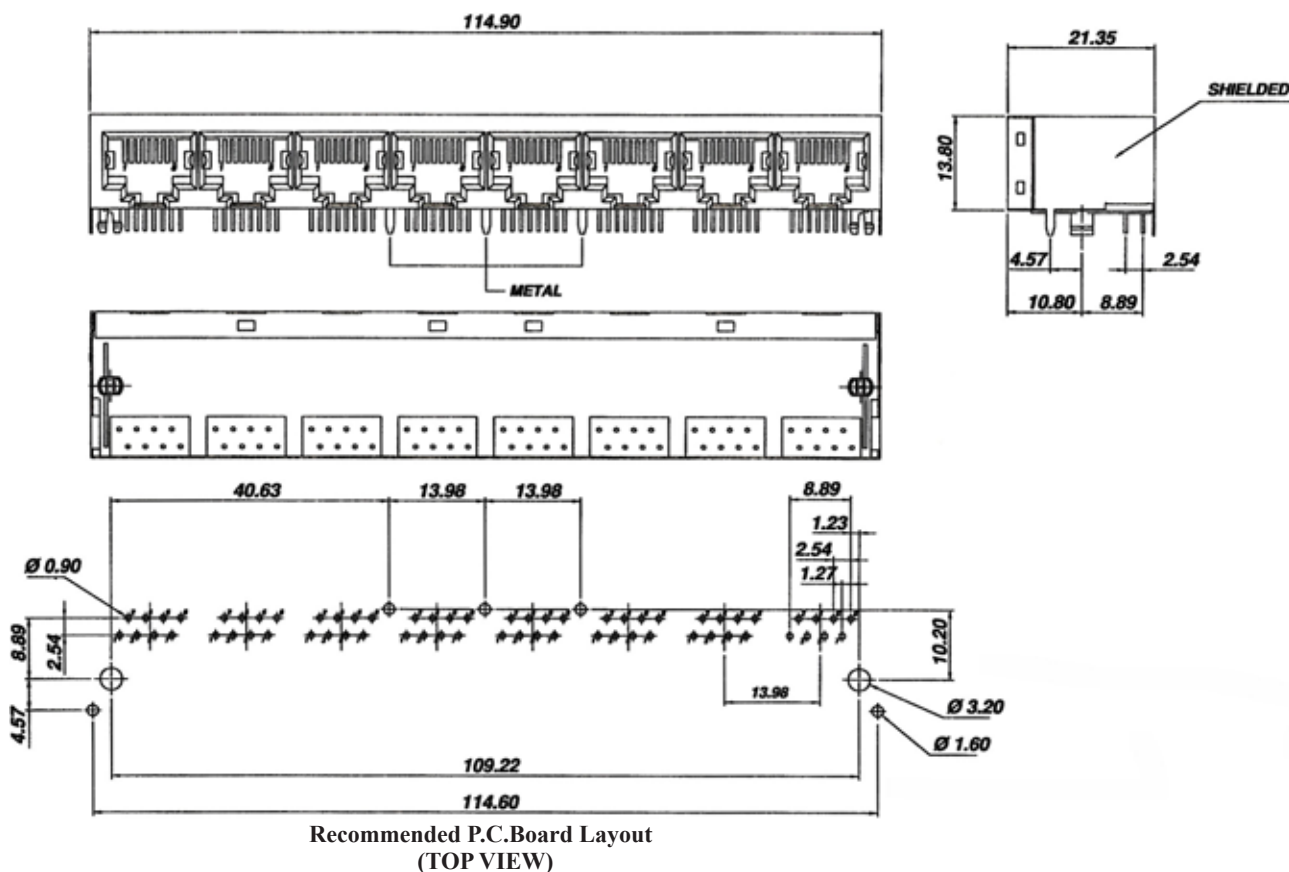
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE 1: P/N MJSJHT-88xB08 FOR HIGH TEMP. VERSION
 NOTE 2: 4.57MM SPACING BEFORE PEG

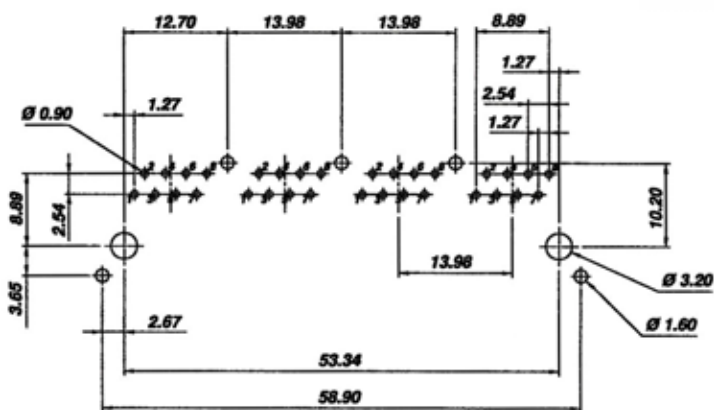
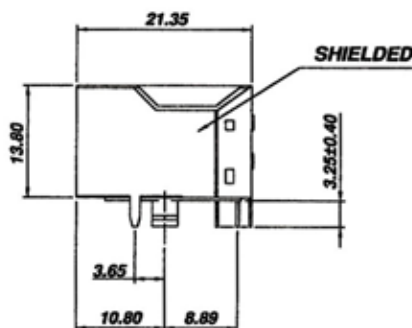
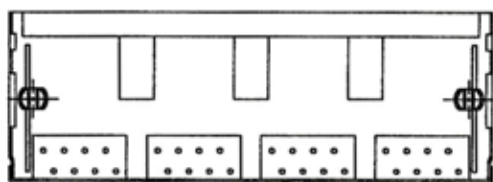
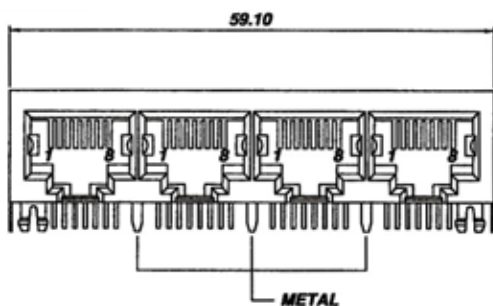
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J S K - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

NOTE 1: P/N MJSKHT-88xB04 FOR HIGH TEMP. VERSION
 NOTE 2: 3.65MM SPACING BEFORE PEG

SIDE ENTRY 6-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

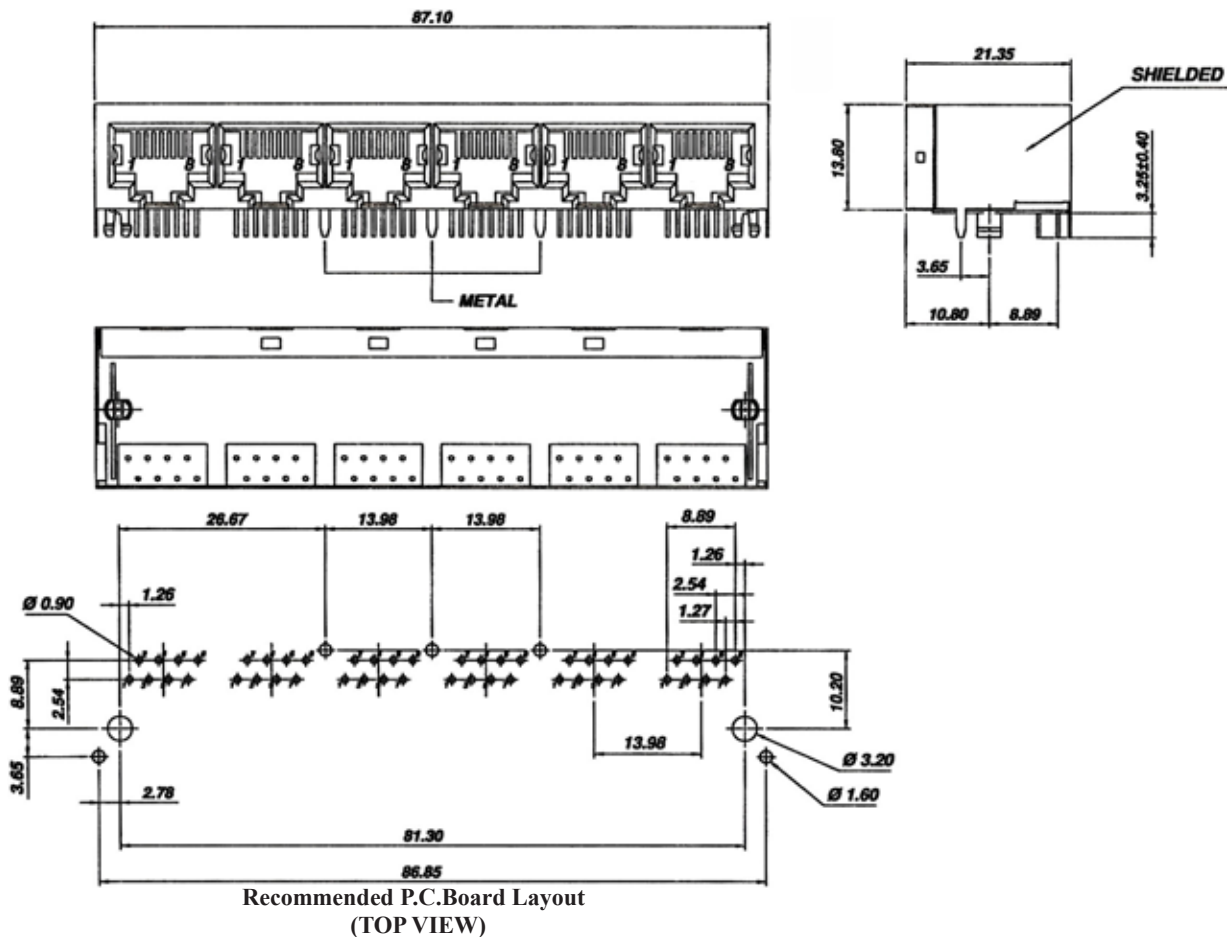
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J S K - $\frac{88}{1} \frac{x}{2}$ B $\frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
06

NOTE 1: P/N MJSKHT-88xB06 FOR HIGH TEMP. VERSION

NOTE 2: 3.65MM SPACING BEFORE PEG

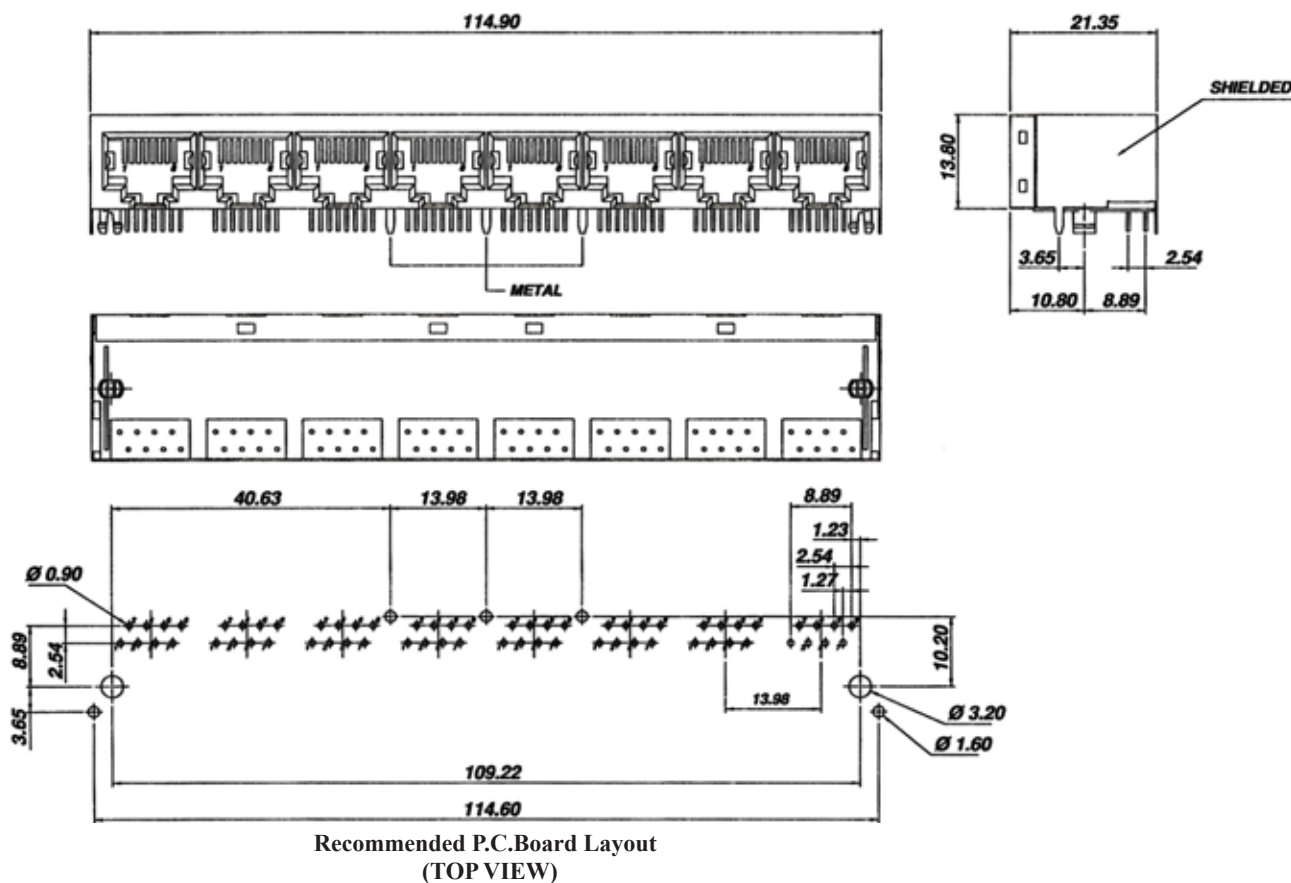
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J S K - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE 1: P/N MJSKHT-88xB08 FOR HIGH TEMP. VERSION
 NOTE 2: 3.65MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

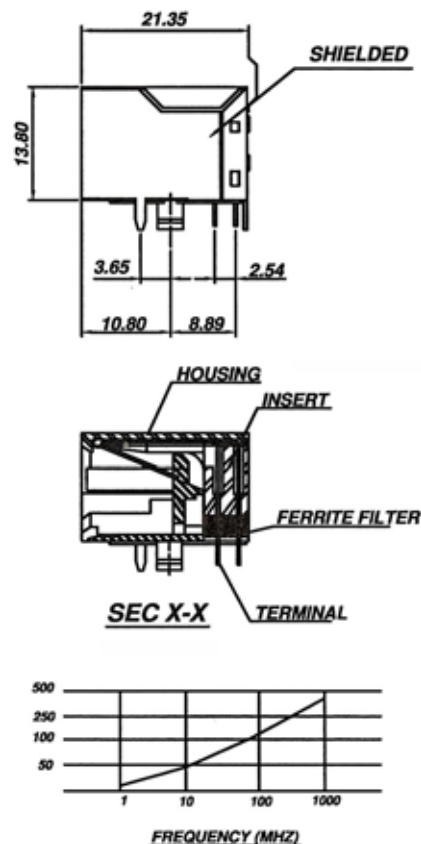
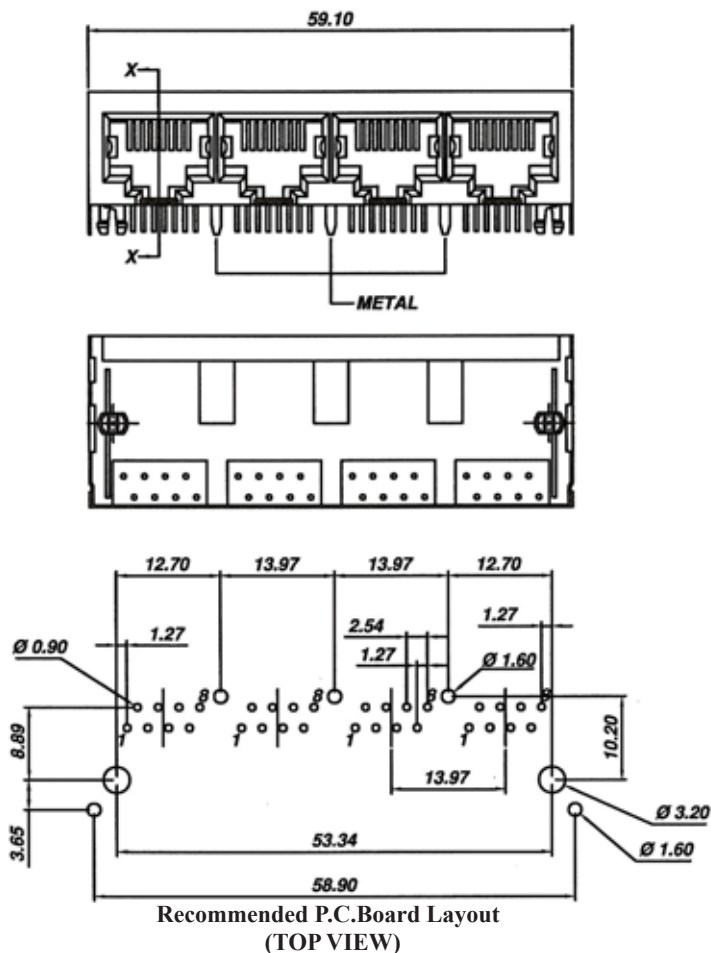
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S H - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 3.65MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

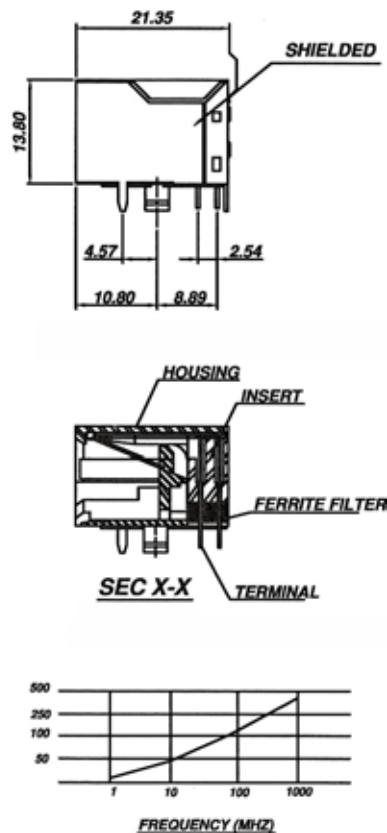
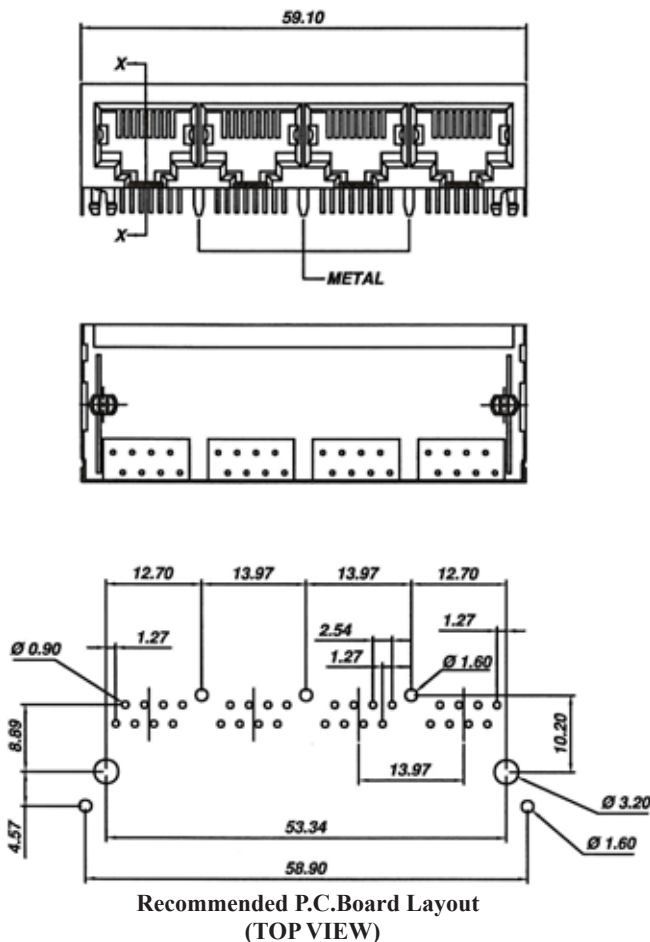
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S G - 88 x B 04
T 2 3

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 4.57MM SPACING BEFORE PEG

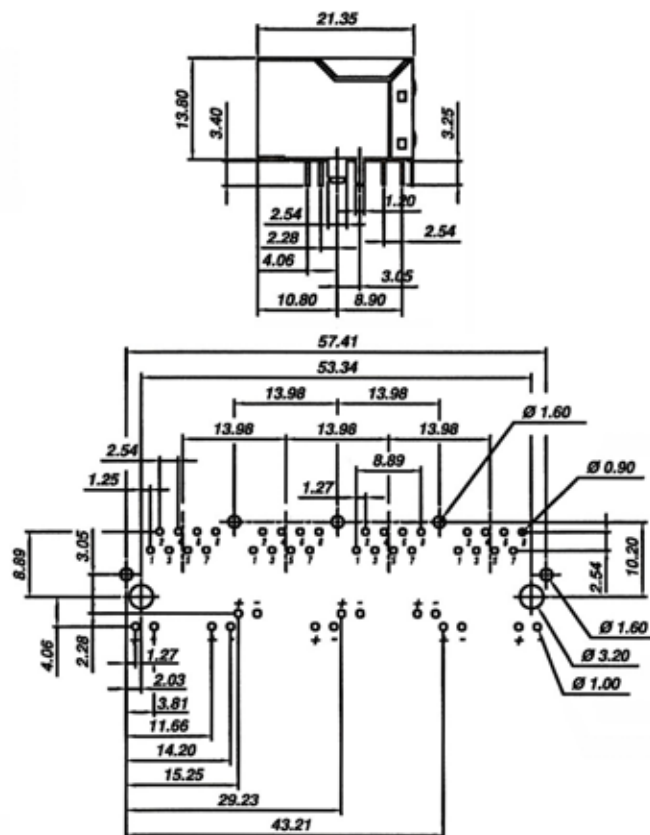
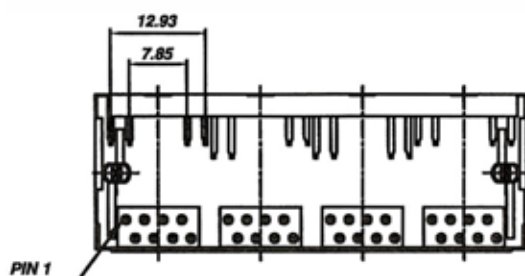
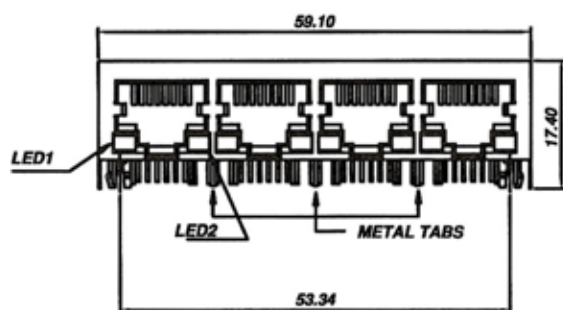
SIDE ENTRY 4-PORT MODULAR PCB JACK WITH LED 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J R J - $\frac{88}{1} \times \frac{B}{2} \times \frac{04}{345}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: 3.05MM SPACING BEHIND PEG

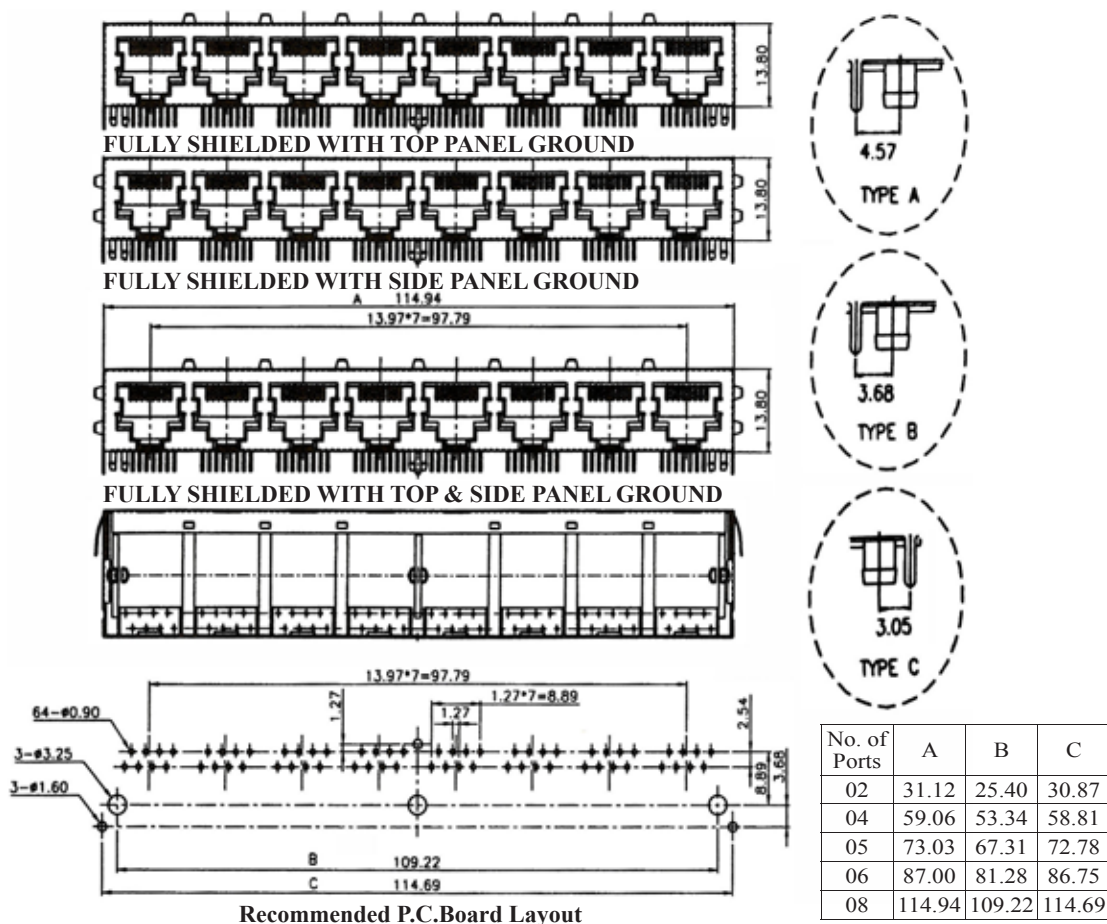
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P+10P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1} - \frac{xxx}{2} \frac{B}{3} \frac{xx}{4}$

1. CONTACT & PANEL GROUND TYPE:

WITH TOP PANEL GROUNDS:

"7G" TYPE A
 "7P" TYPE B
 "7Q" TYPE C

WITH SIDE PANEL GROUNDS:

"2E" TYPE A
 "2F" TYPE B
 "2G" TYPE C

WITH TOP & SIDE PANEL GROUNDS:

"2H" TYPE A
 "2K" TYPE B
 "2L" TYPE C

WITHOUT PANEL GROUNDS:

"7A" TYPE A
 "7B" TYPE B
 "3Y" TYPE C

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "00" 10P10C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

4. NO. OF PORTS:

02, 04, 05, 06, 08

SIDE ENTRY 2-PORT MODULAR PCB JACK 10P8C PROFILE=13.70MM (FULLY SHIELDED)

SPECIFICATIONS

Current Rating: 1.5 Amp Max.

Dielectric Withstanding: 500 Vac For 1 Min.

Contact Resistance: 30m Ohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc..

Operation Temperature: -40°C To +85°C.

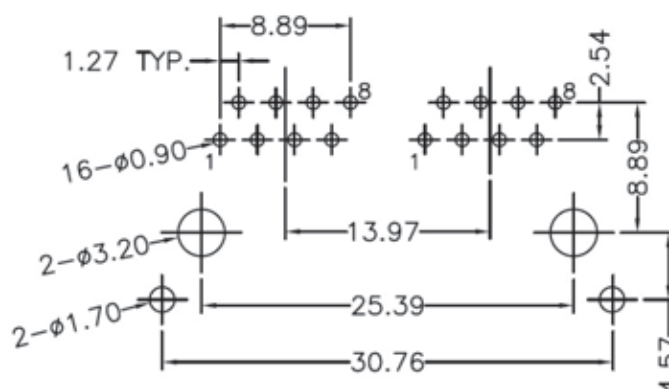
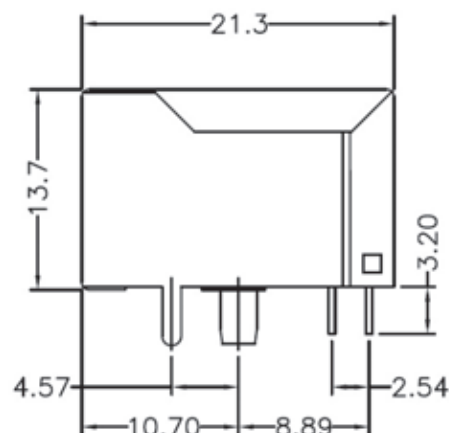
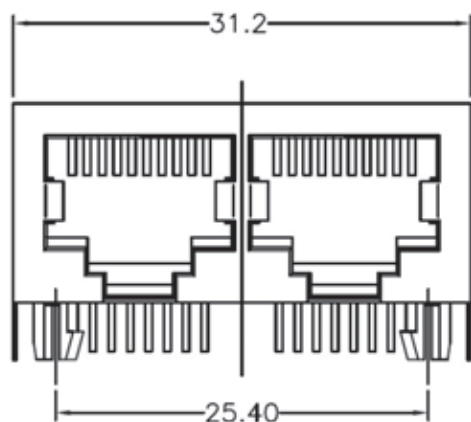
MATERIALS

Housing: PBT(UL 94V-0)

Shell: Copper Alloy,Nickel plating

Terminal: Copper Alloy,Gold Plated

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJSJK - $\frac{08}{1} \times \frac{x}{23} \times \frac{02}{4}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"B" BLACK

"W" WHITE

"N" GREEN

"A" GRAY

"R" RED

"Y" YELLOW

4. NO. OF PORTS:

02

NOTE: IT CAN BE USED FOR REPLACING P/N MJSJ-88xB02.

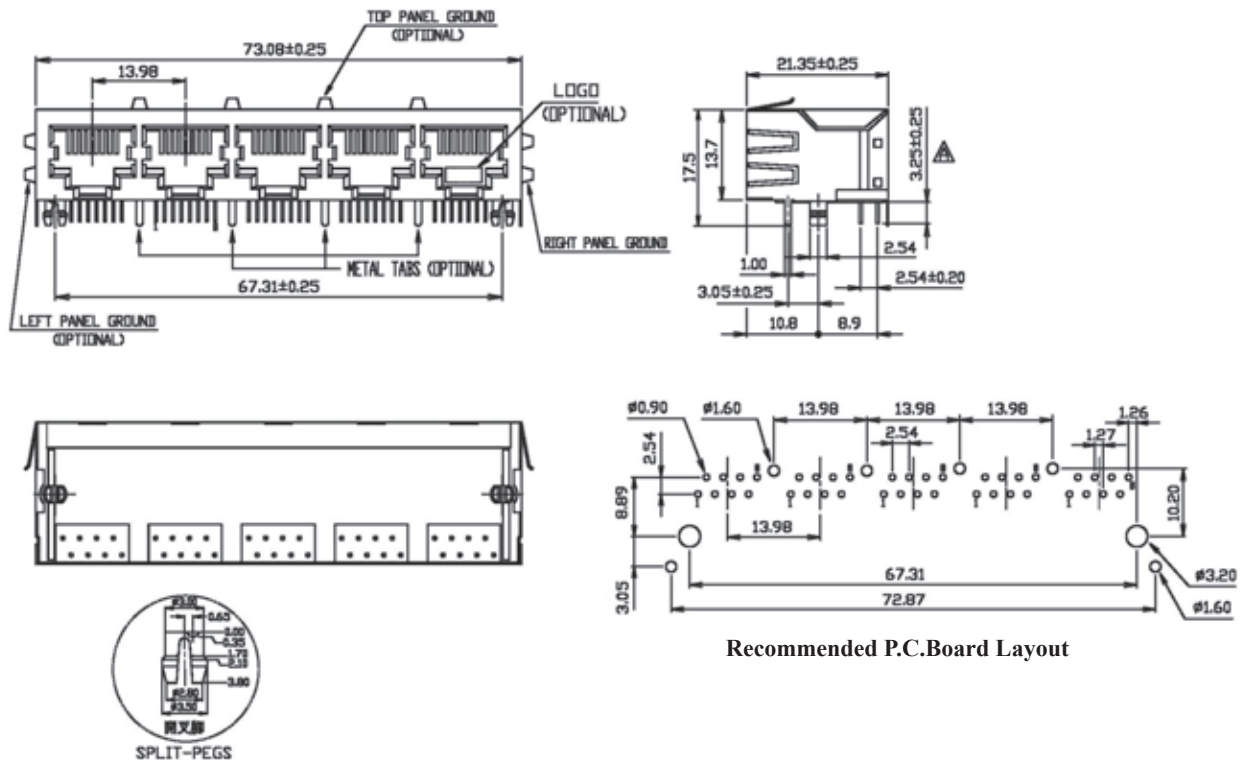
SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$ $\frac{05}{5}$

- MODULAR JACK TYPE:
 "AJ" WITH TOP/RIGHT/LEFT SIDE TABS
 "AK" WITH RIGHT/LEFT TABS
 "AL" WITH TOP SIDE TABS
 "AM" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- NO. OF PORTS:
 05

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

Plastic Housing: Engineering Thermoplastic

Flammability Rating UL 94V-0.

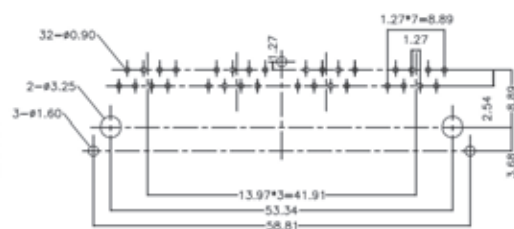
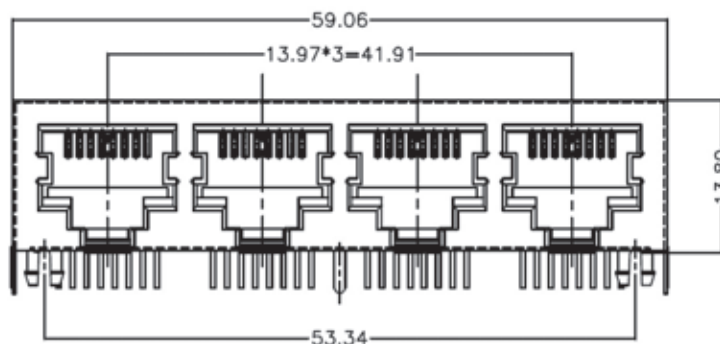
Contacts: 0.35mm Thickness Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,

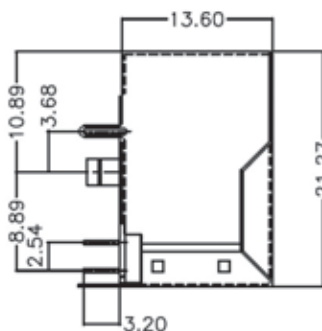
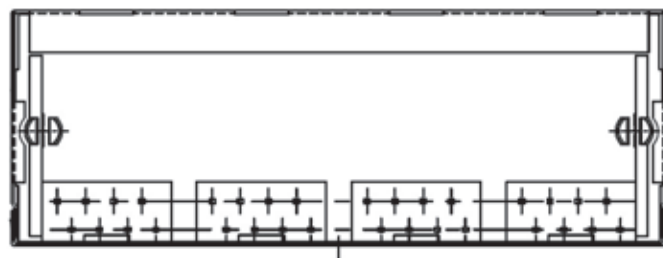
Tin Plating Over Nickel In Solder Area.

Shielded: Brass With Nickel Plated.

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N **M J $\frac{24}{1}$ J - $\frac{88}{2}$ $\frac{x}{3}$ B $\frac{04}{4}$**

1. MODULAR JACK TYPE:
"24J" F3.68 TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. NO. OF PORTS:
04

NOTE: IT CAN BE USED FOR REPLACING P/N MJ24-88xB04.

SIDE ENTRY CAT.5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

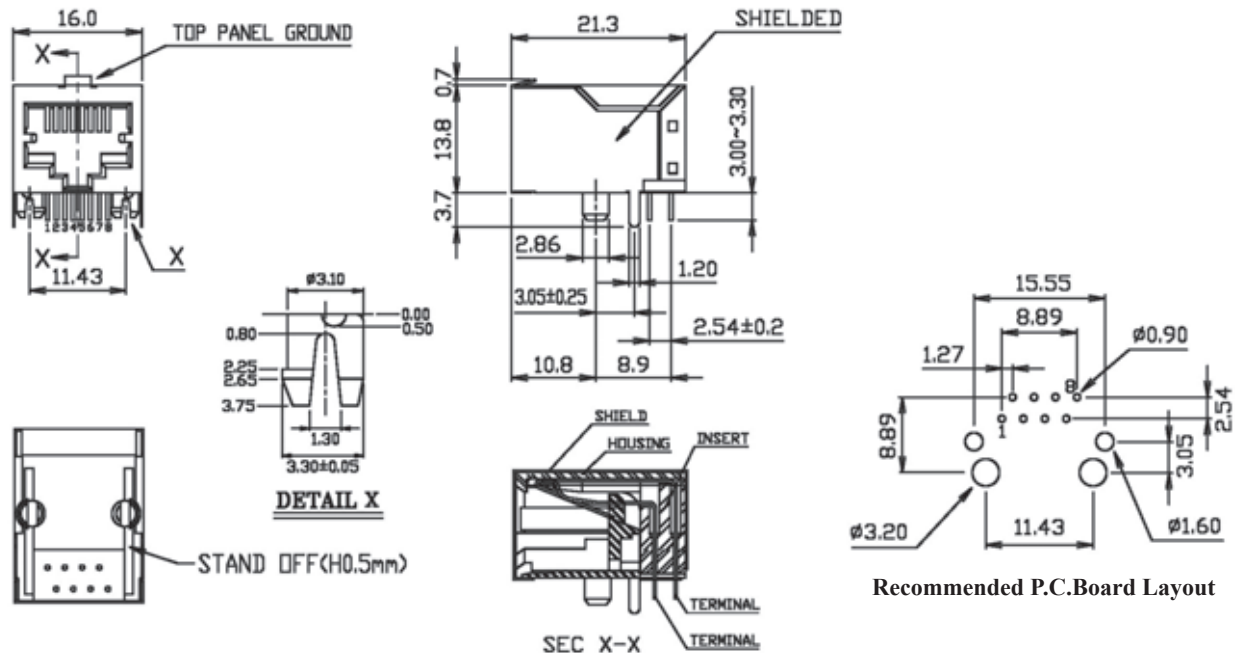
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J NS - 88 X B
 I 2 3 4

1. MODULAR JACK TYPE:
"NS" CAT.5 JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEHIND PEG

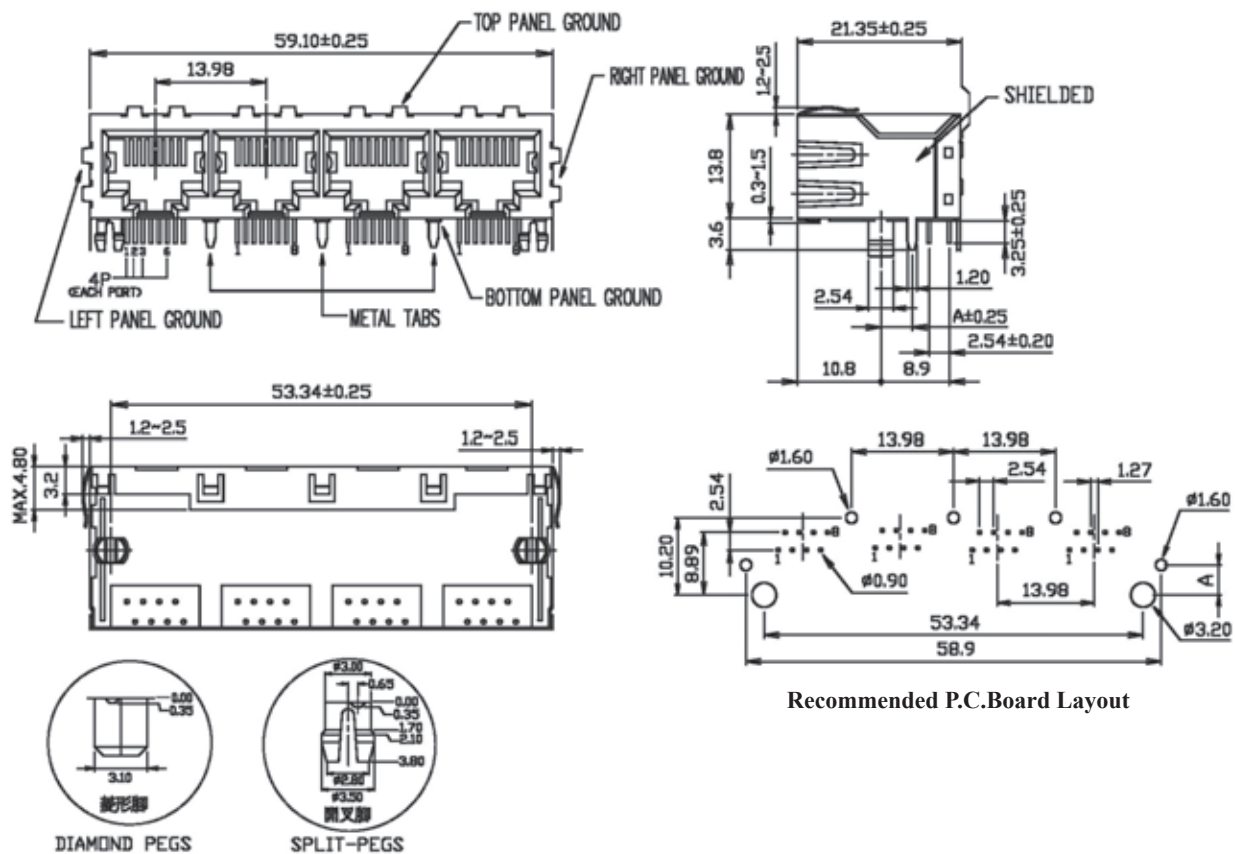
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J KL - 88 x B 04
1 2 3 4 5

- MODULAR JACK TYPE:
"KL" DIM. A=3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- NO. OF PORTS:
04

NOTE: 3.05MM SPACING BEHIND PEG

tel. 02.3361.1626 info@elitaliaweb.it
fax 02.2626.1009 www.elitaliaweb.it

SIDE ENTRY 6-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

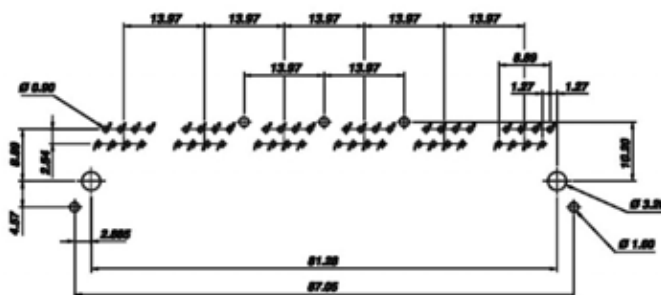
Color: Black

Spring Wire: Phosphor Bronze

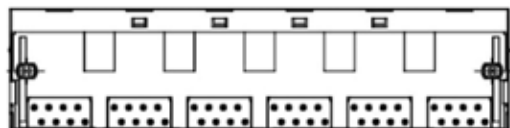
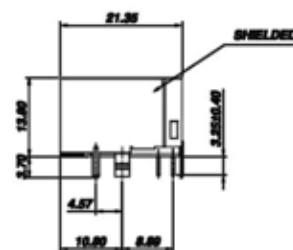
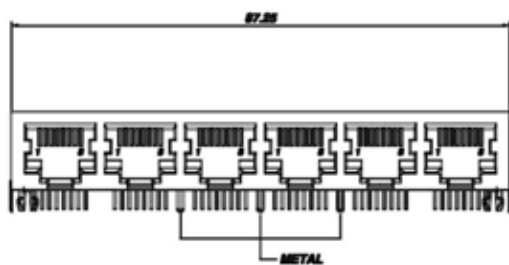
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout (Top View)



ORDERING INFORMATION:

P/N M J S J A - $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
06

NOTE: 4.57MM SPACING BEFORE PEG

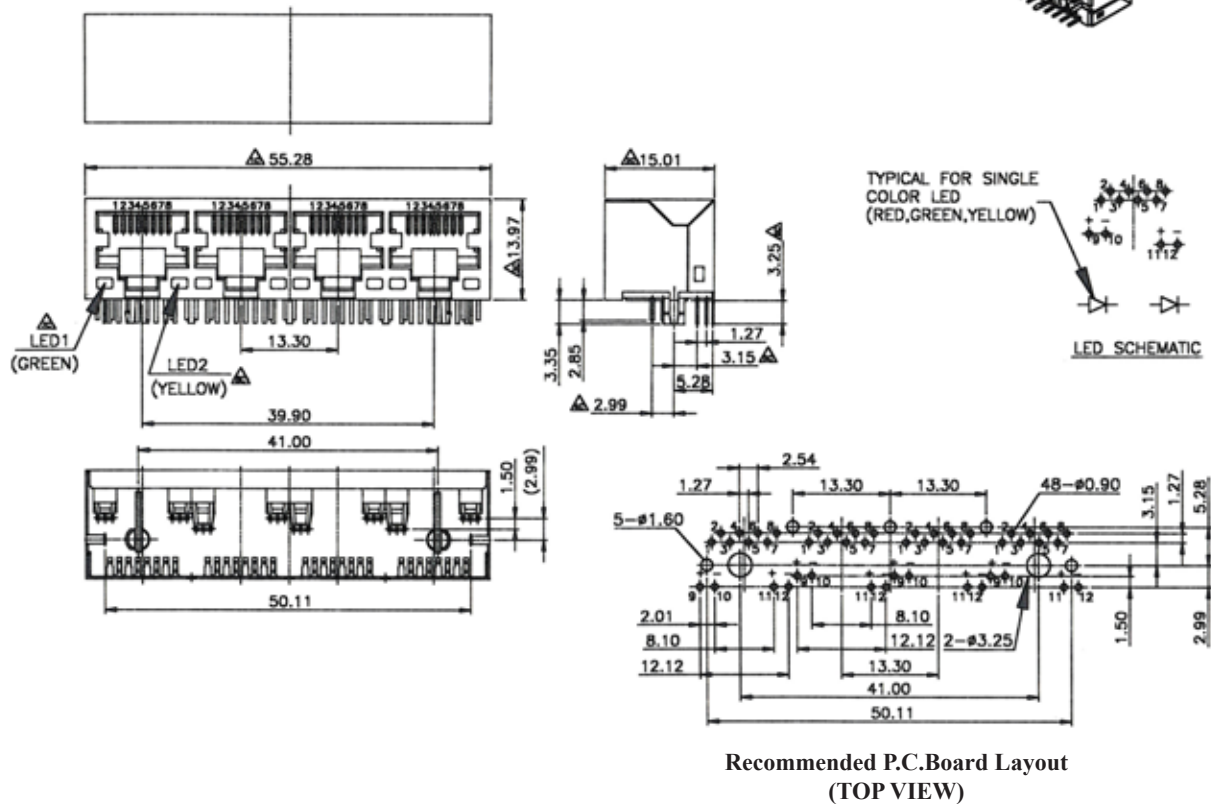
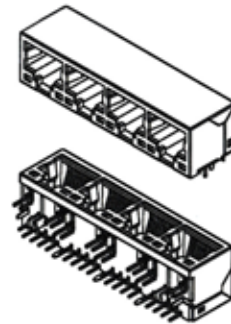
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P WITH LED PROFILE=13.97MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Y N - 8 8 x B x x 0 4
 1 2 3 4 5

- MODULAR JACK TYPE:
"YN" 4-PORT JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

- COLORS OF LED:
"NN" LED1: GREEN & LED2: GREEN
"NY" LED1: GREEN & LED2: YELLOW
"YN" LED1: YELLOW & LED2: GREEN
"YY" LED1: YELLOW & LED2: YELLOW
"XX" W/O LED
- NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

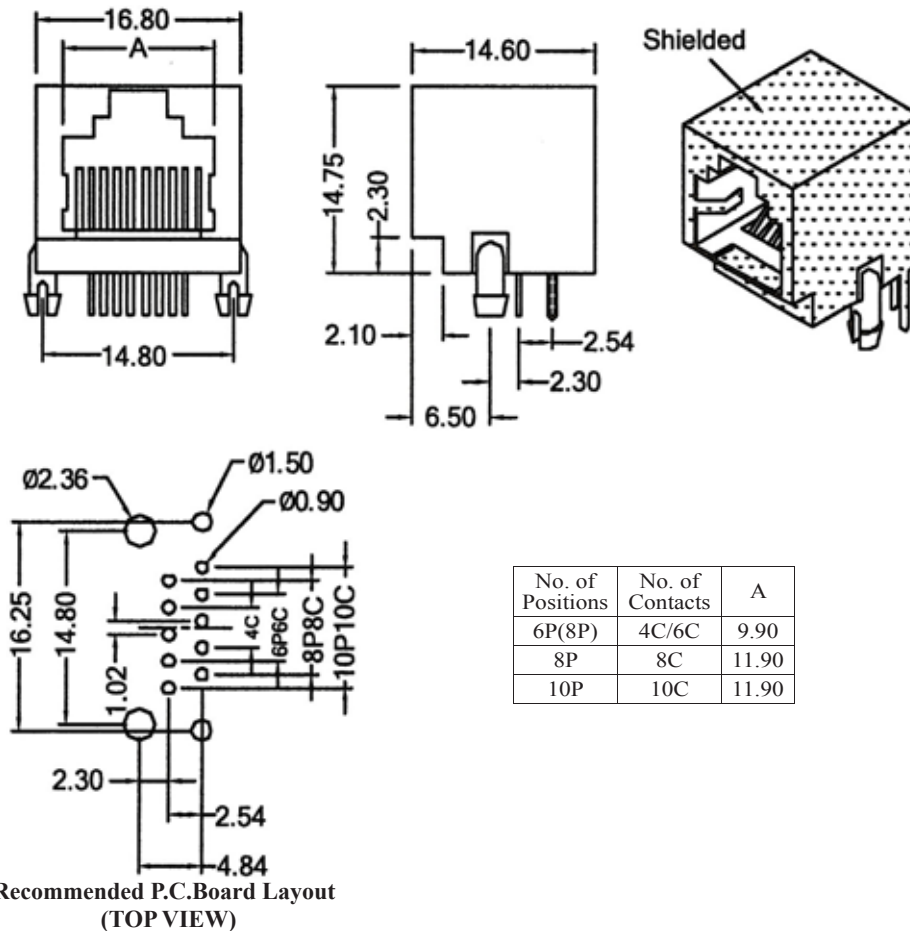
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P+8P+10P PROFILE=14.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R 9 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

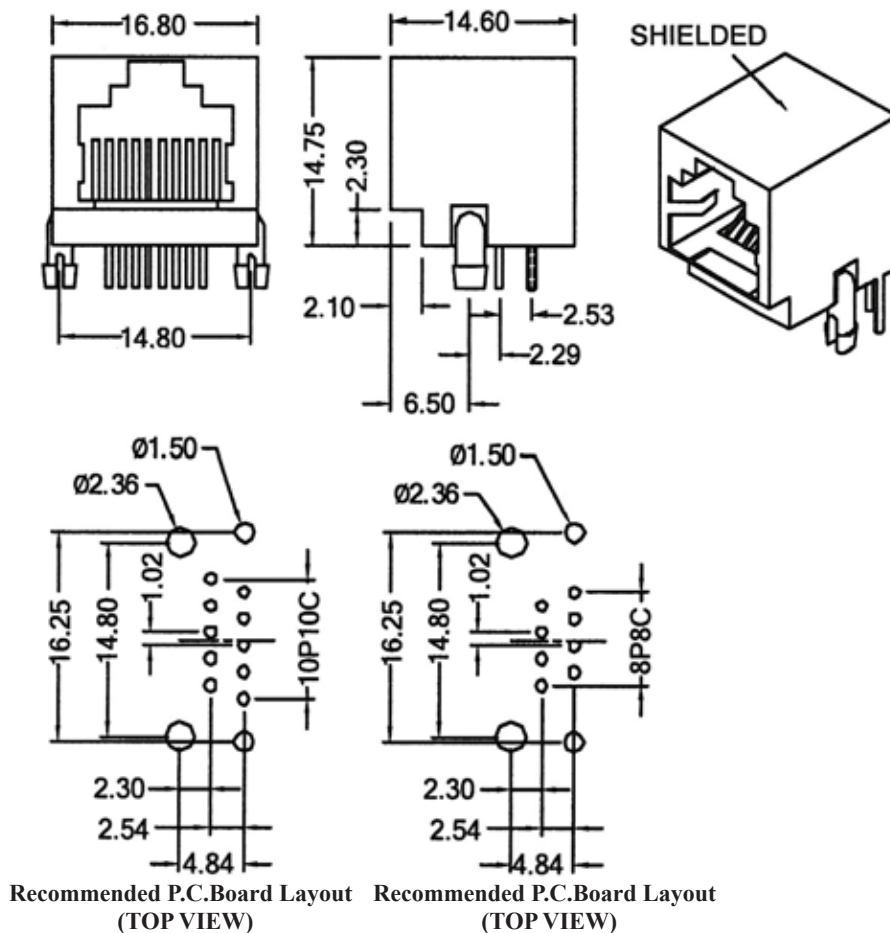
Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S 2 - $\frac{x x x x}{T 2 3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=14.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

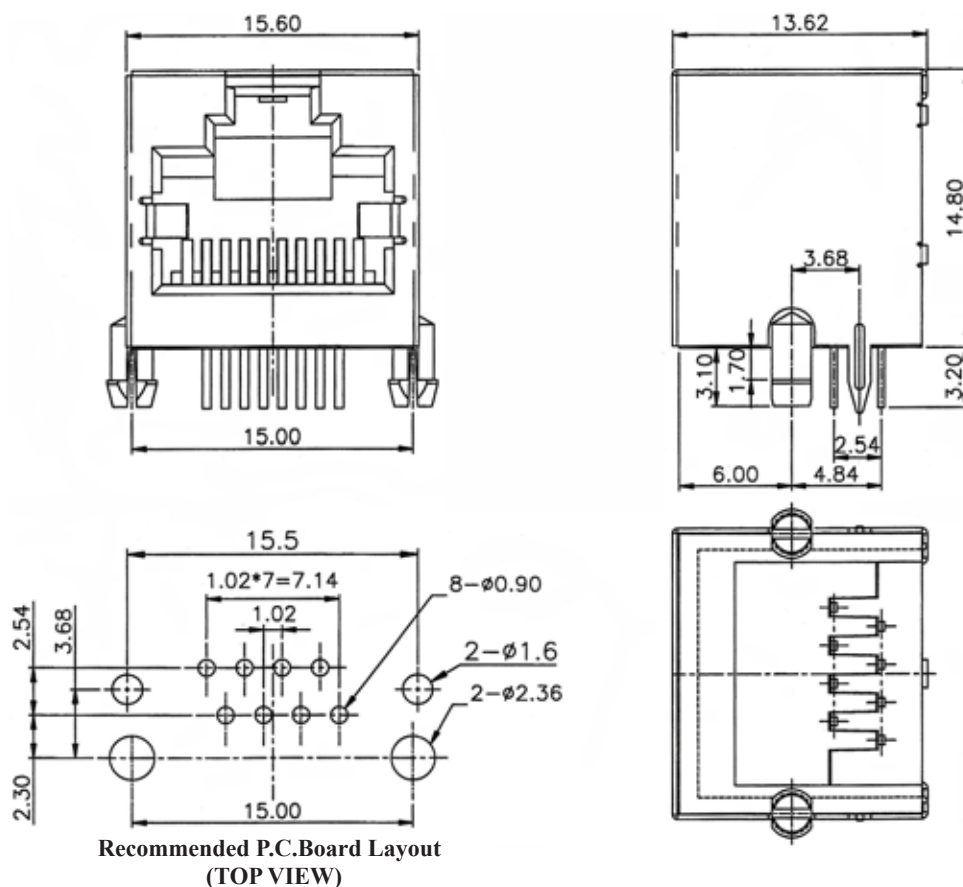
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 M - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

SIDE ENTRY UP LATCH MODULAR PCB JACK PIN REVERSED TYPE 8P PROFILE=14.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

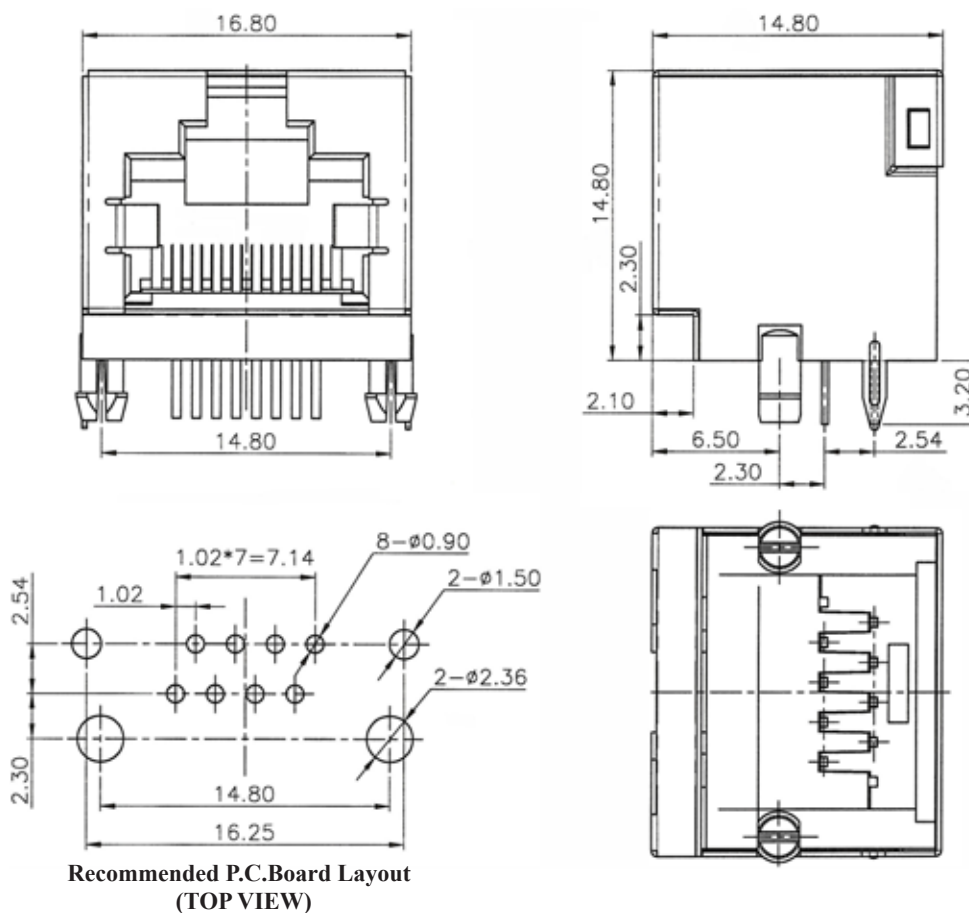
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 S - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: PIN REVERSED TYPE

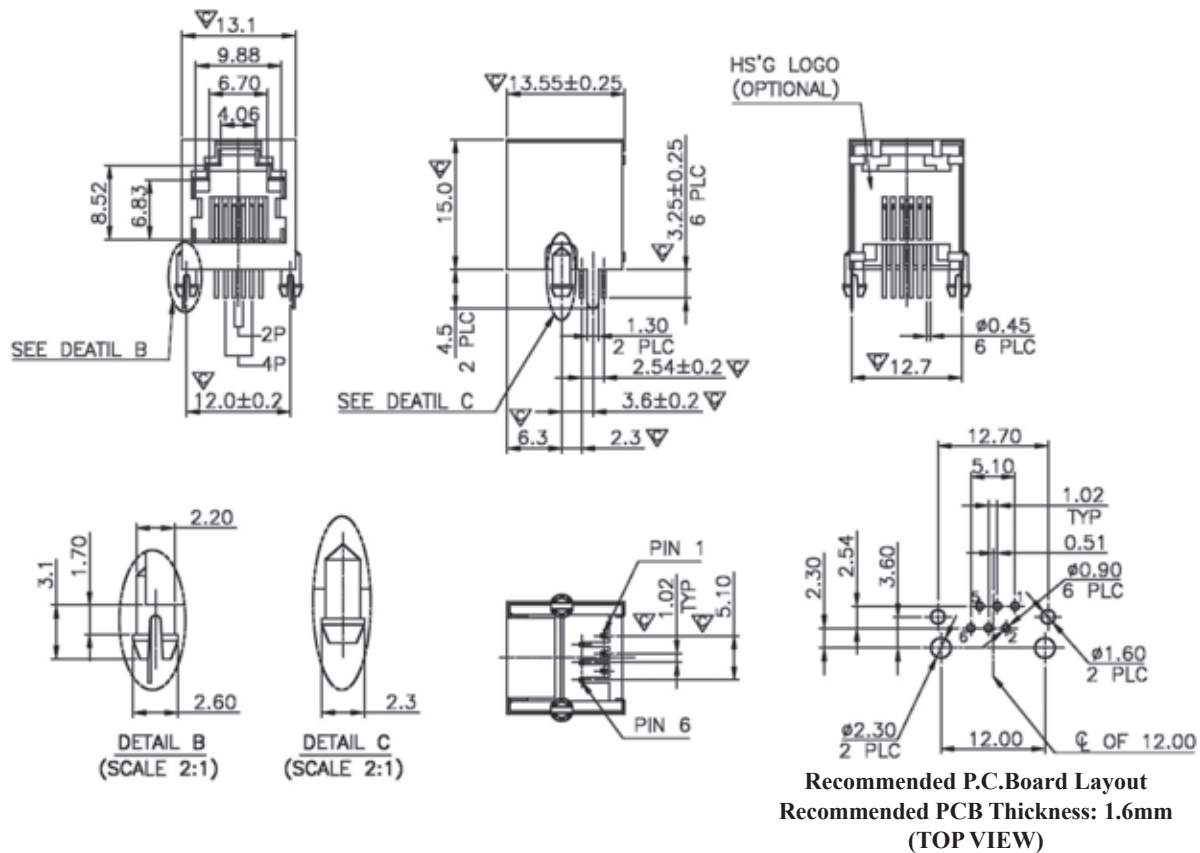
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=15.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{VY}{I} - \frac{66}{2} \times \frac{x}{3} \times \frac{x}{4}$

- MODULAR JACK TYPE:
"VY" MINI LOW PROFILE TYPE WITH SHELL
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P+6P PROFILE=21.50MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

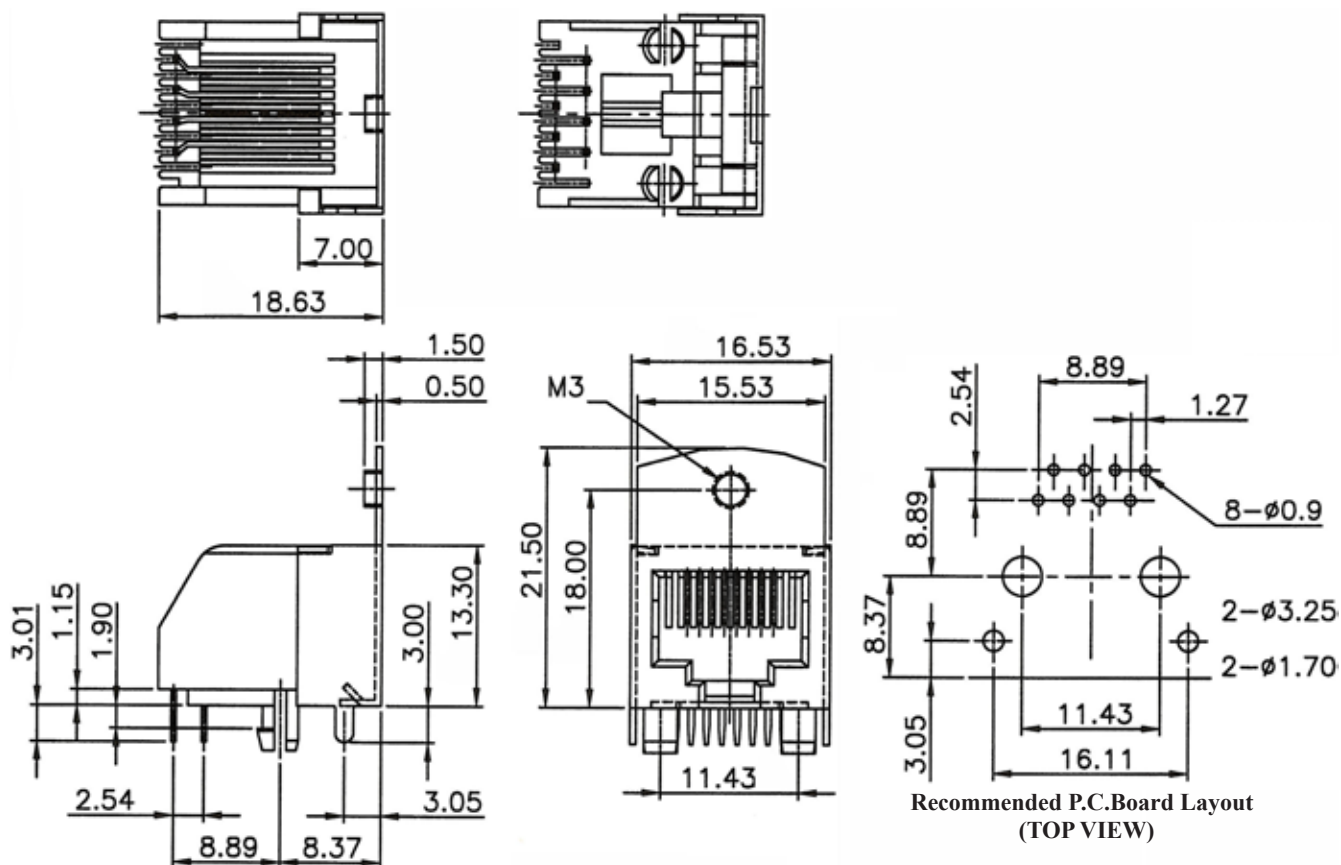
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 W - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION (FOR 8P ONLY):

" " W/O KEYWAY

"K" WITH KEYWAY

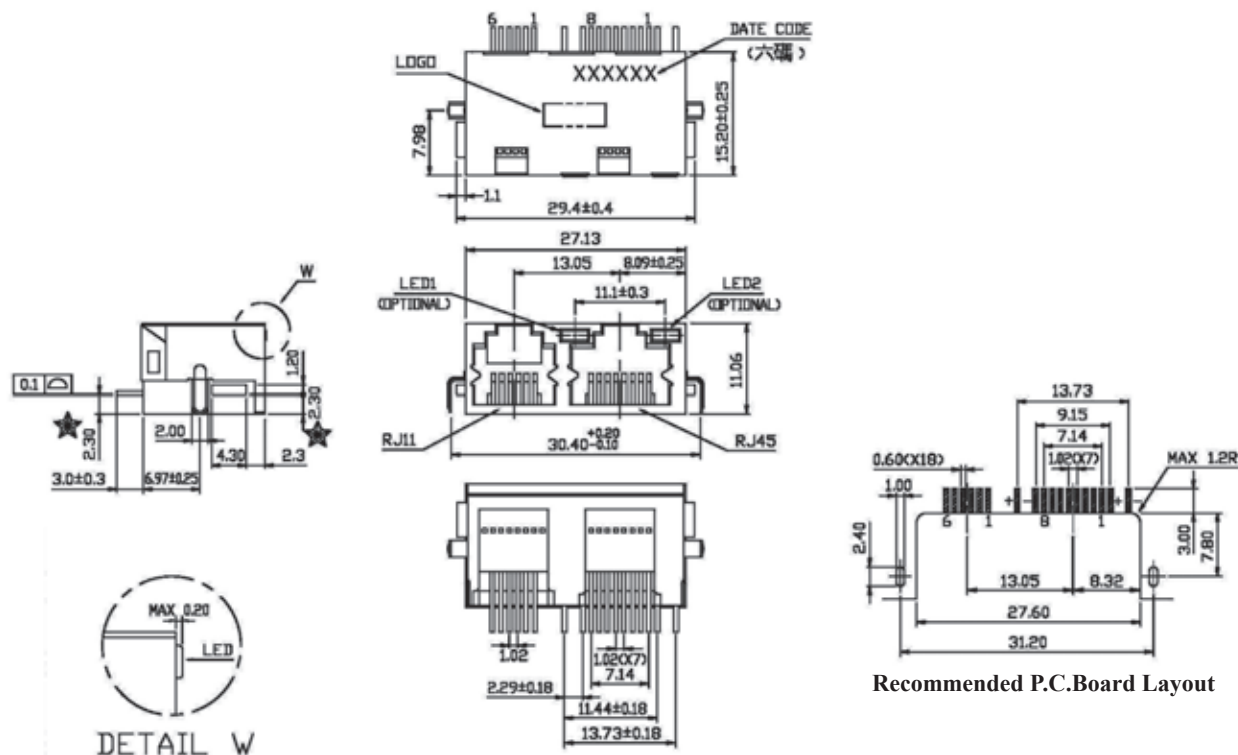
SIDE ENTRY 2-PORT EMBEDDED STANDARD MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J F U - 6 8 X B X X 0 2
1 2 3 4 5

- MODULAR JACK TYPE:
"FU" EMBEDDED SMT TYPE (2.30MM)
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPOM REQUEST!

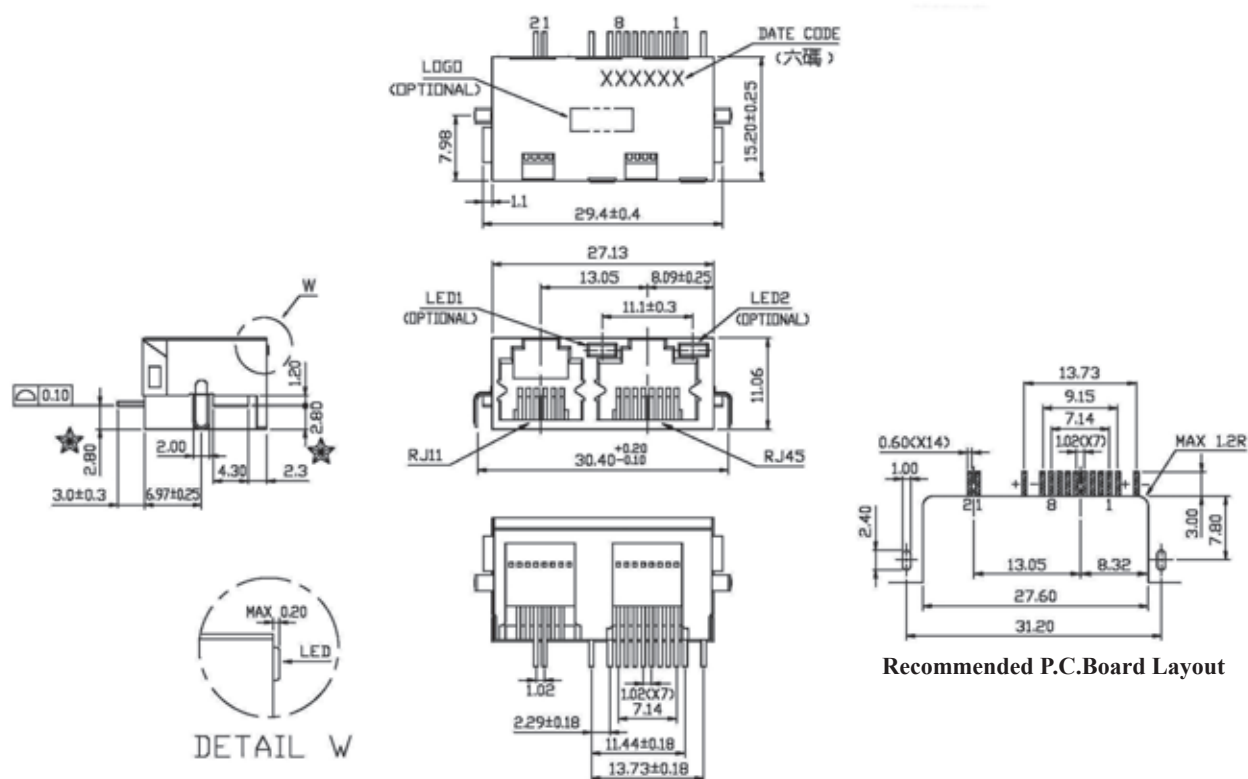
SIDE ENTRY 2-PORT EMBEDDED STANDARD MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J F V - 6 8 x B x x 0 2
1 2 3 4 5

- MODULAR JACK TYPE:
"FV" EMBEDDED SMT TYPE (2.80MM)
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

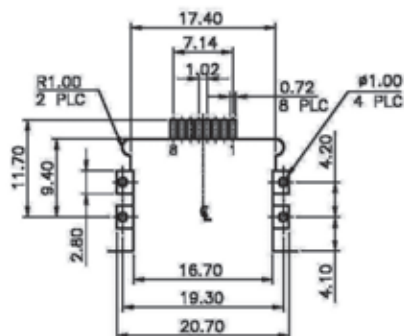
Color: Black

Spring Wire: Phosphor Bronze

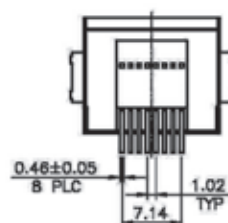
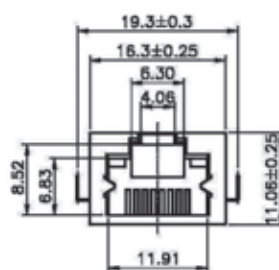
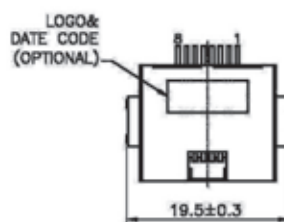
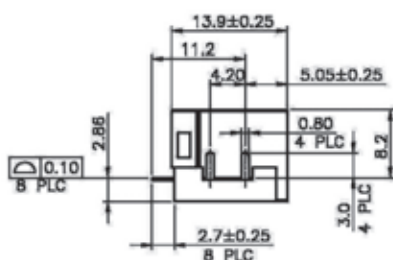
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{FR}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

- MODULAR JACK TYPE:
"FR" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

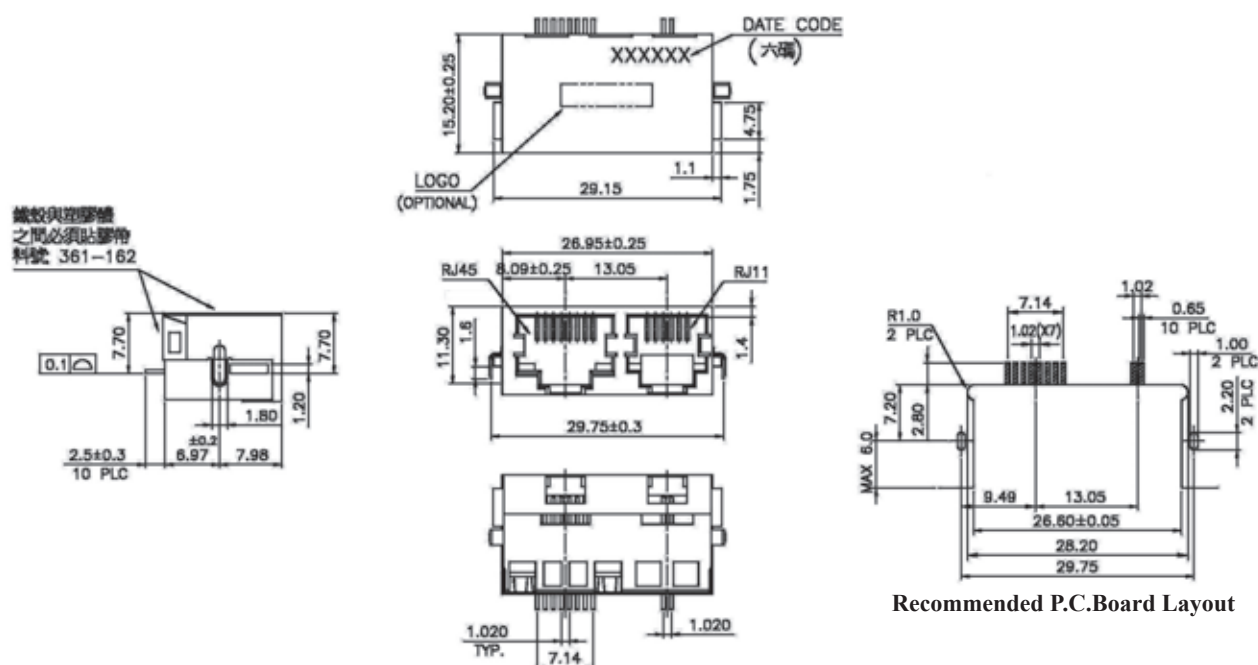
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR SMT JACK 6P+8P PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J FS - 68 x B 02
 1 2 3 4

- MODULAR JACK TYPE:
"FS" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02

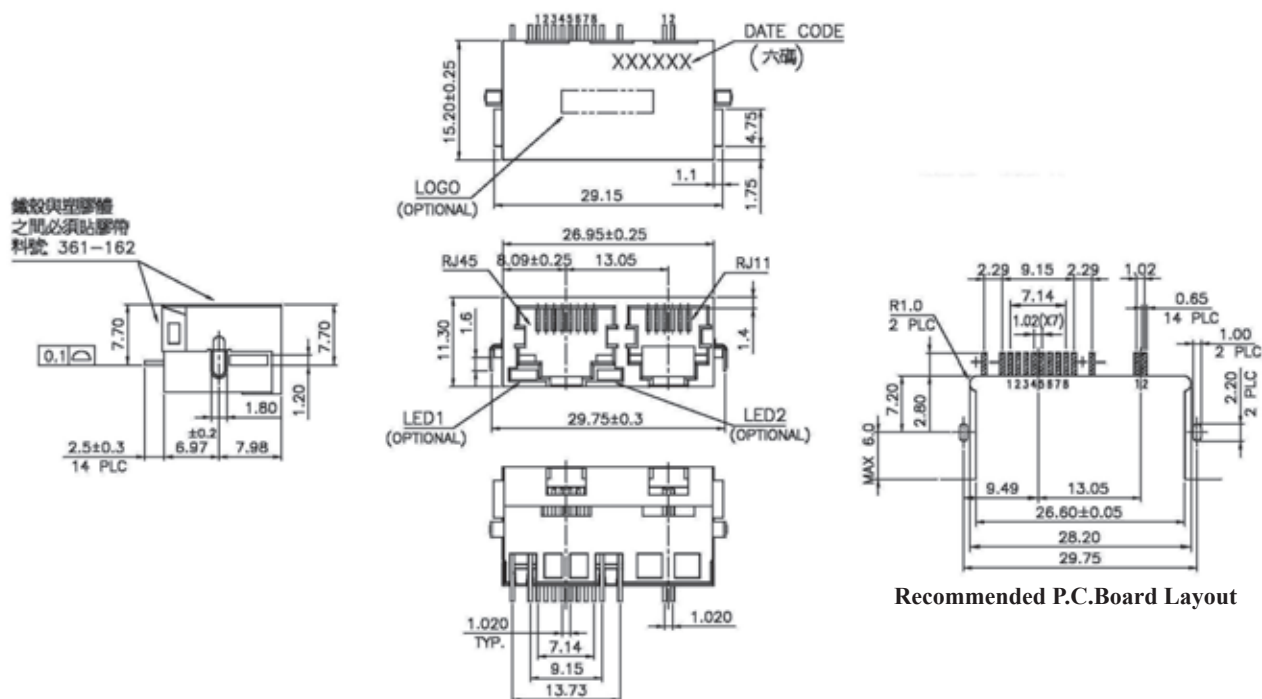
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J FT - 68 X B X X 02
1 2 3 4 5

- MODULAR JACK TYPE:
"FT" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

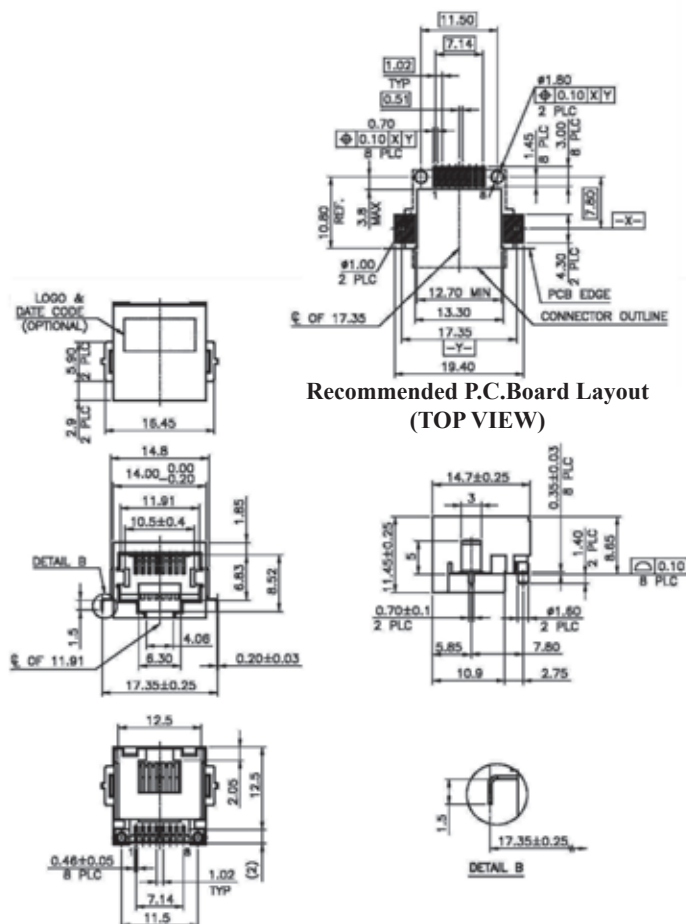
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J F W - $\frac{88}{1} \frac{x}{2} \frac{B}{3} - \frac{x}{4}$

- MODULAR JACK TYPE:
"FW" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

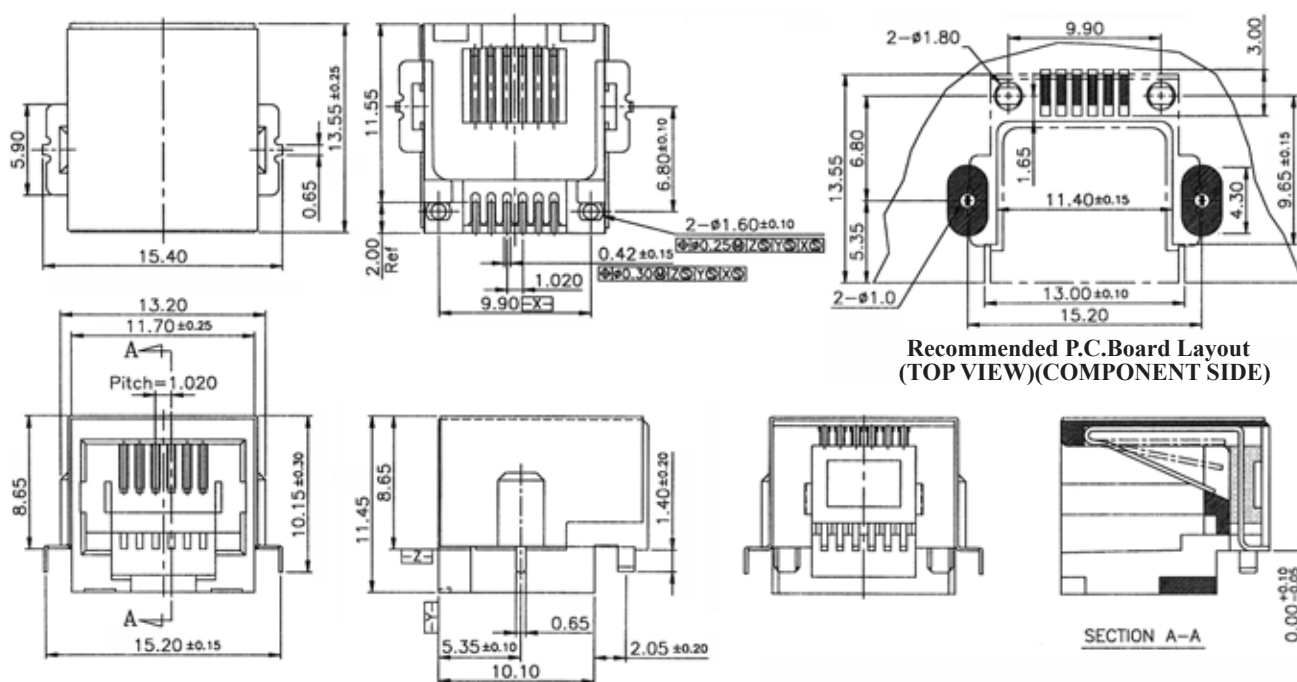
SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 Z - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- PACKAGE OPTION:
 " " TRAY
 "R" TAPE & REEL

SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

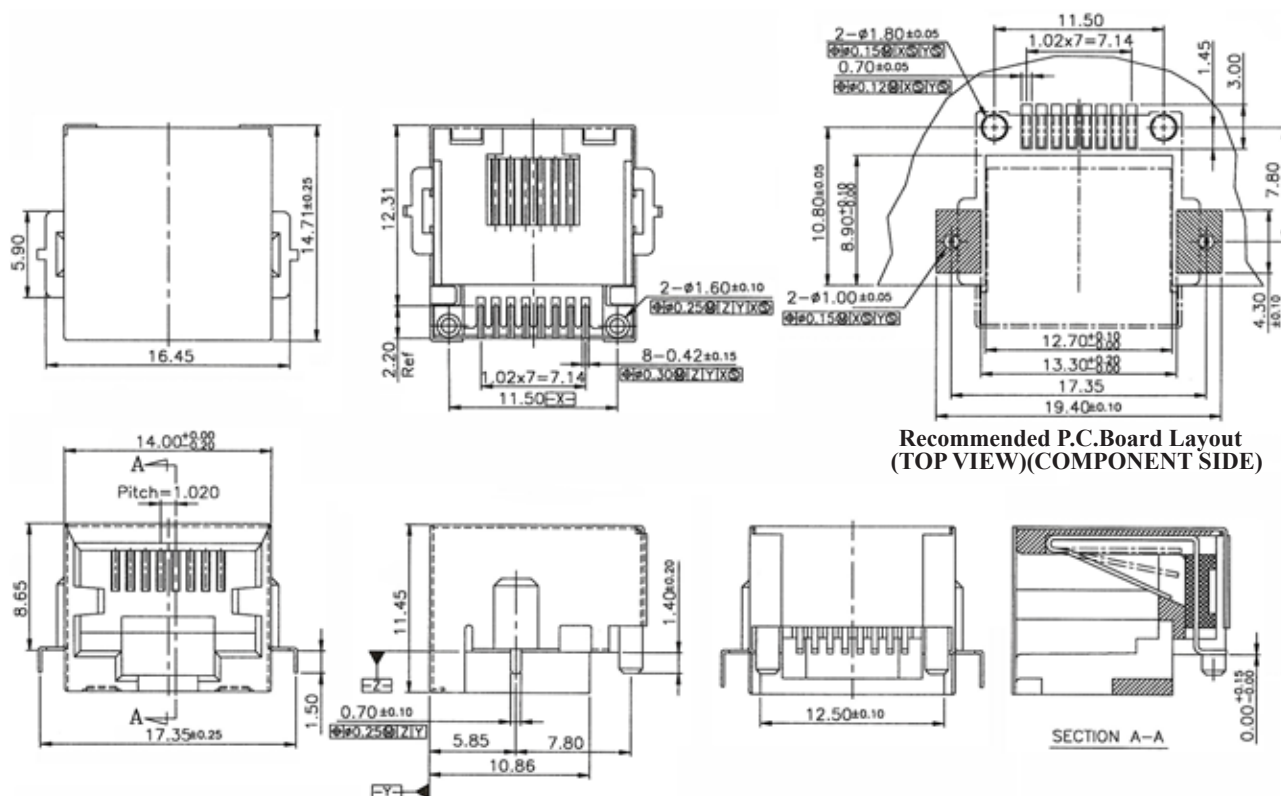
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 Z - $\frac{88}{1} \frac{x}{2} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK REVERSE MOUNT TYPE 8P PROFILE=11.50MM (FULLY SHIELDED)

SPECIFICATIONS

Current Rating: 1.5 Amp Max.

Dielectric Withstanding: 500 Vac For 1 Min.

Contact Resistance: 30m Ohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc..

Operation Temperature: -40°C To +85°C.

MATERIALS

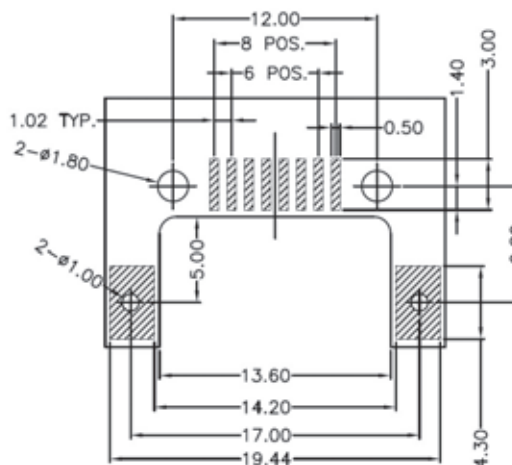
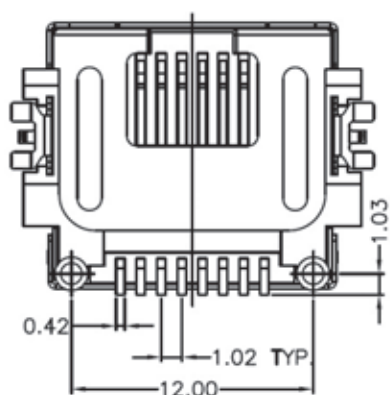
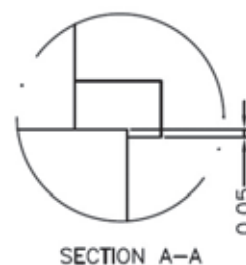
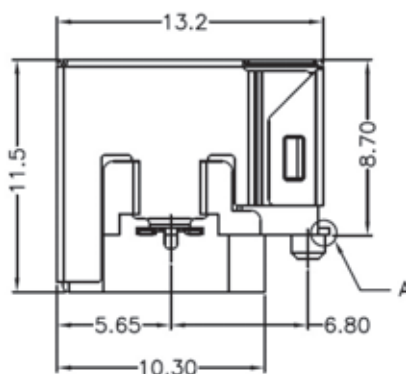
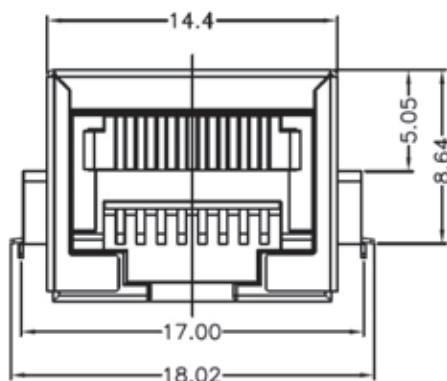
Housing: High Temp. Plastic(UL 94V-0)

Shell: Copper Alloy,Nickel plating

Peg: Copper Alloy,Tin Plated

Terminal: Copper Alloy,Gold Plated

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 9S- x x x x
T 2 3 4

- MODULAR JACK TYPE:
"9S" BOARD CUT REVERSE MOUNT TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH

- HOUSING COLOR:
"B" BLACK
"W" WHITE
"N" GREEN
"A" GRAY
"P" PINK
"O" ORANGE

SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

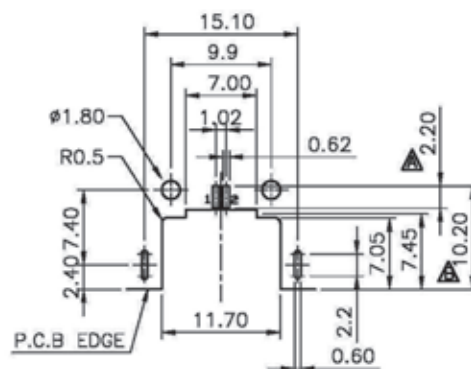
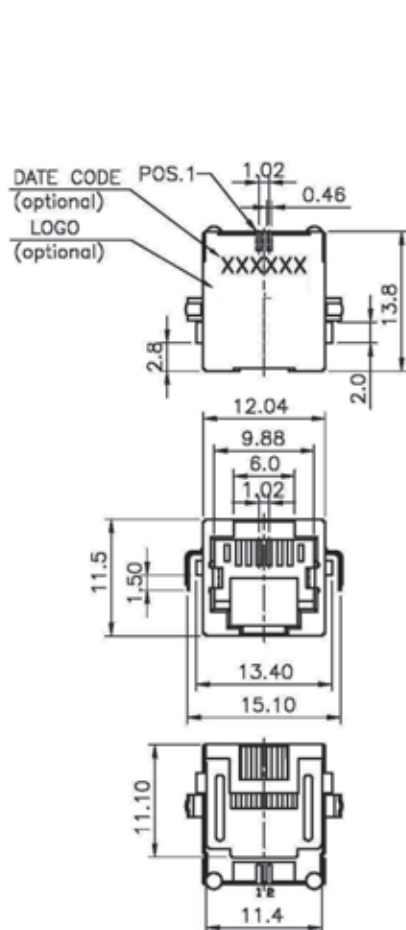
Color: Black

Spring Wire: Phosphor Bronze

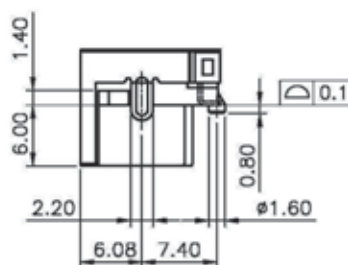
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{FW}{1}$ - $\frac{62}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FW" EMBEDDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"62" 6P2C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

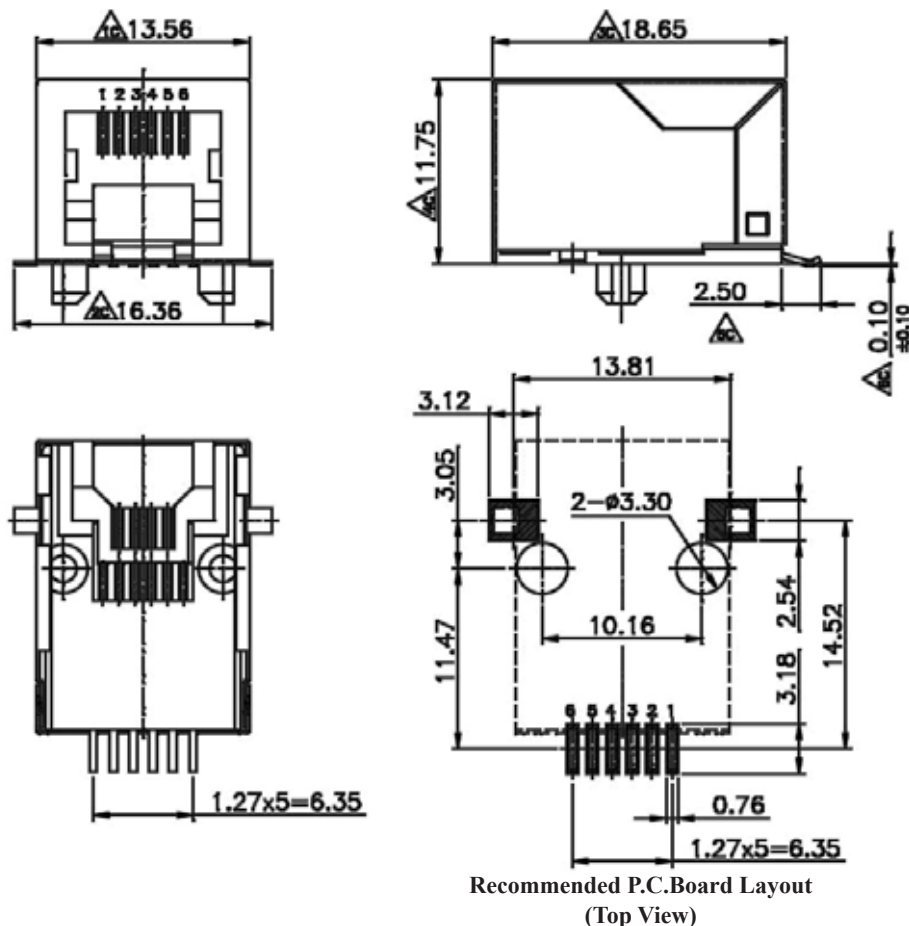
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ19 - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE TYPE:

" " TRAY

"R" TAPE & REEL

NOTE 1: P/N MJ19-66xB9T WITH INSULATOR PA-9T

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

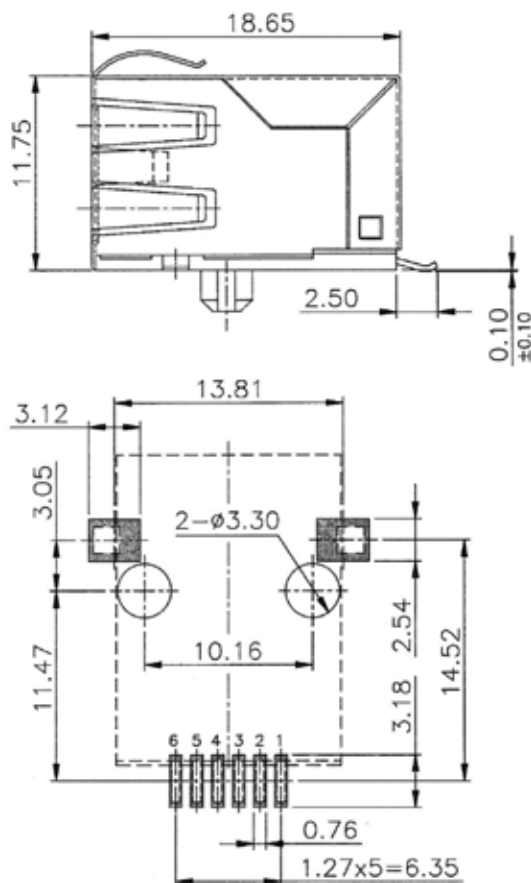
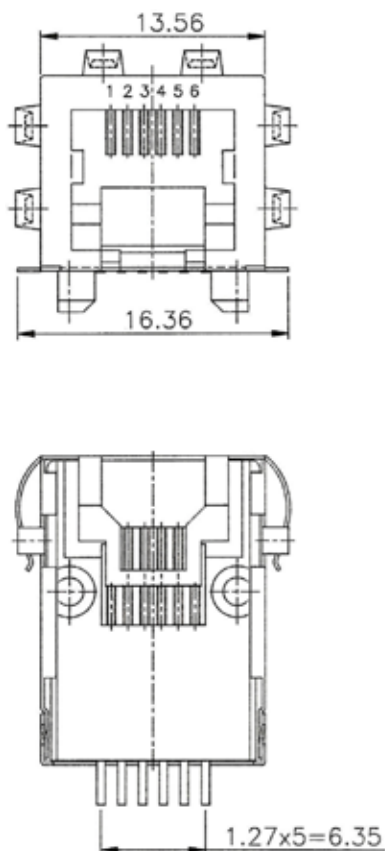
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J 2 Z - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

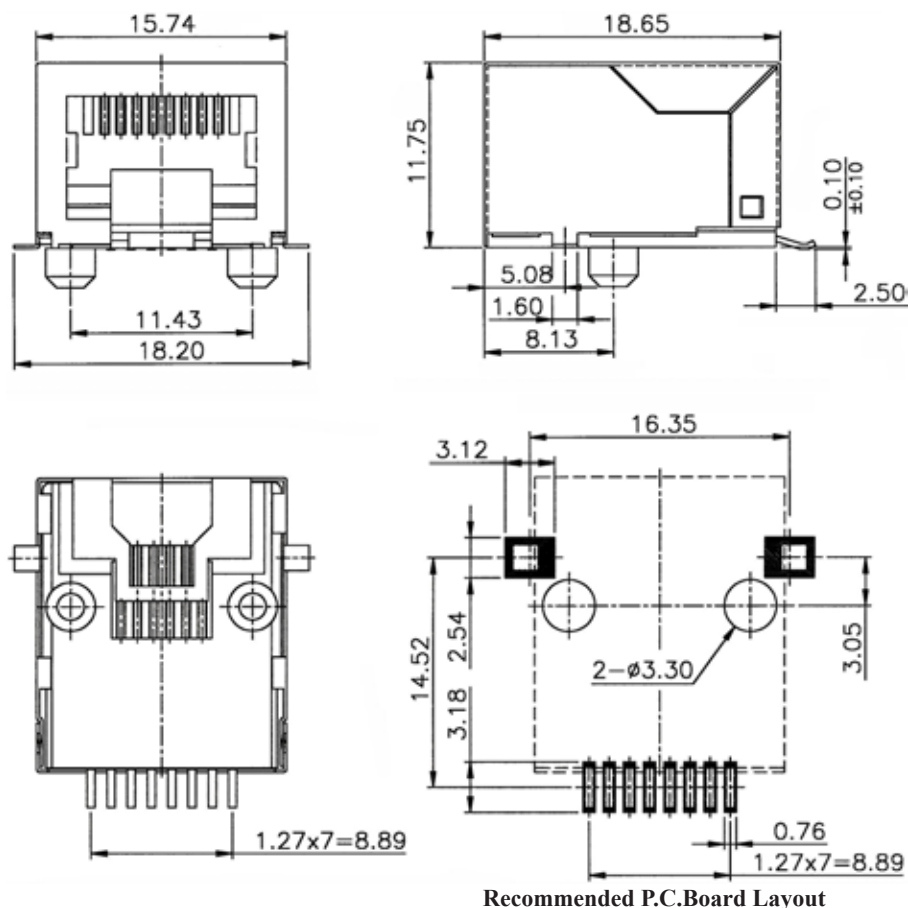
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 9 - $\frac{x}{T} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C (5~10 Seconds)

MATERIALS

Plastic Housing: High Temp. Thermoplastic

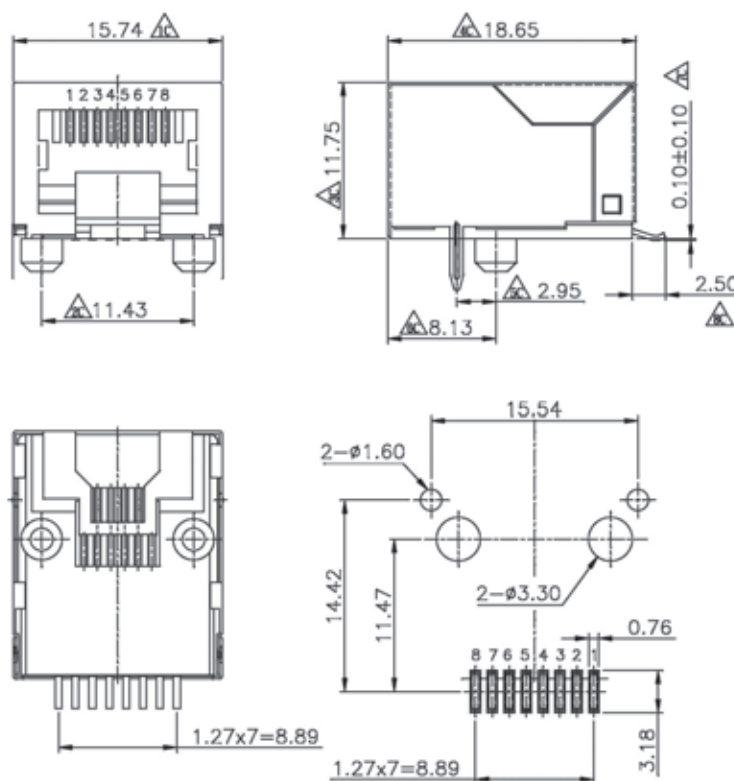
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{6}{1}$ G - $\frac{88}{23}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6G" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: 2.95MM SPACING BEFORE PEGS

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

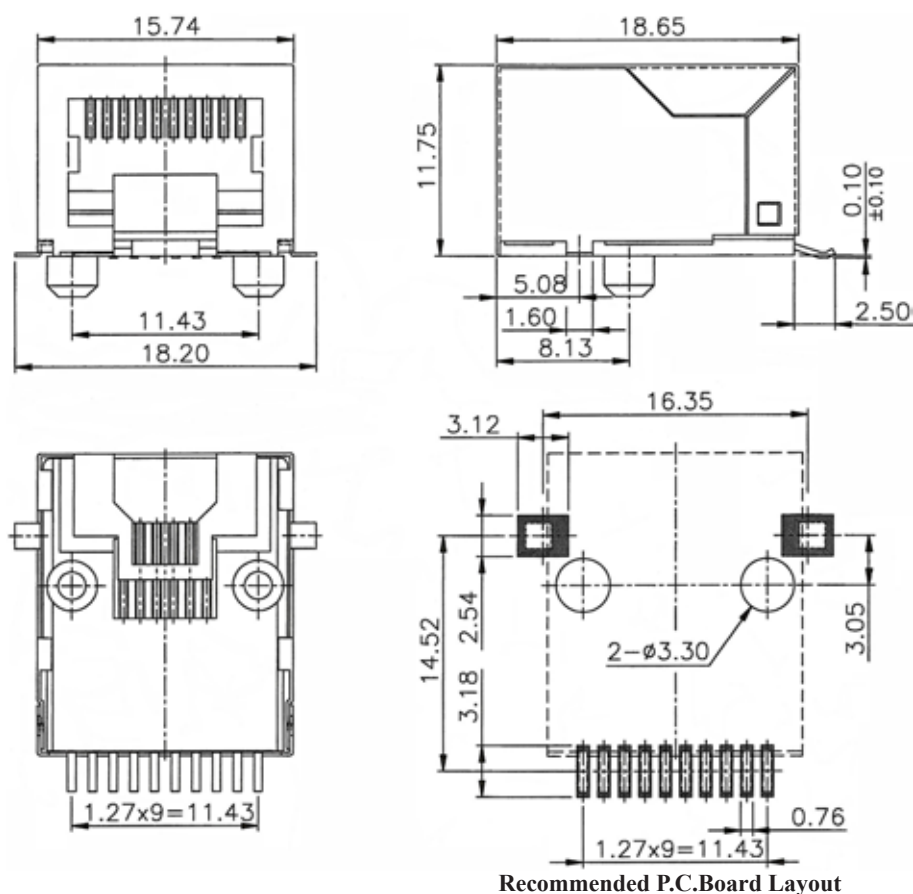
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 9 - $\frac{x}{T} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

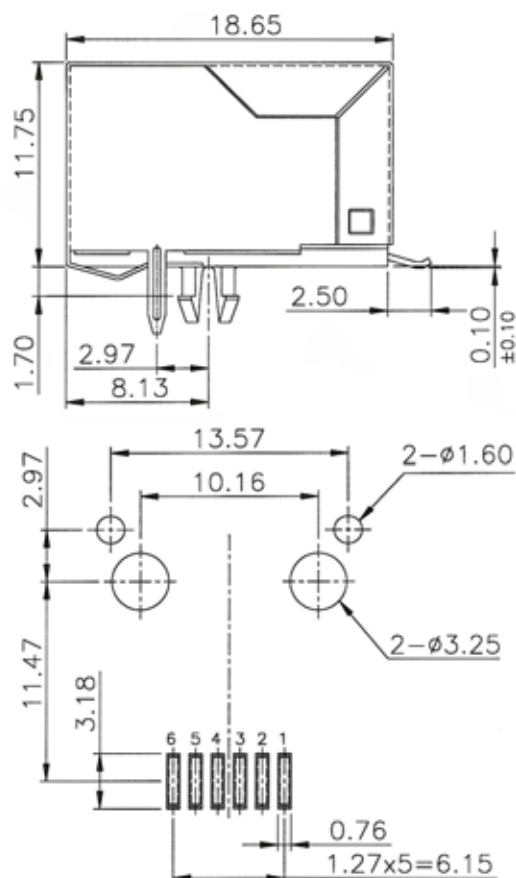
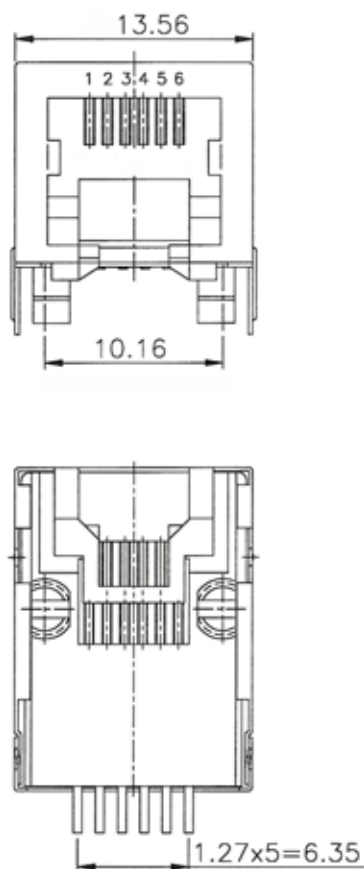
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

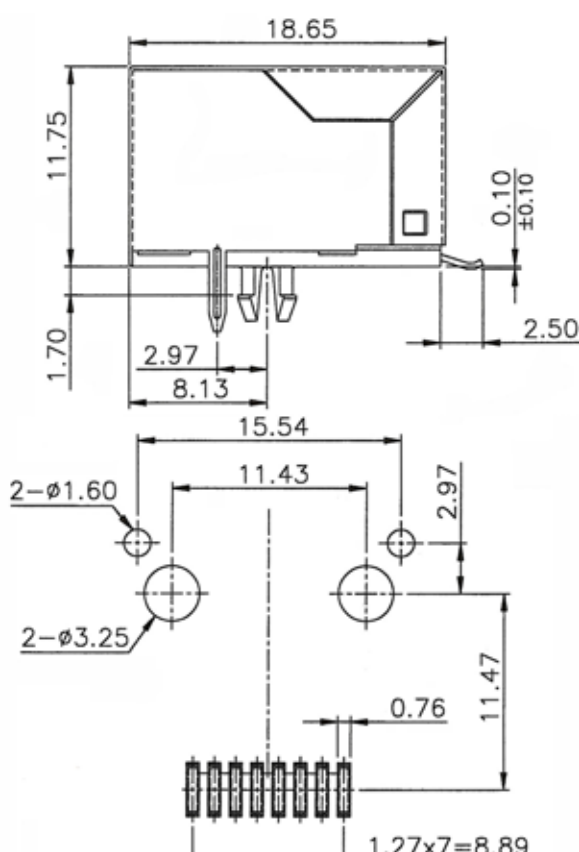
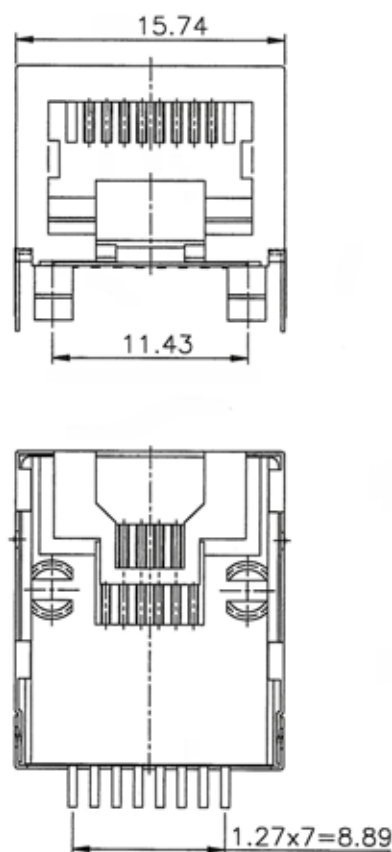
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C (5~10 Seconds)

MATERIALS

Plastic Housing: High Temp. Thermoplastic

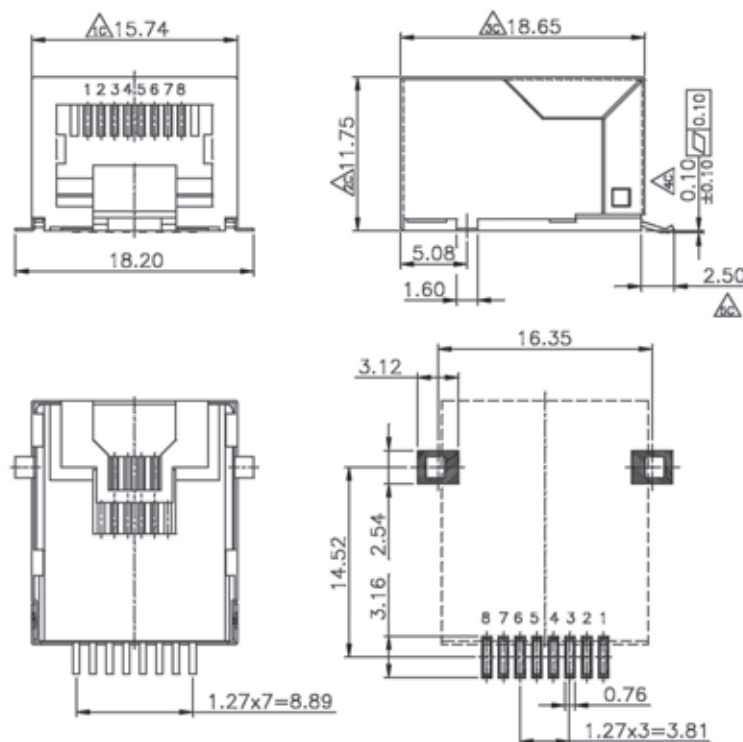
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{6F}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6F" SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: WITHOUT LOCATING PEGS

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

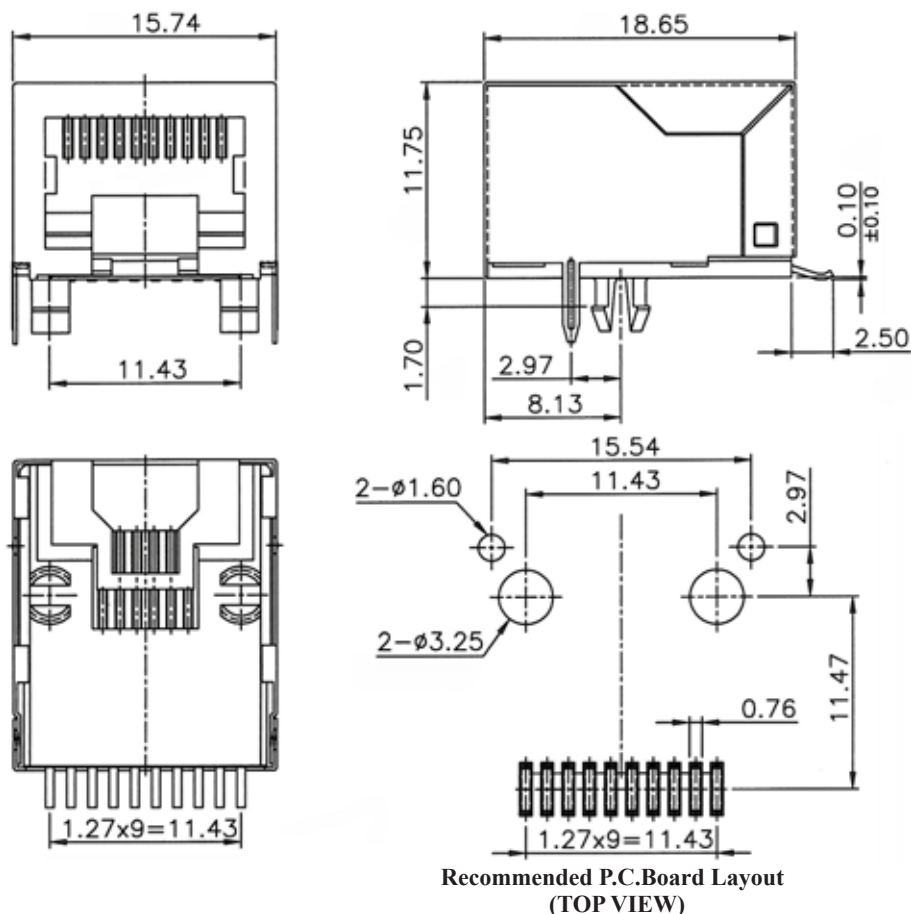
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

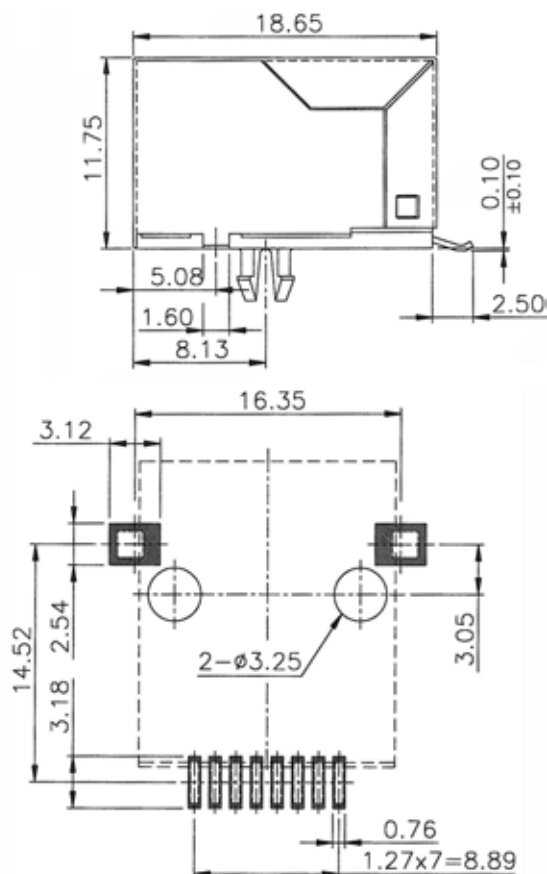
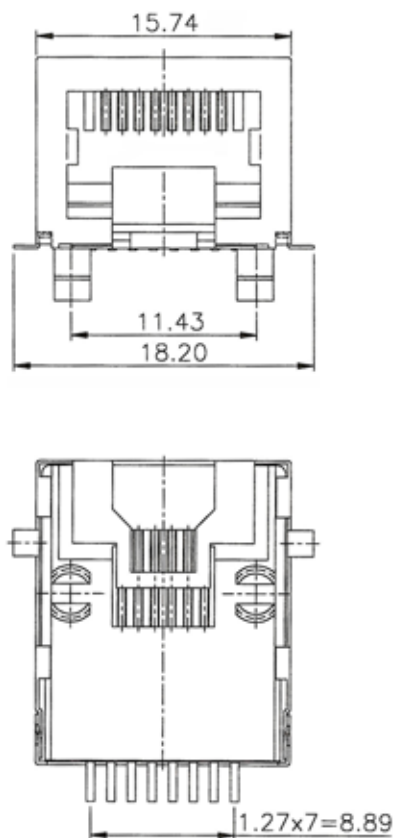
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 8 N - $\frac{88}{1} \frac{x}{2} B \frac{x}{3} - \frac{x}{4}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

4. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

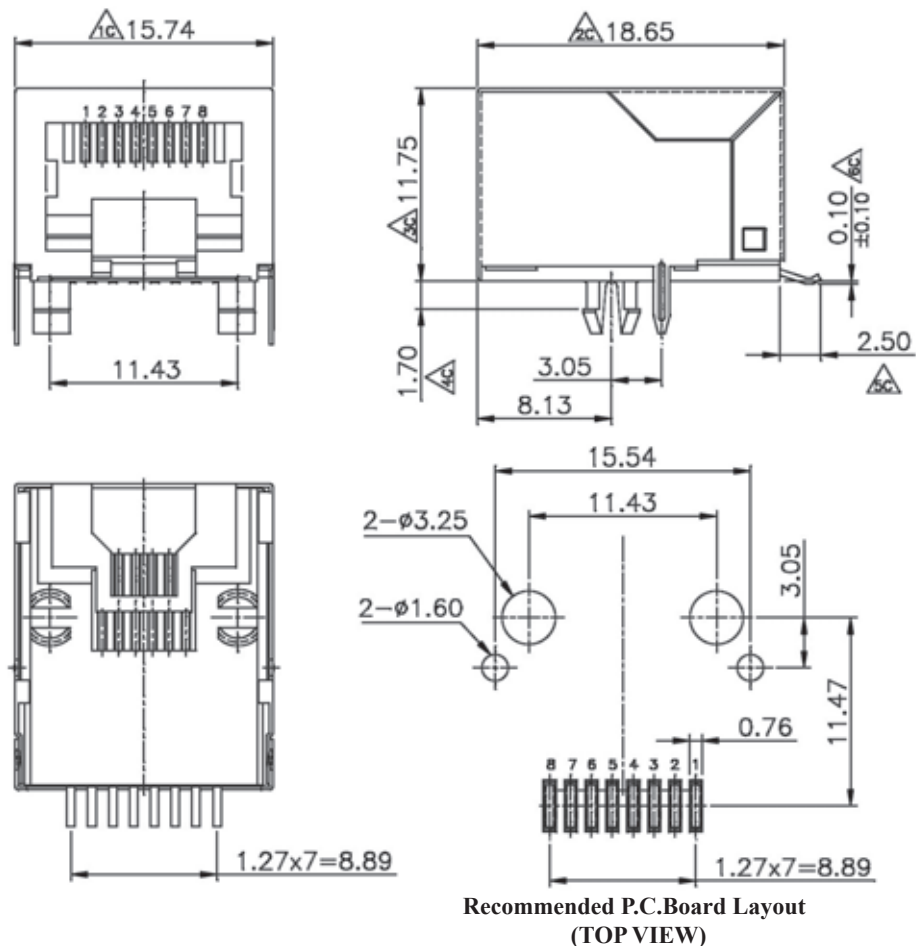
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{6}{1}$ H - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6H" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

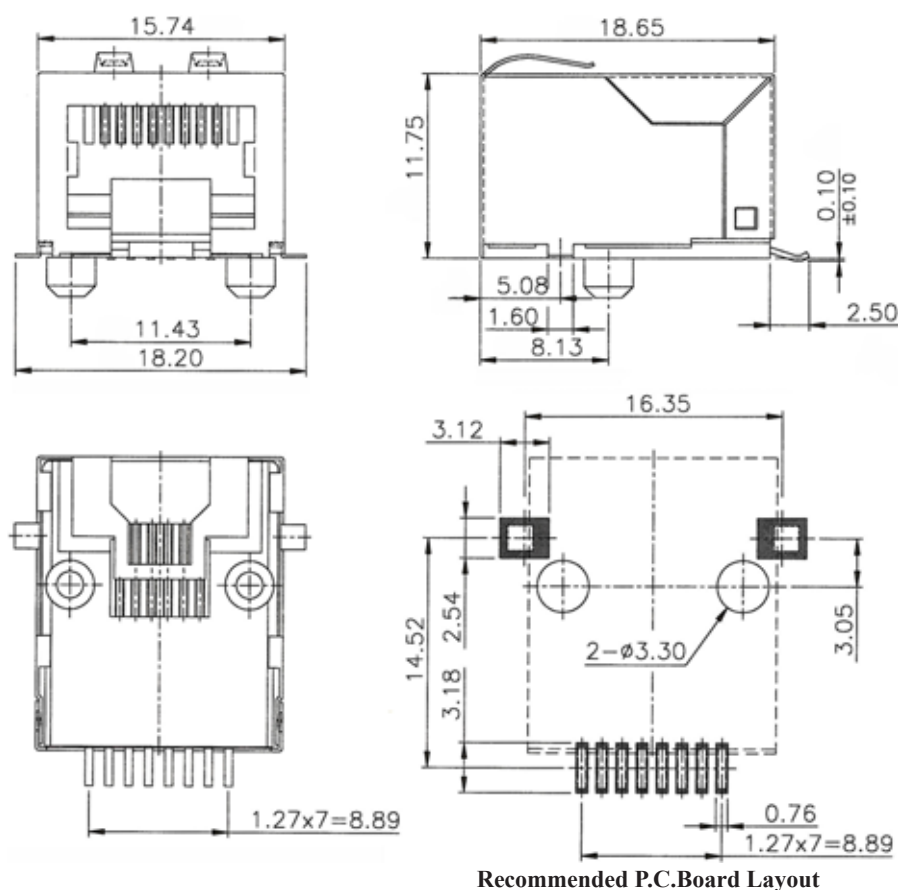
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 W - $\frac{88}{1} \frac{x}{2} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

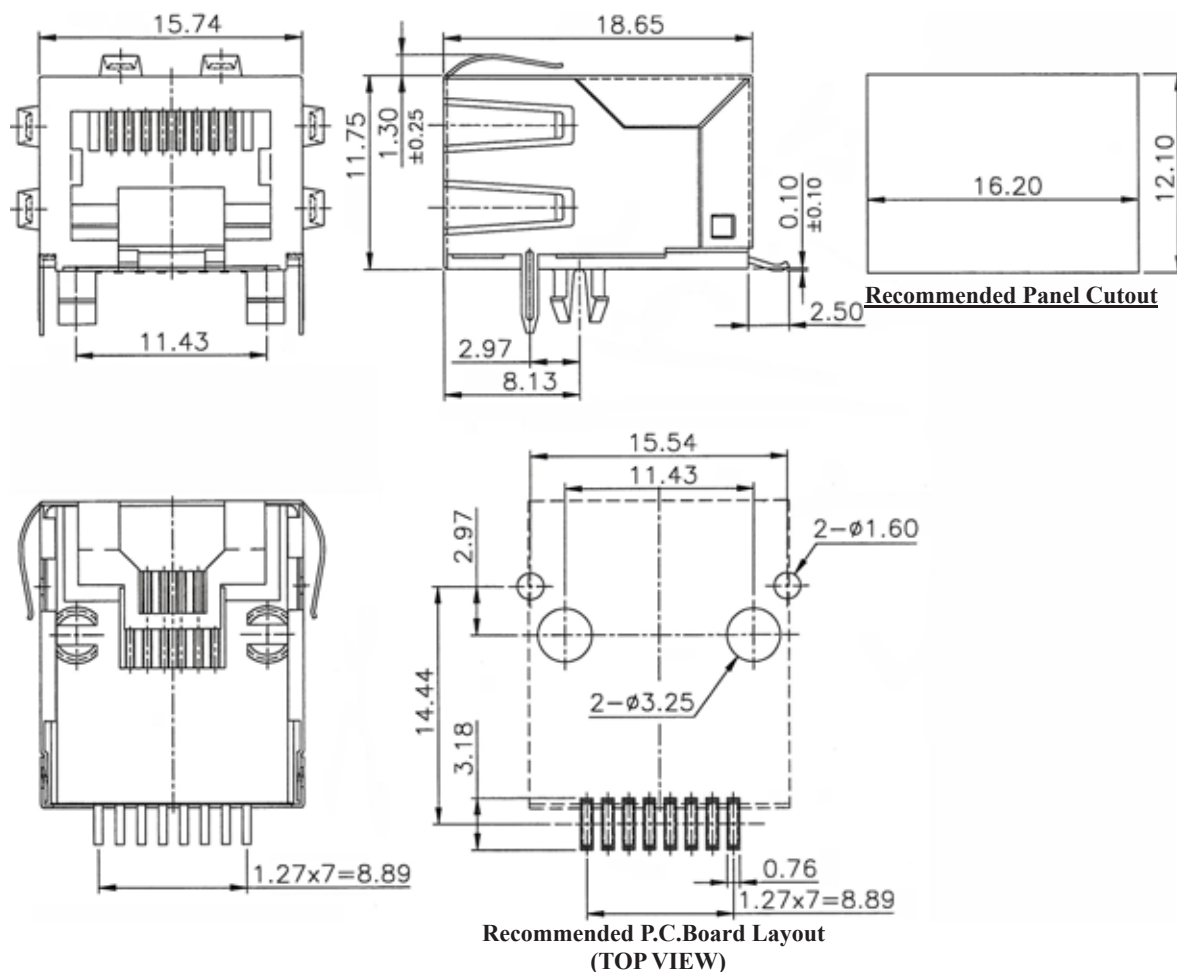
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 Y - $\frac{x}{1} \frac{x}{2} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

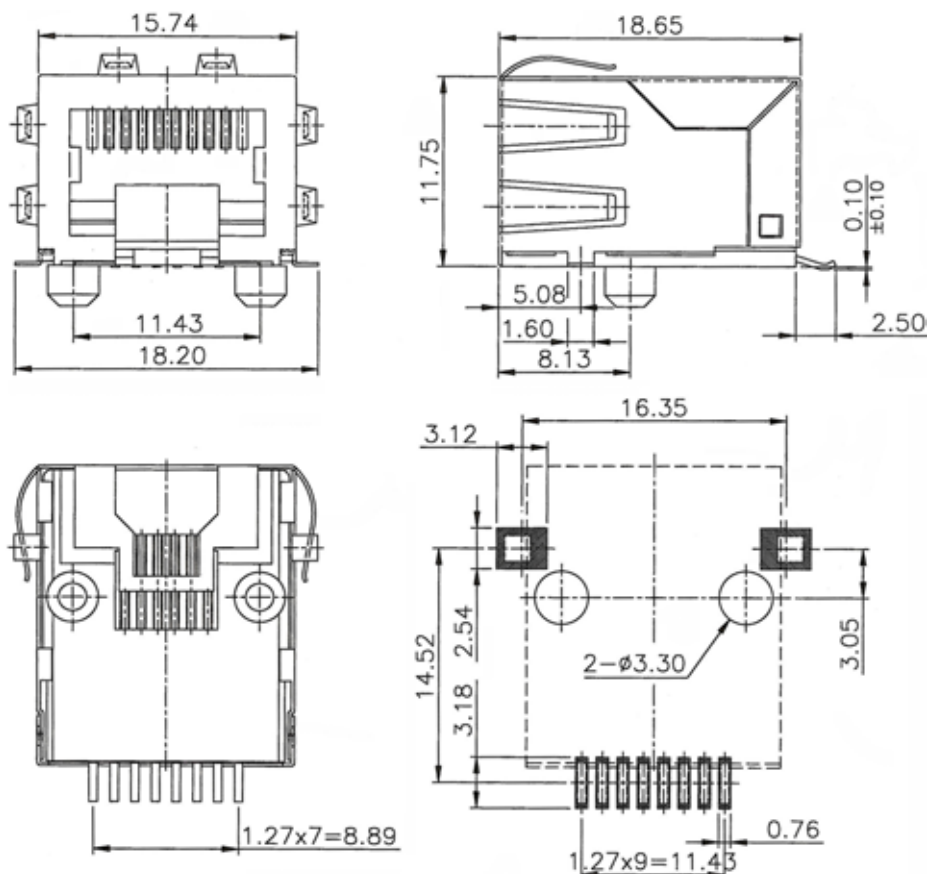
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 2 Z - $\frac{x}{1} \frac{x}{2} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

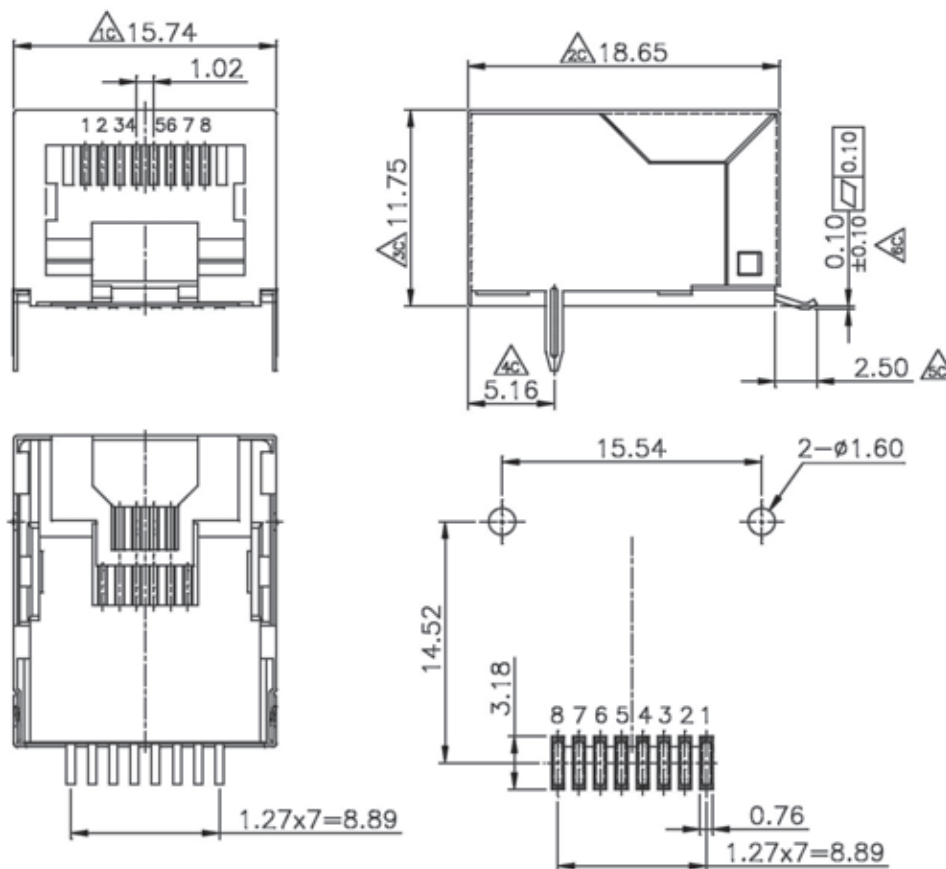
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 K - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min

Contact Resistance: 20 Milliohms Max.

Current Rating: 1.5 A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C To +85°C.

Operating: 500 Cycles Min.

MATERIALS

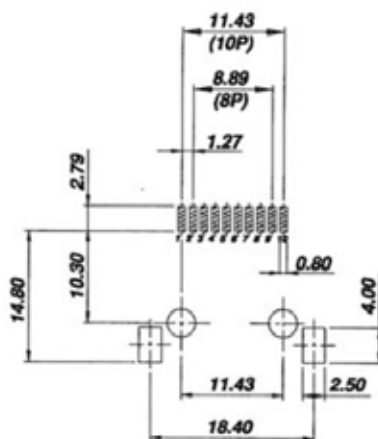
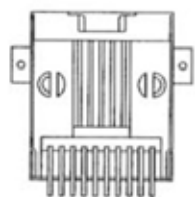
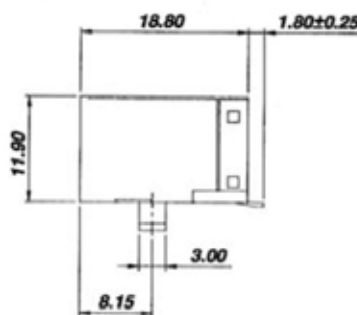
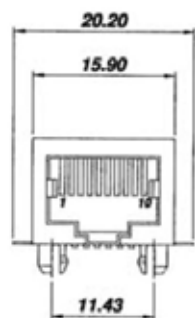
Housing: Nylon(UL 94V-0), Soldering Temperature:260°C

Color: Black

Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel

Shield: Brass Plating Nickel

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J L Q - $\frac{xx}{T}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

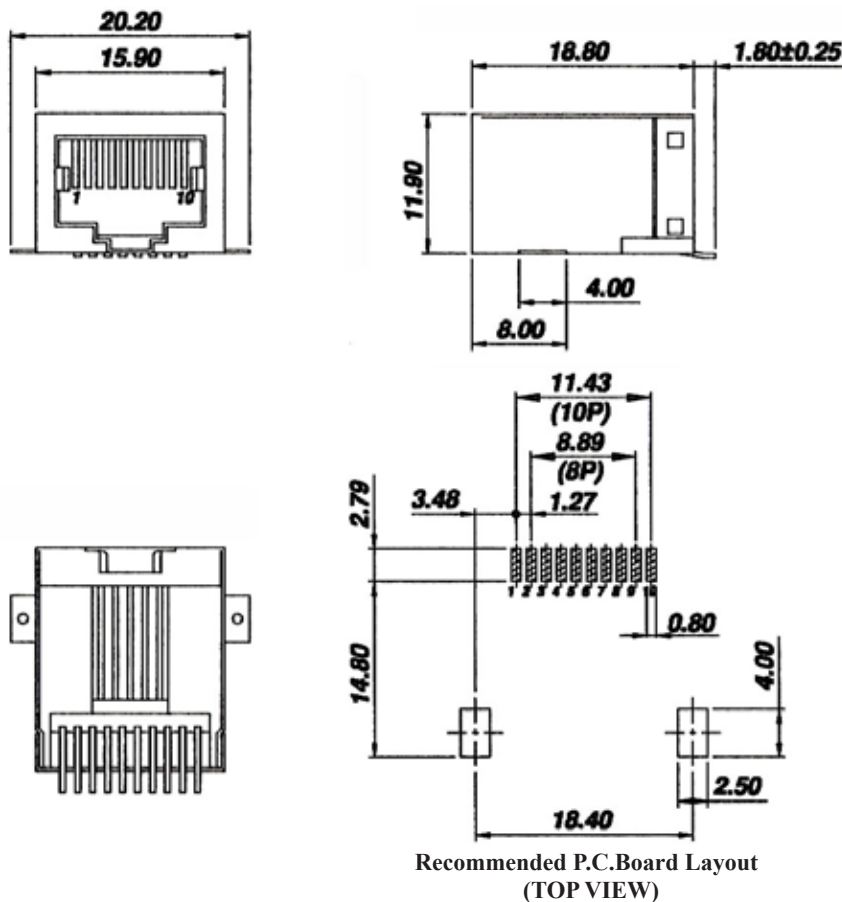
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R Z - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min

Contact Resistance: 20 Milliohms Max.

Current Rating: 1.5 A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C To +85°C.

Operating: 500 Cycles Min.

MATERIALS

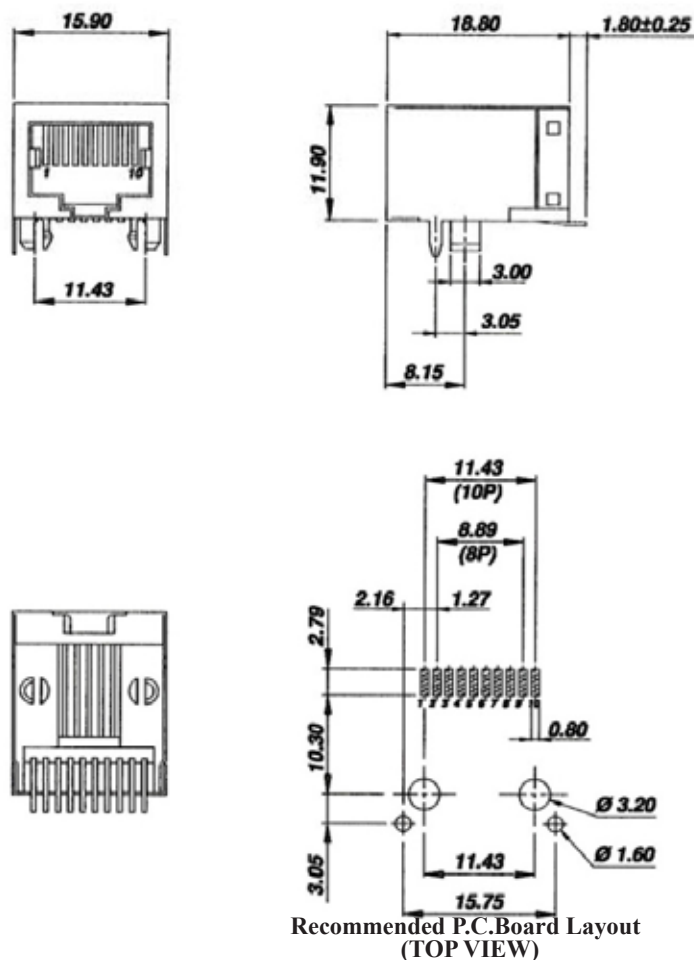
Housing: Nylon(UL 94V-0), Soldering Temperature:260°C

Color: Black

Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel

Shield: Brass Plating Nickel

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L R - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

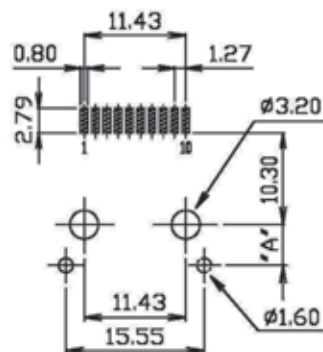
Color: Black

Spring Wire: Phosphor Bronze

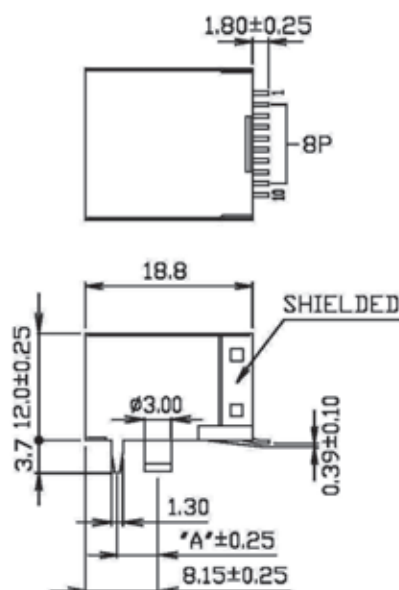
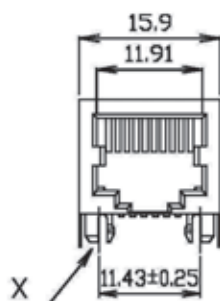
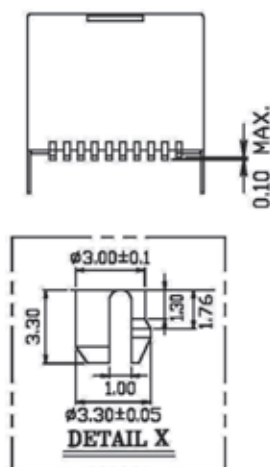
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J FG - 00 x B - x

- MODULAR JACK TYPE:
"FG" LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P8C PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

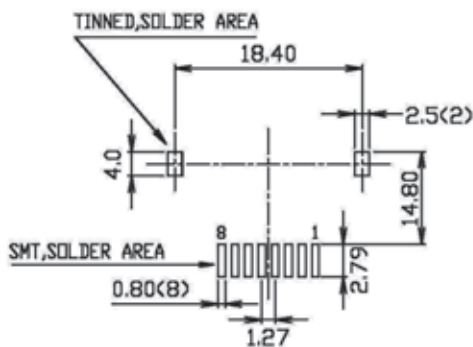
Color: Black

Spring Wire: Phosphor Bronze

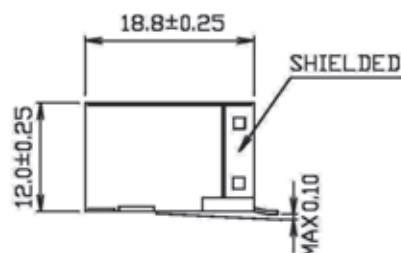
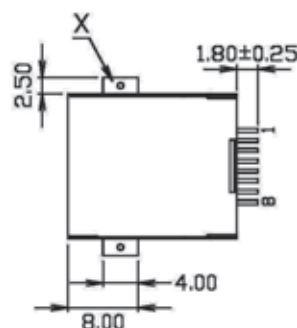
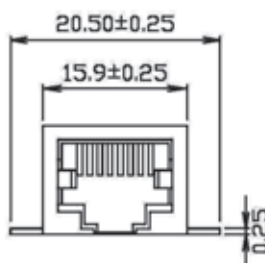
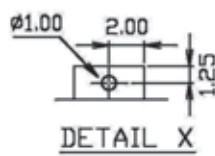
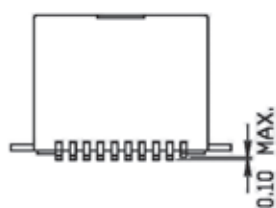
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J F H - $\frac{08}{1} \times \frac{B}{23} - \frac{x}{4}$

- MODULAR JACK TYPE:
"FH" LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY UP LATCH MODULAR SMT JACK 8P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

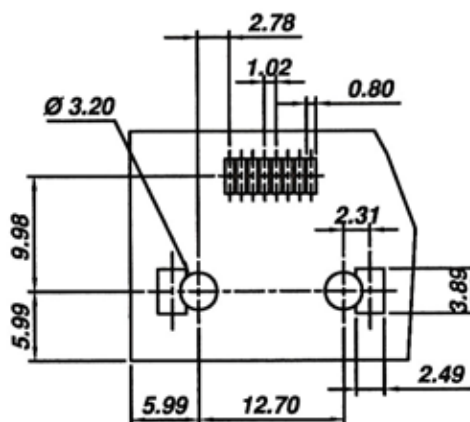
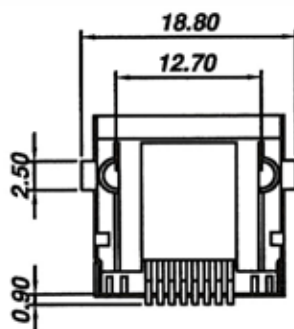
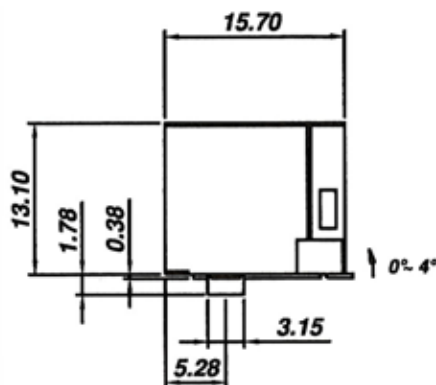
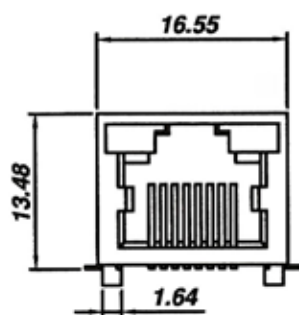
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J R P - $\frac{88}{1} \times \frac{B}{2} - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY UP LATCH MODULAR SMT JACK WITH LED 8P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

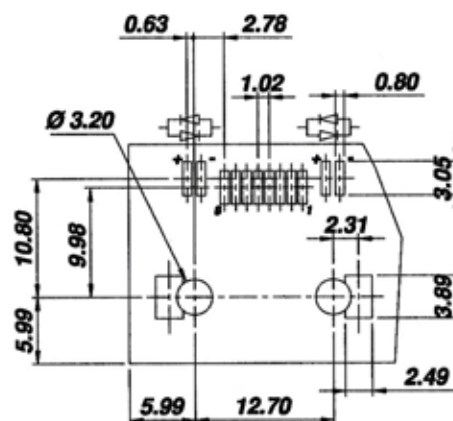
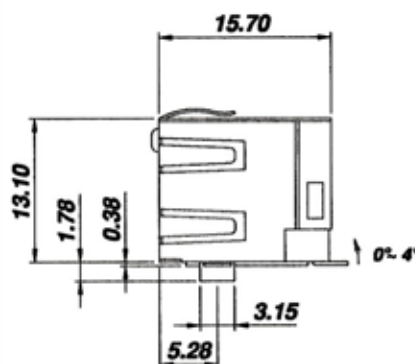
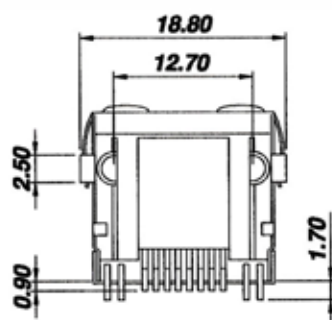
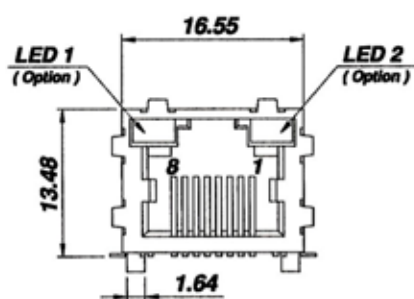
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J R Q - $\frac{88}{12}$ $\frac{B}{34}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. CODE OF LED1 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

4. CODE OF LED2 DESIGNATION:

N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=13.19MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

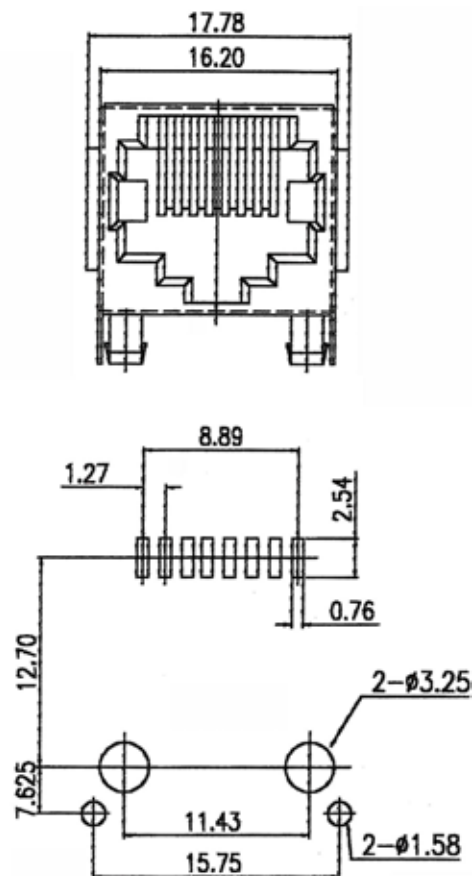
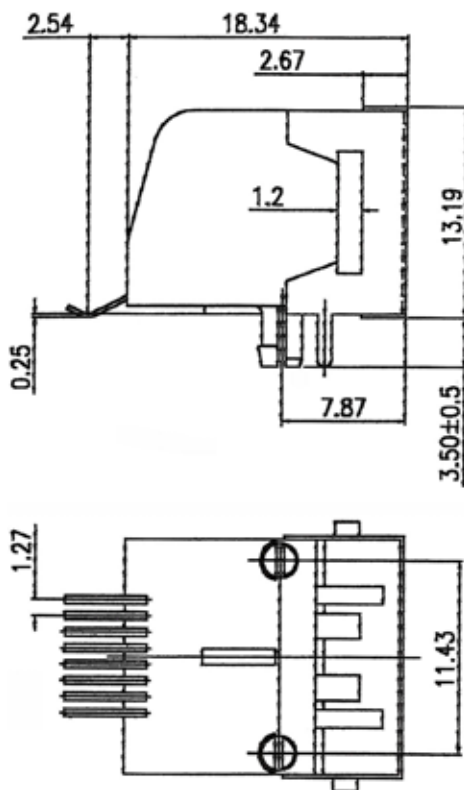
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 3 0 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"86" 8P6C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

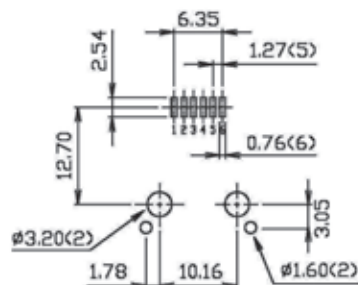
Color: Black

Spring Wire: Phosphor Bronze

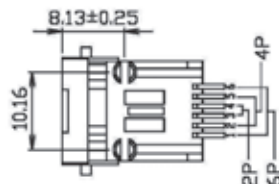
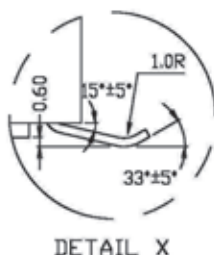
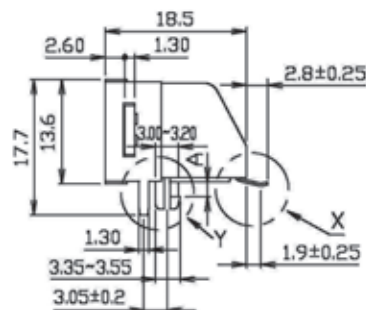
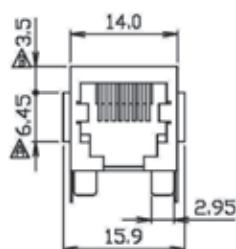
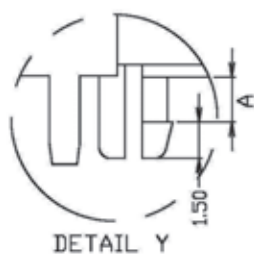
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{FM}{1}$ - $\frac{66}{2}$ $\frac{X}{3}$ B

1. MODULAR JACK TYPE:
"FM" HALF SHIELDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

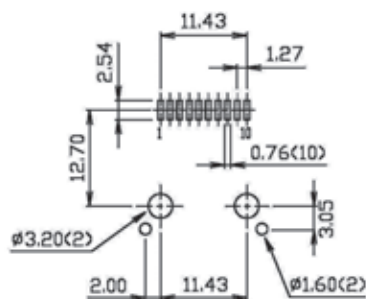
Color: Black

Spring Wire: Phosphor Bronze

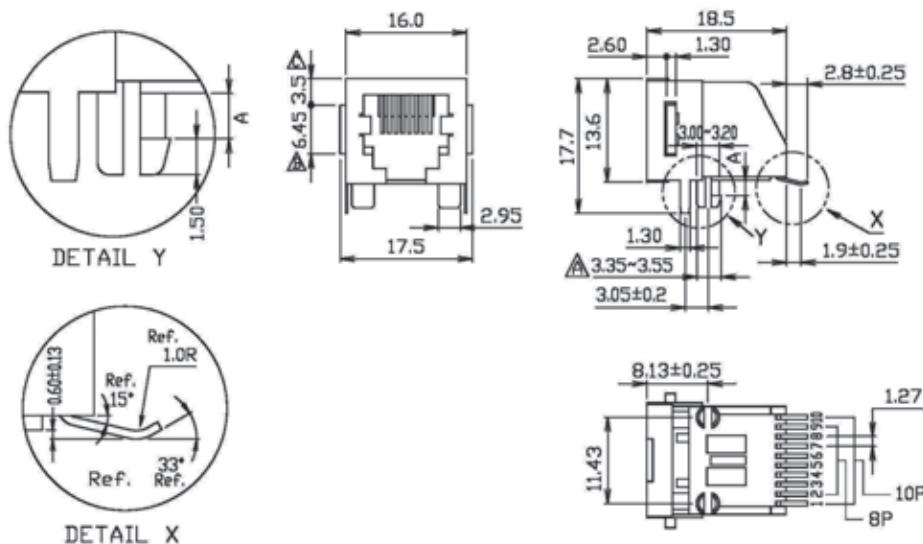
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J F M - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B$

1. MODULAR JACK TYPE:
"FM" HALF SHIELDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

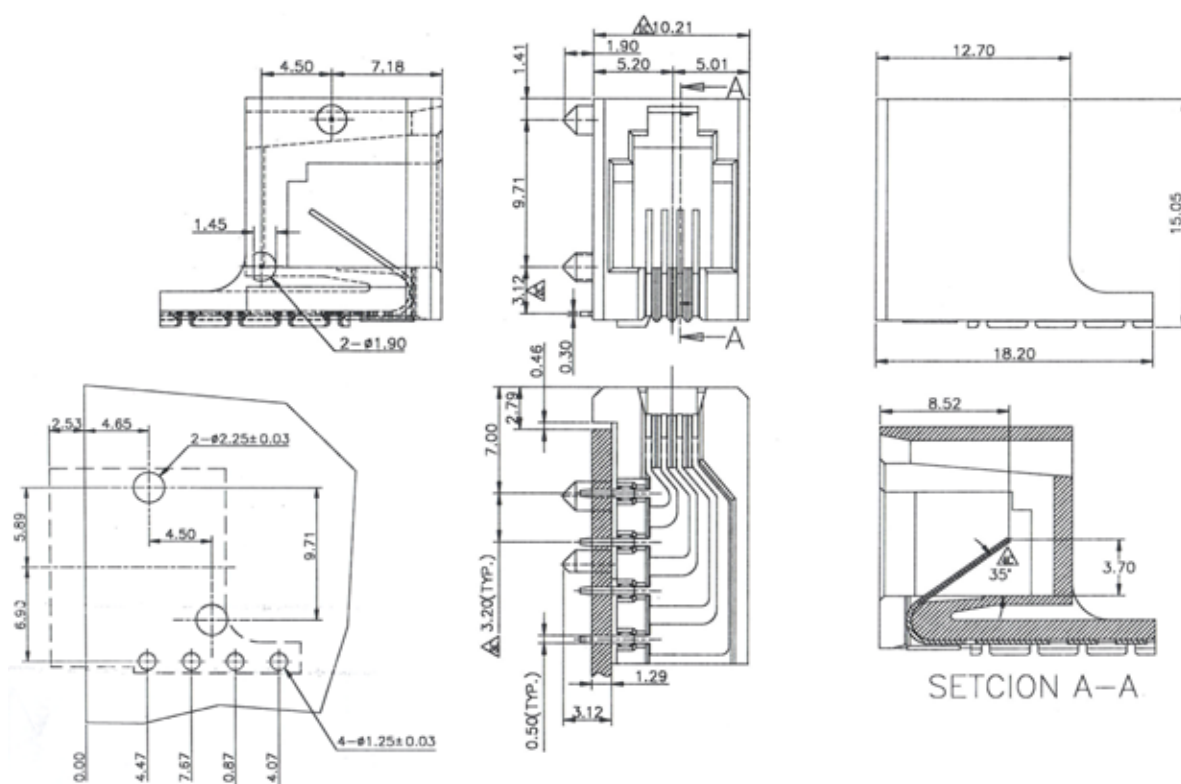
SIDE ENTRY MODULAR PCB JACK 4P NORTEL TYPE PROFILE=10.21MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J Y J - 44 C B
 1 2 3 4

1. MODULAR JACK TYPE:
"YJ" NORTEL 4P4C JACK
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"C" 30 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY LOCK TYPE MODULAR PCB JACK 8P PROFILE=14.65MM (FULLY SHIELDED)

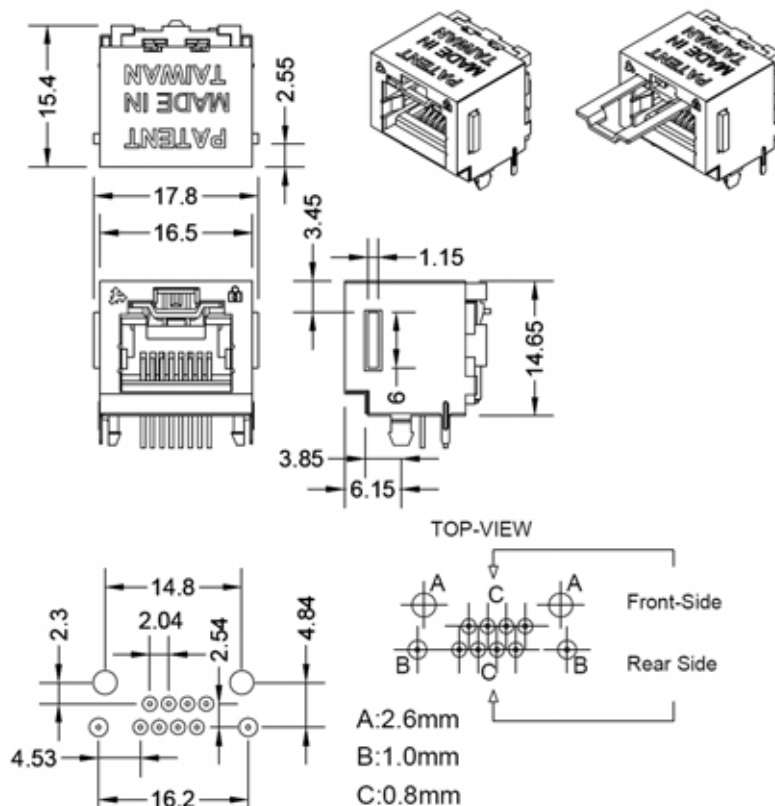
SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

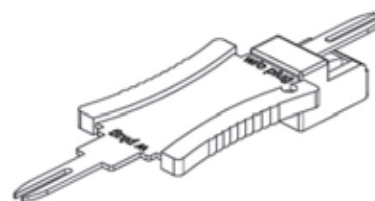
MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Lock Bar: Metal (SPCC)
Spring: SUS
Spring Base: Fireproof UL 94V-2-PC
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



P/N LKEY-88Px

ORDERING INFORMATION:

P/N M J $\frac{x}{1}x - \frac{88}{2} \frac{x}{3} B$

- PANEL STOP OPTION:
 "K1" WITH PANEL STOP
 "K2" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD (STANDARD)

NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-88MT (METAL)
 OR P/N LKEY-88Px (x=B=BLACK ; x=R=RED)!
 SEE PAGE N2291 & N2992!

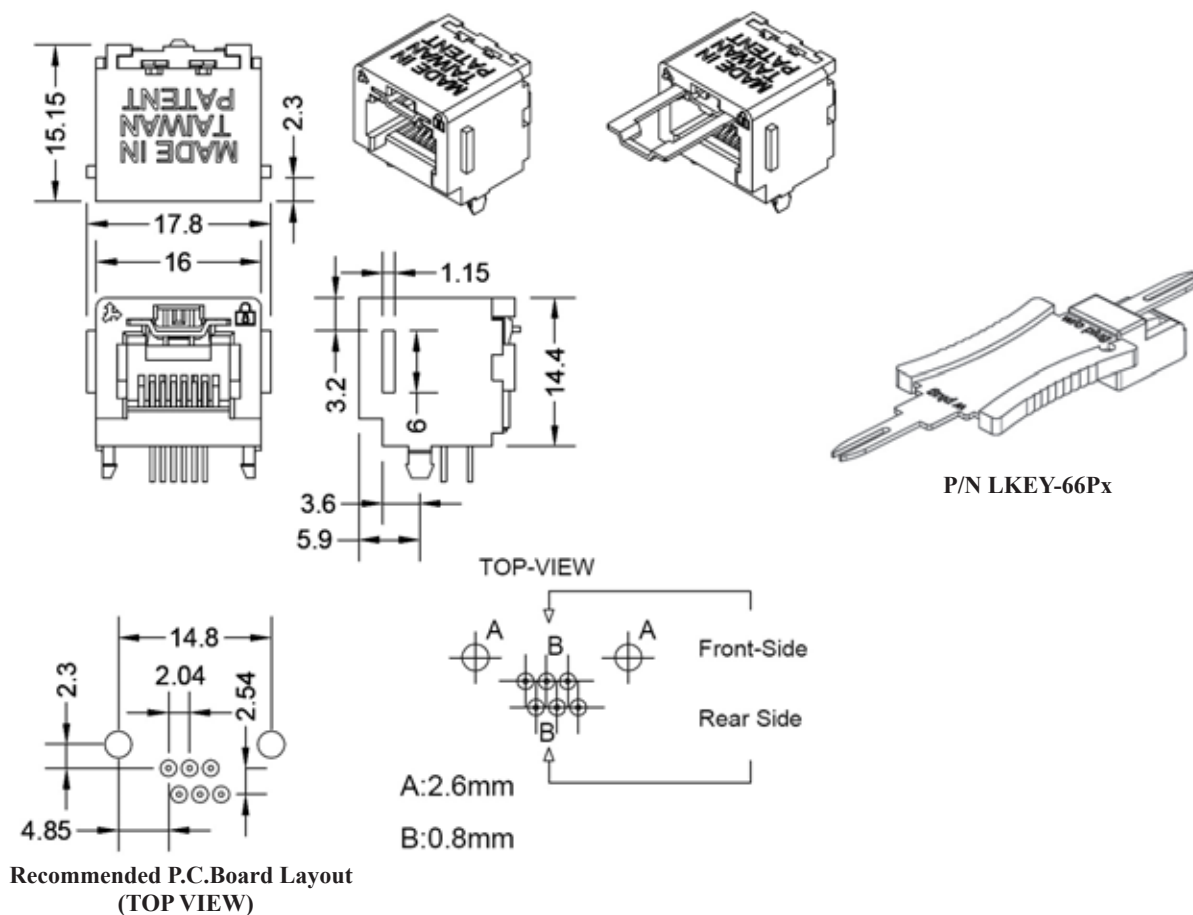
SIDE ENTRY LOCK TYPE MODULAR PCB JACK 6P PROFILE=14.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}x - \frac{66}{2} \frac{x}{3} B$

- PANEL STOP OPTION:
 "K3" WITH PANEL STOP
 "K4" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD (STANDARD)
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-66MT (METAL)
 OR P/N LKEY-66Px (x=B=BLACK ; x=R=RED)!
 SEE PAGE N2291 & N2992!

SIDE ENTRY LOCK TYPE MODULAR PCB JACK 8P PROFILE=14.40MM (UNSHIELDED)

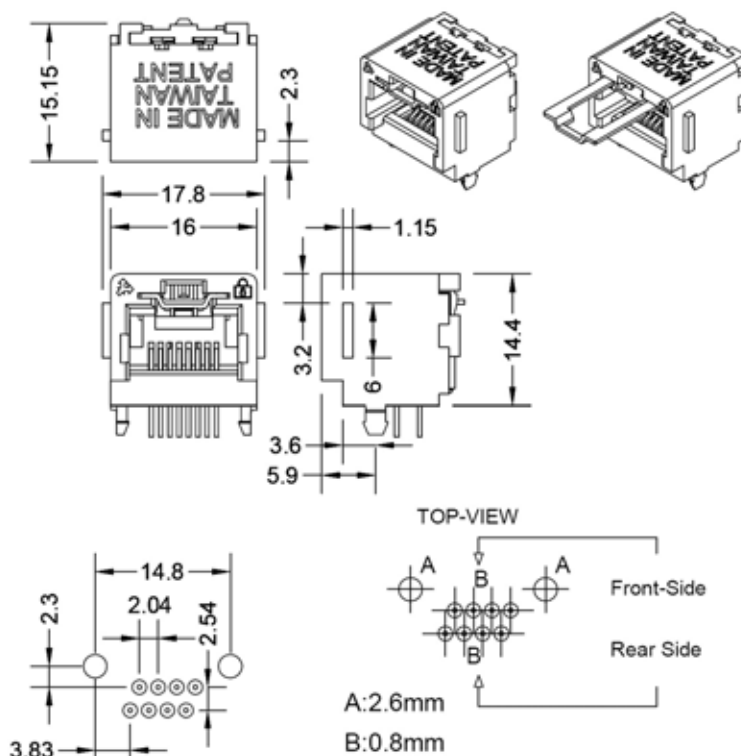
SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

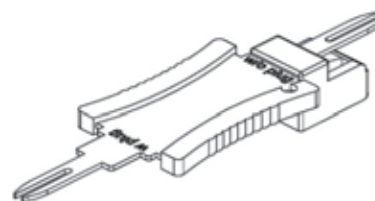
MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Lock Bar: Metal (SPCC)
Spring: SUS
Spring Base: Fireproof UL 94V-2-PC
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



P/N LKEY-88Px

ORDERING INFORMATION:

P/N M J $\frac{x}{1}x - \frac{88}{2} \frac{x}{3} B$

- PANEL STOP OPTION:
 "K3" WITH PANEL STOP
 "K4" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD (STANDARD)

NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-88MT (METAL)
 OR P/N LKEY-88Px (x=B=BLACK ; x=R=RED)!
 SEE PAGE N2291 & N2992!

METALLIC LOCK KEY WITH PVC MOLDED FOR LOCKING & SECURITY RJ45/RJ12 JACK

MATERIALS

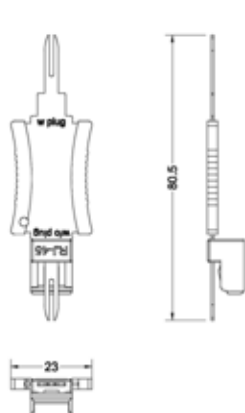
Metal: SPCC

Molding: PVC

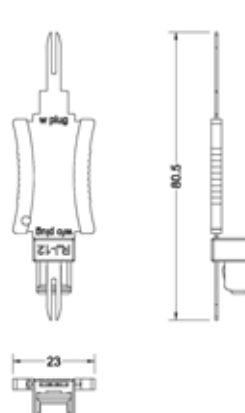
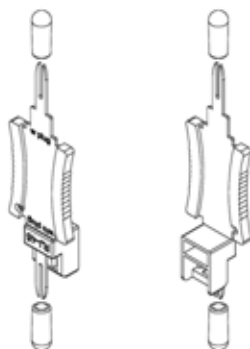
RJ45: PC

Protect Cover: PVC

*RoHS & REACH compliant.



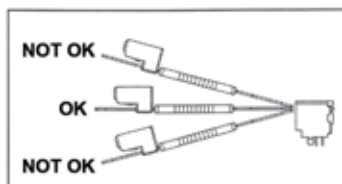
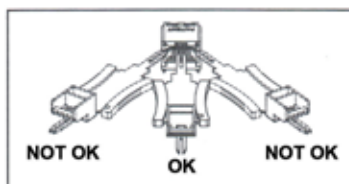
P/N LKEY-88Px



P/N LKEY-66Px



Caution !



Security Applications

Banks, Hotels, Airports, Schools, Hospitals, Retail Stores,
IP Camera Surveillance, Military Equipment.

Vibration Applications

Trains, Aircraft, Vibrating Machinery, Transportation Equipment,
Other Moving Vehicles

ORDERING INFORMATION:

P/N LKEY - $\frac{xx}{T}$ P $\frac{x}{2}$

1. RJ TYPE:

"88" FOR 8P8C (RJ45)

"66" FOR 6P6C (RJ12)

2. PVC COLOR:

"B" BLACK

"R" RED

METALLIC LOCK KEY WITHOUT PVC MOLDED FOR LOCKING & SECURITY RJ45/RJ12 JACK

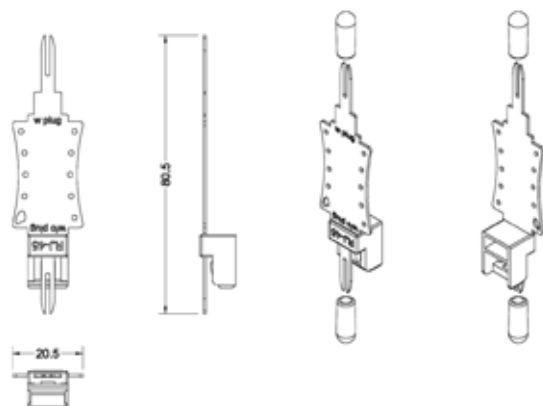
MATERIALS

Metal: SPCC

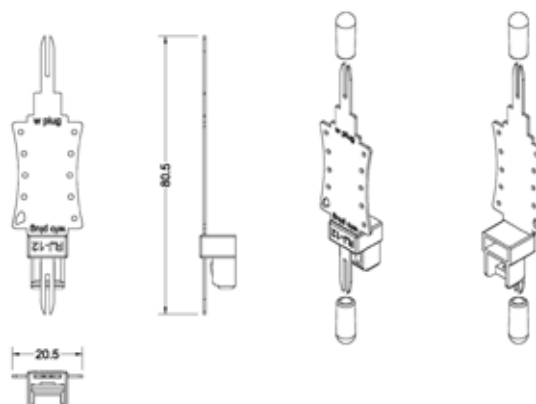
RJ45: PC

Protect Cover: PVC

*RoHS & REACH compliant.

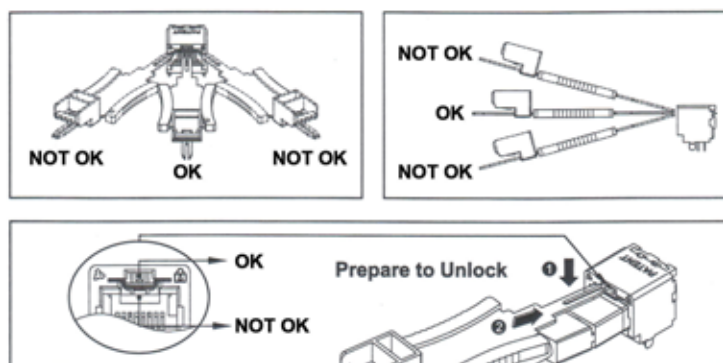


P/N LKEY-88MT



P/N LKEY-66MT

Caution !



Security Applications

Banks, Hotels, Airports, Schools, Hospitals, Retail Stores,
IP Camera Surveillance, Military Equipment.

Vibration Applications

Trains, Aircraft, Vibrating Machinery, Transportation Equipment,
Other Moving Vehicles

ORDERING INFORMATION:

P/N LKEY - xx MT

1. RJ TYPE:

"88" FOR 8P8C (RJ45)

"66" FOR 6P6C (RJ12)